

Intel[®] 400 Series Chipset Family On-Package Platform Controller Hub

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Revision History

Revision Number	Revision Description	Release Date
001	Initial Release	September 2019



1.0 Introduction

This document is intended for Original Equipment Manufacturers (OEMs), Original Design Manufacturers (ODM) and BIOS vendors creating products based on the Intel[®] 400 Series Chipset Family On-Package Platform Controller Hub (PCH).

This manual assumes a working knowledge of the vocabulary and principles of interfaces and architectures such as PCI Express* (PCIe*), Universal Serial Bus (USB), Advance Host Controller Interface (AHCI), eXtensible Host Controller Interface (xHCI), and so on. This manual abbreviates buses as Bn, devices as Dn and functions as Fn. For example Device 31 Function 0 is abbreviated as D31:F0, Bus 1 Device 8 Function 0 is abbreviated as B1:D8:F0. Generally, the bus number will not be used, and can be considered to be Bus 0.

References

Specification	Document Number/Location
Intel [®] 400 Series Chipset Family On-Package Platform Controller Hub Datasheet, Volume 2 of 2	615146

1.1 Overview

The PCH provides extensive I/O support. Functions and capabilities include:

- ACPI Power Management Logic Support, Revision 4.0a
- PCI Express* Base Specification Revision 3.0
- Integrated Serial ATA Host Controller 3.2
- USB 3.2 Gen 2x1 (10 Gb/s) eXtensible Host Controller (xHCI)
- USB 3.2 Gen 1x1 (5 Gb/s) Dual Role (eXtensible Device Controller xDCI) Capability
- Embedded MultiMediaCard (eMMC*) Controller v5.1
- Serial Peripheral Interface (SPI)
- Enhanced Serial Peripheral Interface (eSPI)
- Flexible I/O—Allows some high speed I/O signals to be configured as PCIe*, SATA 6Gb/s or USB 3.2
- General Purpose Input Output (GPIO)
- Low Pin Count (LPC) interface
- Interrupt Controller
- Timer functions
- System Management Bus (SMBus) Specification, Version 2.0
- Integrated Clock Controller (ICC) / Real Time Clock (RTC)
- Intel[®] High Definition Audio and Intel[®] Smart Sound Technology (Intel[®] SST) supporting Intel[®] HD Audio, I²S, MIPI SoundWire*, and DMIC interfaces



- Intel[®] Serial I/O UART Host Controllers
- Intel[®] Serial I/O I²C host Controllers
- Integrated 10/100/1000 Gigabit Ethernet MAC
- Integrated Sensor Hub (ISH)
- Supports Intel[®] Rapid Storage Technology (Intel[®] RST)
- Supports Intel[®] Active Management Technology (Intel[®] AMT)
- Supports Intel[®] Virtualization Technology for Directed I/O (Intel[®] VT-d)
- Supports Intel[®] Trusted Execution Technology (Intel[®] TXT)
- JTAG Boundary Scan support
- Intel[®] Trace Hub (Intel[®] TH) and Direct Connect Interface (DCI) for debug
- Supports $\text{Intel}^{\texttt{®}}$ Converged Security and Management Engine (Intel $^{\texttt{®}}$ CSME) with firmware version 12
- Integrated Intel[®] Wireless-AC Support

1.2 PCH SKUs

The following table provides an overview of the PCH I/O capabilities.

Table 1.PCH I/O Capabilities

Interface	PCH-LP			
CPU Interface	OPI x8 , up to 4 GT/s			
Integrated GbE Controller	1 data link to Intel [®] Ethernet Connection I219			
LPC	24 MHz, No DMA			
eSPI	1 CS#, Quad Mode			
I ² C	6			
UART	3			
Generic SPI (GSPI)	3			
PCIe Root Ports	Up to 6			
Audio DSP Core Count	4			
Integrated Sensor Hub (ISH)	3 I ² C, 2 UART, 1 GSPI			

Table 2.PCH SKUs

Features	Mainstream/Base-U	Premium-U	
USB 2.0 Ports	8	10	
PCIe Lanes	Up to 12 Gen2 Lanes	Up to 16 Gen3 Lanes	
USB 3.2 Ports	Up to 4 (USB 3.2 Gen 1x1 (5 Gb/s))	Up to 6 (USB 3.2 Gen 2x1 (10 Gb/s))	
SATA Ports (all 6 Gb/s capable)	Up to 2	Up to 3	



Table 3.PCH HSIO Detail

HSIO Lane	Mainstream/Base-U	Premium-U
0	USB 3.2 Gen 1x1 (5 Gb/s)	PCIe/USB 3.2 Gen 2x1 (10 Gb/s)
1	USB 3.2 Gen 1x1 (5 Gb/s)	PCIe/USB 3.2 Gen 2x1 (10 Gb/s)
2	USB 3.2 Gen 1x1 (5 Gb/s)	PCIe/USB 3.2 Gen 2x1 (10 Gb/s)
3	USB 3.2 Gen 1x1 (5 Gb/s)	PCIe/USB 3.2 Gen 2x1 (10 Gb/s)
4	PCIe	PCIe/USB 3.2 Gen 2x1 (10 Gb/s)
5	PCIe	PCIe/USB 3.2 Gen 2x1 (10 Gb/s)
6	PCIe/GbE 0A	PCIe /GbE 0A
7	PCIe /GbE 0B	PCIe /GbE 0B
8	PCIe /GbE 0C	PCIe /GbE 0C
9	PCIe	PCIe
10	PCIe/SATA 0A	PCIe/SATA 0A
11	PCIe/SATA 1A	PCIe/SATA 1A
12	PCIe /GbE 0D	PCIe/GbE 0D
13	PCIe/GbE 0E	PCIe /GbE 0E
14	PCIe	PCIe/SATA 1B
15	PCIe	PCIe/SATA 2



2.0 PCH Controller Device IDs

This chapter contains information about the Device and Revision ID table.

2.1 Device and Revision ID Table

The Revision ID (RID) register is an 8-bit register located at offset 08h in the PCI header of every $PCIe^*$ function.

Device ID	Device Function - Device Description	A0 SRID	Note
0280-029F	D31:F0 - LPC Controller (eSPI Enable Strap = 0)/ eSPI Controller (eSPI Enable Strap = 1)	00	PCH Device IDs: PCH-LP Prem-U: 0284 PCH-LP Mainstream/Base U: 0285
02A0	D31:F1 - P2SB	00	
02A1	D31:F2 - PMC	00	
02A3	D31:F4 - SMBus	00	
02A4	D31:F5 - SPI (flash) Controller	00	
0D4E	D31:F6 - GbE Controller	00	Corporate/Intel [®] vPro [™] (Default)
0D4F	D31:F6 - GbE Controller	00	Consumer
02A6	D31:F7 - Intel [®] Trace Hub (Intel [®] TH)	00	
02A8	D30:F0 - UART #0	00	
02A9	D30:F1 - UART #1	00	
02AA	D30:F2 - SPI #0	00	
02AB	D30:F3 - SPI #1	00	
02B0	D29:F0 - PCI Express* Root Port #9	F0	
02B1	D29:F1 - PCI Express* Root Port #10	F0	
02B2	D29:F2 - PCI Express* Root Port #11	F0	
02B3	D29:F3 - PCI Express* Root Port #12	F0	
02B4	D29:F4 - PCI Express* Root Port #13	F0	
02B5	D29:F5 - PCI Express* Root Port #14	F0	
02B6	D29:F6 - PCI Express* Root Port #15	F0	
02B7	D29:F7 - PCI Express* Root Port #16	F0	
02B8	D28:F0 - PCI Express* Root Port #1	F0	
02B9	D28:F1 - PCI Express* Root Port #2	F0	
02BA	D28:F2 - PCI Express* Root Port #3	F0	

Table 4.PCH-U Device and Revision ID Table



Device ID	Device Function - Device Description	A0 SRID	Note
02BB	D28:F3 - PCI Express* Root Port #4	FO	
02BC	D28:F4 - PCI Express* Root Port #5	FO	
02BD	D28:F5 - PCI Express* Root Port #6	F0	
02BE	D28:F6 - PCI Express* Root Port #7	F0	
02BF	D28:F7 - PCI Express* Root Port #8	F0	
02C4	D26:F0 - eMMC*	00	
02C5	D25:F0 - I ² C Controller #4	00	
02C6	D25:F1 - I ² C Controller #5	00	
02C7	D25:F2 - UART #2	00	
02C8	D31:F3 - Intel [®] High Definition Audio (Intel [®] HD Audio) (Audio, Voice, Speech)	00	
02D3	D23:F0 - SATA Controller (AHCI)	00	
02D5	D23:F0 - SATA Controller (RAID 0/1/5/10) - NOT premium	00	
02D7	02D7 D23:F0 - SATA Controller (RAID 0/1/5/10) - premium		
282A	282A D23:F0 - SATA Controller (RAID 0/1/5/10) - In-box Compatible ID		
02E0	D22:F0 - Intel [®] MEI #1	00	
02E1	D22:F1 - Intel [®] MEI #2	00	
02E2	D22:F2 - IDE Redirection (IDER-R)	00	
02E3	D22:F3 - Keyboard and Text (KT) Redirection	00	
02E4	D22:F4 - Intel [®] MEI #3	00	
02E5	D22:F5 - Intel [®] MEI #4	00	
02E8	D21:F0 - I ² C Controller #0	00	
02E9	D21:F1 - I ² C Controller #1	00	
02EA	D21:F2 - I ² C Controller #2	00	
02EB	D21:F3 - I ² C Controller #3	00	
02ED	D20:F0 - USB 3.2 Gen 2x1 (10 Gb/s) xHCI HC	00	
02EE	D20:F1 - USB 3.2 Gen 1x1 (5 Gb/s) Device Controller (xDCI)	00	
02EF	D20:F2 - Shared SRAM	00	
02F0	D20:F3 - CNVi: Wi-Fi*	00	
02F5	D20:F5 - SDXC	00	
02F9	D18:F0 - Thermal Subsystem	00	
02FB	D18:F6 - SPI #2	00	
02FC	D19:F0 - Integrated Sensor Hub	00	



3.0 Flexible I/O

Flexible Input/Output (I/O) is a technology that allows some of the PCH High Speed I/O (HSIO) lanes to be configured for connection to a Gigabit Ethernet (GbE) Controller, a PCIe* Controller, a Extensible Host Controller Interface (xHCI) USB 3.2 Controller, or a Advanced Host Controller Interface (AHCI) SATA Controller. Flexible I/O enables customers to optimize the allocation of the PCH HSIO interfaces to better meet the I/O needs of their system.

NOTE

Some Flexible I/O multiplexing capabilities are not available on all SKUs.

3.1 Flexible I/O Implementation

This section provides information about the following:

- PCH-U
- Flexible I/O Lane Selection

3.1.1 PCH-U

Figure 1. High Speed I/O (HSIO) Lane Multiplexing in PCH-U

Flex I/O Lane	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
High Speed I/O (HSIO) Type and Lane	USB 3.2 Gen 1x1/2x1 #1 PCIe*	USB 3.2 Gen 1x1/2x1 #2 PCIe*	USB 3.2 Gen 1x1/2x1 #3 PCIe*	USB 3.2 Gen 1x1/2x1 #4 PCIe*	USB 3.2 Gen 1x1/2x1 #5 PCIe*	USB 3.2 Gen 1x1/2x1 #6 PCIe*	PCIe* #7	PCIe* #8	PCIe* #9	PCIe* #10	PCIe* #11 S	PCIe* #12 S/	PCIe* #13	PCIe* #14	PCIe* #15 S/	PCIe* #16 S.
	#1	#2	#3	#4	#5	#6	GbE	GbE	GbE		SATA 0	SATA 1a	GbE	GbE	SATA 1b	SATA 2
Intel® RST Support		No Si	ipport			No Si	ipport			Y	es			Ye	es	

The 16 HSIO lanes on PCH-U support the following configurations:

1. Up to 16 PCIe* Lanes



- A maximum of 6 PCIe* Ports (or devices) can be enabled
 - When a GbE Port is enabled, the maximum number of PCIe* Ports (or devices) that can be enabled reduces based off the following:
 - Maximum PCIe* Ports (or devices) = 6 GbE (0 or 1)
- PCIe* Lanes 1-4 (PCIe* Controller #1), 5-8 (PCIe* Controller #2), 9-12 (PCIe* Controller #3), and 13-16 (PCIe* Controller #4) can be individually configured
- 2. Up to 4 SATA Lanes
 - A maximum of 3 SATA Ports (or devices) can be enabled
 - SATA Lane 1 has the flexibility to be mapped to Flex I/O Lane 11 or 14
- 3. Up to 6 USB 3.2 Gen 1x1/2x1 Lanes
 - A maximum of 6 USB 3.2 Gen 1x1/2x1 Ports (or devices) can be enabled
 - USB 3.2 Gen 1x1 = 5 GT/s
 - USB 3.2 Gen 2x1 = 10 GT/s
- 4. Up to 5 GbE Lanes
 - A maximum of 1 GbE Port (or device) can be enabled
- 5. Supports up to two remapped (Intel[®] Rapid Storage Technology) PCIe* storage devices
 - x2 and x4 PCIe* NVMe SSD
 - x2 and x4 Next Generation Intel[®] Optane[™] Memory
 - Refer the "PCI Express* (PCIe*)" chapter for the PCH PCIe* Controllers, configurations, and lanes that can be used for Intel[®] Rapid Storage Technology PCIe* storage support
- 6. For unused SATA/PCIe* Combo Lanes, Flex I/O Lanes that can be configured as PCIe* or SATA, the lanes must be statically assigned to SATA or PCIe* via the SATA/PCIe Combo Port Soft Straps. These unused SATA/PCIe* Combo Lanes must not be assigned as polarity based.

3.1.2 Flexible I/O Lane Selection

HSIO lane configuration and type are statically selected by soft straps.

PCIe*/SATA Lane Selection

In addition to static configuration via soft straps, Flexible I/O Lanes that have PCIe*/ SATA multiplexing can be configured via SATAXPCIE signaling to support implementation like SATA Express or mSATA, where the port configuration is selected by the type of the add-in card that is used.



4.0 Memory Mapping

This section describes (from the processor perspective) the memory ranges that the PCH decodes. This section provides information about the following:

- Functional Description
- Memory Map

4.1 **Functional Description**

This section provides the following information:

- PCI Devices and Functions
- Fixed I/O Address Ranges
- Variable I/O Decode Ranges

4.1.1 PCI Devices and Functions

The PCH incorporates a variety of PCI devices and functions, as shown in the following table. If a particular system platform does not want to support any one of the Device Functions, with the exception of D30:F0, they can individually be disabled. The integrated Gigabit Ethernet controller will be disabled if no Platform LAN Connect component is detected (refer Gigabit Ethernet Controller on page 127).

When a function is disabled, it does not appear to the software. A disabled function will not respond to any register reads or writes, insuring that these devices appear hidden to software.

Devices and Function	Description
Bus M: Device 31: Function 0	LPC Interface (eSPI Enable Strap = 0) eSPI Interface (eSPI Enable Strap = 1)
Bus M: Device 31: Function 1	P2SB
Bus M: Device 31: Function 2	РМС
Bus M: Device 31: Function 3	AVS (Audio, Voice, Speech)
Bus M: Device 31: Function 4	SMBus Controller
Bus M: Device 31: Function 5	SPI
Bus M: Device 31: Function 6	GbE Controller
Bus M: Device 31: Function 7	Intel [®] Trace Hub
Bus M: Device 30: Function 0	UART #0
Bus M: Device 30: Function 1	UART #1
Bus M: Device 30: Function 2	SPI #0
	continued

Table 5. PCI Devices and Functions



Devices and Function	Description
Bus M: Device 30: Function 3	SPI #1
Bus M: Device 29: Function 0	PCI Express* Port 9
Bus M: Device 29: Function 1	PCI Express* Port 10
Bus M: Device 29: Function 2	PCI Express* Port 11
Bus M: Device 29: Function 3	PCI Express* Port 12
Bus M: Device 29: Function 4	PCI Express* Port 13
Bus M: Device 29: Function 5	PCI Express* Port 14
Bus M: Device 29: Function 6	PCI Express* Port 15
Bus M: Device 29: Function 7	PCI Express* Port 16
Bus M: Device 28: Function 0	PCI Express* Port 1
Bus M: Device 28: Function 1	PCI Express* Port 2
Bus M: Device 28: Function 2	PCI Express* Port 3
Bus M: Device 28: Function 3	PCI Express* Port 4
Bus M: Device 28: Function 4	PCI Express* Port 5
Bus M: Device 28: Function 5	PCI Express* Port 6
Bus M: Device 28: Function 6	PCI Express* Port 7
Bus M: Device 28: Function 7	PCI Express* Port 8
Bus M: Device 26: Function 0	eMMC
Bus M: Device 25: Function 0	I ² C Controller #4
Bus M: Device 25: Function 1	I ² C Controller #5
Bus M: Device 25: Function 2	UART Controller #2
Bus M: Device 24: Function 0	Reserved. Used by the NVM Remapping.
Bus M: Device 23: Function 0	SATA Controller
Bus M: Device 22: Function 0	Intel [®] MEI #1
Bus M: Device 22: Function 1	Intel [®] MEI #2
Bus M: Device 22: Function 2	IDE-Redirection (IDE-R)
Bus M: Device 22: Function 3	Keyboard and Text (KT) Redirection
Bus M: Device 22: Function 4	Intel [®] MEI #3
Bus M: Device 22: Function 5	Intel [®] MEI #4
Bus M: Device 22: Function 7	WLAN
Bus M: Device 21: Function 0	I ² C Controller #0
Bus M: Device 21: Function 1	I ² C Controller #1
Bus M: Device 21: Function 2	I ² C Controller #2
Bus M: Device 21: Function 3	I ² C Controller #3
Bus M: Device 20: Function 0	xHCI Controller
	continued



Devices and Function	Description
Bus M: Device 20: Function 1	USB Device Controller
Bus M: Device 20: Function 2	Shared SRAM
Bus M: Device 20: Function 3	CNVi: Wi-Fi
Bus M: Device 20: Function 5	SDXC
Bus M: Device 19: Function 0	Integrated Sensor Hub
Bus M: Device 18: Function 0	Thermal Subsystem
Bus M: Device 18: Function 2	РМТ
Bus M: Device 18: Function 6	SPI #2

4.1.2 Fixed I/O Address Ranges

Table below shows the Fixed I/O decode ranges from the processor perspective. Note that for each I/O range, there may be separate behavior for reads and writes. OPI cycles that go to target ranges that are marked as Reserved will be handled by the PCH; writes are ignored and reads will return all 1s. The P2SB will claim many of the fixed I/O accesses and forward those transactions over IOSF-SB to their functional target.

Address ranges that are not listed or marked Reserved are NOT positively decoded by the PCH (unless assigned to one of the variable ranges) and will be internally terminated by the PCH.

I/O Address			Internal Unit (unless[E]: External) ²	Separate Enable/Disabl
20h – 21h	Interrupt Controller	Interrupt Controller	Interrupt	None
24h – 25h	Interrupt Controller	Interrupt Controller	Interrupt	None
28h – 29h	Interrupt Controller	Interrupt Controller	Interrupt	None
2Ch – 2Dh	Interrupt Controller	Interrupt Controller	Interrupt	None
2Eh-2Fh	Super I/O	Super I/O	[E] Forwarded to LPC/eSPI	Yes. IOE.SE
30h – 31h	Interrupt Controller	Interrupt Controller	Interrupt	None
34h – 35h	Interrupt Controller	Interrupt Controller	Interrupt	None
38h – 39h	Interrupt Controller	Interrupt Controller	Interrupt	None
3Ch – 3Dh	Interrupt Controller	Interrupt Controller	Interrupt	None
40h	Timer/Counter	Timer/Counter	8254 Timer	None
42h-43h	Timer/Counter	Timer/Counter	8254 Timer	None
42n-43n	Timer/Counter	Timer/Counter	8254 Timer	None con

Table 6.Fixed I/O Ranges Decoded by PCH



I/O Address	Read Target	Write Target	Internal Unit (unless[E]: External) ²	Separate Enable/Disable
4Eh-4Fh	Microcontroller	Microcontroller	[E] Forwarded to LPC/eSPI	Yes. IOE.ME2
50h	Timer/Counter	Timer/Counter	8254 Timer	None
52h-53h	Timer/Counter	Timer/Counter	8254 Timer	None
60h	Keyboard Controller	Keyboard Controller	[E] Forwarded to LPC/eSPI	Yes, with 64h. IOE.KE
61h	NMI Controller	NMI Controller	CPU I/F	None
62h	Microcontroller	Microcontroller	[E] Forwarded to LPC/eSPI	Yes, with 66h. IOE.ME1
63h	NMI Controller ¹	NMI Controller ¹	CPU I/F	Yes, alias to 61h. GIC.P61AE
64h	Keyboard Controller	Keyboard Controller	[E] Forwarded to LPC/eSPI	Yes, with 60h. IOE.KE
65h	NMI Controller ¹	NMI Controller ¹	CPU I/F	Yes, alias to 61h. GIC.P61AE
66h	Microcontroller	Microcontroller	[E] Forwarded to LPC/eSPI	Yes, with 62h. IOE.ME1
67h	NMI Controller ¹	NMI Controller ¹	CPU I/F	Yes, alias to 61h. GIC.P61AE
70h	RTC Controller	NMI and RTC Controller	RTC	None
71h	RTC Controller	RTC Controller	RTC	None
72h	RTC Controller	RTC Controller	RTC	None. Alias to 70h if RC.UE=0, else 72h
73h	RTC Controller	RTC Controller	RTC	None. Alias to 71h if RC.UE='0', else 73h
74h	RTC Controller	RTC Controller	RTC	None
75h	RTC Controller	RTC Controller	RTC	None
76h-77h	RTC Controller	RTC Controller	RTC	None. Alias to 70h-71h if RC.UE=0, else 76h-77h
80h ³	LPC/eSPI or PCIe*	LPC/eSPI or PCIe*	Read: LPC/[E] eSPI or PCIe* Write: [E] LPC/[E] eSPI or [E] PCIe*	None. PCIe* if GCS.RPR='1', else LPC/eSPI
84h - 86h	LPC/eSPI or PCIe*	LPC/eSPI or PCIe*	Read: LPC/[E] eSPI or PCIe* Write: [E] LPC/[E] eSPI or [E] PCIe*	None. PCIe* if GCS.RPR='1', else LPC/eSPI continued



I/O Address	Read Target	Write Target	Internal Unit (unless[E]: External) ²	Separate Enable/Disable
88h	LPC/eSPI or PCIe*	LPC/eSPI or PCIe*	Read: LPC/[E] eSPI or PCIe* Write: [E] LPC/[E] eSPI or [E] PCIe*	None. PCIe* if GCS.RPR='1', else LPC/eSPI
8Ch - 8Eh	LPC/eSPI or PCIe*	LPC/eSPI or PCIe*	Read: LPC/[E] eSPI or PCIe* Write: [E] LPC/[E] eSPI or [E] PCIe*	None. PCIe* if GCS.RPR='1', else LPC/eSPI
90h	LPC/eSPI	LPC/eSPI	Read: LPC/[E] eSPI Write: [E] LPC/[E] eSPI	None. Alias to 80h
92h	Reset Generator	Reset Generator	CPU I/F	None
94h - 96h	LPC/eSPI	LPC/eSPI	Read: LPC/[E] eSPI Write: [E] LPC/[E] eSPI	None. Alias to 8xh
98h	LPC/eSPI	LPC/eSPI	Read: LPC/[E] eSPI Write: [E] LPC/[E] eSPI	None. Alias to 88h
9Ch - 9Eh	LPC/eSPI	LPC/eSPI	Read: LPC/[E] eSPI Write: [E] LPC/[E] eSPI	None. Alias to 8xh
A0h - A1h	Interrupt Controller	Interrupt Controller	Interrupt	None
A4h - A5h	Interrupt Controller	Interrupt Controller	Interrupt	None
A8h - A9h	Interrupt Controller	Interrupt Controller	Interrupt	None
ACh - ADh	Interrupt Controller	Interrupt Controller	Interrupt	None
B0h - B1h	Interrupt Controller	Interrupt Controller	Interrupt	None
B2h - B3h	Power Management	Power Management	Power Management	None
B4h - B5h	Interrupt Controller	Interrupt Controller	Interrupt	None
B8h - B9h	Interrupt Controller	Interrupt Controller	Interrupt	None
BCh - BDh	Interrupt Controller	Interrupt Controller	Interrupt	None
200h-207h	Gameport Low	Gameport Low	[E] Forwarded to LPC/eSPI	Yes. IOE.LGE



I/O Address	Read Target	Write Target	Internal Unit (unless[E]: External) ²	Separate Enable/Disable
208h-20Fh	Gameport High	Gameport High	[E] Forwarded to LPC/eSPI	Yes. IOE.HGE
4D0h - 4D1h	Interrupt Controller	Interrupt Controller	Interrupt Controller	None
CF9h	Reset Generator	Reset Generator	Interrupt controller	None
 Notes: 1. Only if the Port 61 Alias Enable bit (GIC.P61AE) bit is set. Otherwise, the cycle is internally terminated by the PCH. 2. Destination of LPC/eSPI is depending on the eSPI/LPC Pin Strap, '1': eSPI, '0': LPC. 				

3. This includes byte, word or double-word (DW) access at I/O address 80h.

4.1.3 Variable I/O Decode Ranges

Table below shows the Variable I/O Decode Ranges. They are set using Base Address Registers (BARs) or other configuration bits in the various configuration spaces. The PnP software (PCI or ACPI) can use their configuration mechanisms to set and adjust these values.

WARNING

The Variable I/O Ranges should not be set to conflict with the Fixed I/O Ranges. There may be some unpredictable results if the configuration software allows conflicts to occur. The PCH does not perform any checks for conflicts.

Table 7.Variable I/O Decode Ranges

Range Name	Mappable	Size (Bytes)	Target
АСРІ	Anywhere in 64K I/O Space	256	Power Management
IDE Bus Master	Anywhere in 64K I/O Space	16 or 32 Bytes	Intel [®] AMT IDE-R
SMBus	Anywhere in 64K I/O Space	32	SMB Unit
тсо	Anywhere in 64K I/O Space	32	SMB Unit
Parallel Port	3 ranges in 64K I/O Space	8	LPC/eSPI
Serial Port 1	8 Ranges in 64K I/O Space	8	LPC/eSPI
Serial Port 2	8 Ranges in 64K I/O Space	8	LPC/eSPI
Serial Port 3	8 Ranges in 64K I/O space	8	LPC/eSPI
Floppy Disk Controller	2 Ranges in 64K I/O Space	8	LPC/eSPI
LPC Generic 1	Anywhere in 64K I/O Space	4 to 256 Bytes	LPC/eSPI
LPC Generic 2	Anywhere in 64K I/O Space	4 to 256 Bytes	LPC/eSPI
LPC Generic 3	Anywhere in 64K I/O Space	4 to 256 Bytes	LPC/eSPI
LPC Generic 4	Anywhere in 64K I/O Space	4 to 256 Bytes	LPC/eSPI
IO Trapping Ranges	Anywhere in 64K I/O Space	1 to 256 Bytes	Тгар
Serial ATA Index/Data Pair	Anywhere in 64K I/O Space	16	SATA Host Controller
		•	continued



Range Name	Mappable	Size (Bytes)	Target
PCI Express* Root Ports	Anywhere in 64K I/O Space	I/O Base/Limit	PCI Express* Root Ports 1-6
Keyboard and Text (KT)	Anywhere in 64K I/O Space	8	Intel [®] AMT Keyboard and Text
Note: All ranges are decoded directly from OPI.			

4.2 Memory Map

Table below shows (from the Processor perspective) the memory ranges that the PCH will decode. Cycles that arrive from OPI that are not directed to any of the internal memory targets that decode directly from OPI will be master aborted.

PCIe* cycles generated by external PCIe* masters will be positively decoded unless they fall in the PCI-PCI bridge memory forwarding ranges (those addresses are reserved for PCI peer-to-peer traffic). If the cycle is not in the internal LAN controllers range, it will be forwarded up to OPI. Software must not attempt locks to the PCH's memory-mapped I/O ranges.

NOTE

Total ports are different for different SKUs.

Memory Range	Target	Dependency/Comments
000E 0000h - 000E FFFFh	LPC/eSPI or SPI	Bit 6 in BIOS Decode Enable Register is set.
000F 0000h - 000F FFFFh	LPC/eSPI or SPI	Bit 7 in BIOS Decode Enable Register is set.
FECX X000h - FECX X040h	I/O(x)APIC inside PCH	XX controlled via APIC Range Select (ASEL) field and APIC Enable (AEN) bit.
FECX X000h - FECX XFFFh	PCIe* port N (N=1 to 16)	X controlled via PCIe* root port N IOxAPIC Range Base/Limit registers and Port N I/OxApic Enable (PAE) is set
FEF0 0000h - FEFF FFFFh	LPC/eSPI or SPI	uCode Patch Region Enable UCPR.UPRE is set
FFC0 0000h - FFC7 FFFFh FF80 0000h - FF87 FFFFh	LPC/eSPI or SPI	Bit 8 in BIOS Decode Enable Register is set
FFC8 0000h – FFCF FFFFh FF88 0000h - FF8F FFFFh	LPC/eSPI or SPI	Bit 9 in BIOS Decode Enable Register is set
FFD0 0000h - FFD7 FFFFh FF90 0000h - FF97 FFFFh	LPC/eSPI or SPI	Bit 10 in BIOS Decode Enable Register is set
FFD8 0000h – FFDF FFFFh FF98 0000h - FF9F FFFFh	LPC/eSPI or SPI	Bit 11 in BIOS Decode Enable Register is set
FFE0 0000h - FFE7 FFFFh FFA0 0000h - FFA7 FFFFh	LPC/eSPI or SPI	Bit 12 in BIOS Decode Enable Register is set
FFE8 0000h – FFEF FFFFh FFA8 0000h – FFAF FFFFh	LPC/eSPI or SPI	Bit 13 in BIOS Decode Enable Register is set
FFF0 0000h - FFF7 FFFFh FFB0 0000h - FFB7 FFFFh	LPC/eSPI or SPI	Bit 14 in BIOS Decode Enable Register is set
	1	continued

Table 8. PCH Memory Decode Ranges (Processor Perspective)



Memory Range	Target	Dependency/Comments
FFFC 0000h - FFFF FFFFh	LPC/eSPI, SPI, or ME	Always enabled. Refer to Table 9 on page 29 for swappable ranges
FFF8 0000h - FFFB FFFFh FFB8 0000h - FFBF FFFFh	LPC/eSPI or SPI	Always enabled. Refer to Table 9 on page 29 for swappable ranges
FF70 0000h - FF7F FFFFh FF30 0000h - FF3F FFFFh	LPC/eSPI or SPI	Bit 3 in BIOS Decode Enable Register is set
FF60 0000h - FF6F FFFFh FF20 0000h - FF2F FFFFh	LPC/eSPI or SPI	Bit 2 in BIOS Decode Enable Register is set
FF50 0000h - FF5F FFFFh FF10 0000h - FF1F FFFFh	LPC/eSPI or SPI	Bit 1 in BIOS Decode Enable Register is set
FF40 0000h - FF4F FFFFh FF00 0000h - FF0F FFFFh	LPC/eSPI or SPI	Bit 0 in BIOS Decode Enable Register is set
FED0 X000h - FED0 X3FFh	НРЕТ	BIOS determines "fixed" location which is one of four 1 KB ranges where X (in the first column) is 0h, 1h, 2h, or 3h.
FED4 0000h - FED4 7FFFh	LPC or SPI (set by strap)	TPM and Trusted Mobile KBC
FED4 C000h - FED4 FFFFh	PCH Internal (PSF Error Handler)	Always enabled
FED5 0000h - FED5 FFFFh	Intel [®] CSME	Always enabled
FED7 0000h - FED7 4FFFh	Internal Device	Security feature related
128 KB anywhere in 4 GB range	LAN Controller (CSR registers)	Enable via standard PCI mechanism (Device 31:Function 6)
4 KB anywhere in 4 GB range	LAN Controller (LAN space on Flash)	Enable via standard PCI mechanism (Device 31:Function 6)
64 KB anywhere in 64-bit address range	USB 3.2 Gen 2x1 (10 Gb/s) Host Controller	Enable via standard PCI mechanism (Device 20, Function 0)
2 MB anywhere in 4 GB range	USB 3.2 Gen 1x1 (5 Gb/s) Device Controller	Enable via standard PCI mechanism (Device 20, Function 1)
24 KB anywhere in 4 GB range	USB 3.2 Gen 1x1 (5 Gb/s) Device Controller	Enable via standard PCI mechanism (Device 20, Function 1)
16 KB anywhere in 64-bit addressing space	Intel [®] HD Audio Subsystem	Enable via standard PCI mechanism (Device 31, Function 3)
4 KB anywhere in 64-bit addressing space	Intel [®] HD Audio Subsystem	Enable via standard PCI mechanism (Device 31, Function 3)
64 KB anywhere in 64-bit addressing space	Intel [®] HD Audio Subsystem	Enable via standard PCI mechanism (Device 31, Function 3)
64 KB anywhere in 4 GB range	LPC/eSPI	LPC Generic Memory Range. Enable via setting bit[0] of the LPC Generic Memory Range register (D31:F0:offset 98h).
32 Bytes anywhere in 64-bit address range	SMBus	Enable via standard PCI mechanism (Device 31: Function 4)
2 KB anywhere above 64 KB to 4 GB range	SATA Host Controller	AHCI memory-mapped registers. Enable via standard PCI mechanism (Device 23: Function 0)
Memory Base/Limit anywhere in 4 GB range	PCI Express* Root Ports	Enable via standard PCI mechanism
Prefetchable Memory Base/ Limit anywhere in 64-bit address range	PCI Express* Root Ports	Enable via standard PCI mechanism



Memory Range Target		Dependency/Comments
4 KB anywhere in 64-bit address range	Thermal Reporting	Enable via standard PCI mechanism (Device 18: Function 0)
16 Bytes anywhere in 64-bit address range	Intel [®] MEI #1, #2, #3, #4	Enable via standard PCI mechanism
4 KB anywhere in 4 GB range	Intel [®] AMT Keyboard and Text	Enable via standard PCI mechanism (Device 22: Function 3)
Eight 4 KB slots anywhere in 64-bit address range	UART, GPI and I ² C controllers	Enable via standard PCI mechanism
4 KB slots anywhere in 64- bit address range	eMMC and SDXC controllers	Enable via standard PCI mechanism
1 MB (BAR0) or 4 KB (BAR1) Integrated Sensor Hub in 4 GB range		Enable via standard PCI mechanism (Device 19: Function 0)
8 KB slot anywhere in 4 GB Integrated Wi-Fi range		Enable via standard PCI mechanism

4.2.1 Boot Block Update Scheme

The PCH supports a "Top-Block Swap" mode that has the PCH swap the top block in the FWH or SPI flash (the boot block) with another location. This allows for safe update of the Boot Block (even if a power failure occurs). When the "top-swap" enable bit is set, the PCH will invert A16 for cycles going to the upper two 64-KB blocks in the FWH or appropriate address lines as selected in Boot Block Size (BOOT_BLOCK_SIZE) soft strap for SPI.

For FHW when top swap is enabled, accesses to FFFF 0000h-FFFF FFFFh are directed to FFFE 0000h-FFFE FFFFh and vice versa. When the Top Swap Enable bit is 0, the PCH will not invert A16.

For SPI when top swap is enabled, the behavior is as described below. When the Top Swap Enable bit is 0, the PCH will not invert any address bit.

Table 9.Boot Block Update Scheme

BOOT_BLOCK_SIZE Value	Accesses to	Being Directed to
000 (64 KB)	FFFF 0000h - FFFF FFFFh	FFFE 000h - FFFE FFFFh and vice versa
001 (128 KB)	FFFE 0000h - FFFF FFFFh	FFFC 0000h - FFFD FFFFh and vice versa
010 (256 KB)	FFFC 0000h - FFFF FFFFh	FFF8 0000h - FFFB FFFFh and vice versa
011 (512 KB)	FFF8 0000h - FFFF FFFFh	FFF0 0000h - FFF7 FFFFh and vice versa
100 (1 MB)	FFF0 0000h - FFFF FFFFh	FFE0 0000h - FFEF FFFFh and vice versa
101 - 111	Reserved	Reserved
Note: This bit is automatically set to 0 by RTCRST#, but not by PLTRST#.		

The scheme is based on the concept that the top block is reserved as the "boot" block, and the block immediately below the top block is reserved for doing boot-block updates.

The algorithm is:

1. Software copies the top block to the block immediately below the top.



- 2. Software checks that the copied block is correct. This could be done by performing a checksum calculation.
- 3. Software sets the "Top-Block Swap" bit. This will invert the appropriate address bits for the cycles going to the FWH or the SPI.
- 4. Software erases the top block.
- 5. Software writes the new top block.
- 6. Software checks the new top block.
- 7. Software clears the top-block swap bit.
- 8. Software sets the Top_Swap Lock-Down bit.

If a power failure occurs at any point after step 3, the system will be able to boot from the copy of the boot block that is stored in the block below the top. This is because the top-swap bit is backed in the RTC well.

There is one remaining unusual case that could occur if the RTC battery is not sufficiently high to maintain the RTC well. To avoid the potentially fatal case (where the Top-Swap bit is NOT set, but the top block is not valid), a pin strap will allow forcing the top-swap bit to be set. This would be a last resort to allow the user to get the system to boot (and avoid having to de-solder the system flash).

When the top-swap strap is used, the top-swap bit will be forced to 1 (cannot be cleared by software).



5.0 System Management

The PCH provides various functions to make a system easier to manage and to lower the Total Cost of Ownership (TCO) of the system. Features and functions can be augmented using external A/D converters and GPIOs, as well as an external micro controller.

Acronyms

Acronyms	Description
ВМС	Baseboard Management Controller
SPD	Serial Presence Detect
тсо	Total Cost of Ownership

5.1 Features

The following features and functions are supported by the PCH:

- First timer timeout to generate SMI# after programmable time:
 - $-\,$ The first timer timeout causes an SMI#, allowing SMM-based recovery from OS lock up
- Various Error detection (such as ECC Errors) indicated by host controller:
 - Can generate SMI#, SCI, SERR, SMI, or TCO interrupt
- Intruder Detect input:
 - Can generate TCO interrupt or SMI#

5.1.1 Theory of Operation

The System Management functions are designed to allow the system to diagnose failing subsystems. The intent of this logic is that some of the system management functionality can be provided without the aid of an external microcontroller.

Handling an Intruder

The PCH has an input signal, INTRUDER#, that can be attached to a switch that is activated by the system's case being open. This input has a two RTC clock debounce. If INTRUDER# goes active (after the debouncer), this will set the INTRD_DET bit in the TCO2_STS register. The INTRD_SEL bits in the TCO2_CNT register can enable the PCH to cause an SMI# or interrupt. The BIOS or interrupt handler can then cause a transition to the S5 state by writing to the SLP_EN bit.

The software can also directly read the status of the INTRUDER# signal (high or low) by clearing and then reading the INTRD_DET bit. This allows the signal to be used as a GPI if the intruder function is not required.



If the INTRUDER# signal goes inactive some point after the INTRD_DET bit is written as a 1, then the INTRD_DET bit will go to a 0 when INTRUDER# input signal goes inactive.

ΝΟΤΕ

This is slightly different than a classic sticky bit, since most sticky bits would remain active indefinitely when the signal goes active and would immediately go inactive when a 1 is written to the bit.

5.1.2 TCO Modes

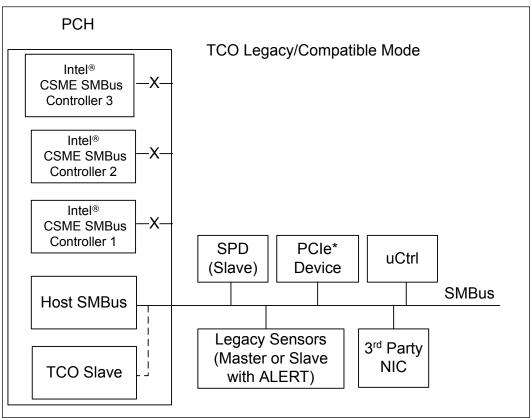
This section provides information about the following:

- TCO Compatible Mode
- Advanced TCO Mode

TCO Compatible Mode

In TCO Legacy/Compatible mode, only the host SMBus is used. The TCO Slave is connected to the host SMBus internally by default. In this mode, the Intel[®] Converged Security and Management Engine (Intel[®] CSME) SMBus controllers are not used and should be disabled by soft strap.

Figure 2. TCO Compatible Mode SMBus Configuration





In TCO Legacy/Compatible mode the PCH can function directly with an external LAN controller or equivalent external LAN controller to report messages to a network management console without the aid of the system processor. This is crucial in cases where the processor is malfunctioning or cannot function due to being in a low-power state. Table below includes a list of events that will report messages to the network management console.

Event	Assertion	Deassertion	Comments
INTRUDER# pin	Yes	No	Must be in "hung S0" state
Watchdog Timer Expired	Yes	NA	"Hung S0" state entered
SMBALERT# pin	Yes	Yes	Must be in "Hung S0" state
BATLOW#	Yes	Yes	Must be in "Hung S0" state
CPU_PWR_FLR	Yes	No	"Hung S0" state entered

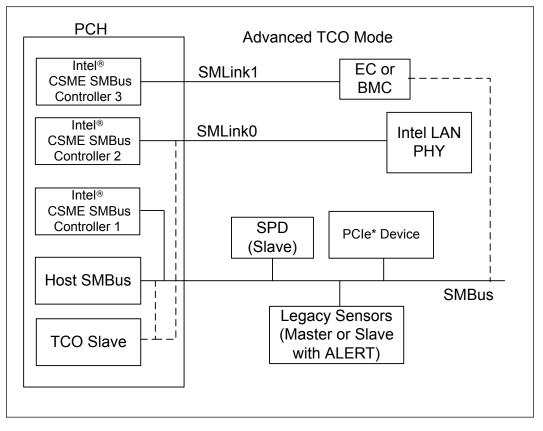
Table 10. Event Transitions that Cause Messages

Advanced TCO Mode

- The PCH supports the Advanced TCO mode in which SMLink0 and SMLink1 are used in addition to the host SMBus. In this mode, the Intel[®] CSME SMBus controllers must be enabled by soft strap in the flash descriptor. Refer to figure below for more details. In advanced TCO mode, the TCO slave can either be connected to the host SMBus or the SMLink0.
- SMLink0 is targeted for integrated LAN use. When an Intel LAN PHY is connected to SMLink0, a soft strap must be set to indicate that the PHY is connected to SMLink0. When the Fast Mode is enabled using a soft strap, the interface will be running at the frequency of up to 1 MHz depending on different factors such as board routing or bus loading.
- SMLink1 can be connected to an Embedded Controller (EC) or Baseboard Management Controller (BMC) use. In the case where a BMC is connected to SMLink1, the BMC communicates with the Intel[®] Converged Security and Management Engine through the Intel[®] CSME SMBus connected to SMLink1. The host and TCO slave communicate with BMC through SMBus.



Figure 3. Advanced TCO Mode





6.0 High Precision Event Timer (HPET)

Specification	Location
IA-PC HPET (High Precision Event Timers) Specification, Revision 1.0a	http://www.intel.com/content/dam/www/ public/us/en/documents/technical-specifications/ software-developers-hpet-spec-1-0a.pdf

This function provides a set of timers that can be used by the operating system. The timers are defined such that the operating system may assign specific timers to be used directly by specific applications. Each timer can be configured to cause a separate interrupt.

The PCH provides eight timers. The timers are implemented as a single counter with a set of comparators. Each timer has its own comparator and value register. The counter increases monotonically. Each individual timer can generate an interrupt when the value in its value register matches the value in the main counter.

Timer 0 supports periodic interrupts.

The registers associated with these timers are mapped to a range in memory space (much like the I/O APIC). However, it is not implemented as a standard PCI function. The BIOS reports to the operating system the location of the register space using ACPI. The hardware can support an assignable decode space; however, BIOS sets this space prior to handing it over to the operating system. It is not expected that the operating system will move the location of these timers once it is set by BIOS.

6.1 Timer Accuracy

The timers are accurate over any 1 ms period to within 0.05% of the time specified in the timer resolution fields.

Within any 100-microsecond period, the timer reports a time that is up to two ticks too early or too late. Each tick is less than or equal to 100 ns; thus, this represents an error of less than 0.2%.

The timer is monotonic. It does not return the same value on two consecutive reads (unless the counter has rolled over and reached the same value).

The main counter uses the PCH's 24 MHz XTAL as its clock. The accuracy of the main counter is as accurate as the crystal that is used in the system. The XTAL clock frequency is determined by the pin strap that is sampled on RSMRST#.

6.2 Timer Off-load

The PCH supports a timer off-load feature that allows the HPET timers to remain operational during very low power S0 operational modes when the 24 MHz clock is disabled. The clock source during this off-load is the Real Time Clocks 32.768 kHz



clock. This clock is calibrated against the 24 MHz clock during boot time to an accuracy that ensures the error introduced by this off-load is less than 10 ppb (. 000001%).

When the 24 MHz clock is active, the 64-bit counter will increment by one each cycle of the 24 MHz clock when enabled. When the 24 MHz clock is disabled, the timer is maintained using the RTC clock. The long-term (> 1 msec) frequency drift allowed by the HPET specification is 500 ppm. The off-load mechanism ensures that it contributes < 1ppm to this, which will allow this specification to be easily met given the clock crystal accuracies required for other reasons.

Timer off-load is prevented when there are HPET comparators active.

The HPET timer in the PCH runs typically on the 24 MHz crystal clock and is off-loaded to the 32 kHz clock once the processor enters C10. This is the state where there are no C10 wake events pending and when the off-load calibrator is not running. HPET timer re-uses this 28 bit calibration value calculated by PMC when counting on the 32 kHz clock. During C10 entry, PMC sends an indication to HPET to off-load and keeps the indication active as long as the processor is in C10 on the 32 kHz clock. The HPET counter will be off-loaded to the 32 KHz clock domain to allow the 24 MHz clock to shut down when it has no active comparators.

Theory of Operation

- The Off-loadable Timer Block consists of a 64b fast clock counter and an 82b slow clock counter. During fast clock mode the counter increments by one on every rising edge of the fast clock. During slow clock mode, the 82-bit slow clock counter will increment by the value provided by the Off-load Calibrator.
- The Off-loadable Timer will accept an input to tell it when to switch to the slow RTC clock mode and provide an indication of when it is using the slow clock mode. The switch will only take place on the slow clock rising edge, so for the 32 kHz RTC clock the maximum delay is around 30 microseconds to switch to or from slow clock mode. Both of these flags will be in the fast clock domain.
- When transitioning from fast clock to slow clock, the fast clock value will be loaded into the upper 64b of the 82b counter, with the 18 LSBs set to zero. The actual transition through happens in two stages to avoid metastability. There is a fast clock sampling of the slow clock through a double flop synchronizer.
- Following a request to transition to the slow clock, the edge of the slow clock is detected and this causes the fast clock value to park. At this point the fast clock can be gated.
- On the next rising edge of the slow clock, the parked fast clock value (in the upper 64b of an 82b value) is added to the value from the Off-load Calibrator. On subsequent edges while in slow clock mode the slow clock counter increments its count by the value from the Off-load Calibrator.
- When transitioning from slow clock to fast clock, the fast clock waits until it samples a rising edge of the slow clock through its synchronizer and then loads the upper 64b of the slow clock value as the fast count value. It then de-asserts the indication that slow clock mode is active. The 32 kHz clock counter no longer counts. The 64-bit MSB will be over-written when the 32 kHz counter is reloaded once conditions are met to enable the 32 kHz HPET counter but the 18-bit LSB is retained and it is not cleared out during the next reload cycle to avoid losing the fractional part of the counter.



• After initiating a transition from fast clock to slow clock and parking the fast counter value, the fast counter no longer tracks. This means if a transition back to fast clock is requested before the entry into off-load slow clock mode completes, the Off-loadable Timer must wait until the next slow clock edge to restart. This case effectively performs the fast clock to slow clock and back to fast clock on the same slow clock edge.

6.3 Interrupt Mapping

The interrupts associated with the various timers have several interrupt mapping options. When reprogramming the HPET interrupt routing scheme (LEG_RT_CNF bit in the General Config Register), a spurious interrupt may occur. This is because the other source of the interrupt (8254 timer) may be asserted. Software should mask interrupts prior to clearing the LEG_RT_CNF bit.

Mapping Option #1 (Legacy Replacement Option)

Table 11. Legacy Replacement Routing

8259 Mapping	APIC Mapping	Comment
IRQ0	IRQ2	In this case, the 8254 timer will not cause any interrupts
IRQ8	IRQ8	In this case, the RTC will not cause any interrupts.
Per IRQ Routing Field.	Per IRQ Routing Field	
Not available	Not available	
	IRQ0 IRQ8 Per IRQ Routing Field.	IRQ0 IRQ2 IRQ8 IRQ8 Per IRQ Routing Field. Per IRQ Routing Field

Note: The Legacy option does not preclude delivery of IRQ0/IRQ8 using processor interrupts messages.

Mapping Option #2 (Standard Option)

In this case, the Legacy Replacement Rout bit (LEG_RT_CNF) is 0. Each timer has its own routing control. The interrupts can be routed to various interrupts in the 8259 or I/O APIC. A capabilities field indicates which interrupts are valid options for routing. If a timer is set for edge-triggered mode, the timers should not be shared with any legacy interrupts.

For the PCH, the only supported interrupt values are as follows:

Timer 0 and 1: IRQ20, 21, 22, and 23 (I/O APIC only).

Timer 2: IRQ11 (8259 or I/O APIC) and IRQ20, 21, 22, and 23 (I/O APIC only).

Timer 3: IRQ12 (8259 or I/O APIC) and IRQ 20, 21, 22, and 23 (I/O APIC only).



NOTES

- 1. Interrupts from Timer 4, 5, 6, 7 can only be delivered via direct FSB interrupt messages.
- 2. System architecture changes since the HPET specification 1.0 was released have made some of the terminology used obsolete. In particular the reference to a Front Side Bus (FSB) has no relevance to current platforms, as this interface is no longer in use. For consistency with the HPET specification though, the FSB and specifically the FSB Interrupt Delivery terminology has been maintained. Where the specification refers to FSB, this should be read as 'processor message interface'; independent of the physical attach mechanism.

Mapping Option #3 (Processor Message Option)

In this case, the interrupts are mapped directly to processor messages without going to the 8259 or I/O (x) APIC. To use this mode, the interrupt must be configured to edge-triggered mode. The Tn_PROCMSG_EN_CNF bit must be set to enable this mode.

When the interrupt is delivered to the processor, the message is delivered to the address indicated in the Tn_PROCMSG_INT_ADDR field. The data value for the write cycle is specified in the Tn_PROCMSG_INT_VAL field.

NOTE

The FSB interrupt deliver option has HIGHER priority and is mutually exclusive to the standard interrupt delivery option. Thus, if the TIMERn_FSB_EN_CNF bit is set, the interrupts will be delivered via the FSB, rather than via the APIC or 8259.

The FSB interrupt delivery can be used even when the legacy mapping is used.

For the Intel PCH HPET implementation, the direct FSB interrupt delivery mode is supported, besides via 8259 or I/O APIC.

6.4 Periodic Versus Non-Periodic Modes

This section provides information about Non-Periodic Mode and Periodic Mode.

Non-Periodic Mode

This mode can be thought of as creating a one-shot.

When a timer is set up for non-periodic mode, it will generate an interrupt when the value in the main counter matches the value in the timer's comparator register. Another interrupt will be generated when the main counter matches the value in the timer's comparator register after a wrap around.

During run-time, the value in the timer's comparator value register will not be changed by the hardware. Software can of course change the value.

The Timer 0 Comparator Value register cannot be programmed reliably by a single 64bit write in a 32-bit environment **except** if only the periodic rate is being changed during run-time. If the actual Timer 0 Comparator Value needs to be reinitialized, then the following software solution will always work regardless of the environment:

1. Set TIMER0_VAL_SET_CNF bit



- 2. Set the lower 32 bits of the Timer0 Comparator Value register
- 3. Set TIMER0_VAL_SET_CNF bit
- 4. Set the upper 32 bits of the Timer0 Comparator Value register

Timer 0 is configurable to 32- (default) or 64-bit mode, whereas Timers 1:7 only support 32-bit mode.

WARNING

Software must be careful when programming the comparator registers. If the value written to the register is not sufficiently far in the future, then the counter may pass the value before it reaches the register and the interrupt will be missed. The BIOS should pass a data structure to the operating system to indicate that the operating system should not attempt to program the periodic timer to a rate faster than 5 microseconds.

All of the timers support non-periodic mode.

Periodic Mode

When a timer is set up for periodic mode, the software writes a value in the timer's comparator value register. When the main counter value matches the value in the timer's comparator value register, an interrupt can be generated. The hardware will then automatically increase the value in the comparator value register by the last value written to that register.

To make the periodic mode work properly, the main counter is typically written with a value of 0 so that the first interrupt occurs at the right point for the comparator. If the main counter is not set to 0, interrupts may not occur as expected.

During run-time, the value in the timer's comparator value register can be read by software to find out when the next periodic interrupt will be generated (not the rate at which it generates interrupts). Software is expected to remember the last value written to the comparator's value register (the rate at which interrupts are generated).

If software wants to change the periodic rate, it should write a new value to the comparator value register. At the point when the timer's comparator indicates a match, this new value will be added to derive the next matching point.

If the software resets the main counter, the value in the comparator's value register needs to reset as well. This can be done by setting the **TIMERn_VAL_SET_CNF** bit. Again, to avoid race conditions, this should be done with the main counter halted. The following usage model is expected:

- 1. Software clears the ENABLE_CNF bit to prevent any interrupts.
- 2. Software clears the main counter by writing a value of 00h to it.
- 3. Software sets the TIMER0_VAL_SET_CNF bit.
- 4. Software writes the new value in the TIMER0_COMPARATOR_VAL register.

Software sets the ENABLE_CNF bit to enable interrupts.



NOTE

As the timer period approaches zero, the interrupts associated with the periodic timer may not get completely serviced before the next timer match occurs. Interrupts may get lost and/or system performance may be degraded in this case.

Each timer is NOT required to support the periodic mode of operation. A capabilities bit indicates if the particular timer supports periodic mode. he reason for this is that supporting the periodic mode adds a significant amount of gates.

For the Intel PCH, only timer 0 will support the periodic mode. This saves a substantial number of gates.

6.5 Enabling the Timers

The BIOS or operating system PnP code should route the interrupts. This includes the Legacy Rout bit, Interrupt Rout bit (for each timer), and interrupt type (to select the edge or level type for each timer).

The Device Driver code should do the following for an available timer:

- 1. Set the Overall Enable bit (Offset 10h, bit 0).
- 2. Set the timer type field (selects one-shot or periodic).
- 3. Set the interrupt enable.
- 4. Set the comparator value.

6.6 Interrupt Levels

Interrupts directed to the internal 8259s are active high. Refer Advanced Programmable Interrupt Controller (APIC) (D31:F0) on page 143 for information regarding the polarity programming of the I/O APIC for detecting internal interrupts.

If the interrupts are mapped to the 8259 or I/O APIC and set for level-triggered mode, they can be shared with legacy interrupts. They may be shared although it is unlikely for the operating system to attempt to do this.

If more than one timer is configured to share the same IRQ (using the TIMERn_INT_ROUT_CNF fields), then the software must configure the timers to level-triggered mode. Edge-triggered interrupts cannot be shared.

6.7 Handling Interrupts

Section 2.4.6 of the IA-PC HPET Specification describes handling interrupts.

6.8 Issues Related to 64-Bit Timers with 32-Bit Processors

Section 2.4.7 of the IA-PC HPET Specification describes issues related to 64-bit timers with 32-bit processors.



7.0 Thermal Management

7.1 PCH Thermal Sensor

The PCH incorporates an on-die Digital Thermal Sensor (DTS) for thermal management.

7.1.1 Modes of Operation

The DTS has two usages when enabled:

- One use is to provide the temperature of the PCH in units of 1 °C. There is a 9 bit field for the temperature, with a theoretical range from -256 °C to +256 °C. Practically the operational range for TS would be between -40 °C and 110 °C.
- The second use is to allow programmed trip points to cause alerts to SW or in the extreme case shutdown. Temperature may be provided without having any SW alerts set.

There are two thermal alert capabilities. One is for the catastrophic event (thermal runaway) which results in an immediate system power down (S5 state). The other alert provides an indication to the platform that a particular temperature has been caused. This second alert needs to be routed to SMI or SCI based on SW programming.

7.1.2 Temperature Trip Point

The internal thermal sensor reports three trip points: Cool, Hot, and Catastrophic trip points in the order of increasing temperature.

Crossing the cool trip point when going from higher to lower temperature may generate an interrupt. Crossing the hot trip point going from lower to higher temp may generate an interrupt. Each trip point has control register bits to select what type of interrupt is generated.

Crossing the cool trip point while going from low to higher temperature or crossing the hot trip point while going from high to lower temperature will not cause an interrupt.

When triggered, the catastrophic trip point will transition the system to S5 unconditionally.

7.1.3 Thermal Sensor Accuracy Taccuracy

The PCH thermal sensor accuracy is:

- ±5 °C over the temperature range from 50 °C to 110 °C.
- ±7 °C over the temperature range from 30 °C to 50 °C.
- ±10 °C over the temperature range from -10 °C to 30 °C.



7.1.4 Thermal Reporting to an EC

To support a platform EC that is managing the system thermals, the PCH provides the ability for the EC to read the PCH temperature over SMLink1 or over eSPI interface.

The PCH supports temperature reporting over SMLink1 using the General Purpose Block Read (GPBR). To enable the support, the related soft straps, SMLink1 GP Target Address and SMLink1 GP Target Address Enabled, must be set appropriately. Refer to the Platform SPI Programming Guide for more info on the soft straps. The EC needs to issue an SMBus Block Read Command (0x40h) and receives a single byte of data indicating the PCH temperature. Upon reset, the value driven to the EC will be FFh. This indicates that BIOS has not enabled the sensor yet and the EC can assume that the system is in the boot phase with unknown temperature. After the sensor is enabled, the EC will receive a value between 0h and 7Fh (0 °C to 127 °C). If the EC ever sees a value between 80h and FEh, that indicates an error has occurred, since the PCH should have shut down the platform before the temperature ever reached 128 °C (Catastrophic trip point will be below 128 °C). The PCH itself does not monitor the temperature and will not flag any error on the temperature value. The polling rate is recommended no more than once every 200ms, although EC can read as often as it wishes.

The PCH also supports temperature reporting over eSPI using eSPI OOB channel. For getting the PCH temperature over eSPI, the EC can send a request packet via OOB channel and receive a response packet consisting of 1 byte of PCH temperature. Refer to the Enhanced Serial Peripheral Interface eSPI on page 107 for detailed info on eSPI request and response packets for getting PCH temperature data.

7.1.5 Thermal Trip Signal (PCHHOT#)

The PCH provides PCHHOT# signal to indicate that it has exceeded some temperature limit. The limit is set by BIOS. The temperature limit (programmed into the PHL register) is compared to the present temperature. If the present temperature is greater than the PHL value then the pin is asserted.

PCHHOT# is an O/D output and requires a Pull-up on the motherboard.

The PCH evaluates the temperature from the thermal sensor against the programmed temperature limit every 1 second.



8.0 **Power and Ground Signals**

This section describes the power rails and ground signals on the PCH.

Table 12.Power Rails Descriptions

Name	Description
VCCA_19P2_1P05	Analog supply for reference clock: 1.05 V
VCCA_BCLK_1P05	Analog supply for BCLK circuitries: 1.05 V
VCCA_SRC_1P05	Analog supply for PCIe* clock circuitries: 1.05 V
VCCA_XTAL_1P05	Analog supply for XTAL circuitries: 1.05 V
VCCDUSB_1P05	Supply for USB digital logic: 1.05 V
VCCAPLL_1P05	Analog supply for BCLK/OPI/Audio PLLs: 1.05 V. This rail can be derived from the VCCPRIM_1P05 rail with the proper isolation.
VCCPRIM_1P05	Primary Well: 1.05 V. For PCIe*/OPI/USB 3.2/SATA MPHY logic, I/O blocks, SRAM, JTAG, CNVi.
VCCDSW_1P05	Deep Sx Well : 1.05 V. This rail is generated by on die DSW low dropout (LDO) linear regulator to supply DSW core logic. Board needs to connect a 1uF capacitor to this rail and power should NOT be driven from the board. When the primary well is powered, under PMC control, the regulation in the DSW LDO is turned off and the bypass option is used to derive DSW 1.05 V supply from primary well 1.05 V supply.
VCCPRIM_MPHY_1P05	Mod PHY Primary : 1.05 V. Primary supply for PCIe*/USB 3.2/SATA MPHY logic and PCIe*/USB PLL dividers.
VCCAMPHYPLL_1P05	Analog supply for USB 3.2, PCIe* Gen 2/Gen 3, and SATA 6 Gb/s PLLs: 1.05 V.
VCCPRIM_CORE	Core Logic Primary Well : This rail operates at 1.05 V. When SLP_SO# is asserted, the rail may optionally be lowered to 0.75 V (refer to VPCLVM support in the Power Management Chapter). Alternately this supply can be combined with the VCCPRIM_1P05 supply if VPCLVM support is not implemented.
VCCPRIM_1P8	1.8 V Primary Well.
VCCPRIM_3P3	3.3 V Primary Well.
VCCSPI	SPI Primary Well 3.3 V or 1.8 V . If powered at 3.3 V, the 3.3 V supply can come from VCCPRIM_3P3 supply. If powered at 1.8 V, the 1.8 V supply can come from VCCPRIM_1P8 supply.
VCCHDA	HDA Audio Power 3.3 V or 1.8V. If powered at 3.3 V, the 3.3 V supply can come from VCCPRIM_3P3 supply. If powered at 1.8 V, the 1.8 V supply can come from VCCPRIM_1P8 supply.
VCCDSW_3P3	3.3 V Deep Sx Well.
VCCRTC	RTC Well Supply . This rail can drop to 2.0 V if all other planes are off. This power is not expected to be shut off unless the RTC battery is removed or drained.
	continued



Name	Description
	Notes: 1. VCCRTC nominal voltage is 3.0 V. This rail is intended to always come up first and always stay on. It should NOT be power cycled regularly on non-coin battery designs.
	Implementation should not attempt to clear CMOS by using a jumper to pull VCCRTC low. Clearing CMOS can be done by using a jumper on RTCRST# or GPI.
DCPRTC	RTC de-coupling capacitor only. This rail should NOT be driven.
VCCDPHY_1P24	1.24 V for CNVi logic . This rail is generated internally with a LDO and needs to be routed to the motherboard so that the rail can be supplied back to the SoC.
VCCDPHY_EC_1P24	For de-coupling capacitor only. This rail should NOT be driven from the motherboard. This rail can optionally be connected to VCCDPHY_1P24 on the motherboard.
VSS	Ground



9.0 Electrical and Thermal Characteristics

This chapter contains the DC and AC characteristics for the PCH.

9.1 Absolute Maximum Ratings

Table 13. PCH Absolute Power Rail Minimum and Maximum Ratings

Voltage Rail	Minimum Limits	Maximum Limits
1.05 V	-0.5 V	1.4 V
1.8 V	-0.5 V	2.3 V
3.3 V	-0.7 V	3.7 V

PCH Absolute Power Rail Minimum and Maximum Ratings specifies absolute maximum and minimum ratings. At conditions outside functional operation condition limits, but within absolute maximum and minimum ratings, neither functionality nor long-term reliability can be expected. If a device is returned to conditions within functional operation limits after having been subjected to conditions outside these limits (but within the absolute maximum and minimum ratings) the device may be functional, but with its lifetime degraded depending on exposure to conditions exceeding the functional operation condition limits.

At conditions exceeding absolute maximum and minimum ratings, neither functionality nor long-term reliability can be expected. Moreover, if a device is subjected to these conditions for any length of time, it will either not function or its reliability will be severely degraded when returned to conditions within the functional operating condition limits.

Although the PCH contains protective circuitry to resist damage from Electrostatic Discharge (ESD), precautions should always be taken to avoid high static voltages or electric fields.

9.2 Thermal Specification

Table 14.Operating Junction Temperature Range

Parameter	Minimum	Maximum	Unit
Operating Junction Temperature Range	0	110	°C



9.3 General DC Characteristics

Table 15.PCH-U Estimated Icc3

Voltage Rail	Voltage (V)	S0 Iccmax Current ² (A)	Sx Icc Idle Current ⁴ (mA)	Deep Sx Icc Idle Current (mA)	G3 (µA)
VCCA_19P2_1P05	1.05	0.027	0.074	0	0
VCCAPLL_1P05	1.05	0.102	0.544	0	0
VCCA_BCLK_1P05	1.05	0.009	0.004	0	0
VCCA_SRC_1P05	1.05	0.042	0.011	0	0
VCCA_XTAL_1P05	1.05	0.002	2	0	0
VCCPRIM_1P05	1.05	0.980	10.261	0	0
VCCPRIM_MPHY_1P05	1.05	Refer Table 16 on page 46	2	0	0
VCCAMPHYPLL_1P05	1.05	0.152	0	0	0
VCCPRIM_CORE	1.05	4.26	78.524	0	0
VCCDUSB_1P05	1.05	0.28	0.45	0	0
VCCDSW_1P05	1.05	0.024	1.76	0	0
VCCPRIM_1P8	1.8	0.134	6.081	0	0
VCCPRIM_3P3	3.3	0.199	1.064	0	0
	3.3	0.006	<0.002	0	0
VCCHDA	1.8	0.004	<0.002	0	0
	1.5	0.002	<0.002	0	0
VCCCPT	3.3	0.002	<0.002	0	0
VCCSPI	1.8	0.002	<0.002	0	0
VCCDSW_3P3	3.3	0.001	1	1	0
VCCDSW_GPIO	3.3	0.003	1	1	0
VCCRTC ¹	3.0	0.002	0.046	0.004	6
VCCDPHY_1P24	1.24	0.61	3.021	0	0

Notes: 1. The VCC rail ICC data is taken at 3.0 V while the system is in a mechanical off (G3) state at room temperature.

2. Iccmax estimates assumes 110 °C.

3. The Iccmax value is a steady state current that can happen after respective power ok has asserted (or reset signal has de-asserted).

4. Sx Icc Idle assumes PCH is idle and $Intel^{\ensuremath{\circledast}}$ CSME is power gated.

Table 16. PCH-U VCCPRIM_MPHY_1P05 Icc Adder Per HSIO Lane

Details	VCCPRIM_MPHY_1P05
Details	Icc (A)
All HSIO disabled	0.332
Each PCIe Gen3 Lane	0.213
Each PCIe Gen2 Lane	0.181
	continued



Details	VCCPRIM_MPHY_1P05
Details	Icc (A)
Each USB 3.2 Gen 2x1(10 Gb/s) Port	0.259
Each USB 3.2 Gen 1x1 (5 Gb/s) Port	0.184
Integrated GbE Port	0.129
Each SATA 6 Gb/s Port	0.193
Each SATA 3 Gb/s Port	0.167

Table 17. Single-Ended Signal DC Characteristics as Inputs or Outputs

Туре	Symbol	Parameter	Minimum	Maximum	Unit	Condition	Notes
the		GPP) listed in the Associat aracteristics as the GPIO p					
ESPI_IO2, GPP_A8 / 9 SD_VDD2 SUS_STAT GPP_A18 / ISH_GP5,	GPP_A4 / L4 CLKRUN#, G _PWR_EN#, (# / ESPI_RE ' ISH_GP0, G GPP_G0 / SE	GPP_A0 / RCIN# / TIME_ AD3 / ESPI_IO3, GPP_A5 PP_A9 / CLKOUT_LPC0 / GPP_A12 / ISH_GP6 / SX SET#, GPP_A15 / SUSAC SPP_A19 / ISH_GP1, GPP_ D_CMD, GPP_G1 / SD_DA P_G6 / SD_CLK, GPP_G7	/ LFRAME# / ESPI_ ESPI_CLK, GPP_A1 _EXIT_HOLDOFF#, K#, GPP_A16 / SD _A20 / ISH_GP2, G TA0, GPP_G2 / SD_	_CS#, GPP_A6 / S 0 / CLKOUT_LPC1 GPP_A13 / SUSW _1P8_SEL, GPP_A PP_A21 / ISH_GP3	ERIRQ, GI , GPP_A1: /ARN# / S 17 / SD_V 3, GPP_A2	PP_A7 / PIRQA# / GS L / PME# / GSPI1_CS USPWRDACK, GPP_A DD1_PWR_EN# / ISH 2 / ISH_GP4, GPP_A2	PI0_CS1#, 1# / 14 / 1_GP7, 23 /
3.3V Ope	ration						
Input	VIH	Input High Voltage Threshold	0.75 x VCC		v		
	VIL	Input Low Voltage Threshold		0.25 x VCC	v		
	IIL	Input Leakage Current	-14	14	μA		
	CIN	Input Pin Capacitance		14	pF		
Output	V _{OH}	Output High Voltage Threshold	VCC-0.45		v	I _{OH} =3 mA	1
	V _{OL}	Output Low Voltage Threshold		0.45	v	I _{OL} =-3 mA	1
	R _{pu}	WPU (Weak Pull-Up) Resistance	5K-70% 20K-25%	5K+70% 20K+35%	ohm		
	R _{pd}	WPD (Weak Pull- Down) Resistance	5K-70% 20K-25%	5K+70% 20K+35%	ohm		
1.8V Ope	ration						
Input	VIH	Input High Voltage Threshold	0.75 x VCC		v		
	VIL	Input Low Voltage Threshold		0.25 x VCC	v		
	IIL	Input Leakage Current	-14	14	μA		
	CIN	Input Pin Capacitance		14	pF		
	V _{OH}	Output High Voltage Threshold	VCC-0.45		v	I _{OH} =3 mA	1
					II	co	ontinued



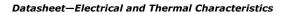
Туре	Symbol	Parameter	Minimum	Maximum	Unit	Condition	Notes
Output	V _{OL}	Output Low Voltage Threshold		0.45	v	I _{OL} =-3 mA	1
	R _{pu}	WPU Resistance	5K-70% 20K-25%	5K+70% 20K+35%	ohm		
	R _{pd}	WPD Resistance	5K-70% 20K-25%	5K+70% 20K+35%	ohm		
Note: 1.	For GPIO sup	ported voltages, refer to	the GPIO chapter.		1		
	#, PCH_JTA	PECI, PROCPWRGD, THR G_TDI, PCH_JTAG_TMS, P			X, PROC_	PRDY#, PROC_PREQ#,	
1.054 Ob		1			1		
	VIH	Input High Voltage Threshold	0.8 x VCC	_	V		
Input	VIL	Input Low Voltage Threshold	_	0.3 x VCC	v		
	IIL	Input Leakage Current	-10	10	μA		
				2	pF		
	CIN	Input Pin Capacitance	—	_			
	CIN VOH	Input Pin Capacitance Output High Voltage Threshold	0.75 x VCC	VCC	v	I _{OH} =6 mA	
		Output High Voltage	0.75 x VCC		v v	I _{OH} =6 mA I _{OL(min)} =-0.5 mA I _{OL(max)} =-1 mA	
Output	VOH	Output High Voltage Threshold Output Low Voltage		VCC		I _{OL(min)} =-0.5 mA	

CPU_GP2, GPP_B4 / CPU_GP3, GPP_B5 / SRCCLKREQ0#, GPP_B6 / SRCCLKREQ1#, GPP_B7 / SRCCLKREQ2#, GPP_B8 / SRCCLKREQ3#, GPP_B9 / SRCCLKREQ4#, GPP_B10 / SRCCLKREQ5#, GPP_B11 / EXT_PWR_GATE#, GPP_B12 / SLP_S0#, GPP_B13 / PLTRST#, GPP_B14 / SPKR, GPP_B15 / GSPI0_CS0#, GPP_B16 / GSPI0_CLK, GPP_B17 / GSPI0_MISO, GPP_B18 / GSPI0_MOSI, GPP_B19 / GSPI1_CS0#, GPP_B20 / GSPI1_CLK, GPP_B21 / GSPI1_MISO, GPP_B22 / GSPI1_MOSI, GPP_B23 / SML1ALERT# / PCHHOT#.

3.3V Ope	eration						
Input	VIH	Input High Voltage Threshold	0.75 x VCC		v		
	VIL	Input Low Voltage Threshold		0.25 x VCC	v		
	IIL	Input Leakage Current	-12	12	μA		
	CIN	Input Pin Capacitance		10	pF		
Output	V _{OH}	Output High Voltage Threshold	VCC-0.45	VCC	v	I _{OH} =3 mA	1
	V _{OL}	Output Low Voltage Threshold		0.45	v	I _{OL} =-3 mA	1
	R _{pu}	WPU Resistance	1K-50% 5K-70%	1K+100% 5K+70%	Ohm		
						cor	ntinued



Туре	Symbol	Parameter	Minimum	Maximum	Unit	Condition	Notes
			20K-35%	20K+35%			
	R _{pd}	WPD Resistance	5K-70% 20K-35%	5K+70% 20K+35%	Ohm		
1.8V Ope	eration						
Input	VIH	Input High Voltage Threshold	0.75 x VCC		v		
	VIL	Input Low Voltage Threshold		0.25 × VCC	v		
	IIL	Input Leakage Current	-12	12	μΑ		
	CIN	Input Pin Capacitance		10	pF		
Output	V _{OH}	Output High Voltage Threshold	VCC-0.45	VCC	v	I _{OH} =3 mA	1
	V _{OL}	Output Low Voltage Threshold		0.45	v	I _{OL} =-3 mA	1
	R _{pu}	WPU Resistance	1K-50% 5K-70% 20K-35%	1K+100% 5K+70% 20K+35%	Ohm		
Associate	ed Signals ¹ :	WPD Resistance ported voltages, refer to t SPI0_IO2, SPI0_IO3, SPI	•	5K+70% 20K+35% SO, SPI0_CS2#, S	Ohm GPI0_CS0#,	SPI0_CS1#, SPI0_	CLK.
Associate	For GPIO sup	pported voltages, refer to t	20K-35% the GPIO chapter.	20K+35%		SPI0_CS1#, SPI0_	CLK.
	For GPIO sup	pported voltages, refer to t	20K-35% the GPIO chapter.	20K+35%		SPI0_CS1#, SPI0_	
Associato 3.3V Ope	For GPIO sup	pported voltages, refer to t SPI0_IO2, SPI0_IO3, SPI	20K-35% the GPIO chapter.	20K+35% SO, SPI0_CS2#, S	5PI0_CS0#,	SPI0_CS1#, SPI0_	CLK.
Associato 3.3V Ope	For GPIO sup ed Signals ¹ : eration VIH	SPI0_IO2, SPI0_IO3, SPI Input High Voltage Threshold Input Low Voltage	20K-35% the GPIO chapter.	20K+35% SO, SPI0_CS2#, S	5PI0_CS0#,	SPI0_CS1#, SPI0_	СLК.
Associato 3.3V Ope	For GPIO sup ed Signals ¹ : eration VIH VIL	Input High Voltage Threshold Input Low Voltage Threshold Input Leakage	20K-35% the GPIO chapter. 10_MOSI, SPI0_MI 0.75 x VCC 	20K+35% SO, SPI0_CS2#, S 	GPI0_CS0#,	SPI0_CS1#, SPI0_	СLК.
Associato	For GPIO sup ed Signals ¹ : eration VIH VIL IIL	Input High Voltage Threshold Input Leakage Current	20K-35% the GPIO chapter. 10_MOSI, SPI0_MI 0.75 x VCC _ -12	20K+35% SO, SPI0_CS2#, S - 0.25 x VCC 12	5PI0_CS0#, V V μA	SPI0_CS1#, SPI0_ I _{OH} =3 mA	CLK.
Associato 3.3V Ope Input	For GPIO sup ed Signals ¹ : eration VIH VIL IIL CIN	SPI0_IO2, SPI0_IO3, SPI Input High Voltage Threshold Input Low Voltage Threshold Input Leakage Current Input Pin Capacitance Output High Voltage	20K-35% the GPIO chapter. 0_MOSI, SPI0_MI 0.75 x VCC 	20K+35% SO, SPI0_CS2#, S - 0.25 x VCC 12 13	5PI0_CS0#, V V μΑ pF		СLК.
Associate	For GPIO sup ed Signals ¹ : eration VIH VIL IIL CIN VOH	Input High Voltage Threshold Input Leakage Current Input Pin Capacitance Output Low Voltage Threshold Output Loy Voltage	20K-35% the GPIO chapter. 0_MOSI, SPI0_MI 0.75 x VCC 	20K+35% SO, SPI0_CS2#, S 0.25 x VCC 12 13 VCC	SPI0_CS0#, V V μA pF V	I _{OH} =3 mA	CLK.
Associato 3.3V Ope Input	For GPIO sup ed Signals ¹ : eration VIH VIL IIL CIN VOH VOL	SPI0_IO2, SPI0_IO3, SPI Input High Voltage Threshold Input Low Voltage Threshold Input Leakage Current Input Pin Capacitance Output High Voltage Threshold Output Low Voltage Threshold WPU (Weak Pull-Up)	20K-35% the GPIO chapter. 10_MOSI, SPI0_MI 0.75 × VCC — -12 — VCC - 0.45 — 5K-70%	20K+35% SO, SPI0_CS2#, S 0.25 × VCC 12 13 VCC 0.45 5K+70%	SPI0_CS0#, V ν μA pF ν ν	I _{OH} =3 mA	
Associate 3.3V Ope Input	For GPIO sup ed Signals ¹ : eration VIH VIL IIL CIN VOH VOL R _{pu} R _{pd}	Input High Voltage Threshold Input Low Voltage Threshold Input Leakage Current Input Pin Capacitance Output High Voltage Threshold Output Low Voltage Threshold WPU (Weak Pull-Up) Resistance WPD (Weak Pull-	20K-35% the GPIO chapter. 10_MOSI, SPI0_MI 0.75 x VCC — -12 — VCC - 0.45 — 5K-70% 20K-25% 5K-70%	20K+35% SO, SPI0_CS2#, S 0.25 × VCC 12 13 VCC 0.45 5K+70% 20K+25% 5K+70%	SPI0_CS0#, V V V μA pF V V ohm	I _{OH} =3 mA	CLK.
Associate 3.3V Ope Input	For GPIO sup ed Signals ¹ : eration VIH VIL IIL CIN VOH VOL R _{pu} R _{pd}	Input High Voltage Threshold Input Low Voltage Threshold Input Leakage Current Input Pin Capacitance Output High Voltage Threshold Output Low Voltage Threshold WPU (Weak Pull-Up) Resistance WPD (Weak Pull-	20K-35% the GPIO chapter. 10_MOSI, SPI0_MI 0.75 x VCC — -12 — VCC - 0.45 — 5K-70% 20K-25% 5K-70%	20K+35% SO, SPI0_CS2#, S 0.25 × VCC 12 13 VCC 0.45 5K+70% 20K+25% 5K+70%	SPI0_CS0#, V V V μA pF V V ohm	I _{OH} =3 mA	





Туре	Symbol	Parameter	Minimum	Maximum	Unit	Condition	Notes
	IIL	Input Leakage Current	-12	12	μΑ		
	CIN	Input Pin Capacitance	_	13	pF		
Output	V _{OH}	Output High Voltage Threshold	VCC - 0.45	VCC	v	I _{OH} =3 mA	
	V _{OL}	Output Low Voltage Threshold	_	0.45	v	I _{OL} =-3 mA	
	R _{pu}	WPU Resistance	5K-70% 20K-25%	5K+70% 20K+25%	ohm		
	R _{pd}	WPD Resistance	5K-70% 20K-25%	5K+70% 20K+25%	ohm		

Associated Signals¹: GPP_D0 / SPI1_CS# / BK0 / SBK0 / GPP_D23 / I2S_MCLK, GPP_D3 / SPI1_MOSI / BK3 / SBK3, GPP_D4 / IMGCLKOUT0 / BK4 / SBK4, GPP_D5 / ISH_I2C0_SDA, GPP_D6 / ISH_I2C0_SCL, GPP_D7 / ISH_I2C1_SDA, GPP_D8 / ISH_I2C1_SCL, GPP_D9 / ISH_SPI_CS# / GSPI2_CS0#, GPP_D10 / ISH_SPI_CLK / GSPI2_CLK, GPP_D11 / ISH_SPI_MISO / GSPI2_MISO, GPP_D12 / ISH_SPI_MOSI / GSPI2_MOSI, GPP_D13 / ISH_UART0_RXD / SML0BDATA / I2C4B_SDA, GPP_D14 / ISH_UART0_TXD / SML0BCLK / I2C4B_SCL, GPP_D15 / ISH_UART0_RTS# / GSPI2_CS1# , GPP_D16 / ISH_UART0_CTS# / SML0BALERT# , GPP_D21 / SPI1_IO2, GPP_D22 / SPI1_IO3, GPP_H0 / I2S2_SCLK / CNV_BT_I2S_SCLK, GPP_H19 / TIME_SYNCO, GPP_H23, GPP_H3 / I2S2_RXD / CNV_BT_I2S_SDO, GPP_H4 / I2C2_SDA, GPP_H5 / I2C2_SCL, GPP_H6 / I2C3_SDA, GPP_H7 / I2C3_SCL, GPP_H8 / I2C4_SDA, GPP_H9 / I2C4_SCL, GPP_H10 / I2C5_SDA / ISH_I2C2_SDA, GPP_H11 / I2C5_SCL / ISH_I2C2_SCL, GPP_H12 / M2_SKT2_CFG0, GPP_H13 / M2_SKT2_CFG1, GPP_H14 / M2_SKT2_CFG2, GPP_H15 / M2_SKT2_CFG3, GPP_H16, GPP_H17, GPP_H18 / CPU_C10_GATE#, GPP_H19 / TIME_SYNCO, GPP_H20 / IMGCLKOUT1, GPP_H21, GPP_H22, GPP_H23, GPP_C0 / SMBCLK, GPP_C19 / I2C1_SCL, GPP_C23 / UART2_CTS#, GPP_C3 / SML0CLK, GPP_C4 / SML0DATA, GPP_C5 / SML0ALERT#, GPP_C6 / SML1CLK, GPP_C7 / SML1DATA, GPP_C8 / UART0_RXD, GPP_C13 / UART1_TXD, GPP_C10 / UART0_RTS#, GPP_C11 / UART1_RTS#, GPP_C15 / UART1_CTS# / ISH_UART1_CTS#, GPP_C16 / I2C0_SDA, GPP_C17 / I2C0_SCL, GPP_C18 / I2C1_SDA, GPP_C19 / I2C1_SCL, GPP_C20 / UART2_RXD , GPP_C21 / UART2_TXD , GPP_C22 / UART2_RTS#, GPP_C23 / UART2_CTS#.

3.3V Operation

5.5V Ope							
	VIH	Input High Voltage Threshold	0.75 x VCC	_	V		
Input	VIL	Input Low Voltage Threshold	_	0.25 x VCC	V		
	IIL	Input Leakage Current	-12	12	μA		
	CIN	Input Pin Capacitance	—	13	pF		
Output	V _{OH}	Output High Voltage Threshold	VCC - 0.45	VCC	V	I _{OH} =3 mA	
	V _{OL}	Output Low Voltage Threshold	_	0.45	V	I _{OL} =-3 mA	
	R _{pu}	WPU Resistance	1K-50% 5K-70% 20K-35%	1K+100% 5K+70% 20K+35%	ohm		
	R _{pd}	WPD Resistance	5K-70% 20K-35%	5K+70% 20K+35%	ohm		
1.8V Ope	ration						
Input	VIH	Input High Voltage Threshold	0.75 x VCC	_	v		
						con	tinued



Туре	Symbol	Parameter	Minimum	Maximum	Unit	Condition	Notes
	VIL	Input Low Voltage Threshold	_	0.25 x VCC	v		
	IIL	Input Leakage Current	-12	12	μA		
	CIN	Input Pin Capacitance	_	13	pF		
	V _{OH}	Output High Voltage Threshold	VCC - 0.45	VCC	v	I _{OH} =3 mA	
	V _{OL}	Output Low Voltage Threshold	_	0.45	v	I _{OL} =-3 mA	
Output	R _{pu}	WPU Resistance	1K-50% 5K-70% 20K-35%	1K+100% 5K+70% 20K+35%	ohm		
	R _{pd}	WPD Resistance	5K-70% 20K-35%	5K+70% 20K+35%	ohm		

Note: 1. For GPIO supported voltages, refer to the GPIO chapter.

Associated Signals¹: GPP_D17 / DMIC_CLK1 / SNDW3_CLK, GPP_D18 / DMIC_DATA1 / SNDW3_DATA, GPP_D19 / DMIC_CLK0 / SNDW4_CLK, GPP_D20 / DMIC_DATA0 / SNDW4_DATA, GPP_D23 / I2S_MCLK, GPP_E0 / SATAXPCIE0 / SATAGP0, GPP_E19 / DPPB_CTRLDATA, GPP_E23 / DPPD_CTRLDATA, GPP_E3 / CPU_GP0, GPP_E4 / DEVSLP0, GPP_E5 / DEVSLP1, GPP_E6 / DEVSLP2, GPP_E7 / CPU_GP1, GPP_E8 / SATALED# / SPI1_CS1#, GPP_E9 / USB2_0C0# / GP_BSSB_CLK, GPP_E10 / USB2_0C1# / GP_BSSB_DI, GPP_E11 / USB2_0C2#, GPP_E12 / USB2_0C3#, GPP_E13 / DDPB_HPD0 / DISP_MISC0, GPP_E14 / DDPC_HPD1 / DISP_MISC1, GPP_E15 / DPPD_HPD2 / DISP_MISC2, GPP_E16, GPP_E17 / EDP_HPD / DISP_MISC4, GPP_E18 / DPPB_CTRLCLK / CNV_BT_HOST_WAKE#, GPP_E19 / DPPB_CTRLDATA, GPP_E20 / DPPC_CTRLCLK, GPP_E21 / DPPC_CTRLDATA, GPP_E22 / DPPD_CTRLCLK, GPP_E23 / DPPD_CTRLDATA.

3.3V Ope	ration						
	VIH	Input High Voltage Threshold	0.75 x VCC	-	v		
Input	VIL	Input Low Voltage Threshold	_	0.25 x VCC	v		
	IIL	Input Leakage Current	-14	14	μA		
	CIN	Input Pin Capacitance	_	14	pF		
	V _{OH}	Output High Voltage Threshold	VCC - 0.45	VCC	v	I _{OH} =3 mA	
	V _{OL}	Output Low Voltage Threshold	_	0.45	v	I _{OL} =-3 mA	
Output	R _{pu}	WPU Resistance	5K-70% 20K-25%	5K+70% 20K+35%	ohm		
	R _{pd}	WPD Resistance	5K-70% 20K-25%	5K+70% 20K+35%	ohm		
1.8V Ope	ration						
	VIH	Input High Voltage Threshold	0.75 x VCC	-	v		
Input	VIL	Input Low Voltage Threshold	_	0.25 x VCC	V		
	IIL	Input Leakage Current	-14	14	μA		
		· · · ·				con	tinued



gnals ¹ : 0 4#, GPD6	Input Pin Capacitance Output High Voltage Threshold Output Low Voltage Threshold WPU Resistance WPD Resistance oorted voltages, refer to to GPD0 / BATLOW#, GPD1 5 / SLP_A#, GPD7, GPD8 #, SLP_SUS#, WAKE#, D	1 / LANPHYPC, GPE / SUSCLK, GPD9 /				
V _{OL} R _{pu} R _{pd} GPIO supp gnals ¹ : 0 4#, GPD6 SLP_LAN#	Threshold Output Low Voltage Threshold WPU Resistance WPD Resistance orted voltages, refer to t GPD0 / BATLOW#, GPD1 5 / SLP_A#, GPD7, GPD8	— 5K-70% 20K-25% 5K-70% 20K-25% the GPIO chapter. 1 / LANPHYPC, GPE / SUSCLK, GPD9 /	0.45 5K+70% 20K+35% 5K+70% 20K+35%	V ohm ohm GPD3 / PV	I _{OL} =-3 mA	
R _{pu} R _{pd} GPIO supp Ggnals ¹ : 0 4#, GPD6 SLP_LAN#	Threshold WPU Resistance WPD Resistance ported voltages, refer to t GPD0 / BATLOW#, GPD1 5 / SLP_A#, GPD7, GPD8	20K-25% 5K-70% 20K-25% the GPIO chapter. 1 / LANPHYPC, GPE / SUSCLK, GPD9 /	5K+70% 20K+35% 5K+70% 20K+35% 20K+35%	ohm ohm GPD3 / PV	NRBTN#, GPD4 / SLP	
R _{pd} GPIO supp ignals ¹ : (4#, GPD6 SLP_LAN#	WPD Resistance ported voltages, refer to t GPD0 / BATLOW#, GPD1 5 / SLP_A#, GPD7, GPD8	20K-25% 5K-70% 20K-25% the GPIO chapter. 1 / LANPHYPC, GPE / SUSCLK, GPD9 /	20K+35% 5K+70% 20K+35% D2 / LAN_WAKE#,	ohm GPD3 / PV		
GPIO supp gnals ¹ : (4#, GPD6 SLP_LAN#	GPD0 / BATLOW#, GPD1 5 / SLP_A#, GPD7, GPD8	20K-25% the GPIO chapter. 1 / LANPHYPC, GPE / SUSCLK, GPD9 /	20K+35%	GPD3 / P\		
ignals ¹ : 0 4#, GPD6 6LP_LAN#	GPD0 / BATLOW#, GPD1 5 / SLP_A#, GPD7, GPD8	1 / LANPHYPC, GPE / SUSCLK, GPD9 /				
4#, GPD6 5LP_LAN# on	5 / SLP_A#, GPD7, GPD8	/ SUSCLK, GPD9 /				
VTH						
	Input High Voltage Threshold	0.75 x VCC	_	v		
VIL	Input Low Voltage Threshold	_	0.25 x VCC	v		
IIL	Input Leakage Current	-10	10	μA		
CIN	Input Pin Capacitance	_	14	pF		
V _{OH}	Output High Voltage Threshold	VCC - 0.45	VCC	v	I _{OH} =3 mA	
V _{OL}	Output Low Voltage Threshold	_	0.45	v	I _{OL} =-3 mA	
R _{pu}	WPU Resistance	1K-50% 5K-70% 20K-35%	1K+100% 5K+70% 20K+35%	ohm		
R _{pd}	WPD Resistance	5K-70% 20K-35%	5K+70% 20K+35%	ohm		
on				I I		-
VIH	Input High Voltage Threshold	0.75 x VCC	_	v		
VIL	Input Low Voltage Threshold	_	0.25 x VCC	v		
IIL	Input Leakage Current	-10	10	μA		
CIN	Input Pin Capacitance	_	14	pF		
V _{OH}	Output High Voltage Threshold	VCC - 0.45	VCC	v	I _{OH} =3 mA	
V _{OL}	Output Low Voltage Threshold	_	0.45	v	I _{OL} =-3 mA	
R _{pu}	WPU Resistance	1K-50% 5K-70%	1K+100% 5K+70%	ohm		
	VIL IIL CIN V _{OL} R _{pu} R _{pd} n VIH VIL IIL CIN V _{OL}	VIII Threshold VIL Input Low Voltage Threshold IIL Input Leakage Current CIN Input Pin Capacitance VoH Output High Voltage Threshold VoL Output Low Voltage Threshold VoL Output Low Voltage Threshold Rpu WPU Resistance M WPD Resistance M Input High Voltage Threshold VIL Input High Voltage Threshold VIL Input Low Voltage Threshold IIL Input Leakage Current CIN Input Pin Capacitance VoH Output High Voltage Threshold VIL Input Pin Capacitance VoH Output High Voltage Threshold VIL Input Pin Capacitance VoH Output Low Voltage Threshold VoL Output Low Voltage Threshold	IIIThreshold0.75 x VCCVILInput Low Voltage Threshold—IILInput Leakage Current-10CINInput Pin Capacitance—VOHOutput High Voltage ThresholdVCC - 0.45VOLOutput Low Voltage Threshold—RpuWPU Resistance1K-50% 5K-70% 20K-35%RpdWPD Resistance5K-70% 20K-35%M	Threshold0.75 x VCCVILInput Low Voltage Threshold-0.25 x VCCIILInput Leakage Current-1010CINInput Pin Capacitance-14VoHOutput High Voltage ThresholdVCC - 0.45VCCVoLOutput Low Voltage Threshold-0.45RpuWPU Resistance1K-50% 5K-70% 20K-35%1K+100% 5K+70% 20K+35%RpdWPD Resistance5K-70% 20K+35%5K+70% 20K+35%M-0.25 x VCC-VILInput High Voltage Threshold-0.25 x VCCIILInput Leakage Current-1010CINInput Leakage Current-1010CINInput Leakage Current-14VoLOutput High Voltage Threshold-14VoHOutput High Voltage Threshold-0.25 x VCCIILInput Leakage Current-14VoHOutput High Voltage Threshold-0.45VOHOutput High Voltage Threshold-0.45VoLOutput Low Voltage Threshold-0.45VoLWPU Resistance1K-50%1K+100%	MHThreshold0.75 x VCCVVILInput Low Voltage Threshold-0.25 x VCCVIILInput Leakage Current-1010µACINInput Pin Capacitance-14pFVoHOutput High Voltage ThresholdVCC - 0.45VCCVVoLOutput Low Voltage Threshold-0.45VRpuWPU Resistance1K-50% 5K-70% 20K-35%1K+100% 5K+70% 20K+35%ohmRpdWPD Resistance5K-70% 20K+35%ohmMHInput High Voltage Threshold-VVILInput Low Voltage Threshold-VVILInput Leakage Current0.75 x VCC-VVILInput Leakage Current-1010µACINInput Leakage Current-1010µACINInput Pin Capacitance-14pFVoHOutput High Voltage Threshold-0.45VVOHOutput High Voltage Threshold-0.45VVOHOutput Leakage Current-14pFVOHOutput Low Voltage Threshold-0.45VVOLOutput Low Voltage Threshold-0.45VVOLOutput Low Voltage Threshold-0.45VVOLOutput Low Voltage Threshold-0.45VVOLOutput Low Voltage Threshold-0.45V </td <td>Threshold$0.75 \times VCC$$V$Input Low Voltage Threshold$0.25 \times VCC$$V$IILInput Leakage Current$-10$$10$$\mu$AIILInput Pin Capacitance$14$$pF$$V_{OH}$Output High Voltage Threshold$0.45$$VCC$$V$$I_{OH}$Output Low Voltage Threshold$0.45$$V$$I_{OL}=-3 \text{ mA}$$N_{OL}$Output Low Voltage Threshold$0.45$$V$$I_{OL}=-3 \text{ mA}$$R_{Pu}$WPU Resistance$1K-50\%$ $20K-35\%$$1K+100\%$ $20K+35\%$$ohm$$R_{pd}$WPD Resistance$5K-70\%$ $20K-35\%$$5K+70\%$ $20K+35\%$$ohm$$M$Input High Voltage Threshold$0.75 \times VCC$$V$$V$Input Leakage Threshold$-10$$10$$\muAVIL$Input Leakage Threshold$-10$$10$$\muAVIL$Input Leakage Threshold$-10$$10$$\muAVIL$Input Leakage Threshold$-10$$10$$\muAV_{OH}$Output High Voltage Threshold$VCC - 0.45$$VCC$$V$$V_{OL}$Output Low Voltage Threshold$0.45$$V$$I_{OH}=3 mA$$V_{OL}$$I_{H}=50\%$$I_{K}=50\%$$I_{K}=100\%$$III$Input Leakage Threshold$0.45$$V$$I_{OL}=-3 mA$$V_{OL}$Output High Voltage Threshold$0.45$$V$</td>	Threshold $0.75 \times VCC$ $ V$ Input Low Voltage Threshold $ 0.25 \times VCC$ V IILInput Leakage Current -10 10 μ AIILInput Pin Capacitance $ 14$ pF V_{OH} Output High Voltage Threshold $ 0.45$ VCC V I_{OH} Output Low Voltage Threshold $ 0.45$ V $I_{OL}=-3 \text{ mA}$ N_{OL} Output Low Voltage Threshold $ 0.45$ V $I_{OL}=-3 \text{ mA}$ R_{Pu} WPU Resistance $1K-50\%$ $20K-35\%$ $1K+100\%$ $20K+35\%$ ohm R_{pd} WPD Resistance $5K-70\%$ $20K-35\%$ $5K+70\%$ $20K+35\%$ ohm M Input High Voltage Threshold $0.75 \times VCC$ $ V$ V Input Leakage Threshold -10 10 μ A VIL Input Leakage Threshold -10 10 μ A VIL Input Leakage Threshold -10 10 μ A VIL Input Leakage Threshold -10 10 μ A V_{OH} Output High Voltage Threshold $VCC - 0.45$ VCC V V_{OL} Output Low Voltage Threshold $ 0.45$ V $I_{OH}=3 mA$ V_{OL} $I_{H}=50\%$ $I_{K}=50\%$ $I_{K}=100\%$ III Input Leakage Threshold $ 0.45$ V $I_{OL}=-3 mA$ V_{OL} Output High Voltage Threshold $ 0.45$ V



Туре	Symbol	Parameter	Minimum	Maximum	Unit	Condition	Notes
			20K-35%	20K+35%			
	R _{pd}	WPD Resistance	5K-70% 20K-35%	5K+70% 20K+35%	ohm		
Note: 1.	For GPIO sup	ported voltages, refer to	GPIO chapter.				•
		HDA_BCLK / I2S0_SCLK, , HDA_SDI0 / I2S0_RXD,				SYNC / I2S0_SFRM,	
3.3V Ope	ration						
	VIH	Input High Voltage Threshold	0.75 x VCC	_	v		
Input	VIL	Input Low Voltage Threshold	_	0.25 x VCC	v		
	IIL	Input Leakage Current	-12	12	μΑ		
	CIN	Input Pin Capacitance	_	13	pF		
	V _{OH}	Output High Voltage Threshold	VCC - 0.45	VCC	v	I _{OH} =3 mA	
_	V _{OL}	Output Low Voltage Threshold	_	0.45	v	I _{OL} =-3 mA	
Output	R _{pu}	WPU Resistance	5K-70% 20K-25%	5K+70% 20K+35%	ohm		
	R _{pd}	WPD Resistance	5K-70% 20K-25%	5K+70% 20K+35%	ohm		
1.8V Ope	ration	1		1			-!
	VIH	Input High Voltage Threshold	0.75 x VCC	_	v		
Input	VIL	Input Low Voltage Threshold	_	0.25 x VCC	v		
	IIL	Input Leakage Current	-12	12	μA		
	CIN	Input Pin Capacitance	_	13	pF		
	V _{OH}	Output High Voltage Threshold	VCC - 0.45	VCC	v	I _{OH} =3 mA	
.	V _{OL}	Output Low Voltage Threshold	_	0.45	v	I _{OL} =-3 mA	
Output	R _{pu}	WPU Resistance	5K-70% 20K-25%	5K+70% 20K+35%	ohm		
	R _{pd}	WPD Resistance	5K-70% 20K-25%	5K+70% 20K+35%	ohm		
Note: 1.	For GPIO sup	ported voltages, refer to	GPIO chapter.	1	1		
Associate	d Signals ^{1.}	eDP_BKLTEN, eDP_BKLT(RESET# (~I_RST#	
3.3V Ope				515_1 WIXOR, 515			
							ntinued



Туре	Symbol	Parameter	Minimum	Maximum	Unit	Condition	Notes
	VIH	Input High Voltage Threshold	0.75 x VCC	_	v		
Input	VIL	Input Low Voltage Threshold	_	0.25 x VCC	v		
	IIL	Input Leakage Current	-10	10	μΑ		
	CIN	Input Pin Capacitance	_	14	pF		
	V _{OH}	Output High Voltage Threshold	VCC - 0.45	VCC	v	I _{OH} =3 mA	
	V _{OL}	Output Low Voltage Threshold	_	0.45	v	I _{OL} =-3 mA	
Output	R _{pu}	WPU Resistance	1K-50% 5K-70% 20K-35%	1K+100% 5K+70% 20K+35%	ohm		
	R _{pd}	WPD Resistance	5K-70% 20K-35%	5K+70% 20K+35%	ohm		
1.8V Ope	ration				1 1		
	VIH	Input High Voltage Threshold	0.75 x VCC	_	V		
Input	VIL	Input Low Voltage Threshold	_	0.25 x VCC	V		
·	IIL	Input Leakage Current	-10	10	μΑ		
	CIN	Input Pin Capacitance	_	14	pF		
	V _{OH}	Output High Voltage Threshold	VCC - 0.45	VCC	V	I _{OH} =3 mA	
	V _{OL}	Output Low Voltage Threshold	_	0.45	v	I _{OL} =-3 mA	
Output	R _{pu}	WPU Resistance	1K-50% 5K-70% 20K-35%	1K+100% 5K+70% 20K+35%	ohm		
	R _{pd}	WPD Resistance	5K-70% 20K-35%	5K+70% 20K+35%	ohm		

Note: 1. For GPIO supported voltages, refer to GPIO chapter.

Table 18. Single-Ended Signal DC Characteristics as Inputs or Outputs

Туре	Symbol	Parameter	Minimum	Maximum	Unit	Condition	Notes			
Associated Signals: INTRUDER#, RSMRST#, PCH_PWROK, DSW_PWROK, SRTCRST#										
Input	V _{IH}	Input High Voltage Threshold	0.65 x VCCRTC	VCCRTC+0.5	v		4, 6			
	V _{IL}	Input Low Voltage Threshold	-0.5	0.3 x VCCRTC	v		6			
Associated Signals: RTCRST#										
						со	ntinued			



Туре	Symbol	Parameter	Minimum	Maximum	Unit	Condition	Notes
Input	V _{IH}	Input High Voltage Threshold	0.75 x VCCRTC	VCCRTC+0.5	v		4, 5, 6
	V _{IL}	Input Low Voltage Threshold	-0.5	0.4 x VCCRTC	v		6
Associated Signals:	RTCX1#		·	•			
Input	V _{IH}	Input High Voltage Threshold	0.8	1.2	v		
	V _{IL}	Input Low Voltage Threshold	-0.5	0.1	v		
Associated Signals:X	TAL24_IN	-			•		3
Input	V _{IH}	Input High Voltage Threshold	0.8	1.2	v		
	V _{IL}	Input Low Voltage Threshold	-0.2	0.2	v		

Notes: 1. The V_{OH} specification does not apply to open-collector or open-drain drivers. Signals of this type must have an external Pull-up resistor, and that is what determines the high-output voltage level.

- 2. Input characteristics apply when a signal is configured as Input or to signals that are only Inputs. Output characteristics apply when a signal is configured as an Output or to signals that are only Outputs.
- 3. Vpk-pk minimum for XTAL24 = 500 mV.
- 4. VCCRTC is the voltage applied to the VCCRTC well of the PCH. When the system is in G3 state, it is generally supplied by the coin cell battery. In S5 or greater state, it is supplied by VCCSUS3_3.

5. V_{IH} min should not be used as the reference point for T200 timing. Refer to the T200 specification for the measurement point detail.

6. These buffers have input hysteresis. V_{IH} levels are for rising edge transitions and V_{IL} levels are for falling edge transitions.

Symbol	Parameter	Minimum	Maximum	Unit	Condition	Notes
Associated Signals: e	MMC*					
1.8V						
VTX-DIFF P-P	Differential Peak to Peak Output Voltage	0.8	1.2	V		
VTX-DIFF P-P - Low	Low power differential Peak to Peak Output Voltage	0.4	1.2	V		
VTX_CM-Acp-p	TX AC Common Mode Output Voltage (5GT/s)	_	100	mV		
ZTX-DIFF-DC	DC Differential TX Impedance	80	120	ohm		
VRX-DIFF p-p	Differential Input Peak to Peak Voltage	0.1	1.2	V		
VRX_CM-ACp	AC peak Common Mode Input Voltage	_	150	mV		
Associated Signals: F	PCIe*					9, 10
Gen 1						
VTX-DIFF P-P	Differential Peak to Peak Output Voltage	0.8	1.2	v		1
VTX-DIFF P-P - Low	Low power differential Peak to Peak Output Voltage	0.4	1.2	V		
	•		•		con	tinued

Table 19. Signal Characteristics



Symbol	Parameter	Minimum	Maximum	Unit	Condition	Notes
VTX_CM-ACp	TX AC Common Mode Output Voltage (2.5 GT/s)	_	20	mV		
ZTX-DIFF-DC	DC Differential TX Impedance	80	120	Ohm		
VRX-DIFF p-p	Differential Input Peak to Peak Voltage	0.12	1.2	v		1
VRX_CM-ACp	AC peak Common Mode Input Voltage	_	150	mV		
Gen 2	ŀ					
VTX-DIFF P-P	Differential Peak to Peak Output Voltage	0.8	1.3	V		
VTX-DIFF P-P - Low	Low power differential Peak to Peak Output Voltage	0.4	1.2	V		
VTX_CM-Acp-p	TX AC Common Mode Output Voltage (5GT/s)	_	100	mV		
ZTX-DIFF-DC	DC Differential TX Impedance	80	120	ohm		
VRX-DIFF p-p	Differential Input Peak to Peak Voltage	0.12	1.2	V		
VRX_CM-ACp	AC peak Common Mode Input Voltage	-	150	mV		
Gen 3	·					
VTX-DIFF P-P	Differential Peak to Peak Output Voltage	0.8	1.3	V		
VTX-DIFF P-P - Low	Low power differential Peak to Peak Output Voltage	0.4	1.2	v		
VTX_CM-Acp-p	TX AC Common Mode Output Voltage (5GT/s)	-	100	mV		
ZTX-DIFF-DC	DC Differential TX Impedance	80	120	ohm		
VRX-DIFF p-p	Differential Input Peak to Peak Voltage	Refer to Stressed Voltage Eye Parameters Table in PCIe* GEN3 industry specifications.				
VRX_CM-ACp	AC peak Common Mode Input Voltage	-	150	mV		
Associated Signals: S	ATA					
VIMIN-Gen1i	Minimum Input Voltage - 1.5Gb/s internal SATA	325	_	mVdiff p-p		2
VIMAX-Gen1i	Maximum Input Voltage - 1.5Gb/s internal SATA	_	600	mVdiff p-p		2
VIMIN-Gen1m	Minimum Input Voltage - 1.5Gb/s eSATA	240	_	mVdiff p-p		2
VIMAX-Gen1m	Maximum Input Voltage - 1.5Gb/s eSATA	_	600	mVdiff p-p		2
VIMIN-Gen2i	Minimum Input Voltage -	275		mVdiff		2



Symbol	Parameter	Minimum	Maximum	Unit	Condition	Notes
VIMAX-Gen2i	Maximum Input Voltage - 3.0Gb/s internal SATA	-	750	mVdiff p-p		2
VIMIN-Gen2m	Minimum Input Voltage - 3.0Gb/s eSATA	240	_	mVdiff p-p		2
VIMAX-Gen2m	Maximum Input Voltage - 3.0Gb/s eSATA	-	750	mVdiff p-p		2
VIMIN-Gen3i	Minimum Input Voltage - 6.0Gb/s internal SATA	240	_	mVdiff p-p		2
VIMAX-Gen3i	Maximum Input Voltage - 6.0Gb/s internal SATA	_	1000	mVdiff p-p		2
VOMIN-Gen1i,m	Minimum Output Voltage 1.5Gb/s internal and eSATA	400	_	mVdiff p-p		3
VOMAX-Gen1i,m	Maximum Output Voltage 1.5Gb/s internal and eSATA	_	600	mVdiff p-p		3
VOMIN-Gen2i,m	Minimum Output Voltage 3.0Gb/s internal and eSATA	400	_	mVdiff p-p		3
VOMAX-Gen2i,m	Maximum Output Voltage 3.0Gb/s internal and eSATA	-	700	mVdiff p-p		3
VOMIN-Gen3i	Minimum Output Voltage 6.0Gb/s internal SATA	200	_	mVdiff p-p		3
VOMAX-Gen3i	Maximum Output Voltage 6.0Gb/s internal SATA	—	900	mVdiff p-p		3
Associated Signals:	USB 2.0					
VDI	Differential Input Sensitivity	0.2	_	V		4, 6
VCM	Differential Common Mode Range	0.8	2.5	v		5, 6
VSE	Single-Ended Receiver Threshold	0.8	2	v		6
VCRS	Output Signal Crossover Voltage	1.3	2	v		6
V _{OL}	Output Low Voltage Threshold	_	0.4	V	I _{OL} =5 mA	6
V _{OH}	Output High Voltage Threshold	3.3V – 0.5	_	v	I _{OH} =-2 mA	6
VHSSQ	HS Squelch Detection Threshold	100	150	mV		7
VHSDSC	HS Disconnect Detection Threshold	525	625	mV		7
VHSCM	HS Data Signaling Common Mode Voltage Range	-50	500	mV		7
VHSOI	HS Idle Level	-10	10	mV		7
VHSOH	HS Data Signaling High	360	440	mV		7
VHSOL	HS Data Signaling Low	-10	10	mV		7
VCHIRPJ	Chirp J Level	700	1100	mV		7
VCHIRPK	Chirp K Level	-900	-500	mV		7
				1	con	tinued



Symbol	Parameter	Minimum	Maximum	Unit	Condition	Notes
New: VDI VCM, VSE, V	CRS, VOL, VOH are USB 2.0 FS/LS	electrical characte	ristic.			
Associated Signals: U	SB 3.2					
VTX-DIFF-PP	Differential Peak to Peak Output Voltage	0.8	1.2	V		
VTX-DIFF P-P - Low	Low power differential Peak to Peak Output Voltage	0.4	1.2	V		8
VTX_CM-Acp-p	TX AC Common Mode Output Voltage (5GT/s)	_	100	mV		
ZTX-DIFF-DC	DC Differential TX Impedance	72	120	Ohm		
VRX-DIFF p-p	Differential Input Peak to Peak Voltage	0.1	1.2	V		
VRX_CM-ACp	AC peak Common Mode Input Voltage	_	150	mV		
connector), v 3. SATA Vdiff, to motherboard 4. V _{DI} = USBF 5. Includes VDI 6. Applies to Lo 7. Applies to His 8. USB 3.2 mVc 9. For PCIe*, G 10.PCIe* specifi 11.Measuremen 12.Measuremen 13.VCross is def 14.Only applies 15.The maximum	w-Speed/Full-Speed USB. gh-Speed USB 2.0. liff p-p = 2* USB3Rp[x] – USB3Rn[EN1, GEN2 and GEN3 correspond to cations are also applicable to the L4 t taken from single-ended waveform t taken from differential waveform of ined as the voltage where Clock = 0 to the differential rising edge (that m voltage including overshoot.	<pre>(]RXP - SATA[x]R) SATA connector or p = 2* SATA[x]TXf x] ; USB 3.2 mVd p the PCIe* base s N port. n on a component te Clock#.</pre>	<pre>KN . h the transmit si P - SATA[x]TXN iff p-p = 2* USE pecification revis test board. st board.</pre>	de (genera 33Tp[x] – sion 1, 2 a	ally, the USB3Tn[x]	
	n voltage including undershoot. iation of all VCross measurements i	n any particular sy	vstem.			
Note: This is	a subset of VCross MIN/MAX (VCro	ss absolute) allow	ed. The intent is	to limit V	Cross induced	

Note: This is a subset of VCross MIN/MAX (VCross absolute) allowed. The intent is to limit VCross induced modulation by setting VCross_Delta to be smaller than VCross absolute.

Table 20. Other DC Characteristics

Symbol	Parameter	Minimum	Nominal	Maximu m	Unit	Notes
VCCPRIM_1p05	Core Logic, Ungated SRAM, I/O Blocks, USB AFE, Processor Sideband, JTAG, Thermal Sensor, MIPI* DPHY Primary WellSP	0.9975	1.05	1.1025	v	1
VCCPRIM_1P8	1.8V Primary Well	1.71	1.8	1.89	v	1
VCCPRIM_3P3	3.3V Primary Well	3.13	3.3	3.46	v	1
VCCPRIM_CORE	Core Logic Primary Well (1.05V)	0.9975	1.05	1.1025	v	1
	Core logic Primary well in Low Voltage Mode (0.75V)	0.71	0.75	0.81	v	1
		•			cont	inued

Symbol	Parameter	Minimum	Nominal	Maximu m	Unit	Notes
VCCAMPHYPLL_1p 05	Analog Supply for USB 3.2, PCIe* Gen2 / Gen 3, and SATA PLL Primary Well	0.9975	1.05	1.1025	v	1
VCCAPLL_1p05	Analog Supply for OPI, USB 2.0 and Audio PLL Primary Well	0.9975	1.05	1.1025	v	1
VCCSPI (3.3 V)	SPI Primary Well - 3.3V	3.13	3.3	3.46	V	1
VCCSPI (1.8 V)	SPI Primary Well - 1.8V	1.71	1.8	1.89	V	1
VCCHDA (3.3 V)	Intel [®] HD Audio Supply Primary Well_1	3.13	3.3	3.46	V	1
VCCHDA (1.8 V)	Intel [®] HD Audio Supply Primary Well_2	1.71	1.8	1.89	V	1
VCCHDA (1.5 V)	Intel [®] HD Audio Supply Primary Well_3	1.425	1.5	1.575	V	1
VCCDSW_3p3	Deep Sx Well for GPD and USB 2.0	3.13	3.3	3.46	V	1
VCCRTC	RTC Well Supply	2.0	3.0	3.465	V	1,2

Notes: 1. The I/O buffer supply voltage is measured at the PCH package pins. The tolerances shown in this Table are inclusive of all noise from DC up to 20 MHz. In testing, the voltage rails should be measured with a bandwidth limited oscilloscope that has a roll off of 3db/decade above 20 MHz.

2. Maximum Crystal ESR is 50 kohms.

9.4 AC Characteristics

Table 21. PCI Express* Interface Timings

Symbol	Parameter	Minimum	Maximu m	Unit	Figures	Notes
Transmitter and Recei	ver Timings				•	
UI (Gen1)	Unit Interval – PCI Express*	399.88	400.12	ps		5
UI (Gen 2)	Unit Interval – PCI Express*	199.9	200.1	ps		5
UI (GEN3)	Unit Interval – PCI Express*	124.96	125.03	ps		
TTX-EYE (Gen 1/Gen 2)	Minimum Transmission Eye Width	0.75	_	UI	Refer Figure 4 on page 60	1,2
T _{TX-EYE-MEDIAN-to-MAX-} _{JITTER} (Gen 1)	Maximum time between the jitter median and maximum deviation from the median	0.125	_	UI		1,2
T _{TX-EYE-MEDIAN-to-MAX-} _{JITTER} (Gen 2)	Maximum time between the jitter median and maximum deviation from the median	0.15	_	UI		
T _{TX-EYE-MEDIAN-to-MAX-} _{JITTER} (Gen 3)	Maximum time between the jitter median and maximum deviation from the median	0.15	_	UI		
TRX-EYE (Gen 1	Minimum Receiver Eye Width	0.4	_	UI	Refer Figure 5 on page 61	3,4
TRX-EYE (Gen 2)	Minimum Receiver Eye Width	0.6	_	UI		3,4
TMin-Pulse (Gen 2)	Instantaneous Pulse Width	0.9	_	UI		

Note: Refer to www.pcisig.com for the updated specifications.

1. Specified at the measurement point into a timing and voltage compliance test load and measured over any 250 consecutive TX UIs. (also refer to the Transmitter compliance eye diagram).

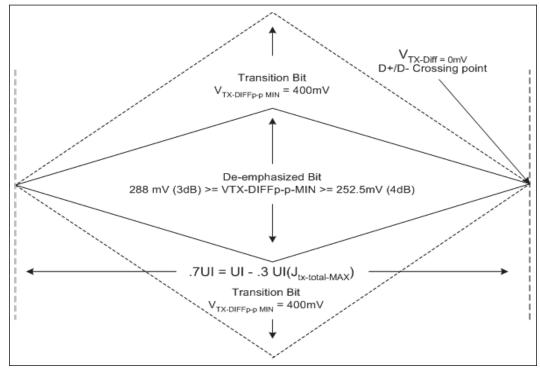
continued...



Symbol	Parameter	Minimum	Maximu m	Unit	Figures	Notes
Transmitter collected distribution in which t collected over any 25	rovides for a total sum of deterministic and r over any 250 consecutive TX UIs. The T_{TXEYE} the median and the maximum deviation from 0 consecutive TX UIs. It should be noted tha point in time where the number of jitter poi- lue.	-MEDIAN-to-MAX- the median i t the median	JITTER SPECIFIC s less than ha is not the san	ation ensu alf of the to ne as the r	res a jitter otal TX jitter mean. The ji	budget tter
Express* specification compliance eye diagra	urement point and measured over any 250 on 2.0 should be used as the RX device when am). If the clocks to the RX and TX are not c consecutive UI must be used as a reference	taking measu lerived from tl	rements (also ne same refei	refer to th	he Receiver	PCI
interconnect collected which the median and over any 250 consect describes the point in	rovides for a total sum of 0.60 UI determinis I any 250 consecutive UIs. The $_{TRX-EYE-MEDIAN}$ I the maximum deviation from the median is itive TX UIs. It should be noted that the med time where the number of jitter points on e If the clocks to the RX and TX are not derive	-toMAX-JITTER S less than hal lian is not the ither side is ap	specification e f of the total same as the oproximately	ensures a j 0.6 UI jitte mean. The equal as o	itter distribu er budget col e jitter media pposed to th	ition in llected an ne

- from 3500 consecutive UI must be used as the reference for the eye diagram.
- 5. Nominal Unit Interval is 400 \mbox{ps} for 2.5 GT/s and 200 \mbox{ps} for 5 GT/s.



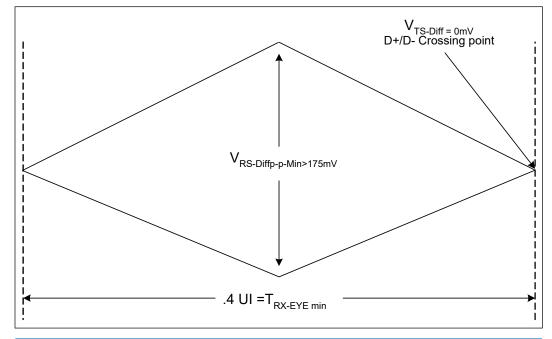


NOTE

Gen1 example is shown for the illustration.*Refer to www.pcisig.com for the updated specifications.*



Figure 5. PCI Express* Receiver Eye



NOTE

Gen1 example is shown for the illustration.*Refer to www.pcisig.com for the updated specifications.*

Table 22.DDC Characteristics

Signal Group: eDP_VDDEN, eDP_BKLTEN, eDP_BKLTCTL, DDP[D:C:B]_CTRLCLK, DDP[D:C:B]_CTRLDATA

Symbol	Parameter	Standard Mode	Fast N	lode	1 M	1Hz	Units
		Maximum	Minimum	Maximum	Minimum	Maximum	
F _{scl}	Operating Frequency	100	0	400	0	1000	kHz
Tr	Rise Time ¹	1000	20+0.1Cb ²	300	_	120	ns
Τ _f	Fall Time ¹	300	20+0.1Cb ²	300	_	120	ns

Notes: 1. Measurement Point for Rise and Fall time: $V_{IL}(max)-V_{IH}(min)$

2. Cb = total capacitance of one bus line in pF. If mixed with High-speed mode devices, faster fall times according to High-Speed mode T_r/T_f are allowed.

9.4.1 Panel Power Sequencing and Backlight Control

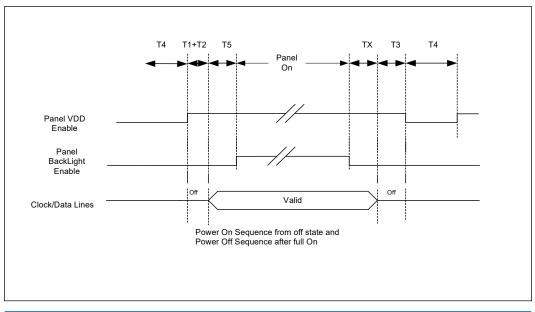
The PCH continues to integrate Panel power sequencing and Backlight control signals for eDP* interfaces on the processor.



This section provides details for the power sequence timing relationship of the panel power, the backlight enable, and the eDP* data timing delivery. To meet the panel power timing specification requirements two signals, eDP_VDDEN and eDP_BKLTEN, are provided to control the timing sequencing function of the panel and the backlight power supplies.

A defined power sequence is recommended when enabling the panel or disabling the panel. The set of timing parameters can vary from panel to panel vendor, provided that they stay within a predefined range of values. The panel VDD power, the backlight on/off state, and the eDP* data lines are all managed by an internal power sequencer.

Figure 6. Panel Power Sequencing



NOTE

Support for programming parameters TX and T1 through T5 using software is provided.

Table 23. DisplayPort* Hot-Plug Detect Interface

Signal Group: DDPB_HPD0, DDPC_HPD1, DDPD_HPD2, DDPE_HPD3, eDP_HPD

Symbol	Parameter	Minimum	Maximum	Unit	Figures	Notes
Tir	Input Time Rise	50	500	ps		
Tif	Input Time Fall	50	500	ps		
Tidr	Input Delay Rise	0.3	2.5	ns		
Tidf	Input Delay Fall	0.3	2.5	ns		



Symbol	Parameter	Minimum	Maximum	Unit	Notes	Figure
LPC Clock (C	LKOUT_LPC[1:0])	·	·			
t1	Period	41.16	42.18	ns		Figure 7 on page 66
t2	High Time	16.67	25	ns		Figure 7 on page 66
	Low Time	16.67	25	ns		Figure 7 on page 66
10	Duty Cycle	40	60	%		
t3	Jitter	-	500	ps	8, 9	
	Flight Time (PCH to Device)	-	3	ns		
CLKOUT_PCI	E_P/N[5:0], CLKOUT_ITPXDP_[P,N]				
Period	Period SSC On	9.849	10.201	ns		Figure 8 on page 67
Period	Period SSC Off	9.849	10.151	ns		Figure 8 on page 67
DtyCyc	Duty Cycle	40	60	%		Figure 8 on page 67
V_Swing	Differential Output Swing	300	-	mV		Figure 8 on page 67
Slew_rise	Rising Edge Rate	1.5	4	V/ns		Figure 8 on page 67
Slew_fall	Falling Edge Rate	1.5	4	V/ns		Figure 8 on page 67
SSC	Jitter	_	150	ps	8, 9, 10	
	Spread Spectrum	0	0.5	%	11	
SMBus/SMLi	nk Clock (SMBCLK, SML[1:0]CLK)				
fsmb	Operating Frequency	10	100	kHz		
t18	High Time	4	50	μs	2	Figure 9 on page 68
t19	Low Time	4.7	-	μs		Figure 9 on page 68
t20	Rise Time	-	1000	ns		Figure 9 on page 68
t21	Fall Time	-	300	ns		Figure 9 on page 68
SMLink[1,0]	(SML[1:0]CLK) (Fast Mode: Refe	er note 15)			•	
fsmb	Operating Frequency	0	400	kHz		
t18_SMLFM	High Time	0.6	50	μs	2	Figure 9 on page 68
t19_SMLFM	Low Time	1.3	-	μs		Figure 9 on page 68
t20_SMLFM	Rise Time	-	300	ns		Figure 9 on page 68
t21_SMLFM	Fall Time	-	300	ns		Figure 9 on page 68
SMLink[1,0]	(SML[1,0]CLK) (Fast Mode Plus:	Refer note 17)				
fsmb	Operating Frequency	0	1000	kHz		
t18_SMLFMP	High Time	0.26	-	μs	2	Figure 9 on page 68
t19_SMLFMP	Low Time	0.5	-	μs		Figure 9 on page 68
t20_SMLFMP	Rise Time	_	120	ns		Figure 9 on page 68
120_SHEI HF				1		

Table 24.Clock Timings



Symbol	Parameter	Minimum	Maximum	Unit	Notes	Figure
I ² C Clock (St	tandard Mode)					
fsmb	Operating Frequency	0	100	kHz		
t18_I2CSM	High Time	4	-	μs	2	Figure 9 on page 68
t19_I2CSM	Low Time	4.7	_	μs		Figure 9 on page 68
t20_I2CSM	Rise Time	-	1000	ns		Figure 9 on page 68
t21_I2CSM	Fall Time	-	300	ns		Figure 9 on page 68
I ² C Clock (Fa	ast Mode)					
fsmb	Operating Frequency	0	400	kHz		
t18_I2CFM	High Time	0.6	-	μs	2	Figure 9 on page 68
t19_I2CFM	Low Time	1.3	-	μs		Figure 9 on page 68
t20_I2CFM	Rise Time	20	300	ns		Figure 9 on page 68
t21_I2CFM	Fall Time	20 x (V _{DD} /5.5 V)	300	ns		Figure 9 on page 68
I ² C Clock (Fa	ast Mode Plus)	•				
fsmb	Operating Frequency	0	1	MHz		
t18_I2CFMP	High Time	0.26	_	μs	2	Figure 9 on page 68
t19_I2CFMP	Low Time	0.5	_	μs		Figure 9 on page 68
t20_I2CFMP	Rise Time	-	120	ns		Figure 9 on page 68
t21_I2CFMP	Fall Time	20 x (V _{DD} /5.5 V)	120	ns		Figure 9 on page 68
I ² C Clock (H	igh Speed Mode, Maximum Bus Ca	apacitance (C _B)) = 100 pF)			
fsmb	Operating Frequency	0	3.4	MHz		
t18_I2CHS1	High Time	60	_	ns	2	Figure 9 on page 68
t19_I2CHS1	Low Time	160	_	ns		Figure 9 on page 68
t20_I2CHS1	Rise Time	10	40	ns		Figure 9 on page 68
t21_I2CHS1	Fall Time	10	40	ns		Figure 9 on page 68
I ² C Clock (H	igh Speed Mode, Maximum Bus Ca	apacitance (C _B)) = 400 pF)			
fsmb	Operating Frequency	0	1.7	MHz		
t18_I2CHS2	High Time	120	-	ns	2	Figure 9 on page 68
t19_I2CHS2	Low Time	320	-	ns		Figure 9 on page 68
t20_I2CHS2	Rise Time	20	80	ns		Figure 9 on page 68
t21_I2CHS2	Fall Time	20	80	ns		Figure 9 on page 68
HDA_BLK (I	ntel [®] High Definition Audio)					
f	Operating Frequency	24	-	MHz		
f _{HDA}	Frequency Tolerance	-	100	ppm		
t26a	Input Jitter (refer to Clock Chip Specification)	-	300	ppm		
		1	1	1	1	continued



Symbol	Parameter	Minimum	Maximum	Unit	Notes	Figure
t27a	High Time (Measured at 0.75 VCC)	18.75	22.91	ns		Refer Figure 7 on page 66
t28a	Low Time (Measured at 0.35 VCC)	18.75	22.91	ns		Refer Figure 7 on page 66
Suspend Cloc	k (SUSCLK)					
fsusclk	Operating Frequency	32		kHz	4	
t39	High Time	9.5	-	μs	4	
t39a	Low Time	9.5	-	μs	4	
XTAL24_IN/X	KTAL24_OUT					
ppm ¹²	Crystal Tolerance cut accuracy maximum	35 ppm (@ 25	°C ±3 °C)			
ppm ¹²	Temp Stability Maximum	30 ppm (10 – 1	70 °C)			
ppm ¹²	Aging Maximum	5 ppm				
Notes: 1. NA						

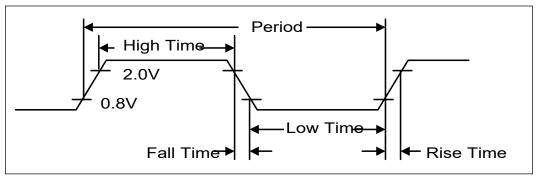
- 2. The maximum high time (t18 Max.) provide a simple ensured method for devices to detect bus idle conditions.
- 3. BCLK Rise and Fall times are measured from 10% VDD and 90% VDD.
- 4. SUSCLK duty cycle can range from 30% minimum to 70% maximum.
- 5. Edge rates in a system as measured from 0.8 2.0 V.
- The active frequency can be 5 MHz, 50 MHz, or 62.5 MHz depending on the interface speed. Dynamic changes of the normal operating frequency are not allowed.
- 7. Testing condition: 1 kohm Pull-up to VCC, 1 kohm Pull-down and 10 pF Pull-down and 1/2 inch trace.
- Jitter is specified as cycle-to-cycle as measured between two rising edges of the clock being characterized. Period minimum and maximum includes cycle-to-cycle jitter and is also measured between two rising edges of the clock being characterized.
- 9. On all jitter measurements care should be taken to set the zero crossing voltage (for rising edge) of the clock to be the point where the edge rate is the fastest. Using a Math function = Average(Derivative(Ch1)) and set the averages to 64, place the cursors where the slope is the highest on the rising edge—usually this lower half of the rising edge. The reason this is defined is for users trying to measure in a system it is impossible to get the probe exactly at the end of the Transmission line with large Flip-Chip components. This results in a reflection induced ledge in the middle of the rising edge and will significantly increase measured jitter.
- 10. Phase jitter requirement: The designated outputs will meet the reference clock jitter requirements from the *PCI Express** *Base Specification*. The test is to be performed on a component test board under quiet conditions with all clock outputs on. Jitter analysis is performed using a standardized tool provided by the PCI SIG. Measurement methodology is defined in the Intel document "*PCI Express** *Reference Clock Jitter Measurements*. This is not for ITPXDP_P/N.
- 11. Spread Spectrum (SSC) is referenced to rising edge of the clock.
- 12. Total of crystal cut accuracy, frequency variations due to temperature, parasitics, load capacitance variations and aging is recommended to be less than 90 ppm.
- 13. Spread Spectrum (SSC) is referenced to rising edge of the clock.
- 14.Spread Spectrum (SSC) of 0.25% on CLKOUT_PCIE[7:0] and CLKOUT_PEG_[B:A] is used for WiMAX friendly clocking purposes.
- 15. When SMLink[1,0] is configured to run in Fast Mode (FM) using a soft strap, the supported operating range is 0 Hz \sim 400 kHz, but the typical operating frequency is in the range of 300 kHz 400 kHz.
- 16. The 25 MHz output option for CLKOUTFLEX2 is derived from the 25 MHz crystal input to the PCH. The PPM of the 25 MHz output is equivalent to that of the crystal.
- 17. When SMLink[1,0] is configured to run in Fast Mode Plus (FMP) using a soft strap, the supported operating range is 0 Hz ~ 1 MHz, but the typical operating frequency is in the range of 900 kHz 1000 kHz. This is the default mode for this interface.
- 18. Higher fall times are expected at High Speed mode. Validation data shows no functional failures with fall times as low as 9.8 ns and 8.6 ns on SDA and SCL respectively in High Speed mode at 3.3 V with Cb=100 pF.



NOTE

Refer to PCI Local Bus Specification for measurement details.

Figure 7. Clock Timing





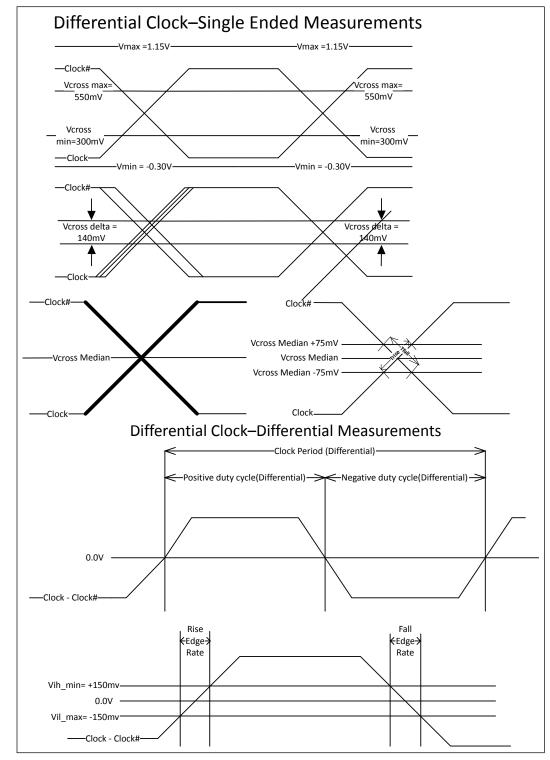
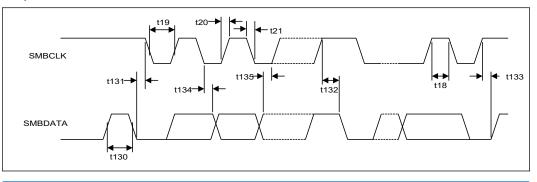


Figure 8. Measurement Points for Differential Waveforms



Figure 9. I²C, SMBus and SMLink Transaction



NOTE

txx also refers to txx_SMLFM and txx_SMLFMP, txxx also refers to txxxSMLFM and txxxSMLFMP, SMBCLK also refers to SML[1:0]CLK, and SMBDATA also refers to SML[1:0]DATA.

Figure 10. PCH Test Load

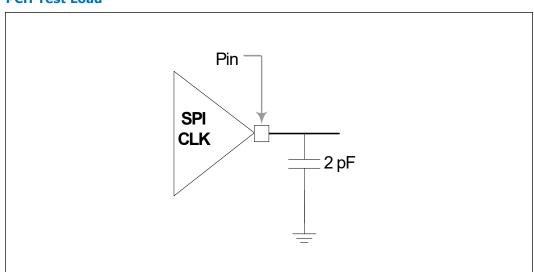


Table 25. USB 2.0 Timing

Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure				
	Full-speed Source (Note 7)									
t100	USBPx+, USBPx- Driver Rise Time	4	20	ns	1,6 CL = 50 pF	Figure 11 on page 70				
t101	USBPx+, USBPx- Driver Fall Time	4	20	ns	1,6 CL = 50 pF	Figure 11 on page 70				
t102	Source Differential Driver Jitter - To Next Transition - For Paired Transitions	-3.5 -4	3.5 4	ns ns	2, 3	Figure 12 on page 70				
t103	Source SE0 interval of EOP	160	175	ns	4	Figure 13 on page 71				
	•		•		•	continued				



Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure
		Full-speed Source	e (Note 7)			
t104	Source Jitter for Differential Transition to SE0 Transition	-2	5	ns	5	
t105	Receiver Data Jitter Tolerance - To Next Transition - For Paired Transitions	-18.5 -9	18.5 9	ns ns	3	Figure 12 or page 70
t106	EOP Width: Receiver must accept EOP	82	-	ns	4	Figure 13 or page 71
t107	Width of SE0 interval during differential transition	_	14	ns		
ow-Spee	ed Source (Note 8)		-			
t108	USBPx+, USBPx – Driver Rise Time	75	300	ns	1,6 CL = 200 pF CL = 600 pF	Figure 11 or page 70
t109	USBPx+, USBPx – Driver Fall Time	75	300	ns	1,6 CL = 200 pF CL = 600 pF	Figure 11 or page 70
t110	Source Differential Driver Jitter - To Next Transition - For Paired Transitions	-25 -14	25 14	ns ns	2,3	Figure 12 or page 70
t111	Source SE0 interval of EOP	1.25	1.5	μs	4	Figure 13 or page 71
t112	Source Jitter for Differential Transition to SE0 Transition	-40	100	ns	5	
t113	Receiver Data Jitter Tolerance - To Next Transition - For Paired Transitions	-152 -200	152 200	ns ns	3	Figure 12 or page 70
t114	EOP Width: Receiver must accept EOP	670	-	ns	4	Figure 13 or page 71
	Width of SE0 interval during differential transition	_	210	ns		

3. Measured at crossover point of differential data signals.

4. Measured at 50% swing point of data signals.

5. Measured from last crossover point to 50% swing point of data line at leading edge of EOP.

6. Measured from 10% to 90% of the data signal.

7. Full-speed Data Rate has minimum of 11.97 Mb/s and maximum of 12.03 Mb/s.

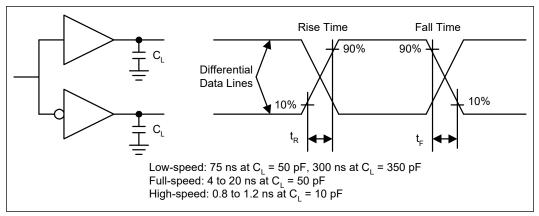
8. Low-speed Data Rate has a minimum of 1.48 Mb/s and a maximum of 1.52 Mb/s.



Symbol	Description	USB 3.2 Gen	1x1 (5 Gb/s)	USB 3.2 Gen		
	Parameter	Minimum	Maximum	Minimum	Maximum	Units
UI	Unit Interval	199.94	200.06	99.97	100.03	ps
T _{TX-EYE}	Minimum Transmission Eye Width	0.625	-	0.646	_	UI
P _{U3}	Polling Period U3 State	—	100	-	100	mS
P _{RX-Detect}	Polling Period Rx Detect	_	100	_	100	mS

Table 26. USB 3.2 Interface Transmit and Receiver Timings

Figure 11. USB Rise and Fall Times





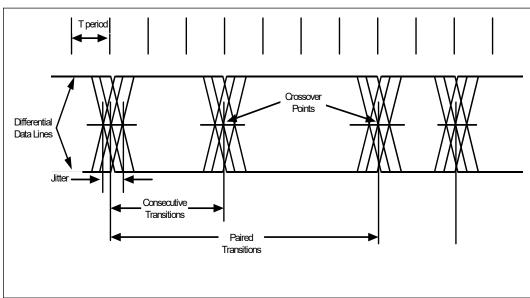


Figure 13. USB EOP Width

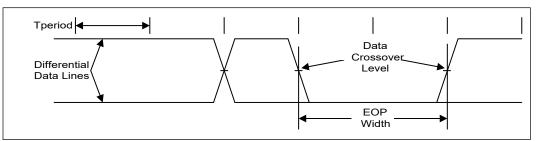


Table 27. SATA Interface Timings

Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure
UI-3	Gen III Operating Data Period (6 Gb/s)	166.6083	166.6667	ps		
t120gen3	Rise Time	0.2	0.48	UI	1	
t121gen3	Fall Time	0.2	0.48	UI	2	
t122	TX differential skew	_	20	ps		
t123	COMRESET	304	336	ns	3	
t124	COMWAKE transmit spacing	101.3	112	ns	3	
t125	OOB Operating Data period	646.67	686.67	ns	4	

Notes: 1. 20 - 80% at transmitter

2. 80 – 20% at transmitter

3. As measured from 100 mV differential crosspoints of last and first edges of burst.

4. Operating data period during Out-Of-Band burst transmissions.

Table 28. SMBusTiming

Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure
t130 _{100 kHz}	Bus Free Time Between Stop and Start Condition	4.7	-	μs		Figure 9 on page 68
t130 _{400 kHz}	Bus Free Time Between Stop and Start Condition	1.3	-	μs		Figure 9 on page 68
t130 _{1 MHz}	Bus Free Time Between Stop and Start Condition	0.5	-	μs		Figure 9 on page 68
t131 _{100 kHz}	Hold Time after (repeated) Start Condition. After this period, the first clock is generated.	4	_	μs		Figure 9 on page 68
t131 _{400 kHz}	Hold Time after (repeated) Start Condition. After this period, the first clock is generated.	0.6	_	μs		Figure 9 on page 68
t131 _{1 MHz}	Hold Time after (repeated) Start Condition. After this period, the first clock is generated.	0.26	_	μs		Figure 9 on page 68
t132 _{100 kHz}	Repeated Start Condition Setup Time	4.7	_	μs		Figure 9 on page 68
t132 _{400 kHz}	Repeated Start Condition Setup Time	0.6	_	μs		Figure 9 on page 68
	•	•	•		•	continued



Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure
t132 _{1 MHz}	Repeated Start Condition Setup Time	0.26	_	μs		Figure 9 on page 68
t133 _{100 kHz}	Stop Condition Setup Time	4	_	μs		Figure 9 on page 68
t133 _{400 kHz}	Stop Condition Setup Time	0.6	_	μs		Figure 9 on page 68
t133 _{1 MHz}	Stop Condition Setup Time	0.26	_	μs		Figure 9 on page 68
t134 _{100 kHz}	Data Hold Time	0	_	ns		Figure 9 on page 68
t134 _{400 kHz}	Data Hold Time	0	_	ns		Figure 9 on page 68
t134 _{1 MHz}	Data Hold Time	0	_	ns		Figure 9 on page 68
t135 _{100 kHz}	Data Setup Time	250	_	ns		Figure 9 on page 68
t135S _{400 kHz}	Data Setup Time	100	_	ns		Figure 9 on page 68
t135S _{1 MHz}	Data Setup Time	50	_	ns		Figure 9 on page 68
t136	Device Time Out	25	35	ms	1	
t137	Cumulative Clock Low Extend Time (slave device)	_	25	ms	2	Figure 14 on page 73
t138	Cumulative Clock Low Extend Time (master device)	_	10	ms	3	Figure 14 on page 73
T _{por}	Time in which a device must be operational after power-on reset	_	500	ms		

Notes: 1. A device will timeout when any clock low exceeds this value.

 t137 is the cumulative time a slave device is allowed to extend the clock cycles in one message from the initial start to stop. If a slave device exceeds this time, it is expected to release both its clock and data lines and reset itself.

3. t138 is the cumulative time a master device is allowed to extend its clock cycles within each byte of a message as defined from start-to-ack, ack-to-ack, or ack-to-stop.

Table 29.I²C and SMLink Timing

Symbol ²	Parameter	Minimum	Maximum	Units	Notes	Figure
t130 _{SM}	Bus Free Time Between Stop and Start Condition	4.7	_	μs		Figure 9 on page 68
t130 _{FM}	Bus Free Time Between Stop and Start Condition	1.3	_	μs		Figure 9 on page 68
t130 _{FMP}	Bus Free Time Between Stop and Start Condition	0.5	-	μs		Figure 9 on page 68
t131 _{SM}	Hold Time after (repeated) Start Condition. After this period, the first clock is generated.	4	_	μs		Figure 9 on page 68
t131 _{FM}	Hold Time after (repeated) Start Condition. After this period, the first clock is generated.	0.6	_	μs		Figure 9 on page 68
t131 _{FMP}	Hold Time after (repeated) Start Condition. After this period, the first clock is generated.	0.26	_	μs		Figure 9 on page 68
t131 _{HSM}	Hold Time after (repeated) Start Condition. After this period, the first clock is generated.	160	_	ns		Figure 9 on page 68
		•		•	•	continued

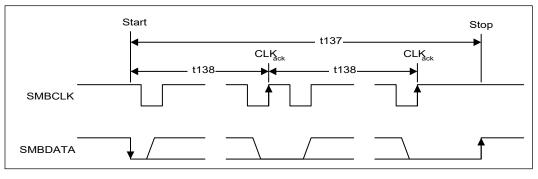


Symbol ²	Parameter	Minimum	Maximum	Units	Notes	Figure
t132 _{SM}	Repeated Start Condition Setup Time	4.7	_	μs		Figure 9 on page 68
t132 _{FM}	Repeated Start Condition Setup Time	0.6	-	μs		Figure 9 on page 68
t132 _{FMP}	Repeated Start Condition Setup Time	0.26	-	μs		Figure 9 on page 68
t132 _{HSM}	Repeated Start Condition Setup Time	160	-	ns		Figure 9 on page 68
t133 _{SM}	Stop Condition Setup Time	4	-	μs		Figure 9 on page 68
t133 _{FM}	Stop Condition Setup Time	0.6	-	μs		Figure 9 on page 68
t133 _{FMP}	Stop Condition Setup Time	0.26	-	μs		Figure 9 on page 68
t133 _{HSM}	Stop Condition Setup Time	160	-	ns		Figure 9 on page 68
t134 _{SM}	Data Hold Time	300	-	ns	1	Figure 9 on page 68
t134 _{FM}	Data Hold Time	0	-	ns		Figure 9 on page 68
t134 _{FMP}	Data Hold Time	0	-	ns		Figure 9 on page 68
t135 _{SM}	Data Setup Time	250	_	ns		Figure 9 on page 68
t135 _{FM}	Data Setup Time	100	-	ns		Figure 9 on page 68
t135 _{FMP}	Data Setup Time	50	-	ns		Figure 9 on page 68
t135 _{HSM}	Data Setup Time	10	_	ns		Figure 9 on page 68

Notes: 1. t134 has a minimum timing for SMLINK is 300 ns.

2. Timings with the SM designator apply to I2C[0:5] and SMLink[1,0] when operating in Standard Mode, timings with the FM designator apply to I2C[0:5] and SMLink[1:0] when operating in Fast Mode, timings with the FMP designator apply to I2C[0:5] and SMLink[1:0] when operating in Fast Mode Plus and timing with the HSM designator apply only to I2C[0:5] when operating in High Speed Mode

Figure 14. SMBus/SMLink Timeout



NOTE

SMBCLK also refers to SML[1:0]CLK and SMBDATA also refers to SML[1:0]DATA in Figure 9 on page 68



Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure
t143	Time duration for which HDA_SDO is valid before HDA_BCLK edge.	6.4	13.2	ns		Figure 15 on page 74
t144	Time duration for which HDA_SDO is valid after HDA_BCLK edge.	6.4	13.2	ns		Figure 15 on page 74
t145	Setup time for HDA_SDI[1:0] at rising edge of HDA_BCLK	22	-	ns		Figure 15 on page 74
t146	Hold time for HDA_SDI[1:0] at rising edge of HDA_BCLK	3	-	ns		Figure 15 on page 74

Table 30. Intel[®] High Definition Audio (Intel[®] HD Audio) Timing

Figure 15. Intel[®] High Definition Audio (Intel[®] HD Audio) Input and Output Timings

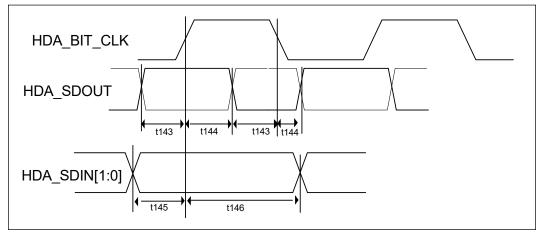


Table 31.DMIC Timing

Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure
	DMIC_DATA[0:1] Setup Time to DMIC_CLK[0:1] Rising	23.5	_	ns		Figure 17 on page 75
	DMIC_DATA[0:1] Hold Time from DMIC_CLK[0:1] Rising	1	_	ns		Figure 17 on page 75
Notar DMIC into	face rise and fall times are characterized	l at the DCU a				

Note: DMIC interface rise and fall times are characterized at the PCH package ball.

Table 32.LPC Timing (24 MHz)

Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure	
t150	LAD[3:0] Valid Delay from CLKOUT_LPC[1:0] Rising	1.5	23.5	ns		Figure 16 on page 75	
t151	LAD[3:0] Output Enable Delay from CLKOUT_LPC[1:0] Rising	2	_	ns		Figure 19 on page 76	
t152	LAD[3:0] Float Delay from CLKOUT_LPC[1:0] Rising	_	28	ns		Figure 18 on page 76	
continued							

Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure
t153	LAD[3:0] Setup Time to CLKOUT_LPC[1:0] Rising	20	_	ns		Figure 17 on page 75
t154	LAD[3:0] Hold Time from CLKOUT_LPC[1:0] Rising	2	_	ns		Figure 17 on page 75
t157	LFRAME# Valid Delay from CLKOUT_LPC[1:0] Rising	0	23.5	ns		Figure 16 on page 75

Figure 16. Valid Delay from Rising Clock Edge

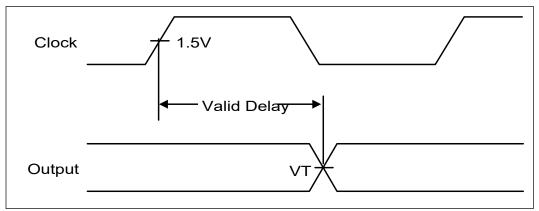


Figure 17. Setup and Hold Times

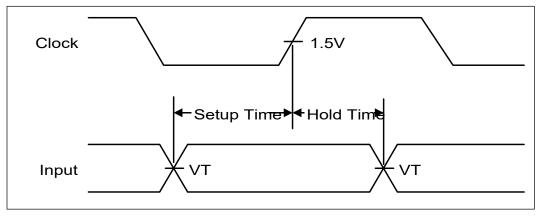




Figure 18. Float Delay

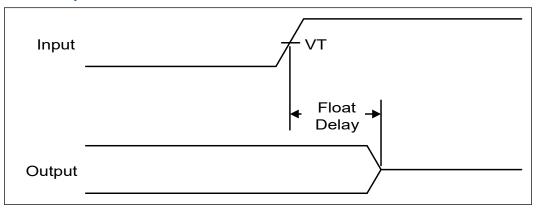


Figure 19. Output Enable Delay

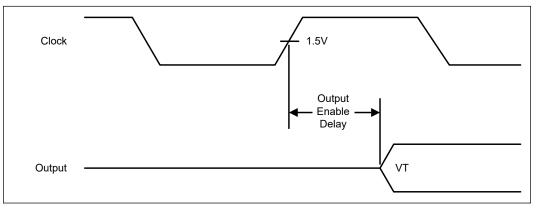


Table 33. Miscellaneous Timings

Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure
t160	SERIRQ Setup Time to PCICLK Rising	7	_	ns		Figure 17 on page 75
t161	SERIRQ Hold Time from PCICLK Rising	0	_	ns		
t162	GPIO, USB Resume Pulse Width	2	_	RTCCLK		Figure 22 on page 77
t163	SPKR Valid Delay from OSC Rising	_	200	ns		Figure 16 on page 75



Figure 20. Valid Delay from Rising Clock Edge

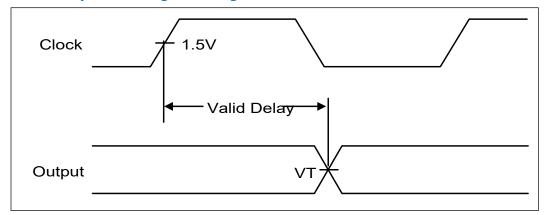


Figure 21. Setup and Hold Times

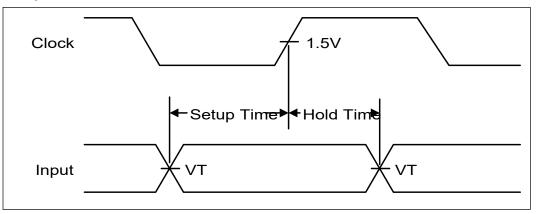


Figure 22. Pulse Width

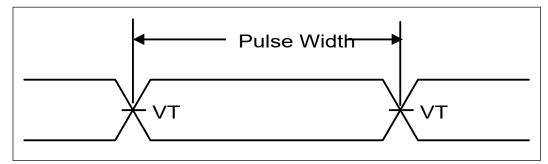


Table 34. SPI Timings (17 MHz)

Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure
t180a	Serial Clock Frequency	16.8	17.48	MHz	1	
t183a	Tco of SPI MOSI and SPI I/O with respect to serial clock falling edge at the host	-24.44	14	ns		Figure 23 on page 80
						continued



Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure
t184a	Setup of SPI MISO and SPI I/O with respect to serial clock falling edge at the host	45.77	_	ns		Figure 23 on page 80
t185a	Hold of SPI MISO and SPI I/O with respect to serial clock falling edge at the host	0.73	_	ns		Figure 23 on page 80
t186a	Setup of SPI CS# assertion with respect to serial clock rising edge at the host	30	_	ns		Figure 23 on page 80
t187a	Hold of SPI CS# assertion with respect to serial clock falling edge at the host	30	_	ns		Figure 23 on page 80
t188a	SPI CLK High time	26.37	_	ns	2	Figure 23 on page 80
t189a	SPI CLK Low time	26.82	_	ns	2	Figure 23 on page 80
2. Measu	ypical clock frequency driven by the PCH urement point for low time and high time output timing such as Tco, are simulatior	e is taken at 0.	. ,	pF.		

Table 35.SPI0 Timings (30 MHz)

Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure
t180b	Serial Clock Frequency	29.4	30.6	MHz	1	Figure 23 on page 80
t183b	Tco of SPI MOSI and SPI I/O with respect to serial clock falling edge at the host	7.02	8	ns		Figure 23 on page 80
t184b	Setup of SPI MISO and SPI I/O with respect to serial clock falling edge at the host	19.93	_	ns		Figure 23 on page 80
t185b	Hold of SPI MISO and SPI I/O with respect to serial clock falling edge at the host	0.83	_	ns		Figure 23 on page 80
t186b	Setup of SPI CS# assertion with respect to serial clock rising edge at the host	30	_	ns		Figure 23 on page 80
t187b	Hold of SPI CS# assertion with respect to serial clock falling edge at the host	30	_	ns		Figure 23 on page 80
t188b	SPI CLK High time	14.88	_	ns	2	Figure 23 on page 80
t189b	SPI CLK Low time	15.18	_	ns	2	Figure 23 on page 80
2. Mea	typical clock frequency driven by the PCH surement point for low time and high tim output timing such as Tco, are simulatio	e is taken at	, ,	2pF.		



Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure
t180b	Serial Clock Frequency	29.4	30.6	MHz	1	Figure 23 on page 80
t183b	Tco of SPI MOSI and SPI I/O with respect to serial clock falling edge at the host	-2.5	7.0 (3.3 V) 7.5 (1.8 V)	ns		Figure 23 on page 80
t184b	Setup of SPI MISO and SPI I/O with respect to serial clock falling edge at the host	15		ns		Figure 23 on page 80
t185b	Hold of SPI MISO and SPI I/O with respect to serial clock falling edge at the host	1		ns		Figure 23 on page 80
t186b	Setup of SPI CS# assertion with respect to serial clock rising edge at the host	30	_	ns		Figure 23 on page 80
t187b	Hold of SPI CS# assertion with respect to serial clock falling edge at the host	30	_	ns		Figure 23 on page 80
t188b	SPI CLK High time	14.88	-	ns	2	Figure 23 on page 80
t189b	SPI CLK Low time	15.18	-	ns	2	Figure 23 on page 80

SPI1 Timing (30 MHz) Table 36.

Notes: 1. The typical clock frequency driven by the PCH is 30 MHz.

2. Measurement point for low time and high time is taken at 0.5(VCCSPI).

3. PCH output timing such as Tco, are simulation values, with a test load of 2pF.

Table 37. SPI Timings (48 MHz)

Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure		
t180c	Serial Clock Frequency	47.04	48.96	MHz	1	Figure 23 on page 80		
t183c	Tco of SPI MOSI and SPI I/O with respect to serial clock falling edge at the host	-3	6.2	ns		Figure 23 on page 80		
t184c	Setup of SPI MISO and SPI I/O with respect to serial clock falling edge at the host	8	_	ns		Figure 23 on page 80		
t185c	Hold of SPI MISO and SPI I/O with respect to serial clock falling edge at the host	1.5	_	ns		Figure 23 on page 80		
t186c	Setup of SPI CS# assertion with respect to serial clock rising edge at the host	30	_	ns		Figure 23 on page 80		
t187c	Hold of SPI CS# assertion with respect to serial clock falling edge at the host	30	_	ns		Figure 23 on page 80		
	continued							



Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure		
t188c	SPI CLK High time	7.1	_	ns	2, 3	Figure 23 on page 80		
t189c	SPI CLK Low time	11.17	_	ns	2, 3	Figure 23 on page 80		
2. When Meas	 Notes: 1. Typical clock frequency driven by the PCH is 48 MHz. 2. When using 48 MHz mode ensure target flash component can meet t188c and t189c specifications. Measurement should be taken at a point as close as possible to the package pin. 3. Measurement point for low time and high time is taken at 0.5(VCCSPI). 							

4. PCH output timing such as Tco, are simulation values, with a test load of 2pF.

Figure 23. SPI Timings

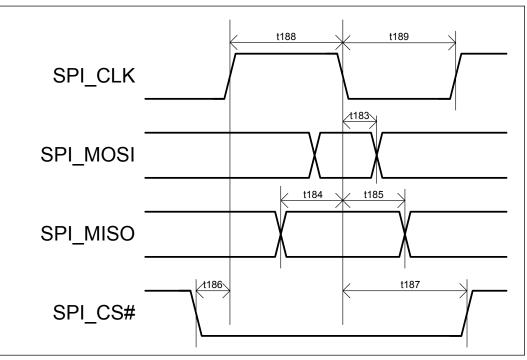


Table 38. GSPI Timings (20 MHz)

Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure
F	Serial Clock Frequency	_	20	MHz		Figure 24 on page 81
t183	Tco of SPI MOSI with respect to serial clock falling edge	-15	7.6	ns		Figure 24 on page 81
t184	Setup of SPI MISO and SPI I/O with respect to serial clock rising edge	3.8	_	ns		Figure 24 on page 81
t185	Hold of SPI MISO and SPI I/O with respect to serial clock rising edge	20	_	ns		Figure 24 on page 81
t186	Setup of SPI CS# assertion with respect to serial clock rising edge	20	_	ns		Figure 24 on page 81
t187	Hold of SPI CS# assertion with respect to serial clock falling edge	20	_	ns		Figure 24 on page 81





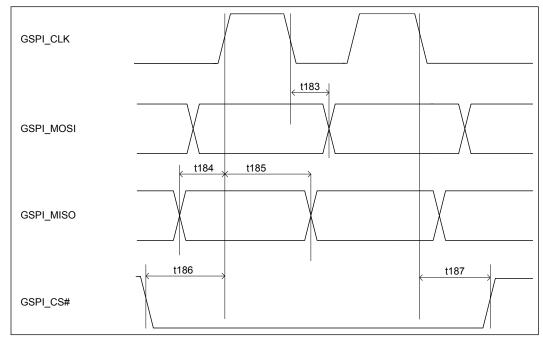


Table 39. **Controller Link Receive Timings**

Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure			
t190	Single bit time	13	_	ns		Figure 25 on page 82			
t191	Single clock period	30	_	ns		Figure 25 on page 82			
t193	Setup time before CL_CLK	0.9	_	ns		Figure 25 on page 82			
t194	Hold time after CL_CLK	0.9	_	ns		Figure 25 on page 82			
V _{IL_AC}	Input low voltage (AC)	_	CL_Vref – 0.08	V	2				
V _{IH_AC}	Input high voltage (AC)	CL_Vref +0.08	_	v	2				
this m	Notes: 1. Measured from (CL_Vref - 50 mV to CL_Vref + 50 mV) at the receiving device side. No test load is required for this measurement as the receiving device fulfills this purpose. 2. CL_Vref = 0.12*(VccSus3_3).								

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Figure 25. Controller Link Receive Timings

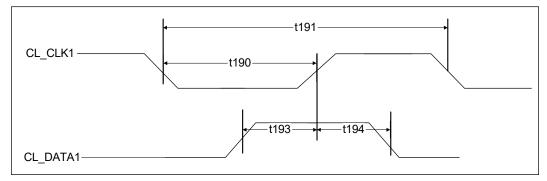


Figure 26. Controller Link Receive Slew Rate

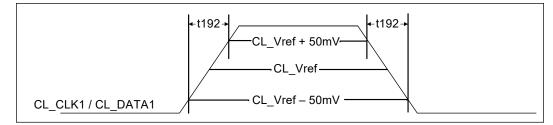


Table 40. UART Timings

Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure
F	Operating Frequency	-	6.25	Mbps		
Slew_rise	Output Rise Slope	1.452	2.388	V/ns		
Slew_fall	Output Fall Slope	1.552	2.531	V/ns		

Table 41.I²S Timings Master Mode

Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure		
SCLK			•			•		
F _{I2S}	Clock Frequency in (non S0ix)	_	12.288	MHz				
F _{I2S}	Clock Frequency (S0ix)	_	9.6	MHz				
SFRM								
T _{CO}	Clock to Output Delay	-8	15	ns				
RXD								
T _{SU}	Setup Time	40	-	ns				
T _{HD}	Hold Time	1	-	ns				
TXD								
T _{CO}	Clock to Output Delay	-8	15	ns				

Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure
SCLK	•		·			
F _{I2S}	Clock Frequency	-	12.288	MHz		
SFRM						
T _{SU}	Setup Time	9	-	ns		
T _{HD}	Hold Time	10	-	ns		
RXD		L.				
T _{SU}	Setup Time	9	-	ns		
T _{HD}	Hold Time	10	-	ns		
ТХD		l		1	,	
T _{CO}	Clock to Output Delay	0	21	ns		

Table 42. I²S Timing Slave Mode (Non S0ix)

Table 43. I²S Timing Slave Mode (S0ix)

Symbol	Parameter	Minimum	Maximum	Units	Notes	Figure	
SCLK	•						
F _{I2S}	Clock Frequency	-	9.6	MHz			
SFRM	-						
T _{SU}	Setup Time	15	-	ns			
T _{HD}	Hold Time	10	_	ns			
RXD							
T _{SU}	Setup Time	15	-	ns			
T _{HD}	Hold Time	10	-	ns			
ТХD		·				•	
T _{CO}	Clock to Output Delay	0	28	ns			

Table 44. eSPI Timing

Parameter	Minimum	Maximum	Units
Serial Clock Frequency	20	60	MHz
Tco of eSPI MOSI and eSPI I/O with respect to serial clock falling edge at the host	-3.0 (60 MHz) -3.0 (48 MHz) -15.73 (30 MHz)	2.5 (60 MHz) 2.5 (48 MHz) 13.38 (30 MHz)	ns
Setup of eSPI MISO and eSPI I/ O with respect to serial clock falling edge at the host	5.5 (60 MHz) 5.5 (48 MHz) 24.17 (30MHz)		ns
Hold of eSPI MISO and eSPI I/ O with respect to serial clock falling edge at the host	0.5 (60 MHz) 0.5(48 MHz) 1.09 (30MHz)		ns
Setup of eSPI CS# assertion with respect to serial clock rising edge at the host	22 (60 MHz) 30 (48 MHz) 45 (30 MHz)		ns
	•	сог	ntinued



Parameter	Minimum	Maximum	Units
Hold of eSPI CS# assertion with respect to serial clock falling edge at the host	15 (60 MHz) 20 (48 MHz) 30 (25 MHz)		ns
eSPI CLK High time (Clock High time measured at 50% of VCCPRIM_1P8)	6 (60 MHz) 8 (48 MHz) 12 (30 MHz)		ns
eSPI CLK Low time (Clock Low time measured at 50% of VCCPRIM_1P8)	6 (60 MHz) 8 (48 MHz) 12 (30 MHz)		ns

9.5 Overshoot/Undershoot Guidelines

Overshoot (or undershoot) is the absolute value of the maximum voltage above VCC or below VSS. The PCH can be damaged by single and/or repeated overshoot or undershoot events on any input, output, or I/O buffer if the charge is large enough. Baseboard designs that meet signal integrity and timing requirements and that do not exceed the maximum overshoot or undershoot limits listed in Table 41 on page 82 and Table 43 on page 83 will ensure reliable I/O performance for the lifetime of the PCH.

Signal Group	Voltage (Vccx) (V)	Overshoot Voltage Magnitude (V)	Overshoot Duration (nS)	Undershoot Voltage Magnitude (V)	Undershoot Duration (nS)
	1.0	2.01	0.6	-0.15	0.6
	1.8	1.97	1.2	-0.12	1.2
GPP_A, SPI, GPP_G	3.3	3.65	2.5	-0.26	2.5
	3.3	3.61	5	-0.21	5
GPP_D[17:20], DMIC, HDA, GPP_E	1.8	2.01	0.6	-0.15	0.6
	1.0	1.97	1.2	-0.12	1.2
	3.3	3.65	2.5	-0.26	2.5
		3.61	5	-0.21	5
	1.8	2.27	0.6	-0.42	0.6
GPP_F		2.2	1.2	-0.34	1.2
GPP_C,	1.8	1.95	0.6	-0.1	0.6
GPP_D[0:16],GPP_D[21:23], ISH, SPI1, GPD, GPP_B, GPP_H,	1.0	1.90	1.2	-0.05	1.2
eDP_BKLTEN, eDP_BKLTCTL, eDP_VDDEN, SYS_PWROK,	2.2	3.51	2.5	-0.11	2.5
SYS_RESET#, CL_RST#	3.3	3.45	5	-0.05	5
USB 2.0	3.3	4.356	20.825	-1.056	20.835

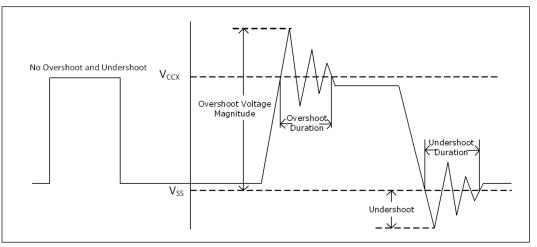
Table 45. Overshoot/Undershoot Specifications

Notes: 1. These specifications are measured at the PCH pin.

 Voltage (Vccx) refers to the supply voltage at the pin. Refer below figure for pictorial description of allowable overshoot/undershoot magnitude and duration.



Figure 27. Maximum Acceptable Overshoot/Undershoot Waveform





10.0 Pin Straps

The following signals are used for static configuration. They are sampled at the rising edge of DSW_PWROK, RSMRST#, or PCH_PWROK to select configuration and then revert later to their normal usage. To invoke the associated mode, the signal should meet both set up and hold time of 1 us, with respect to the rising edge of the sampling signal.

The PCH implements soft straps, which are used to configure specific functions within the PCH and processor very early in the boot process before BIOS or software intervention. The PCH will read soft strap data out of the SPI device prior to the deassertion of reset to both the Intel[®] Converged security and Management Engine and the Host system.

GPP_B14 / SPKR Top Swap Override GPP_B18 / GSPI0_MOSI No Reboot	Rising edge of PCH_PWROK	 The signal has a weak internal pull-down. 0 = Disable "Top Swap" mode. (Default) 1 = Enable "Top Swap" mode. This inverts an address on access to SPI and firmware hub (FWH), so the processor believes it fetches the alternate boot block instead of the original bootblock. PCH will invert A16 (default) for cycles going to the upper two 64-KB blocks in the FWH or the appropriate address lines (A16, A17 or A18) as selected in Top Swap Block size soft strap. Notes: 1. The internal pull-down is disabled after PCH_PWROK is high. 2. Software will not be able to clear the Top Swap bit until the system is reboated. 3. The status of this strap is readable using the Top Swap bit (Bus 0, Device 31, Function 0, offset DCh, bit4).
		4. This signal is in the primary well.
	Rising edge of PCH_PWROK	The signal has a weak internal pull-down. 0 = Disable "No Reboot" mode. (Default) 1 = Enable "No Reboot" mode. PCH will disable the TCO Timer system reboot feature. This function is useful when running ITP/ XDP. <i>Notes:</i> 1. The internal pull-down is disabled after PCH_PWROK is high. 2. This signal is in the primary well.
GPP_C2 / TLS SMBALERT# Y	Rising edge of RSMRST#	 This signal has a weak internal pull-down. 0 = Disable Intel[®] CSME Crypto Transport Layer Security (TLS) cipher suite (no confidentiality). (Default) 1 = Enable Intel[®] CSME Crypto Transport Layer Security (TLS) cipher suite (with confidentiality). Must be pulled up to support Intel[®] AMT with TLS. Notes: 1. The internal pull-down is disabled after RSMRST# de-asserts. 2. This signal is in the primary well.



Signal	Usage	When Sampled	Comment		
			This Signal has a weak internal p This field determines the destina memory range. Also controllable (Bus0, Device31, Function0, offs	tion of accesses to the BIOS using Boot BIOS Destination bit	
			Bit 6	Boot BIOS Destination	
			0	SPI (Default)	
			1	LPC	
GPP_B22 / GSPI1_MOSI	Boot BIOS Strap Bit BBS	Rising edge of PCH_PWROK	have SPI flash connec bus with a valid descr 3. Boot BIOS Destinatior strap or using Boot BI	lected, BIOS may still be platforms are required to ted directly to the PCH's SPI iptor in order to boot. n select to LPC by functional OS Destination bit will not itiated by Intel [®] CSME or	
GPP_C5 / SMLOALERT#	eSPI or LPC Select	Rising edge of RSMRST#	 This signal has a weak internal pull-down. 0 = LPC is selected (for EC). (Default) 1 = eSPI is selected (for EC). Notes: 1. The internal pull-down is disabled after RSMRST# de-asserts. 2. This signal is in the primary well. Warning: If this strap is configured to '0' (eSPI is disabled), the eSPI Flash Sharing Mode strap must be configured to '0' as well (SAFS is disabled) 		
SPI0_MOSI	Reserved	Rising edge of RSMRST#	External pull-up is required. Recommend 100 kohm if pulled up to 3.3V or 75 kohm if pulled up to 1.8V. This strap should sample HIGH. There should NOT be any on- board device driving it to opposite direction during strap sampling.		
GPP_D12 / ISH_SPI_MOSI / GSPI2_MOSI	Reserved	Rising edge of RSMRST#	External pull-up is required. Recommend 100 kohm if pulled up to 3.3V or 75 kohm if pulled up to 1.8V. This strap should sample HIGH. There should NOT be any on- board device driving it to opposite direction during strap sampling.		
GPP_B23 / SML1ALERT# / PCHHOT#	Intel® DCI- OOB	Rising edge of RSMRST#	 This signal has an internal pull-down. 0 = Disable Intel[®] DCI-OOB (Default) 1 = Enable Intel[®] DCI-OOB <i>Notes:</i> 1. The internal pull-down is disabled after RSMRST# de-asserts. 2. When used as PCHHOT# and strap low, a 150 kohm pull-up is needed to ensure it does not override the internal pull-down strap sampling. 3. This signal is in the primary well. 		
SPI0_IO2	Reserved	Rising edge of RSMRST#	External pull-up is required. Recommend 100 kohm if pulled up to 3.3V or 75 kohm if pulled up to 1.8V. This strap should sample HIGH. There should NOT be any on-board device driving it to opposite direction during strap sampling.		
SPI0_103	Reserved	Rising edge of RSMRST#	External pull-up is required. Record to 3.3V or 75 kohm if pulled up t		
	1	1	1	continued	



Signal	Usage	When Sampled	Comment
			This strap should sample HIGH. There should NOT be any on- board device driving it to opposite direction during strap sampling.
HDA_SDO / I2S0_TXD	Flash Descriptor Security Override	Rising edge of PCH_PWROK	This signal has a weak internal pull-down. 0 = Enable security measures defined in the Flash Descriptor. (Default) 1 = Disable Flash Descriptor Security (<u>override</u>). This strap should be asserted high using external Pull-up in manufacturing/ debug environments ONLY. <i>Notes:</i> 1. The internal pull-down is disabled after PCH_PWROK is high. 2. This signal is in the primary well.
GPP_E19 / DDPB_CTRLDATA / CNV_BT_IF_SELECT	Display Port B Detected	Rising edge of PCH_PWROK	This signal has a weak internal Pull-down 0 = Port B is not detected. (Default) 1 = Port B is detected. <i>Notes:</i> 1. The internal Pull-down is disabled after PCH_PWROK is high. 2. This signal is in the primary well.
GPP_E21 / DDPC_CTRLDATA	Display Port C Detected	Rising edge of PCH_PWROK	This signal has a weak internal Pull-down. 0 = Port C is not detected. (Default) 1 = Port C is detected. <i>Notes:</i> 1. The internal pull-down is disabled after PCH_PWROK is high. 2. This signal is in the primary well.
GPP_E23 / DDPD_CTRLDATA	Display Port D Detected	Rising edge of PCH_PWROK	This signal has a weak internal pull-down. 0 = Port D is not detected. (Default) 1 = Port D is detected. <i>Notes:</i> 1. The internal pull-down is disabled after PCH_PWROK is high. 2. This signal is in the primary well.
ITP_PMODE	Reserved	Rising edge of RSMRST#	This signal has a weak internal pull-up. This strap should sample HIGH. There should NOT be any on- board device driving it to opposite direction during strap sampling.
GPP_H17	Reserved	Rising edge of PCH_PWROK	This signal has a weak internal pull-down. This strap should sample LOW. There should NOT be any on- board device driving it to opposite direction during strap sampling. Notes: 1. The internal pull-down is disabled after PCH_PWROK is high. 2. This signal is in the primary well.
GPP_H21	XTAL Frequency Select	Rising edge of RSMRST#	 This signal has a weak internal pull-down. An external pull-up is required on this strap since 38.4 MHz XTAL is not supported on the PCH. 0 = 38.4 XTAL frequency selected. (Default) 1 = 24MHz XTAL frequency selected. <i>Notes:</i> 1. The internal pull-down is disabled after RSMRST# de-asserts. 2. This signal is in the primary well.
GPP_F6 / CNV_RGI_DT	M.2 CNV Mode Select	Rising edge of RSMRST#	A weak external pull-up is required. 0 = Integrated CNVi enable. 1 = Integrated CNVi disable. continued



Signal	Usage	When Sampled	Comment		
			<i>Note:</i> When a RF companion chip is connected to the PCH CNVi interface, the device internal pull-down resistor will pull the strap load to enable CNVi interface.		
INPUT3VSEL	3.0V Select	Input pin must always be driven to a valid logic level	External pull-up or pull-down is required 0 = 3.3V supply is 3.3V +/- 5% 1 = 3.3V supply is 3.0V +/- 5% <i>Note:</i> This strap should only be used for specific targeted 1S battery systems.		
GPD7	Reserved	Rising edge of DSW_PWROK	External pull-up is required. Recommend 100 kohm. This strap should sample HIGH. There should NOT be any on- board device driving it to opposite direction during strap sampling		
GPP_H23	eSPI Flash Sharing Mode	Rising edge of RSMRST#	 This signal has a weak internal pull-down. 0 = Master Attached Flash Sharing (MAFS) enabled (Default) 1 = Slave Attached Flash Sharing (SAFS) enabled. <i>Notes:</i> 1. The internal pull-down is disabled after RSMRST# de-asserts. 2. This signal is in the primary well. <i>Warning:</i> This strap must be configured to '0' (SAFS is disabled) if the <i>eSPI or LPC</i> strap is configured to '0' (eSPI is disabled) 		



11.0 8254 Timers

The PCH contains two counters that have fixed uses. All registers and functions associated with these timers are in the Primary well. The 8254 unit is clocked by a 1.193 MHz periodic timer tick, which is functional only in S0 states. The 1.193 MHz periodic timer tick is generated off the 24 MHz xtal clock.

Counter 0, System Timer

This counter functions as the system timer by controlling the state of IRQ0 and is typically programmed for Mode 3 operation. The counter produces a square wave with a period equal to the product of the counter period (838 ns) and the initial count value. The counter loads the initial count value 1 counter period after software writes the count value to the counter I/O address. The counter initially asserts IRQ0 and decrements the count value by two each counter period. The counter negates IRQ0 when the count value reaches 0. It then reloads the initial count value and again decrements the initial count value by two each counter period. The counter then asserts IRQ0 when the count value reaches 0, reloads the initial count value, and repeats the cycle, alternately asserting and negating IRQ0.

Counter 2, Speaker Tone

This counter provides the speaker tone and is typically programmed for Mode 3 operation. The counter provides a speaker frequency equal to the counter clock frequency (1.193 MHz) divided by the initial count value. The speaker must be enabled by a write to port 061h (Refer to the NMI Status and Control ports).

11.1 Timer Programming

The counter/timers are programmed in the following fashion:

- 1. Write a control word to select a counter.
- 2. Write an initial count for that counter.
- Load the least and/or most significant bytes (as required by Control Word Bits 5, 4) of the 16-bit counter.
- 4. Repeat with other counters.

Only two conventions need to be observed when programming the counters. First, for each counter, the control word must be written before the initial count is written. Second, the initial count must follow the count format specified in the control word (least significant byte only, most significant byte only, or least significant byte, and then most significant byte).

A new initial count may be written to a counter at any time without affecting the counter's programmed mode. Counting is affected as described in the mode definitions. The new count must follow the programmed count format.



If a counter is programmed to read/write two-byte counts, the following precaution applies – a program must not transfer control between writing the first and second byte to another routine which also writes into that same counter. Otherwise, the counter will be loaded with an incorrect count.

The Control Word Register at port 43h controls the operation of all three counters. Several commands are available:

- **Control Word Command.** Specifies which counter to read or write, the operating mode, and the count format (binary or BCD).
- **Counter Latch Command.** Latches the current count so that it can be read by the system. The countdown process continues.
- **Read Back Command.** Reads the count value, programmed mode, the current state of the OUT pins, and the state of the Null Count Flag of the selected counter.

The Table below lists the six operating modes for the interval counters:

Mode	Function	Description
0	Out signal on end of count (=0)	Output is 0. When count goes to 0, output goes to 1 and stays at 1 until counter is reprogrammed.
1	Hardware retriggerable one-shot	Output is 0. When count goes to 0, output goes to 1 for one clock time.
2	Rate generator (divide by n counter)	Output is 1. Output goes to 0 for one clock time, then back to 1 and counter is reloaded.
3	Square wave output	Output is 1. Output goes to 0 when counter rolls over, and counter is reloaded. Output goes to 1 when counter rolls over, and counter is reloaded, and so on.
4	Software triggered strobe	Output is 1. Output goes to 0 when count expires for one clock time.
5	Hardware triggered strobe	Output is 1. Output goes to 0 when count expires for one clock time.

Table 47. Counter Operating Modes

11.2 Reading From Interval Timer

It is often desirable to read the value of a counter without disturbing the count in progress. There are three methods for reading the counters—a simple read operation, counter Latch command, and the Read-Back command. Each one is explained below:

With the simple read and counter latch command methods, the count must be read according to the programmed format; specifically, if the counter is programmed for two byte counts, two bytes must be read. The two bytes do not have to be read one right after the other. Read, write, or programming operations for other counters may be inserted between them.

Simple Read

The first method is to perform a simple read operation. The counter is selected through Port 40h (Counter 0) or 42h (Counter 2).



NOTE

Performing a direct read from the counter does not return a determinate value, because the counting process is asynchronous to read operations. However, in the case of Counter 2, the count can be stopped by writing to the GATE bit in Port 61h.

Counter Latch Command

The Counter Latch command, written to Port 43h, latches the count of a specific counter at the time the command is received. This command is used to ensure that the count read from the counter is accurate, particularly when reading a two-byte count. The count value is then read from each counter's Count register as was programmed by the Control register.

The count is held in the latch until it is read or the counter is reprogrammed. The count is then unlatched. This allows reading the contents of the counters on the fly without affecting counting in progress. Multiple Counter Latch Commands may be used to latch more than one counter. Counter Latch commands do not affect the programmed mode of the counter in any way.

If a Counter is latched and then, some time later, latched again before the count is read, the second Counter Latch command is ignored. The count read is the count at the time the first Counter Latch command was issued.

Read Back Command

The Read Back command, written to Port 43h, latches the count value, programmed mode, and current states of the OUT pin and Null Count flag of the selected counter or counters. The value of the counter and its status may then be read by I/O access to the counter address.

The Read Back command may be used to latch multiple counter outputs at one time. This single command is functionally equivalent to several counter latch commands, one for each counter latched. Each counter's latched count is held until it is read or reprogrammed. Once read, a counter is unlatched. The other counters remain latched until they are read. If multiple count Read Back commands are issued to the same counter without reading the count, all but the first are ignored.

The Read Back command may additionally be used to latch status information of selected counters. The status of a counter is accessed by a read from that counter's I/O port address. If multiple counter status latch operations are performed without reading the status, all but the first are ignored.

Both count and status of the selected counters may be latched simultaneously. This is functionally the same as issuing two consecutive, separate Read Back commands. If multiple count and/or status Read Back commands are issued to the same counters without any intervening reads, all but the first are ignored.

If both count and status of a counter are latched, the first read operation from that counter returns the latched status, regardless of which was latched first. The next one or two reads, depending on whether the counter is programmed for one or two type counts, returns the latched count. Subsequent reads return unlatched count.



12.0 Audio Video and Speech

This section will cover some of the details of the separate subsystem parts and how they interact starting with the $Intel^{\mbox{\tiny B}}$ HD Audio Controller.

The Intel[®] HD Audio controller consists of a set of DMA engines that are used to move samples of digitally encoded data between system memory and an internal/external codec(s), with enhancements from the optional Intel[®] Smart Sound Technology (DSPs). The controller communicates with the internal/external codec(s) over the Audio Link. The Audio Link is a collection of Intel[®] High Definition Audio serial link, Intel[®] Display Audio serial link, and other DSP I/O peripheral for proprietary interfaces (For example I²S, MIPI* SoundWire* and DMIC).

The Intel[®] HD Audio controller implements a number of output DMA engines and input DMA engines. The Output DMA engines move digital data from system memory to a DAC in a codec. The Input DMA engines move digital data from the ADC in the codec to system memory. The audio link supports a number of internal/external codecs by implementing Serial Data Input signals, one dedicated to each of the supported codecs. Audio software renders outbound, and processes inbound data to/from buffers in memory. The Output DMA engines fetch the digital data from memory and reformat it based on the programmed sample rate, bits/sample and number of channels. The data from the Output DMA engines is then combined and serially sent to the codec(s) over the audio link. The Input DMA engines receive data from the codec(s) over the audio link and format the data based on the programmable attributes for that stream. The data is then written to memory in the predefined format for software to process. Each DMA engine moves one "stream" of data. A single codec can accept or generate multiple "streams" of data, one for each ADC or DAC in the codec. Multiple codecs can accept the same output "stream" processed by a single DMA engine.

The audio subsystem contains serial audio interfaces (I²S and Intel[®] Display Audio Interface), PDM digital microphone interfaces (DMIC), multi-context DMA controllers for transferring data between audio interfaces and memories, on-die SRAMs for storing data and code and serving as a shared L2 memory, and four processor cores (DSPs) based on Cadence* Tensilica* HiFi3/LX6 cores.

The Intel[®] Smart Sound Technology subsystem contains four DSPs are located in their own power domains together with their L1 cache controllers and cache memories. The DSP domains may operate up to 400 MHz. One of the DSPs can be enabled in the D0ix state of the overall audio subsystem, the others are powered down and can be made operational only in D0 state.

The power gating and LDOs are controlled by the Local Power Sequencer (LPS) assisted by the DSP firmware. This approach allows for flexible and robust fine grain power management. The LPS communicates with the Power Management Controller (PMC) to request power supplies.

Acronyms

inte

Acronyms	Description
DMIC	Digital Microphone. PDM based MEMs microphone modules
DSP	Digital Signal Processor. In AVS specifically an DSP to process audio data.
I ² S	Inter IC Sound. A serial bus using PCM.
LDO	Low Drop Out. A type of voltage regulator that can regulate output voltage when input voltage is close to output voltage.
MEMs	Micro electrical mechanical Systems. For AVS devices such as Digital MEMs Microphones.
PCM	Pulse Code Modulation. Modulation with amplitude coded into stream.
PDM	Pulse Density Modulation. Modulation with amplitude coded by pulse density.
SoC	System On Chip.
VAD	Voice Activity Detector.
VOIP	Voice Over Internet Protocol
ADC	Analog -to-Digital Converter
DAC	Digital-to-Analog Converter

12.1 Signal Description

Name	Туре	Description
Intel [®] High Defin	nition Audio	Signals
HDA_RST#/ I2S1_SCLK / SNDW1_CLK	0	Intel [®] HD Audio Reset: Master H/W reset to internal/external codecs.
HDA_SYNC / I2S0_SFRM	0	Intel [®] HD Audio Sync: 48-kHz fixed rate frame sync to the codecs. Also used to encode the stream number.
HDA_BCLK / I2S0_SCLK	0	Intel [®] HD Audio Bit Clock: Up to 24 MHz serial data clock generated by the Intel HD Audio controller.
HDA_SDO / I2S0_TXD	0	Intel [®] HD Audio Serial Data Out: Serial TDM data output to the codecs. The serial output is double-pumped for a bit rate of up to 48 Mb/s.
HDA_SDI0 / I2S0_RXD /	I/O	Intel [®] HD Audio Serial Data In 0: Serial TDM data input from the two codec(s). The serial input is single-pumped for a bit rate of up to 24 Mb/s. These signals contain integrated Pull-down resistors, which are enabled while the primary well is powered.
HDA_SDI1 / I2S1_RXD / SNDW1_DATA	I/O	Intel [®] HD Audio Serial Data In 1: Serial TDM data input from the two codec(s). The serial input is single-pumped for a bit rate of up to 24 Mb/s. These signals contain integrated Pull-down resistors, which are enabled while the primary well is powered.
I ² S/PCM Interfa	ce	-
12S0_SCLK/ HDA_BCLK	0	I ² S/PCM serial bit clock 0: Clock used to control the timing of a transfer. Can be generated internally (Master mode) or taken from an external source (Slave mode).
I2S1_SCLK / HDA_RST / SNDW1_CLK	0	I ² S/PCM serial bit clock 1: This clock is used to control the timing of a transfer. Can be generated internally (Master mode) or taken from an external source (Slave mode).
I2S2_SCLK / GPP_H0	0	I ² S/PCM serial bit clock 2: This clock is used to control the timing of a transfer. Can be generated internally (Master mode) or taken from an external source (Slave mode).
	1	continued



Name	Туре	Description
I2S0_SFRM / HDA_SYNC	0	I ² S/PCM serial frame indicator 0: This signal indicates the beginning and the end of a serialized data word. Can be generated internally (Master mode) or taken from an external source (Slave mode).
I2S1_SFRM / SNDW2_CLK	0	I ² S/PCM serial frame indicator 1: This signal indicates the beginning and the end of a serialized data word. Can be generated internally (Master mode) or taken from an external source (Slave mode).
I2S2_SFRM / GPP_H1 CNV_RF_RESET#	0	I ² S/PCM serial frame indicator 2: This signal indicates the beginning and the end of a serialized data word. Can be generated internally (Master mode) or taken from an external source (Slave mode).
I2S0_TXD / HDA_SDO	0	I ² S/PCM transmit data (serial data out)0: This signal transmits serialized data. The sample length is a function of the selected serial data sample size.
I2S1_TXD / SNDW2_DATA	0	I ² S/PCM transmit data (serial data out)1: This signal transmits serialized data. The sample length is a function of the selected serial data sample size.
I2S2_TXD / GPP_H2 / MODEM_CLKREQ	0	I ² S/PCM transmit data (serial data out) ² : This signal transmits serialized data. The sample length is a function of the selected serial data sample size.
12S0_RXD / HDA_SDI0	I	I²S/PCM receive data (serial data in)0: This signal receives serialized data. The sample length is a function of the selected serial data sample size.
I2S1_RXD / HDA_SDI1 / SNDW1_DATA	I	I ² S/PCM receive data (serial data in)1: This signal receives serialized data. The sample length is a function of the selected serial data sample size.
I2S2_RXD / GPP_H3	I	I ² S/PCM receive data (serial data in)2: This signal receives serialized data. The sample length is a function of the selected serial data sample size.
I2S_MCLK / GPP_D23	0	I ² S/PCM Master reference clock: This signal is the master reference clock that connects to an audio codec.
DMIC Interface	-	
DMIC_CLK0 / GPP_D19 / SNDW4_CLK	0	Digital Mic Clock: Serial data clock generated by the HD Audio controller. The clock output frequency is up to 4.8 MHz.
DMIC_CLK1 / GPP_D17/ SNDW3_CLK	0	Digital Mic Clock: Serial data clock generated by the HD Audio controller. The clock output frequency is up to 4.8 MHz.
DMIC_DATA0 / GPP_D20/ SNDW4_DATA	I	Digital Mic Data:Serial data input from the digital mic.
DMIC_DATA1 / GPP_D18/ SNDW3_DATA	I	Digital Mic Data:Serial data input from the digital mic.
MIPI* SoundWire	Interface	1
SNDW1_CLK / HDA_RST / I2S1_SCLK	0	SoundWire Clock: Serial data clock to external peripheral devices.
SNDW2 _CLK / I2S1_SFRM /	0	SoundWire Clock: Serial data clock to external peripheral devices.
SNDW3_CLK / GPP_D17/ DMIC_CLK1	0	SoundWire Clock: Serial data clock to external peripheral devices.
SNDW4_CLK / GPP_D19/ DMIC_CLK0	0	SoundWire Clock: Serial data clock to external peripheral devices.
		continued



Name	Туре	Description	
SNDW1_DATA / HDA_SDI1 / I2S1_RXD	I/O	SoundWire Data: Serial data input from external peripheral devices.	
SNDW2 _DATA / I2S1_TXD	I/O	SoundWire Data: Serial data input from external peripheral devices.	
SNDW3_DATA / GPPC_D18 / DMIC_DATA1	I/O	SoundWire Data: Serial data input from external peripheral devices.	
SNDW4_DATA / GPPC_D20 / DMIC_DATA0	I/O	SoundWire Data: Serial data input from external peripheral devices.	
Misc			
SPKR	0	Speaker Output: Used for connection to external speaker for POST sounds if not using the Intel HD Audio embedded option.	

12.2 Integrated Pull-Ups and Pull-Downs

Signal	Resistor Type	Value
HDA_SYNC	Pull-down	14 kohm- 26 kohm
HDA_SDO	Pull-down	14 kohm- 26 kohm
HDA_SDI[1:0]	Pull-down	14 kohm- 26 kohm
I2S[2:0]_SFRM	Pull-down	14 kohm - 26 kohm
I2S[2:0]_RXD	Pull-down	14 kohm - 26 kohm
I2S[2:0]_SCLK	Pull-down	14 kohm - 26 kohm
DMIC_DATA[1:0]	Pull-down	14 kohm - 26 kohm
SNDW_DATA[3:0]	Pull-down	14 kohm - 26 kohm
SPKR	Pull-down	14 kohm - 26 kohm

12.3 I/O Signal Planes and States

Signal Name	Power Plane	During Reset ²	Immediately After Reset ²	S3/S4/S5	Deep Sx
Intel [®] High Definition I	nterface				
HDA_RST#	Primary	Driven Low	Driven Low	Driven Low	OFF
HDA_SYNC	Primary	Internal Pull-down	Driven Low	Internal Pull- down	OFF
HDA_BLK	Primary	Driven Low	Driven Low	Driven Low	OFF
HDA_SDO	Primary	Internal Pull-down	Driven Low	Internal Pull- down	OFF
HDA_SDI[1:0]	Primary	Internal Pull-down	Internal Pull-down	Internal Pull- down	OFF
I ² S/PCM Interface	•				
					continued



Signal Name	Power Plane	During Reset ²	Immediately After Reset ²	S3/S4/S5	Deep Sx
I2S[2:0]_SCLK	Primary	Internal Pull-down	Internal Pull-down	Internal Pull- down	OFF
I2S[2:0]_SFRM	Primary	Internal Pull-down	Internal Pull-down	Internal Pull- down	OFF
I2S0_TXD	Primary	Internal Pull-down	Driven Low	Low then disabled (Refer Note)	OFF
I2S[1:0]_TXD	Primary	Driven Low	Driven Low	Driven Low	OFF
I2S[2:0]_RXD	Primary	Internal Pull-down	Internal Pull-down	Internal Pull- down	OFF
I2S_MCLK	Primary	Driven Low	Driven Low	Driven Low	OFF
DMIC Interface					
DMIC_CLK[1:0]	Primary	Driven Low	Driven Low	Driven Low	OFF
DMIC_DATA[1:0]	Primary	Internal Pull-down	Internal Pull-down	Internal Pull- down	OFF
SoundWire Interface	-	·			
SNDW_DATA[1:4]	Primary	Internal Pull-down	Internal Pull-down	Internal Pull- down	OFF
SNDW_CLK[1:4]	Primary	Driven Low	Driven Low	Driven Low	OFF
Misc					
SPKR	Primary	Driven Low	Driven Low	Low then disabled (Refer note)	OFF

2. Reset reference for primary well pins is RSMRST#, DSW well pins is DSW_PWROK, and RTC well pins is RTCRST#.

12.4 AVS Feature Summary

The AVS Feature Summary includes the following:

- Intel[®] High Definition Audio Controller Capabilities
- Audio DSP Capabilities
- Intel[®] High Definition Audio Link Capabilities
- Intel[®] Display Audio Link Capabilities
- DMIC Interface
- I²S/PCM Interface
- SoundWire Interface

12.4.1 Intel[®] High Definition Audio Controller Capabilities

- PCI/PCI Express* controller
- Supports data transfers, descriptor fetches, and DMA position writes using VC0.



- Independent Bus Master logic for 16 general purpose streams: 7 input and 9 output.
- Supports variable length stream slots
- Supports up to:
 - 16 streams (7 input and 9 output)
 - 16 channels per stream
 - 32 bits/sample
 - 192 KHz sample rate
- Supports memory-based command/response transport
- Three 8-channel universal DMA interfaces for transferring data between memory buffers and peripherals and between memories
- Supports optional Immediate Command/Response mechanism
- Supports output and input stream synchronization
- Supports global time synchronization
- Supports MSI interrupt delivery
- Support for ACPI D3 and D0 Device States
- Supports Function Level Reset (FLR)
 - Only if exposed as PCI Express* device
- Support 1 ms of buffering with all DMA running with maximum bandwidth.
- Support 10 ms of buffering with 1 output DMA and 1 input DMA running at 2 channels, 96 KHz, 16-bit audio.

12.4.2 Audio DSP Capabilities

- DSP off load for low power audio rendering and recording
- Intel $^{\ensuremath{\text{\$}}}$ Wake on Voice supported in Connected Standby and D3/Sx
- High Performance DSP based on Cadence* Tensilica* LX6 HIFI3 DSP Cores operating up to 400 MHz
- Various DSP functions provided by DSP Core: MP3, AAC, 3rd Party IP Algorithms, etc.

12.4.3 Intel[®] High Definition Audio Link Capabilities

- Two SDI signals to support two external codecs.
- Drives variable frequency (6 MHz to 24 MHz) BCLK to support:
- - SDO double pumped up to 48 Mb/s
 - SDIs single pumped up to 24 Mb/s
- Provides cadence for 44.1 kHz-based sample rate output.
- Supports 1.8 V and 3.3 V I/O voltages.

12.4.4 Intel[®] Display Audio Link Capabilities

• One SDI signal to support one display audio codec.



- Drives variable frequency (6 MHz to 96 MHz) BCLK to support:
 - SDO single pumped up to 96 Mb/s
 - SDI's single pumped up to 96 Mb/s
- Provides cadence for 44.1 kHz-based sample rate output.

12.4.5 DMIC Interface

- Two DMIC PDM interfaces with each port capable of supporting up to 4 digital MEMs microphones.
- The audio clock output can operate up to 4.8 MHz.
- Supports 1.8 V and 3.3 V I/O voltages.

12.4.6 I²S/PCM Interface

- Three bi-directional I²S/PCM ports to support up to three I²S connections.
- Support of serial bit rates of 19.2Mbps or 24Mbps.
- Can support three modes: Slave Mode, Slave Mode with Locally Generated Master Clock, or Master Mode one bi-directional $\rm I^2S$ / PCM ports to support one $\rm I^2S$ connection.

12.4.7 SoundWire Interface

- Four SoundWire Interfaces also referred to as ports for connection to platform peripherals.
- Supports only 1.8 V I/O voltage.

13.0 Controller Link

The Controller Link interface is used to connect the Intel[®] CSME to a wireless LAN device supporting Intel[®] Active Management Technology. The Controller Link interface will transmit data at up to 60 Mbps with the clock frequency at 30 MHz.

13.1 Signal Description

Name	Туре	Description	
CL_DATA	I/O	Controller Link Data: Bi-directional data that connects to a Wireless LAN Device supporting Intel [®] Active Management Technology.	
CL_CLK	I/O	Controller Link Clock: Bi-directional clock that connects to a Wireless LAN Device supporting Intel [®] Active Management Technology.	
CL_RST#	O OD	Controller Link Reset: Controller Link reset that connects to a Wireless LAN Device supporting Intel [®] Active Management Technology.	

13.2 Integrated Pull-Ups and Pull-Downs

Signal	Resistor Type	Value (Ohm)	Notes
CL_DATA	Pull-up	31.25	Refer I/O Signal Planes and
	Pull-down	100	States on page 100
CL_CLK	Pull-up	31.25	Refer I/O Signal Planes and
	Pull-down	100	States on page 100

13.3 I/O Signal Planes and States

Signal Name	Power Plane	During Reset ³ Immediately After Reset ³		S3/S4/S5	Deep Sx		
CL_DATA	Primary	Refer Notes 1 and 2	Refer Notes	Internal Pull-down	OFF		
CL_CLK	Primary	Refer Notes 1 and 2	Refer Notes	Internal Pull-down	OFF		
CL_RST#	Primary	Driven Low	Driven High	Driven High	OFF		
Notes: 1. The Controller Link clock and data buffers use internal Pull-up or Pull-down resistors to drive a logical 1 or 0. 2. The terminated state is when the I/O buffer Pull-down is enabled. 3. Reset reference for primary well pins is RSMRST#.							



13.4 External CL RST# Pin Driven/Open-drain Mode Support

The WLAN has transitioned to 1.8 V for external CL_RST# pin, while PCH Controller Link I/O buffer still drives 3.3 V on this pin. This creates voltage in-compatibility issue. In order to support either 1.8 V or 3.3 V on the device CL_RST# pin, the PCH operates/controls the CL_RST# pin as dual modes, which is determined by a Softstrap bit:

- 1. Driven mode: To drive "1" on this pin, Controller Link turn-on the output enable and output=1 to drive 3.3 V on this pin. This mode can only be enabled with older version of WLAN which is 3.3 V tolerant.
- 2. Open-drain mode: To drive "1", Controller Link turn-off the output-enable, and external (required) pull-up will pull the pin up to 1.8 V, which is compatible with WLAN voltage requirement.

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14.0 Processor Sideband Signals

The sideband signals are used for the communication between the processor and PCH.

Acronyms

Acronyms	Description
PECI	Platform Environmental Control Interface

14.1 Signal Description

Name	Туре	Description			
CPUPWRGD	0	Signal to the processor to indicate its primary power is good.			
THRMTRIP#	I	Signal from the processor to indicate that a thermal overheating has occurred.			
PM_SYNC	0	Power Management Sync: State exchange from the PCH to the Processor			
PM_DOWN	I	Power Management Sync: State exchange from the Processor to the PCH			
PLTRST_CPU#	0	Platform reset to the Processor			
PECI	I/O	Single-wire serial bus for accessing processor digital thermometer			
GPP_E3 / CPU_GP0	I				
GPP_E7 / CPU_GP1	I				
GPP_B3 / CPU_GP2	I	- Thermal management signal			
GPP_B4 / CPU_GP3	I				

14.2 I/O Signal Planes and States

Signal Name	Power Plane	During Reset*	Immediately after Reset (Note 1)	S3/S4/S5	Deep S	
CPUPWRGD	Primary	Undriven	Driven High	OFF	OFF	
THRMTRIP#	Primary	Undriven	Undriven	OFF	OFF	
PM_SYNC	Primary	Driven Low	Driven Low	OFF	OFF	
PM_DOWN	Primary	Undriven	Undriven	OFF	OFF	
PLTRST_CPU#	Primary	Driven Low	Driven High	OFF	OFF	
PECI	Primary	Undriven	Undriven	OFF	OFF	
CPU_GP[3:0]	Primary	Undriven	Undriven	Undriven	OFF	
Note: 1. Reset reference for primary well pins is RSMRST#.						



14.3 Functional Description

- CPUPWRGD signal is output to the processor that indicates that the primary power is ramped up and stable. CPUPWRGD will be undriven by the PCH (high Z) when RSMRST# is asserted and driven high after RSMRST# is de-asserted
- If THRMTRIP# goes active, the processor is indicating an overheat condition, and the PCH will immediately transition to an S5 state. CPU_GP can be used from external sensors for the thermal management.
- PM_SYNC is used to provide early warning to the processor that a global reset is in progress and that the memory contents should be saved and placed into self refresh.
- PM_DOWN is input to PCH indicates the processor wake up event.



15.0 Digital Display Signals

Acronyms

Acronyms	Description
eDP*	embedded Display Port*

15.1 Signal Description

Display is divided between processor and PCH. The processor houses memory interface, display planes, pipes, and digital display interfaces/ports, while the PCH has DDC bus, Hot-Plug Detect, Panel Power and Backlight controls.

The DDC (Display Data Channel) bus is used for communication between the host system and display. A pair of DDC (DDC_CLK and DDC_DATA) signals exist on the PCH for each digital port on the processor. DDC is based on I^2C protocol.

The Hot-Plug Detect (HPD) signal serves as an interrupt request for the sink device for DisplayPort* and HDMI*. It is a 3.3V tolerant signal pin on the PCH.

The Panel Power and Backlight controls are used to control power for an internal panel and drive the backlight.

Table 48.Digital Display Signals

Name	Туре	Description
DDPB_HPD0 /GPP_E13 / DISP_MISC0	I	Display Port B:HPD Hot-Plug Detect
DDPC_HPD1 /GPP_E14 / DISP_MISC1	I	Display Port C:HPD Hot-Plug Detect
DPPD_HPD2 /GPP_E15 / DISP_MISC2	Ι	Display Port D: HPD Hot-Plug Detect or eDP*[1] Hot-Plug Detect
DPPB_CTRLCLK/GPP_E18 / CNVi_BT_HOST_WAKE#	I/O	Display Port B:Control Clock.
DPPB_CTRLDATA / GPP_E19	I/O	Display Port B:Control Data.
DPPC_CTRLCLK / GPP_E20	I/O	Display Port C: Control Clock
DPPC_CTRLDATA GPP_E21	I/O	Display Port C:Control Data

15.2 Embedded DisplayPort* (eDP*) Backlight Control Signals

Name	Туре	Description			
eDP_VDDEN / GPP_F19	0	eDP Panel power Enable: Panel power control enable. This signal is used to control the VDC source of the panel logic.			
eDP_BKLTEN / GPP_F20	0	eDP Backlight Enable: Panel backlight enable control for eDP This signal is used to gate power into the backlight circuitry.			
eDP_BKLTCTL / GPP_F21	0	eDP Panel Backlight Brightness control: Panel brightness control for eDP.			
	'	continued			



Name	Туре	Description		
		This signal is used as the PWM Clock input signal		
EDP_HPD / GPP_I4 / DISP_MISC4	I	eDP: Hot-Plug Detect		
Note: eDP_VDDEN, eDP_BKLTEN, eDP_BKLTCTL can be left as no connect if eDP* is not used.				

Name	Туре	Description
eDP_VDDEN	0	eDP* Panel Power Enable: Panel power control enable. This signal is used to control the VDC source of the panel logic.
eDP_BKLTEN	0	eDP* Backlight Enable: Panel backlight enable control for eDP* This signal is used to gate power into the backlight circuitry.
eDP_BKLTCTL	0	eDP* Panel Backlight Brightness control: Panel brightness control for eDP*. This signal is used as the PWM Clock input signal
EDP_HPD /GPP_E17 / DISP_MISC4	I	eDP*: Hot-Plug Detect
Note: eDP_VDDEN, eDP_BKI	LTEN, eDP_BKLTCTL can b	be left as no connect if eDP* is not used.

15.3 Integrated Pull-Ups and Pull-Downs

Signal	Resistor Type	Value	Notes
DPPB_CTRLDATA / GPP_E19	Pull-down	15 kohm-40 kohm	Refer to the note below.
DPPC_CTRLDATA / GPP_E21	Pull-down	15 kohm-40 kohm	Refer to the note below.

NOTE

The internal pull-up/pull-down is only applied during the strap sampling window (PCH_PWROK) and is then disabled. Enabling can be done using a 2.2 kohm Pull-up resistor.

15.4 I/O Signal Planes and States

Signal Name	Power Plane	During Reset ²	Immediately after Reset ²	S3/S4/S5	Deep Sx
DDPB_HPD0 /GPP_ E13 / DISP_MISC0	Primary	Undriven	Undriven	Undriven	OFF
DDPC_HPD1 / GPP_ E14/ DISP_MISC1	Primary	Undriven	Undriven	Undriven	OFF
D PPD_HPD2 / GPP_E15 / DISP_MISC2	Primary	Undriven	Undriven	Undriven	OFF
DPPB_CTRLCLK / GPP_E18 / CNVi_BT_HOST_WAKE#	Primary	Undriven	Undriven	Undriven	OFF
D PPB_CTRLDATA/ GPP_ E19	Primary	Internal Pull- down	Driven Low	Internal Pull- down	OFF
DPPC_CTRLCLK / GPP_E20	Primary	Undriven	Undriven	Undriven	OFF
DPPC_CTRLDATA / GPP_E21	Primary	Internal Pull- down	Driven Low	Internal Pull- down	OFF
continued					



Signal Name	Power Plane	During Reset ²	Immediately after Reset ²	S3/S4/S5	Deep Sx
eDP_VDDEN	Primary	Driven Low	Driven Low	Driven Low	OFF
eDP_BKLTEN	Primary	Driven Low	Driven Low	Driven Low	OFF
eDP_BKLTCTL / GPP_F21	Primary	Driven Low	Driven Low	Driven Low	OFF
EDP_HPD / GPP_ E17 / DISP_MISC4	Primary	Undriven	Undriven	Undriven	OFF



16.0 Enhanced Serial Peripheral Interface eSPI

The PCH provides the Enhanced Serial Peripheral Interface (eSPI) to support connection of an EC (typically used in mobile platform) or an SIO (typically used in desktop platform) to the platform.

The interface supports 1.8 V only and is a dedicated single-slave bus interface for client platforms. Depending on PCH SKU, the interface can support either one device (via one chip select signal) or two devices (via two chip select signals). Refer to the PCH SKU section in Chapter 1 for more information. This interface is not shared and distinct from the SPI bus interface used for flash device and TPM.

NOTE

The PCH LPC and eSPI interfaces are mutually exclusive. A hardware strap is used to determine which interface is used on the platform.

Acronyms

Acronyms	Description	
EC	Embedded Controller	
MAFCC	Master Attached Flash Channel Controller (MAFCC)	
ООВ	Out-of-Band	
TAR	Turn-around cycle	

Reference Documents

16.1 Signal Description

Name	Туре	Description		
ESPI_CLK/CLKOUT_LPC0/ GPP_A9	0	eSPI Clock: eSPI clock output from the PCH to slave device.		
ESPI_IO0/LAD0/GPP_A1	I/O	eSPI Data Signal 0 : Bi-directional pin used to transfer data between the PCH and eSPI slave device.		
ESPI_IO1/LAD1/GPP_A2	I/O	eSPI Data Signal 1 : Bi-directional pin used to transfer data between the PCH and eSPI slave device		
ESPI_IO2/LAD2/GPP_A3	I/O	eSPI Data Signal 2 : Bi-directional pin used to transfer data between the PCH and eSPI slave device		
ESPI_IO3/LAD3/GPP_A4	I/O	eSPI Data Signal 3 : Bi-directional pin used to transfer data between the PCH and eSPI slave device		
ESPI_CS #/LFRAME#/ GPP_A5	0	eSPI Chip Select : Driving CS# signal low to select eSPI slave for the transaction.		
ESPI_RESET#/SUS_STAT#/ GPP_A14	0	eSPI Reset:Reset signal from the PCH to eSPI slave.		



16.2 Integrated Pull-Ups and Pull-Downs

Signal	Resistor Type	Value	Notes
ESPI_CLK	Pull-down	20 kohm +/- 30%	
ESPI_IO[3:0]	Pull-up	20 kohm +/- 30%	
ESPI_ CS #	Pull-up	20 kohm +/- 30%	

16.3 I/O Signal Planes and States

Signal Name	Power Plane	During Reset ¹	Immediately After Reset ¹	S3/S4/S5	Deep Sx		
ESPI_CLK	Primary	Internal Pull- down	Driven Low	Driven Low	OFF		
ESPI_IO [3:0]	Primary	Internal Pull-up	Internal Pull-up	Internal Pull-up	OFF		
ESPI_CS#	Primary	Internal Pull-up	Driven High	Driven High	OFF		
ESPI_RESET#	Primary	Driven Low	Driven High	Driven High	OFF		
Note: 1. Reset reference for primary well pins is RSMRST#.							

16.4 Functional Description

The Functional Description includes the following topics:

- Features
- Protocols
- WAIT States from eSPI Slave
- In-Band Link Reset
- Slave Discovery
- Flash Sharing Mode
- PECI Over eSPI
- Channels and Supported Transactions

16.4.1 Features

The PCH eSPI controller supports the following features:

- Support for Master Attached Flash and Slave Attached Flash.
- Support for 20 MHz, 24 MHz, 30 MHz, 48 MHz, and 60 MHz (configured by soft straps).
- 1.8 V support only.
- Up to quad mode support.
- In-band messages for communication between the PCH and slave device to eliminate side-band signals.
- Real time SPI flash sharing, allowing real time operational access by the PCH and slave device.
- Transmitting RTC time/date to the slave device upon request.



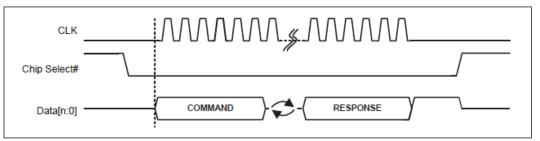
NOTE

For client platform, the PCH eSPI controller does not support a discrete ALERT# pin (as described in the eSPI specification) since the PCH supports only a Single Master - Single Slave configuration. Only ALERT# signaling (over ESPI_IO1) is supported.

16.4.2 Protocols

Below is an overview of the basic eSPI protocol. Refer to the latest eSPI Specification and corresponding platform eSPI Compatibility Specification for more details. Refer Enhanced Serial Peripheral Interface eSPI on page 107

Figure 28. Basic eSPI Protocol



An eSPI transaction consists of a Command phase driven by the master, a turn-around phase (TAR), and a Response phase driven by the slave.

A transaction is initiated by the PCH through the assertion of CS#, starting the clock and driving the command onto the data bus. The clock remains toggling until the complete response phase has been received from the slave.

The serial clock must be low at the assertion edge of the CS# while ESPI_RESET# has been de-asserted. The first data is driven out from the PCH while the serial clock is still low and sampled on the rising edge of the clock by the slave. Subsequent data is driven on the falling edge of the clock from the PCH and sampled on the rising edge of the clock by the slave. Data from the slave is driven out on the falling edge of the clock and is sampled on a falling edge of the clock by the PCH.

All transactions on eSPI are in multiple of 8 bits (one byte).

16.4.3 WAIT States from eSPI Slave

There are situations when the slave cannot predict the length of the command packet from the master (PCH). For non-posted transactions, the slave is allowed to respond with a limited number of WAIT states.

A WAIT state is a 1-byte response code. They must be the first set of response byte from the slave after the TAR cycles.



16.4.4 In-Band Link Reset

In case the eSPI link may end up in an undefined state (for example, when a CRC error is received from the slave in a response to a Set_Configuration command), the PCH issues an In-Band Reset command that resets the eSPI link to the default configuration. This allows the controller to re-initialize the link and reconfigure the slave.

16.4.5 Slave Discovery

The PCH eSPI interface is enabled using a hard pin strap. If this strap is asserted (high) at RSMRST# de-assertion, the eSPI controller is enabled and assumes that a slave is connected to the interface. The controller does not perform any other discovery to confirm the presence of the slave connection.

If the ESPI_EN HW strap is de-asserted (low), the eSPI controller will gate all its clocks and put itself to sleep.

16.4.6 Flash Sharing Mode

eSPI supports both Master and Slave Attached Flash sharing (abbreviated in this as MAFS and SAFS, respectively). The Flash sharing mode selected for a specific platform is dependent on pin strap settings.

In order for SAFS to work, the Slave must support the Flash Access channel.

16.4.7 PECI Over eSPI

When PECI Over eSPI is enabled, the eSPI device (i.e. EC) can access the processor PECI interface via eSPI controller, instead of the physical PECI pin. The support can improve the PECI responsiveness, and reduce PECI pins.

The PECI bus may be connected to the PCH via either the legacy PECI pin or the eSPI interface. The operation via legacy PECI pin or over eSPI is selected via a soft strap and only one or the other is enabled in a given platform.

PECI over eSPI is not supported in Sx state. EC/BMC is not allowed to send the PECI command to eSPI in Sx states. More specifically, EC can only send PECI requests after VW PLTRST# de-assertion.

In S0ix, upon receiving a PECI command, the PMC will wake up the CPU from Cx and respond back once the data is available from CPU.

Refer to the eSPI Compatibility Specification for more details.

16.4.8 Channels and Supported Transactions

An eSPI channel provides a means to allow multiple independent flows of traffic to share the same physical bus. Refer to the eSPI specification for more detail.

Each of the channels has its dedicated resources such as queue and flow control. There is no ordering requirement between traffic from different channels.

The number of types of channels supported by a particular eSPI slave is discovered through the GET_CONFIGURATION command issued by the PCH to the eSPI slave during initialization.



The Table below summarizes the eSPI channels and supported transactions.

Table 43. ESPI Chamlels and Supported Transactions						
CH #	Channel	Posted Cycles Supported	Non-Posted Cycles Supported			
0	Peripheral	Memory Write, Completions	Memory Read, I/O Read/Write			
1	Virtual Wire	Virtual Wire GET/PUT	N/A			
2	Out-of-Band Message	SMBus Packet GET/PUT	N/A			
3	Flash Access	N/A	Flash Read, Write, Erase			
N/A	General	Register Accesses	N/A			

Table 49. eSPI Channels and Supported Transactions

Peripheral Channel (Channel 0) Overview

The Peripheral channel performs the following Functions:

- Target for PCI Device D31:F0: The eSPI controller duplicates the legacy LPC PCI Configuration space registers. These registers are mostly accessed via the BIOS, though some are accessed via the OS as well.
- Tunnel all Host to eSPI slave (EC/SIO) debug device accesses: these are the accesses that used to go over the LPC bus. These include various programmable and fixed I/O ranges as well as programmable Memory ranges. The programmable ranges and their enables reside in the PCI Configuration space.
- Tunnel all accesses from the eSPI slave to the Host. These include Memory Reads and Writes.

Virtual Wire Channel (Channel 1) Overview

The Virtual Wire channel uses a standard message format to communicate several types of signals between the components on the platform.

- Sideband and GPIO Pins: System events and other dedicated signals between the PCH and eSPI slave. These signals are tunneled between the 2 components over eSPI.
- Serial IRQ Interrupts: Interrupts are tunneled from the eSPI slave to the PCH. Both edge and triggered interrupts are supported.
- eSPI Virtual Wires (VW)

The Table below summarizes the PCH virtual wires in eSPI mode. Refer to the eSPI Compatibility Specification for details.

Table 50.eSPI Virtual Wires (VW)

Virtual Wire	PCH Pin Direction	Reset Control	Pin Retained in PCH (For Use by Other Components)			
SUS_STAT#	Output	ESPI_RESET#	No			
SUSWARN#	Output	ESPI_RESET#	No			
SUS_ACK	Input	ESPI_RESET#	No			
SUSPWRDNACK	Output	ESPI_RESET#	No			
PLTRST#	Output	ESPI_RESET#	Yes			
PME# (eSPI Peripheral PME)	Input	ESPI_RESET#	N/A			
continued						



Virtual Wire	PCH Pin Direction	Reset Control	Pin Retained in PCH (For Use by Other Components)
WAKE#	Input	ESPI_RESET#	No
SMI#	Input	PLTRST#	N/A
SCI#	Input	PLTRST#	N/A
RCIN#	Input	PLTRST#	No
SLP_A#	Output	ESPI_RESET#	Yes
SLP_S3#/SLP_S4#/SLP_S5#/ SLP_LAN#/SLP_WLAN#	Output	DSW_PWROK	Yes
SLAVE_BOOT_LOAD_DONE	Input	ESPI_RESET#	N/A
SLAVE_BOOT_LOAD_STATUS	Input	ESPI_RESET#	N/A
HOST_RST_WARN	Output	PLTRST#	N/A
HOST_RST_ACK	Input	PLTRST	N/A
OOB_RST_WARN	Output	ESPI_RESET#	N/A
OOB_RST_ACK	Input	ESPI_RESET#	N/A
HOST_C10	Output	PLTRST#	N/A
ERROR_NONFATAL	Input	ESPI_RESET#	N/A
ERROR_FATAL	Input	ESPI_RESET#	N/A

• Interrupt Events

eSPI supports both level and edge-triggered interrupts. Refer to the eSPI Specification for details on the theory of operation for interrupts over eSPI.

The PCH eSPI controller will issue a message to the PCH interrupt controller when it receives an IRQ group in its VW packet, indicating a state change for that IRQ line number.

The eSPI slave can send multiple VW IRQ index groups in a single eSPI packet, up to the Operating Maximum VW Count programmed in its Virtual Wire Capabilities and Configuration Channel.

The eSPI controller acts only as a transport for all interrupt events generated from the slave. It does not maintain interrupt state, polarity or enable for any of the interrupt events.

Out-of-Band Channel (Channel 2) Overview

The Out-of-Band channel performs the following Functions:

- Tunnel MCTP Packets between the Intel[®] CSME and eSPI slave device: The Intel[®] CSME communicates MCTP messages to/from the device by embedding those packets over the eSPI protocol. This eliminates the SMBus connection between the PCH and the slave device which was used to communicate the MCTP messages in prior to the PCH generations. The eSPI controller simply acts as a message transport and forwards the packets between the Intel[®] CSME and eSPI device.
- Tunnel PCH Temperature Data to the eSPI slave: The eSPI controller stores the PCH temperature data internally and sends it to the slave using a posted OOB message when a request is made to a specific destination address.



Tunnel PCH RTC Time and Date Bytes to the eSPI slave: the eSPI controller captures this data internally at periodic intervals from the PCH RTC controller and sends it to the slave device using a posted OOB message when a request is made to a specific destination address.

PCH Temperature Data Over eSPI OOB Channel

eSPI controller supports the transmitting of PCH thermal data to the eSPI slave. The thermal data consists of 1 byte of PCH temperature data that is transmitted periodically (~ 1 ms) from the thermal sensor unit.

The packet formats for the temperature request from the eSPI slave and the PCH response back are shown in the two Figures below:

eSPI Slave Request to PCH for PCH Temperature Figure 29.

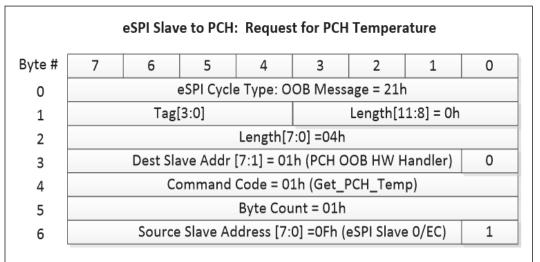
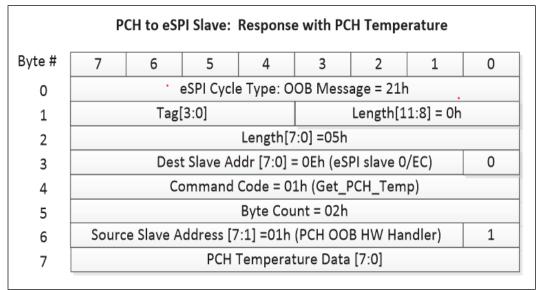


Figure 30. PCH Response to eSPI Slave with PCH Temperature



PCH RTC Time/Date to EC Over eSPI OOB Channel

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The PCH eSPI controller supports the transmitting of PCH RTC time/date to the eSPI slave. This allows the eSPI slave to synchronize with the PCH RTC system time. Moreover, using the OOB message channel allows reading of the internal time when the system is in Sx states.

The RTC time consists of 7 bytes: seconds, minutes, hours, day of week, day of month, month and year. The controller provides all the time/date bytes together in a single OOB message packet. This avoids the boundary condition of possible roll over on the RTC time bytes if each of the hours, minutes, and seconds bytes is read separately.

The packet formats for the RTC time/date request from the eSPI slave and the PCH response back to the device are shown in the two Figures below:

Figure 31. eSPI Slave Request to PCH for PCH RTC Time

eSPI Slave to PCH: Request for RTC Time								
Byte #	7	6	5	4	3	2	1	0
0	eSPI Cycle Type: OOB Message = 21h							
1	Tag[3:0] Length[11:8] = 0h							
2	Length[7:0] =04h							
3	Dest Slave Addr [7:1] = 01h (PCH OOB HW Handler) 0						0	
4	Command Code = 02h (Get_PCH_RTC_Time)							
5	Byte Count = 01h							
6	Source Slave Address [7:0] =0Fh (eSPI Slave 0/EC) 1						1	

		PCH to e	SPI Slave	: Respor	ise with	PCH RTC	Time	
Byte #	7	6	5	4	3	2	1	0
0			eSPI Cycle	e Type: O	OB Mess	age = 21ł	1	
1		Tag	[3:0]			Length[1	1:8] = 0h	
2				Length[7	':0] =0Ch			
3		Des	t Slave Ac	dr [7:0] :	= 0Eh (eS	PI slave 0	/EC)	0
4	Command Code = 02h (Get_PCH_RTC_Time)							
5	Byte Count = 09h							
6	Source Slave Address [7:1] =01h (PCH OOB HW Handler) 1					1		
7	Reserved DM HF DS					DS		
8	PCH RTC Time: Seconds							
9	PCH RTC Time: Minutes							
10	PCH RTC Time: Hours							
11	PCH RTC Time: Day of Week							
12	PCH RTC Time: Day of Month							
13	PCH RTC Time: Month							
14			F	PCH RTC	Fime: Yea	r		

Figure 32. PCH Response to eSPI Slave with RTC Time

NOTES

- 1. DS: Daylight Savings. A 1 indicates that Daylight Saving has been comprehended in the RTC time bytes. A 0 indicates that the RTC time bytes do not comprehend the Daylight Savings.
- 2. HF: Hour Format. A 1 indicates that the Hours byte is in the 24-hr format. A 0 indicates that the Hours byte is in the 12-hr format. In 12-hr format, the seventh bit represents AM when it is a 0 and PM when it is a 1.
- 3. DM: Data Mode. A 1 indicates that the time byte are specified in binary. A 0 indicates that the time bytes are in the Binary Coded Decimal (BCD) format.

Flash Access Channel (Channel 3) Overview

The Flash Access channel supports the Master Attached Flash (MAF) configuration, where the flash device is directly attached to the PCH. This configuration allows the eSPI device to access the flash device attached to the PCH through a set of flash access commands. These commands are routed to the flash controller and the return data is sent back to the eSPI device.

The Master Attached Flash Channel controller (MAFCC) tunnels flash accesses from eSPI slave to the PCH flash controller. The MAFCC simply provides Flash Cycle Type, Address, Length, Payload (for writes) to the flash controller. The flash controller is



responsible for all the low level flash operations to perform the requested command and provides a return data/status back to the MAFCC, which then tunnels it back to the eSPI slave in a separate completion packet.

• Master Attached Flash Channel Controller (MAFCC) Flash Operations and Addressing

The EC is allocated a dedicated region within the eSPI Master-Attached flash device. The EC has default read, write, and erase access to this region.

The EC can also access any other flash region as permitted by the Flash Descriptor settings. As such, the EC uses linear addresses, valid up to the maximum supported flash size, to access the flash.

The MAFCC supports flash read, write, and erase operations only.

Slave Attached Flash Channel Controller (SAFCC) Flash Operation and Addressing

The PCH is allocated dedicated regions (for each of the supported masters) within the eSPI slave-attached flash devices. The PCH has read, write, and erase access to these regions, as well as any other regions that maybe permitted by the region protections set in the Flash Descriptor.

The Slave will optionally perform additional checking on the PCH provided address. In case of an error due to incorrect address or any other issues it will synthesize an unsuccessful completion back to the eSPI Master.

The SAFCC supports Flash Read, Write and Erase operations. It also supports the RPMC, Read SFDP and Read JEDEC ID commands.



17.0 General Purpose Input and Output

The PCH General Purpose Input/Output (GPIO) signals are grouped into multiple groups (such as GPP_A, GPP_B, and so on) and are powered by either the PCH Primary well or Deep Sleep well. Many GPIO signals are multiplexed with other native functions.

The high level features of GPIO:

- Configurable 3.3V or 1.8V voltage (except for GPP F and GPD groups).
- Configurable as an input or output signal.
- Configurable GPIO pad ownership by host, Intel[®] CSME, or ISH.
- SCI (GPE) and IOAPIC interrupt capable on all GPIOs.
- NMI and SMI capability capable (on selected GPIOs).
- PWM, Serial Blink capable (on selected GPIOs).
- Programmable hardware debouncer (on GPD3/PWRBTN# pin).

17.1 Functional Description

The Functional Description includes the following topics:

- Configurable GPIO Voltage
- GPIO Buffer Impedance Compensation
- Programmable Hardware Debouncer
- Integrated Pull-ups and Pull-downs
- SCI / SMI# and NMI
- Timed GPIO
- GPIO Blink (BK) and Serial Blink (SBK)
- GPIO Ownership

17.1.1 Configurable GPIO Voltage

Except for all pads in GPIO F group and GPD group, all other GPIO pads support perpad configurable voltage, which allows control selection of 1.8V or 3.3V for each pad. The configuration is done via soft straps.

Before soft straps are loaded, the default voltage of each pin depends on its default as input or output.

- Input: 1.8V level with 3.3V tolerant.
- Output: defaults to `0', except for the following GPIOs which defaults to `1' via a ~20K pull-up to 3.3V:

— GPP_B0



- GPP_B1
- GPP_B11 / EXT_PWR_GATE#
- GPP_B12 / SLP_S0#
- GPP_H18 / CPU_C10_GATE#

A 1.8V device connected to these GPIOs must be capable of taking 20 kohm pull-up to 3.3V.

WARNING

GPIO pad voltage configuration must be set correctly depending on device connected to it; otherwise, damage to the PCH or the device may occur.

NOTES

- 1. GPIO F group supports 1.8V only.
- 2. GPD group supports 3.3V only.

17.1.2 GPIO Buffer Impedance Compensation

All GPIO buffers require impedance compensation for 1.8V and 3.3V operation. The impedance compensation is done via the SD_1P8_RCOMP and SD_3P3_RCOMP signals. Therefore, SD_1P8_RCOMP and SD_3P3_RCOMP signals must have a precision pull down resistor of 200 Ohm (1%) to GND (regardless of SDXC being used or not). The resistor can be shared between the two RCOMP pins. Without proper impedance compensation, the GPIO buffers, including the muxed native functions, may not operate as expected.

17.1.3 Interrupt / IRQ via GPIO Requirement

A GPIO, as an input, can be used to generate an interrupt/IRQ to the PCH. In this case, it is required that the pulse width on the GPIO must be at least 4 us for the PCH to recognize the interrupt.

17.1.4 Programmable Hardware Debouncer

Hardware debounce capability is supported on GPD3/PWRBTN# pad. The capability can be used to filter signal from switches and buttons if needed.

The period can be programmed from 8 to 32768 times of the RTC clock by programming the Pad Configuration DW2 register. At 32 kHz RTC clock, the debounce period is 244 us to 1 s.

17.1.5 Integrated Pull-ups and Pull-downs

All GPIOs have programmable internal pull-up/pull-down resistors (20 Kohm) which are off by default. The internal pull-up/pull-down for each GPIO can be enabled by BIOS programming the corresponding PAD_CFG_DW1 register. Refer to Volume 2 (Register Info) for more details. The internal pull-up / pull down can only be implemented if the toggle rate of the GPIO is no more than 300 KHz.



Note that certain GPIOs used as pin straps have internal PU/PD enabled during reset by default.

17.1.6 SCI / SMI# and NMI

SCI capability is available on all GPIOs, while SMI and NMI capability is available on only select GPIOs.

Below are the PCH GPIOs that can be routed to generate SMI# or NMI:

- GPP_B14, GPP_B20, GPP_B23
- GPP_C[23:22]
- GPP_D[4:0]
- GPP_E[8:0], GPP_E[16:13]

17.1.7 Timed GPIO

The PCH supports 2 Timed GPIOs as native function (TIME_SYNC) that is muxed on GPIO pins. The intent usage of the Timed GPIO function is for time synchronization purpose.

Timed GPIO can be an input or an output.

- As an input, a GPIO input event triggers the HW to capture the PCH Always Running Timer (ART) time in the Time Capture register. The GPIO input event must be asserted for at least 2 crystal oscillator clocks period in order for the event to be recognized.
- As an output, a match between the ART time and the software programmed time value triggers the HW to generate a GPIO output event and capture the ART time in the Time Capture register. If periodic mode is enabled, HW generates the periodic GPIO events based on the programmed interval. The GPIO output event is asserted by HW for at least 2 crystal oscillator clocks period.

Timed GPIO supports event counter. When Timed GPIO is configured as input, event counter increments by 1 for every input event triggered. When Timed GPIO is configured as output, event counter increments by 1 for every output event generated. The event counter provides the correlation to associate the Timed GPIO event (the nth event) with the captured ART time. The event counter value is captured when a read to the Time Capture Value register occurs.

NOTE

When Timed GPIO is enabled, the crystal oscillator will not be shut down as crystal clock is needed for the Timed GPIO operation. As a result, SLP_SO# will not be asserted. This has implication to platform power (such as IDLE or S0ix power). Software should only enable Timed GPIO when needed and disable it when Timed GPIO functionality is not required.



17.1.8 GPIO Blink (BK) and Serial Blink (SBK)

Certain GPIOs are capable of supporting blink and serial blink, indicated as BK and SBK respectively in the GPIO Signals table above. The BK and SBK are implemented as native functions muxed on the selected GPIOs. To enable BK or SBK on a GPIO having the capability, BIOS needs to select the assigned native function for BK or SBK on the GPIO.

17.1.9 GPIO Ownership

Any PCH GPIO can be owned either by the host or the Intel[®] CSME. The designer can select GPIOs that are required by a Intel[®] CSME feature When selected and controlled by the Intel[®] CSME, those GPIOs cannot be used by the host anymore.

17.1.10 Virtual GPIO (vGPIO)

vGPIO is a special type of GPIO implemented in the PCH for a specific functionality. vGPIO is not a physical GPIO; the signal is not balled out on the package. Programming the vGPIO is similar to programming a physical GPIO.

The PCH implements vGPIO39 (in GPIO community 1), which is specifically used for SD card detection as an interrupt generation. If the PCH integrated SD card is utilized, in conjunction of the SD_CD# pin to be used as card detect, a physical GPIO pin is required for interrupt generation. vGPIO39 is intended to replace the need for this addition physical GPIO if desired. SW needs to program the vGPIO accordingly to enable this functionality.



18.0 Intel[®] Serial I/O Inter-Integrated Circuit (I²C) Controllers

The PCH implements six I²C controllers for six independent I²C interfaces, I2C0-I2C5. Each interface is a two-wire serial interface consisting of a serial data line (SDA) and a serial clock (SCL).

I2C4 and I2C5 only implement the I2C host controllers and do not incorporate a DMA controller. Therefore, I2C4 and I2C5 are restricted to operate in PIO mode only.

Acronyms	Description
I ² C	Inter-Integrated Circuit
PIO	Programmed Input/Output
SCL	Serial Clock Line
SDA	Serial Data Line

Acronyms

References

Specification	Location
The I ² C Bus Specification, Version 6	www.nxp.com/documents/user_manual/UM10204.pdf

18.1 Signal Description

Name	Туре	Description
I2C0_SDA/ GPP_C16	I/OD	I ² C Link 0 Serial Data Line External Pull-up resistor is required.
I2C0_SCL/ GPP_C17	I/OD	I ² C Link 0 Serial Clock Line External Pull-up resistor is required.
I2C1_SDA/ GPP_C18	I/OD	I ² C Link 1 Serial Data Line External Pull-up resistor is required.
I2C1_SCL/ GPP_C19	I/OD	I ² C Link 1 Serial Clock Line External Pull-up resistor is required.
I2C2_SDA/ GPP_H4	I/OD	I ² C Link 2 Serial Data Line External Pull-up resistor is required.
I2C2_SCL/ GPP_H5	I/OD	I ² C Link 2 Serial Clock Line External Pull-up resistor is required.
I2C3_SDA/ GPP_H6	I/OD	I ² C Link 3 Serial Data Line External Pull-up resistor is required.
I2C3_SCL/GPP_H7	I/OD	I ² C Link 3 Serial Clock Line External Pull-up resistor is required.
		continued



Name	Туре	Description
I2C4_SDA/ GPP_H8	I/OD	I ² C Link 4 Serial Data Line External Pull-up resistor is required.
12C4_SCL/ GPP_H9	I/OD	I ² C Link 4 Serial Clock Line External Pull-up resistor is required.
I2C4B_SDA/GPP_D13 / ISH_UART0_RXD / SMLOBDATA	I/OD	2nd instance of the I ² C Link 4 Data used for Comms Hub External Pull-up resistor is required.
I2C4B_SCL/ GPP_D14 / ISH_UART0_TXD / SML0BCLK	I/OD	2nd instance of the I ² C Link 4 Clock used for Comms Hub External Pull-up resistor is required.
I2C5_SDA/ GPP_H10/ ISH_I2C2_SDA	I/OD	I ² C Link 5 Serial Data Line External Pull-up resistor is required.
I2C5_SCL/ GPP_H11/ ISH_I2C2_SCL	I/OD	I ² C Link 5 Serial Clock Line External Pull-up resistor is required.

18.2 I/O Signal Planes and States

Signal Name	Power Plane	During Reset	Immediately after Reset	S3/S4/S5	Deep Sx		
12C [5:0]_SDA	Primary	Undriven	Undriven	Undriven	OFF		
12C [5:0]_SCL	Primary	Undriven	Undriven	Undriven	OFF		
Note: Reset reference for primary well pins is RSMRST#.							

18.3 Functional Description

This topic has the following sections:

- Features
- Protocols Overview
- DMA Controller
- Reset
- Power Management
- Interrupts
- Error Handling
- Programmable SDA Hold Time

18.3.1 Features

The I2C interfaces support the following features:

- Speed: standard mode (up to 100 Kb/s), fast mode (up to 400 Kb/s), fast mode plus (up to 1 MB/s) and High speed mode (up to 3.2 Mb/s)
- 1.8V or 3.3V support (depending on the voltage supplied to the I²C signal group)
- Master I2C operation only
- 7-bit or 10-bit addressing



- 7-bit or 10-bit combined format transfers
- Bulk transmit mode
- Ignoring CBUS addresses (an older ancestor of I2C used to share the I2C bus)
- Interrupt or polled-mode operation
- Bit and byte waiting at all bus speed
- Component parameters for configurable software driver support
- Programmable SDA hold time (tHD; DAT)
- DMA support with 64-byte DMA FIFO per channel (up to 32-byte burst)
- 64-byte Tx FIFO and 64-byte Rx FIFO
- SW controlled serial data line (SDA) and serial clock (SCL)

NOTES

- 1. The controllers must only be programmed to operate in master mode only. I2C slave mode is not supported.
- 2. I2C multi masters is not supported.
- 3. Simultaneous configuration of Fast Mode and Fast Mode Plus/High speed mode is not supported.
- 4. I2C General Call is not supported.

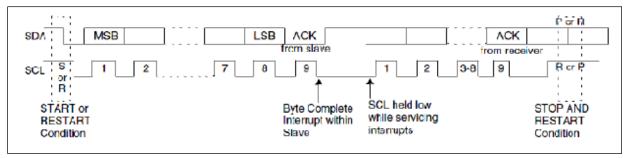
18.3.2 Protocols Overview

For more information on the I2C protocols and command formats, refer to the industry I2C specification. Below is a simplified description of I^2C bus operation:

- The master generates a START condition, signaling all devices on the bus to listen for data.
- The master writes a 7-bit address, followed by a read/write bit to select the target device and to define whether it is a transmitter or a receiver.
- The target device sends an acknowledge bit over the bus. The master must read this bit to determine whether the addressed target device is on the bus.
- Depending on the value of the read/write bit, any number of 8-bit messages can be transmitted or received by the master. These messages are specific to the I²C device used. After 8 message bits are written to the bus, the transmitter will receive an acknowledge bit. This message and acknowledge transfer continues until the entire message is transmitted.
- The message is terminated by the master with a STOP condition. This frees the bus for the next master to begin communications. When the bus is free, both data and clock lines are high.







Combined Formats

The PCH I2C controllers support mixed read and write combined format transactions in both 7-bit and 10-bit addressing modes.

The PCH controllers do not support mixed address and mixed address format (which means a 7-bit address transaction followed by a 10-bit address transaction or vice versa) combined format transaction.

To initiate combined format transfers, IC_CON.IC_RESTSART_EN should be set to 1. With this value set and operating as a master, when the controller completes an I2C transfer, it checks the transmit FIFO and executes the next transfer. If the direction of this transfer differs from the previous transfer, the combined format is used to issue the transfer. If the transmit FIFO is empty when the current I2C transfer completes, a STOP is issued and the next transfer is issued following a START condition.

18.3.3 DMA Controller

The I²C controllers 0 to 3 (I2C0 - I2C3) each has an integrated DMA controller. The I2C controller 4 and 5 (I2C4 and I2C5) only implement the I2C host controllers and do not incorporate a DMA. Therefore, I2C4 and I2C5 are restricted to operate in PIO mode only.

DMA Transfer and Setup Modes

The DMA can operate in the following modes:

- 1. Memory to peripheral transfers. This mode requires the peripheral to control the flow of the data to itself.
- 2. Peripheral to memory transfer. This mode requires the peripheral to control the flow of the data from itself.

The DMA supports the following modes for programming:

- 1. Direct programming. Direct register writes to DMA registers to configure and initiate the transfer.
- 2. Descriptor based linked list. The descriptors will be stored in memory (such as DDR or SRAM). The DMA will be informed with the location information of the descriptor. DMA initiates reads and programs its own register. The descriptors can form a linked list for multiple blocks to be programmed.
- 3. Scatter Gather mode.



Channel Control

- The source transfer width and destination transfer width is programmable. The width can be programmed to 1, 2, or 4 bytes.
- Burst size is configurable per channel for source and destination. The number is a power of 2 and can vary between 1,2,4,...,128. This number times the transaction width gives the number of bytes that will be transferred per burst.
- Individual channel enables. If the channel is not being used, then it should be clock gated.
- Programmable Block size and Packing/Unpacking. Block size of the transfer is programmable in bytes. The block size is not be limited by the source or destination transfer widths.
- Address incrementing modes: The DMA has a configurable mechanism for computing the source and destination addresses for the next transfer within the current block. The DMA supports incrementing addresses and constant addresses.
- Flexibility to configure any hardware handshake sideband interface to any of the DMA channels
- Early termination of a transfer on a particular channel.

18.3.4 Reset

Each host controller has an independent reset associated with it. Control of these resets is accessed through the Reset Register.

Each host controller and DMA will be in reset state once powered ON and require SW (BIOS or driver) to write into specific reset register to bring the controller from reset state into operational mode.

NOTE

To avoid a potential I^2C peripheral deadlock condition where the reset goes active in the middle of a transaction, the I^2C controller must be idle before a reset can be initiated.

18.3.5 Power Management

Device Power Down Support

To power down peripherals connected to PCH I^2C bus, the idle configured state of the I/O signals is retained to avoid voltage transitions on the bus that can affect the connected powered peripheral. Connected devices are allowed to remain in the D0 active or D2 low power states when I^2C bus is powered off (power gated). The PCH HW will prevent any transitions on the serial bus signals during a power gate event.

Latency Tolerance Reporting (LTR)

Latency Tolerance Reporting is used to allow the system to optimize internal power states based on dynamic data, comprehending the current platform activity and service latency requirements. The interface supports this by reporting its service latency requirements to the platform power management controller using LTR registers.



The controller's latency tolerance reporting can be managed by one of the two following schemes. The platform integrator must choose the correct scheme for managing latency tolerance reporting based on the platform, OS and usage.

- 1. Platform/HW Default Control. This scheme is used for usage models in which the controller's state correctly informs the platform of the current latency requirements.
- 2. Driver Control. This scheme is used for usage models in which the controller state does not inform the platform correctly of the current latency requirements. If the FIFOs of the connected device are much smaller than the controller FIFOs, or the connected device's end to end traffic assumptions are much smaller than the latency to restore the platform from low power state, driver control should be used.

18.3.6 Interrupts

 $\mathrm{I}^{2}\mathrm{C}$ interface has an interrupt line which is used to notify the driver that service is required.

When an interrupt occurs, the device driver needs to read the host controller, DMA interrupt status and TX completion interrupt registers to identify the interrupt source. Clearing the interrupt is done with the corresponding interrupt register in the host controller or DMA.

All interrupts are active high and their behavior is level triggered.

18.3.7 Error Handling

Errors that might occur on the external I^2C signals are comprehended by the I^2C host controller and reported to the I^2C bus driver through the MMIO registers.

18.3.8 Programmable SDA Hold Time

PCH includes a software programmable register to enable dynamic adjustment of the SDA hold time, if needed.



19.0 Gigabit Ethernet Controller

The Gigabit Ethernet controller(D31:F6) in conjunction with the Intel[®] Ethernet Connection I219 provides a complete LAN solution. This chapter describes the behavior of the Gigabit Ethernet Controller. For details on the Intel[®] Ethernet Connection I219, refer to Intel[®] Ethernet Connection I219 Datasheet (#544486). The Gigabit Ethernet Controller can operate at multiple speeds (10/100/1000 Mbps) and in either full duplex or half duplex mode.

Acronyms

Acronyms	Description
GbE	Gigabit Ethernet

References

Specification	Location
Alert Standard Format Specification, Version 1.03	http://www.dmtf.org/standards/asf
IEEE 802.3 Fast Ethernet	https://standards.ieee.org/standard/802_3-2018.html
Intel [®] Ethernet Connection I219 Datasheet	http://www.intel.com/content/www/us/en/embedded/ products/networking/ethernet-connection-i219- datasheet.html

19.1 Signal Description

Table 51.GbE LAN Signals

Name	Туре	Description
PCIE7_TXP PCIE7_TXN PCIE8_TXP PCIE8_TXN PCIE9_TXP PCIE9_TXN PCIE13_TXN PCIE13_TXN PCIE14_TXP PCIE14_TXN	0	Refer PCI Express* (PCIe*) on page 164 for details on the PCI Express transmit signals. Note: For PCH-U, the Inte [®] Ethernet Connection I219 can be connected to one of the following PCI Express ports 7, 8, 9, 13 or 14.
PCIE7_RXP PCIE7_RXN PCIE8_RXP PCIE8_RXN PCIE9_RXP PCIE9_RXN PCIE13_RXP PCIE13_RXN	I	Refer PCI Express* (PCIe*) on page 164 for details on the PCI Express transmit signals. Note: For PCH-U, the Intel [®] Ethernet Connection I219 can be connected to one of the following PCI Express ports 7, 8, 9, 13 or 14.
		continued



Name	Туре	Description
SMLODATA/GPP_C4	I/OD	Refer System Management Interface and SMLink on page 220 for details on the SML0DATA signal. <i>Note:</i> The Intel [®] Ethernet Connection I219 connects to SML0DATA signal.
SMLOCLK/GPP_C3	I/OD	Refer System Management Interface and SMLink on page 220 for details on the SML0CLK signal. <i>Note:</i> The Intel [®] Ethernet Connection I219 connects to SML0CLK signal.
LANPHYPC/GPD11	o	 LAN PHY Power Control: LANPHYPC should be connected to LAN_DISABLE_N on the PHY. PCH will drive LANPHYPC low to put the PHY into a low power state when functionality is not needed. Notes: LANPHYPC can only be driven low if SLP_LAN# is de- asserted. Signal can instead be used as GPD11.
SLP_LAN#	0	LAN Sub-System Sleep Control: If the Gigabit Ethernet Controller is enabled, when SLP_LAN# is de-asserted it indicates that the PHY device must be powered. When SLP_LAN# is asserted, power can be shut off to the PHY device. Note: If Gigabit Ethernet Controller is statically disabled via BIOS, SLP_LAN# will be driven low.
LAN_WAKE#/GPD2	I	LAN WAKE: LAN Wake Indicator from the GbE PHY. Note: LAN_WAKE# functionality is only supported with Intel PHY I219. Connection of a third party LAN device's wake signal to LAN_WAKE# is not supported.

19.2 Integrated Pull-Ups and Pull-Downs

Signal	Resistor Type	Value	Notes
LAN_WAKE#/GPD2	External Pull-up required. Internal Pull- down may be enabled in DeepSx	4.7 k ohm 5%	Note: 10 k ohm 5% pull-up resistor is also acceptable

19.3 I/O Signal Planes and States

Table 52.	Power Plane and	States for	Output Signals
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Signal Name	Power Plane	During Reset ³	Immediately after Reset ³	S3/S4/S5	Deep Sx	
LANPHYPC / DSW GPD11		Undriven	Undriven	Undriven ¹	Undriven ¹	
SLP_LAN#	DSW	0/12	0/12	0/12	0/12	
 Notes: 1. Based on wake events and Intel[®] CSME state 2. Configurable based on BIOS settings: '0' When LAN controller is configured as "Disabled" in BIOS, SLP_LAN# will drive "Low"; '1' When LAN controller is configured as "Enabled" in BIOS, SLP_LAN# will drive "High" 3. Reset reference for DSW well pins is DSW_PWROK 						

Table 53.Power Plane and States for Input Signals

Signal Name	Power Plane	During Reset	Immediately after Reset	S3/S4/S5	Deep Sx
LAN_WAKE#/GPD2	AN_WAKE#/GPD2 DSW		Undriven	Undriven	Undriven



19.4 Functional Description

The PCH integrates a Gigabit Ethernet (GbE) controller. The integrated GbE controller is compatible with the Intel[®] Ethernet Connection I219. The integrated GbE controller provides two interfaces for 10/100/1000 Mbps and manageability operation:

- Data link based on PCIe* A high-speed interface that uses PCIe* electrical signaling at half speed and custom logical protocol for active state operation mode.
- System Management Link (SMLink0)—A low speed connection for low power state mode for manageability communication only. The frequency of this connection can be configured to one of three different speeds (100 kHz, 400 kHz or 1 MHz).

The Intel[®] Ethernet Connection I219 only runs at a speed of 1250 Mbps, which is 1/2 of the 2.5 Gb/s PCI Express frequency. Each of the PCIe* root ports in the PCH have the ability to run at the 1250-Mbps rate. There is no need to implement a mechanism to detect that the Platform LAN Device is connected. The port configuration (if any), attached to the Platform LAN Device, is pre-loaded from the NVM. The selected port adjusts the transmitter to run at the 1250 Mbps rate and does not need to be PCIe* compliant.

NOTE

PCIe* validation tools cannot be used for electrical validation of this interface—however, PCIe* layout rules apply for on-board routing.

The integrated GbE controller operates at full-duplex at all supported speeds or halfduplex at 10/100 Mbps. It also adheres to the IEEE 802.3x Flow Control Specification.

NOTE

GbE operation (1000 Mbps) is only supported in S0 mode. In Sx modes, the platform LAN Device may maintain 10/100 Mbps connectivity and use the SMLink interface to communicate with the PCH.

The integrated GbE controller provides a system interface using a PCIe* function. A full memory-mapped or I/O-mapped interface is provided to the software, along with DMA mechanisms for high performance data transfer.

The integrated GbE controller features are:

• Network Features

- Compliant with the 1 Gb/s Ethernet IEEE 802.3, IEEE 802.3u, IEEE 802.3ab specifications
- Multi-speed operation: 10/100/1000 Mbps
- Full-duplex operation at 10/100/1000 Mbps: Half-duplex at 10/100 Mbps
- Flow control support compliant with the 802.3X specification
- VLAN support compliant with the 802.3q specification
- MAC address filters: perfect match unicast filters; multicast hash filtering, broadcast filter and promiscuous mode
- PCIe*/SMLink interface to GbE PHYs
- Host Interface Features



- $-\,$ 64 bit address master support for systems using more than 4 GB of physical memory
- Programmable host memory receive buffers (256 bytes to 16 KB)
- Intelligent interrupt generation features to enhance driver performance
- Descriptor ring management hardware for transmit and receive
- Software controlled reset (resets everything except the configuration space)
- Message Signaled Interrupts
- Performance Features
 - Configurable receive and transmit data FIFO, programmable in 1 KB increments
 - TCP segmentation off loading features
 - Fragmented UDP checksum off load for packet reassembly
 - IPv4 and IPv6 checksum off load support (receive, transmit, and large send)
 - Split header support to eliminate payload copy from user space to host space
 - Receive Side Scaling (RSS) with two hardware receive queues
 - Supports 9018 bytes of jumbo packets
 - Packet buffer size 32 KB
 - TimeSync off load compliant with IEEE 802.1as specification
 - Platform time synchronization
- Power Management Features
 - Magic Packet* wake-up enable with unique MAC address
 - ACPI register set and power down functionality supporting D0 and D3 states
 - Full wake up support (APM, ACPI)
 - MAC power down at Sx, DM-Off with and without WoL
 - Auto connect battery saver at S0 no link and Sx no link
 - Energy Efficient Ethernet (EEE) support
 - Latency Tolerance Reporting (LTR)
 - ARP and ND proxy support through LAN Connected Device proxy
 - Wake on LAN (WoL) from Deep Sx
 - Windows* InstantGo* Support

19.4.1 GbE PCI Express* Bus Interface

The GbE controller has a PCIe* interface to the host processor and host memory. The following sections detail the bus transactions.

Transaction Layer

The upper layer of the host architecture is the transaction layer. The transaction layer connects to the device GbE controller using an implementation specific protocol. Through this GbE controller-to-transaction-layer protocol, the application-specific parts of the device interact with the subsystem and transmit and receive requests to or from the remote agent, respectively.



Data Alignment

• 4 KB Boundary

PCI requests must never specify an address/length combination that causes a memory space access to cross a 4-KB boundary. It is hardware's responsibility to break requests into 4 KB aligned requests (if needed). This does not pose any requirement on software. However, if software allocates a buffer across a 4 KB boundary, hardware issues multiple requests for the buffer. Software should consider aligning buffers to a 4 KB boundary in cases where it improves performance. The alignment to the 4 KB boundaries is done by the GbE controller. The transaction layer does not do any alignment according to these boundaries.

• PCI Request Size

PCI requests are 128 bytes or less and are aligned to make better use of memory controller resources. Writes, however, can be on any boundary and can cross a 64-byte alignment boundary.

Configuration Request Retry Status

The integrated GbE controller might have a delay in initialization due to an NVM read. If the NVM configuration read operation is not completed and the device receives a configuration request, the device responds with a configuration request retry completion status to terminate the request, and thus effectively stalls the configuration request until such time that the sub-system has completed local initialization and is ready to communicate with the host.

19.4.2 Error Events and Error Reporting

Completer Abort Error Handling

A received request that violates the LAN Controller programing model will be discarded, for non posted transactions an unsuccessful completion with CA completion status will be returned. For posted transactions if both SERR# enable and URRE# enable are enabled, the LAN Controller will assert SERR#.

Unsupported Request Error Handling

A received unsupported request to the LAN Controller will be discarded, for non posted transactions an unsuccessful completion with UR completion status will be returned. The URD bit will be set in ECTL register, If both SERR# enable and URRE# enable are enabled, the LAN Controller will assert SERR#. For posted transactions, if both SERR# enable and URRE# enable are enabled, the LAN Controller will assert SERR#.

19.4.3 Ethernet Interface

The integrated GbE controller provides a complete CSMA/CD function supporting IEEE 802.3 (10 Mbps), IEEE 802.3u (100 Mbps) implementations. It also supports the IEEE 802.3z and IEEE 802.3ab (1000 Mbps) implementations. The device performs all of the functions required for transmission, reception, and collision handling called out in the standards.

The mode used to communicate between the PCH and the Intel[®] Ethernet Connection I219 supports 10/100/1000 Mbps operation, with both half- and full-duplex operation at 10/100 Mbps, and full-duplex operation at 1000 Mbps.



Intel[®] Ethernet Connection I219

The integrated GbE controller and the Intel[®] Ethernet Connection I219 communicate through the PCIe* and SMLink0 interfaces. All integrated GbE controller configuration is performed using device control registers mapped into system memory or I/O space. The Platform LAN Phy is configured using the PCI Express or SMLink0 interface.

The integrated GbE controller supports various modes as listed in the tablebelow .

Table 54.LAN Mode Support

Mode	System State	Interface Active	Connections
Normal 10/100/1000 Mbps	S0	PCIe*	Intel [®] Ethernet Connection I219
Manageability and Wake-on-LAN	Sx	SMLink0	Intel [®] Ethernet Connection I219
Wake-on-LAN	Deep Sx	LAN_WAKE#	Intel [®] Ethernet Connection I219

19.4.4 PCI Power Management

The integrated GbE controller supports the Advanced Configuration and Power Interface (ACPI) specification as well as Advanced Power Management (APM). This enables the network-related activity (using an internal host wake signal) to wake up the host. For example, from Sx (S3–S5) and Deep Sx to S0.

NOTE

The Intel[®] Ethernet Connection I219 must be powered during the Deep Sx state in order to support host wake up from Deep Sx. GPD_2_LAN_WAKE# on the PCH must be configured to support wake from Deep Sx and must be connected to LANWAKE_N on the Platform LAN Connect Device. The SLP_LAN# signal must be driven high (deasserted) in the Deep Sx state to maintain power to the Platform LAN Connect Device.

The integrated GbE controller contains power management registers for PCI and supports D0 and D3 states. PCIe* transactions are only allowed in the D0 state, except for host accesses to the integrated GbE controller's PCI configuration registers.

NOTE

SLP_LAN# pin behavior are detailed in SLP_LAN# Pin Behavior.



20.0 Interrupt Interface

The interrupt controllers are used by the OS to dynamically route PCI interrupts to interrupt requests (IRQs).

Acronyms

Acronyms	Description
AEOI	Automatic End Of Interrupt
APIC	Advanced Programmable Interrupt Controller
НРЕТ	High Precision Event Timer
PIC	Programmable Interrupt Controller

20.1 Signal Description

Name	Туре	Description	
GPP_A6/ SERIRQ	I/O	Serial Interrupt Request Note: An external Pull-up is required	
GPP_A7 / PIRQA#	I/OD	PCI Interrupt Request Ax Note: An external Pull-up is required	

20.2 Integrated Pull-Ups and Pull-Downs

None.

20.3 I/O Signal Planes and States

Signal Name	Power Plane	During Reset*	Immediately after Reset*	S3/S4/S5	Deep Sx	
SERIRQ	Primary	Undriven	Undriven	Undriven	OFF	
PIRQA# Primary Undriven Undriven OFF						
Note: *Reset reference for primary well pins is RSMRST#						

20.4 Functional Description

The PCH supports both APIC and PIC modes.

Interrupt sharing from the perspective of the Interrupt Controller that receives the Interrupts is limited to IRQ 0-23.

• Shareable interrupts requires the Interrupt Controller to track the Assert/Deassert Sideband message from each interrupt source. The Interrupt Controller achieves this through Source ID decode of the message.



- Maintains backwards compatibility with the prior generations where only the lower 24 IRQs are available to support Interrupt Sharing.
- Interrupts are dedicated and not shareable from the perspective of the Interrupt Controller for IRQ 24-119. In other words, not more than 1 Interrupt Initiator is allowed to be assigned to the same IRQ# for IRQ 24-119. For example, GPIO (multi-cause Interrupt Initiator) and Intel[®] Serial I/O interfaces (I²C, UART, GSPI) (multi-function Interrupt Initiator) should not both generate Assert/De-assert IRQn that maps to IRQ24.
- Possible multi-cause Interrupt Initiator that maps to IRQ24-119 are GPIO, eSPI, and so on.
- Possible multi-function Interrupt Initiators that maps to IRQ24-119 are HD Audio, I²C/UART/GSPI (Intel Serial I/O Interfaces), ISH, and so on.

Interrupt Sharing Compliance Requirement for the Interrupt Initiator are as follows:

- 1. For multi-cause Initiators (Multiple Interrupt Cause from Single Source and Single Sideband (SB) Port ID, e.g. GPIO, eSPI): If more than 1 interrupt cause has to use the same IRQ#, it has to be aggregated or guaranteed through BIOS/SW to assign a unique IRQ per Interrupt Cause.
- For multi-function devices (1 Interrupt Cause per Source but many Sources are behind Single SB Port ID, e.g. Intel[®] Serial I/O interfaces (I²C, UART, GSPI)): Again if sharing is needed, the interrupts have to be aggregated or guaranteed through SW to ensure a unique IRQ is assigned per Interrupt Cause.
- 3. IPs that have 1:1 mapping to the IRQ# such as eSPI and LPC are not impacted by this requirement. For eSPI, it is expected that the EC devices aggregate the interrupts before these are communicated to eSPI.
- 4. Single-cause or Single-function device behind a unique SB Port ID is not subjected to this requirement.

Only level-triggered interrupts can be shared. PCI interrupts (PIRQs) are inherently shared on the board; these should, therefore, be programmed as level-triggered.

The following tables show the mapping of the various interrupts in Non-APIC and APIC modes.

IRQ#	Pin	SERIRQ	PCI Message	Internal Modules		
0	No	No	No	8254 Counter 0, HPET#0		
1	No	Yes	No	Option for configurable sources including GPIO, eSPI and internal PCI/ACPI devices		
2	No	No	No	8259 #2 cascade only		
3:7	PIRQA	Yes	Yes	Option for configurable sources including PIRQx, GPIO, eSPI and internal PCI/ACPI devices		
8	No	No	No	RTC, HPET#1		
9:10	PIRQA	Yes	Yes	Option for configurable sources including PIRQx, GPIO, eSPI, internal PCI/ACPI devices, SCI and TCO.		
11	PIRQA	Yes	Yes	Option for configurable sources including PIRQx, GPIO, eSPI, internal ACPI devices, SCI, TCO, HPET #2		
	continued					

Table 55. Interrupt Options - 8259 Mode



IRQ#	Pin	SERIRQ	PCI Message	Internal Modules
12	PIRQA	Yes	Yes	Option for configurable sources including PIRQx, GPIO, eSPI, internal ACPI devices, HPET#3
13	No	No	Yes	Option for configurable sources including GPIO, eSPI, internal ACPI devices
14:15	PIRQA	Yes	Yes	Option for configurable sources including PIRQx, GPIO, eSPI and internal ACPI devices

Notes: 1. 8259 Interrupt Request Lines 0, 2 and 8 are non-shareable and dedicated. Only one interrupt source is allowed to use the Interrupt Request Line at any one time.

 If an interrupt is used for PCI IRQ [A:H], SCI, or TCO, it should not be used for ISA-style interrupts (via SERIRQ).

3. In 8259 mode, PCI interrupts are mapped to IRQ3, 4, 5, 6, 7, 9, 10, 11, 12, 14, or 15. It can be programmed via PIRQ[A-H] Routing Control at ITSS Private CR + Offset 3100h-3107h.

IRQ#	Pin	SERIRQ	PCI Message	IRQ Sharable?	Internal Modules
0	No	No	No	No	Cascade from 8259 #1
1	No	Yes	No	Yes	Option for configurable sources including GPIO, eSPI, internal ACPI/PCI devices
2	No	No	No	No	8254 Counter 0, HPET #0 (legacy mode)
3:7	No	Yes	No	Yes	Option for configurable sources including GPIO, eSPI, internal ACPI/PCI devices
8	No	No	No	No	RTC, HPET #1 (legacy mode)
9:10	No	Yes	No	Yes	Option for configurable sources including GPIO, eSPI, internal ACPI/PCI devices, SC and TCO
11	No	Yes	No	Yes	Option for configurable sources including GPIO, eSPI, internal ACPI/PCI devices, SC TCO, HPET #2
12	No	Yes	No	Yes	Option for configurable sources including GPIO, eSPI, internal ACPI/PCI devices, HPET#3
13	No	No	No	Yes	Option for configurable sources including GPIO, eSPI and internal ACPI/PCI devices
14:15	No	Yes	No	Yes	Option for configurable sources including GPIO, eSPI and internal ACPI/PCI devices
16	PIRQA	PIRQA	Yes	Yes	Option for configurable sources including internal PIRQA, GPIO, eSPI and internal ACPI/PCI devices
17:19	No	PIRQ[B-D]	Yes	Yes	Option for configurable sources including internal PIRQ[B-D], GPIO, eSPI and internal ACPI/PCI devices
	I	I	1	1	continued.

Table 56.Interrupt Options - APIC Mode



IRQ#	Pin	SERIRQ	PCI Message	IRQ Sharable?	Internal Modules
20:23	No	No	No	Yes	Option for configurable sources including internal PIRQ[E-H], GPIO, eSPI, SCI, TCO, internal ACPI/PCI devices and HPET
24:119	No	No	No	No	Option for configurable sources including GPIO, eSPI and internal ACPI/PCI devices

Notes: 1. Interrupts 24 through 119 are dedicated and not shareable from the perspective of the Interrupt Controller. Not more than 1 Interrupt source is allowed to be assigned to the same IRQ#. For example, GPIO and Intel[®] Serial I/O interfaces (I²C, UART, GSPI) should not generate Assert/Deassert_IRQn that maps to IRQ24. Although dedicated, Interrupts 24 through 119 can be configured to be level or edge-triggered.

3. In APIC mode, the PCI interrupts [A:H] are directly mapped to IRQ[16:23].

4. When programming the polarity of internal interrupt sources on the APIC, interrupts 0 through 15, and 24 through 119 receive active-high internal interrupt sources; interrupts 16 through 23 receive active-low internal interrupt sources.

5. The internal ACPI/PCI devices refer to PCI/PCIe devices configured to the ACPI or PCI function mode. If in ACPI function mode, the device interrupt is map directly to one of the available IRQ. If in PCI function mode, the device interrupt is map to INT[A-D] and then to the IRQ before these devices issue the Interrupt Message using Assert/Deassert_IRQn.

PCI Message refers to the downstream Assert/Deassert_INT[A-D] messages forwarded from the processor complex.

Table 57.Interrupt Logic Signals

Signal Name	С3	S3	S5
SERIRQ	Can be running	OFF	OFF
PIRQA#	Can go active	OFF	OFF

20.4.1 8259 Interrupt Controllers (PIC)

The ISA-compatible interrupt controller (PIC) incorporates the functionality of two 8259 interrupt controllers. The following table shows how the cores are connected.

Table 58.Interrupt Controllers PIC

8259	8259 Input	Typical Interrupt Source	Connected Pin/Function		
	0	Internal	Internal Timer/Counter 0 output or Multimedia Timer #0		
	1	Keyboard	IRQ1 via SERIRQ. Option for configurable sources including eSPI, GPIO, internal ACPI devices.		
	2	Internal	Slave Controller INTR output		
	3	Serial Port A	IRQ3 from configurable sources including PIRQx, SERIRQ, eSPI, GPIO, internal ACPI devices.		
Master	4	Serial Port B	IRQ4 from configurable sources including PIRQx, SERIRQ, eSPI, GPIO, internal ACPI devices.		
	5	Parallel Port/Generic	IRQ5 from configurable sources including PIRQx, SERIRQ, eSPI, GPIO, internal ACPI devices.		
	6	Floppy Disk	IRQ6 from configurable sources including PIRQx, SERIRQ, eSPI, GPIO, internal ACPI devices.		
	7	Parallel Port/Generic	IRQ7 from configurable sources including PIRQx, SERIRQ, eSPI, GPIO, internal ACPI devices.		
continued					

If an interrupt is used for PCI IRQ [A:H], SCI, or TCO, it should not be used for ISA-style interrupts (via SERIRQ).



8259	8259 Input	Typical Interrupt Source	Connected Pin/Function	
Slave	0	Real Time Clock	Inverted IRQ8# from internal RTC or Multimedia Timer #1	
	1	Generic	IRQ9 from configurable sources including PIRQx, SERIRQ, eSPI, GPIO, internal ACPI devices, SCI, TCO.	
	2	Generic	IRQ10 from configurable sources including PIRQx, SERIRQ, eSPI, GPIO, internal ACPI devices, SCI, TCO.	
	3	Generic	IRQ11 from configurable sources including PIRQx, SERIRQ, eSPI, GPIO, internal ACPI devices, SCI, TCO or HPET #2.	
	4	PS/2 Mouse	IRQ12 from configurable sources including PIRQx, SERIRQ, eSPI, GPIO, internal ACPI devices, SCI, TCO or HPET #3.	
	5	Internal	IRQ13 from configurable sources including PIRQx, eSPI, GPIO, internal ACPI devices.	
	6	Internal	IRQ14 from configurable sources including PIRQx, SERIRQ, eSPI, GPIO, internal ACPI devices.	
	7	Internal	IRQ15 from configurable sources including PIRQx, SERIRQ, eSPI, GPIO, internal ACPI devices.	

The slave controller is cascaded onto the master controller through master controller interrupt input 2. This means there are only 15 possible interrupts for PCH PIC.

Interrupts can individually be programmed to be edge or level triggered, except for IRQ0, IRQ1, IRQ2 and IRQ8# which always default to edge.

Active-low interrupt sources, such as the PIRQ#s, are internally inverted before being sent to the PIC. In the following descriptions of the 8259s, the interrupt levels are in reference to the signals at the internal interface of the 8259s, after the required inversions have occurred. Therefore, the term "high" indicates "active", which means "low" on an originating PIRQ#.

20.4.2 Interrupt Handling

Generating Interrupts

The PIC interrupt sequence involves three bits, from the IRR, ISR, and IMR, for each interrupt level. These bits are used to determine the interrupt vector returned, and status of any other pending interrupts. The table below defines the IRR, ISR, and IMR.

Bit	Description		
IRR	Interrupt Request Register. This bit is set on a low to high transition of the interrupt line in edge mode, and by an active high level in level mode. This bit is set whether or not the interrupt is masked. However, a masked interrupt will not generate INTR.		
ISR	Interrupt Service Register. This bit is set, and the corresponding IRR bit cleared, when an interrupt acknowledge cycle is seen, and the vector returned is for that interrupt.		
IMR	Interrupt Mask Register. This bit determines whether an interrupt is masked. Masked interrupts will not generate INTR.		

Table 59.Interrupt Status Registers



Acknowledging Interrupts

The processor generates an interrupt acknowledge cycle that is translated by the host bridge into a PCI Interrupt Acknowledge Cycle to the PCH. The PIC translates this command into two internal INTA# pulses expected by the 8259 cores. The PIC uses the first internal INTA# pulse to freeze the state of the interrupts for priority resolution. On the second INTA# pulse, the master or slave sends the interrupt vector to the processor with the acknowledged interrupt code. This code is based on Bits [7:3] of the corresponding ICW2 register, combined with three bits representing the interrupt within that controller.

Table 60. Content of Interrupt Vector Byte

Master, Slave Interrupt	Bits [7:3]	Bits [2:0]
IRQ7,15	ICW2[7:3]	111
IRQ6,14		110
IRQ5,13		101
IRQ4,12		100
IRQ3,11		011
IRQ2,10		010
IRQ1,9		001
IRQ0,8		000

Hardware/Software Interrupt Sequence

- 1. One or more of the Interrupt Request lines (IRQ) are raised high in edge mode, or seen high in level mode, setting the corresponding IRR bit.
- 2. The PIC sends INTR active to the processor if an asserted interrupt is not masked.
- 3. The processor acknowledges the INTR and responds with an interrupt acknowledge cycle. The cycle is translated into a PCI interrupt acknowledge cycle by the host bridge. This command is broadcast over PCI by the PCH.
- 4. Upon observing its own interrupt acknowledge cycle on PCI, the PCH converts it into the two cycles that the internal 8259 pair can respond to. Each cycle appears as an interrupt acknowledge pulse on the internal INTA# pin of the cascaded interrupt controllers.
- 5. Upon receiving the first internally generated INTA# pulse, the highest priority ISR bit is set and the corresponding IRR bit is reset. On the trailing edge of the first pulse, a slave identification code is broadcast by the master to the slave on a private, internal three bit wide bus. The slave controller uses these bits to determine if it must respond with an interrupt vector during the second INTA# pulse.
- 6. Upon receiving the second internally generated INTA# pulse, the PIC returns the interrupt vector. If no interrupt request is present because the request was too short in duration, the PIC returns vector 7 from the master controller.
- 7. This completes the interrupt cycle. In AEOI mode the ISR bit is reset at the end of the second INTA# pulse. Otherwise, the ISR bit remains set until an appropriate EOI command is issued at the end of the interrupt subroutine



20.4.3 Initialization Command Words (ICWx)

Before operation can begin, each 8259 must be initialized. In the PCH, this is a four byte sequence. The four initialization command words are referred to by their acronyms: ICW1, ICW2, ICW3, and ICW4.

The base address for each 8259 initialization command word is a fixed location in the I/O memory space: 20h for the master controller, and A0h for the slave controller.

ICW1

An I/O write to the master or slave controller base address with data bit 4 equal to 1 is interpreted as a write to ICW1. Upon sensing this write, the PCH's PIC expects three more byte writes to 21h for the master controller, or A1h for the slave controller, to complete the ICW sequence.

A write to ICW1 starts the initialization sequence during which the following automatically occur:

- 1. Following initialization, an interrupt request (IRQ) input must make a low-to-high transition to generate an interrupt.
- 2. The Interrupt Mask Register is cleared.
- 3. IRQ7 input is assigned priority 7.
- 4. The slave mode address is set to 7.
- 5. Special mask mode is cleared and Status Read is set to IRR.

ICW2

The second write in the sequence (ICW2) is programmed to provide bits [7:3] of the interrupt vector that will be released during an interrupt acknowledge. A different base is selected for each interrupt controller.

ICW3

The third write in the sequence (ICW3) has a different meaning for each controller.

- For the master controller, ICW3 is used to indicate which IRQ input line is used to cascade the slave controller. Within the PCH, IRQ2 is used. Therefore, Bit 2 of ICW3 on the master controller is set to a 1, and the other bits are set to 0s.
- For the slave controller, ICW3 is the slave identification code used during an interrupt acknowledge cycle. On interrupt acknowledge cycles, the master controller broadcasts a code to the slave controller if the cascaded interrupt won arbitration on the master controller. The slave controller compares this identification code to the value stored in its ICW3, and if it matches, the slave controller assumes responsibility for broadcasting the interrupt vector.

ICW4

The final write in the sequence (ICW4) must be programmed for both controllers. At the very least, Bit 0 must be set to a 1 to indicate that the controllers are operating in an Intel Architecture-based system.



20.4.4 Operation Command Words (OCW)

These command words reprogram the interrupt controller to operate in various interrupt modes.

- OCW1 masks and unmasks interrupt lines.
- OCW2 controls the rotation of interrupt priorities when in rotating priority mode, and controls the EOI function.
- OCW3 sets up ISR/IRR reads, enables/disables the special mask mode (SMM), and enables/disables polled interrupt mode.

20.4.5 Modes of Operation

Fully-Nested Mode

In this mode, interrupt requests are ordered in priority from 0 through 7, with 0 being the highest. When an interrupt is acknowledged, the highest priority request is determined and its vector placed on the bus. Additionally, the ISR for the interrupt is set. This ISR bit remains set until: the processor issues an EOI command immediately before returning from the service routine; or if in AEOI mode, on the trailing edge of the second INTA#. While the ISR bit is set, all further interrupts of the same or lower priority are inhibited, while higher levels generate another interrupt. Interrupt priorities can be changed in the rotating priority mode.

Special Fully-Nested Mode

This mode is used in the case of a system where cascading is used, and the priority has to be conserved within each slave. In this case, the special fully-nested mode is programmed to the master controller. This mode is similar to the fully-nested mode with the following exceptions:

- When an interrupt request from a certain slave is in service, this slave is not locked out from the master's priority logic and further interrupt requests from higher priority interrupts within the slave are recognized by the master and initiate interrupts to the processor. In the normal-nested mode, a slave is masked out when its request is in service.
- When exiting the Interrupt Service Routine, software has to check whether the interrupt serviced was the only one from that slave. This is done by sending a Non-Specific EOI command to the slave and then reading its ISR. If it is 0, a Non-Specific EOI can also be sent to the master.

Automatic Rotation Mode (Equal Priority Devices)

In some applications, there are a number of interrupting devices of equal priority. Automatic rotation mode provides for a sequential 8-way rotation. In this mode, a device receives the lowest priority after being serviced. In the worst case, a device requesting an interrupt has to wait until each of seven other devices are serviced at most once.

There are two ways to accomplish automatic rotation using OCW2: the Rotation on Non-Specific EOI Command (R=1, SL=0, EOI=1) and the rotate in automatic EOI mode which is set by (R=1, SL=0, EOI=0).



Specific Rotation Mode (Specific Priority)

Software can change interrupt priorities by programming the bottom priority. For example, if IRQ5 is programmed as the bottom priority device, then IRQ6 is the highest priority device. The Set Priority Command is issued in OCW2 to accomplish this, where: R=1, SL=1, and LO-L2 is the binary priority level code of the bottom priority device.

In this mode, internal status is updated by software control during OCW2. However, it is independent of the EOI command. Priority changes can be executed during an EOI command by using the Rotate on Specific EOI Command in OCW2 (R=1, SL=1, EOI=1 and LO-L2=IRQ level to receive bottom priority.

Poll Mode

Poll mode can be used to conserve space in the interrupt vector table. Multiple interrupts that can be serviced by one Interrupt Service Routine do not need separate vectors if the service routine uses the poll command. Poll mode can also be used to expand the number of interrupts. The polling Interrupt Service Routine can call the appropriate service routine, instead of providing the interrupt vectors in the vector table. In this mode, the INTR output is not used and the microprocessor internal Interrupt Enable flip-flop is reset, disabling its interrupt input. Service to devices is achieved by software using a Poll command.

The Poll command is issued by setting P=1 in OCW3. The PIC treats its next I/O read as an interrupt acknowledge, sets the appropriate ISR bit if there is a request, and reads the priority level. Interrupts are frozen from the OCW3 write to the I/O read. The byte returned during the I/O read contains a 1 in Bit 7 if there is an interrupt, and the binary code of the highest priority level in Bits 2:0.

Edge and Level Triggered Mode

In ISA systems this mode is programmed using Bit 3 in ICW1, which sets level or edge for the entire controller. In the PCH, this bit is disabled and a register for edge and level triggered mode selection, per interrupt input, is included. This is the Edge/Level control Registers ELCR1 and ELCR2.

If an ELCR bit is 0, an interrupt request will be recognized by a low-to-high transition on the corresponding IRQ input. The IRQ input can remain high without generating another interrupt. If an ELCR bit is 1, an interrupt request will be recognized by a high level on the corresponding IRQ input and there is no need for an edge detection. The interrupt request must be removed before the EOI command is issued to prevent a second interrupt from occurring.

In both the edge and level triggered modes, the IRQ inputs must remain active until after the falling edge of the first internal INTA#. If the IRQ input goes inactive before this time, a default IRQ7 vector is returned.

End Of Interrupt (EOI) Operations

An EOI can occur in one of two fashions: by a command word write issued to the PIC before returning from a service routine, the EOI command; or automatically when AEOI bit in ICW4 is set to 1.



Normal End of Interrupt

In normal EOI, software writes an EOI command before leaving the Interrupt Service Routine to mark the interrupt as completed. There are two forms of EOI commands: Specific and Non-Specific. When a Non-Specific EOI command is issued, the PIC clears the highest ISR bit of those that are set to 1. Non-Specific EOI is the normal mode of operation of the PIC within the PCH, as the interrupt being serviced currently is the interrupt entered with the interrupt acknowledge. When the PIC is operated in modes that preserve the fully nested structure, software can determine which ISR bit to clear by issuing a Specific EOI. An ISR bit that is masked is not cleared by a Non-Specific EOI if the PIC is in the special mask mode. An EOI command must be issued for both the master and slave controller.

Automatic End of Interrupt Mode

In this mode, the PIC automatically performs a Non-Specific EOI operation at the trailing edge of the last interrupt acknowledge pulse. From a system standpoint, this mode should be used only when a nested multi-level interrupt structure is not required within a single PIC. The AEOI mode can only be used in the master controller and not the slave controller.

20.4.6 Masking Interrupts

Masking on an Individual Interrupt Request

Each interrupt request can be masked individually by the Interrupt Mask Register (IMR). This register is programmed through OCW1. Each bit in the IMR masks one interrupt channel. Masking IRQ2 on the master controller masks all requests for service from the slave controller.

Special Mask Mode

Some applications may require an Interrupt Service Routine to dynamically alter the system priority structure during its execution under software control. For example, the routine may wish to inhibit lower priority requests for a portion of its execution but enable some of them for another portion.

The special mask mode enables all interrupts not masked by a bit set in the Mask Register. Normally, when an Interrupt Service Routine acknowledges an interrupt without issuing an EOI to clear the ISR bit, the interrupt controller inhibits all lower priority requests. In the special mask mode, any interrupts may be selectively enabled by loading the Mask Register with the appropriate pattern. The special Mask Mode is set by OCW3.SSMM and OCW3.SMM set, and cleared when OCW3.SSMM and OCW3.SMM are cleared.

20.4.7 Steering PCI Interrupts

The PCH can be programmed to allow PIRQ[A:D]# to be internally routed to interrupts 3-7, 9-12, 14 or 15, through the PARC, PBRC, PCRC, PDRC, PERC, PFRC, PGRC, and PHRC registers in the chipset configuration section. One or more PIRQx# lines can be routed to the same IRQx input.



The PIRQx# lines are defined as active low, level sensitive. When PIRQx# is routed to specified IRQ line, software must change the corresponding ELCR1 or ELCR2 register to level sensitive mode. The PCH will internally invert the PIRQx# line to send an active high level to the PIC. When a PCI interrupt is routed onto the PIC, the selected IRQ can no longer be used by an ISA device.

20.5 Advanced Programmable Interrupt Controller (APIC) (D31:F0)

In addition to the standard ISA-compatible PIC described in the previous section, the PCH incorporates the APIC. While the standard interrupt controller is intended for use in a uni-processor system, APIC can be used in either a uni-processor or multi-processor system.

20.5.1 Interrupt Handling

The I/O APIC handles interrupts very differently than the 8259. Briefly, these differences are:

- **Method of Interrupt Transmission.** The I/O APIC transmits interrupts through memory writes on the normal data path to the processor, and interrupts are handled without the need for the processor to run an interrupt acknowledge cycle.
- **Interrupt Priority.** The priority of interrupts in the I/O APIC is independent of the interrupt number. For example, interrupt 10 can be given a higher priority than interrupt 3.
- More Interrupts. The I/O APIC in the PCH supports a total of 24 interrupts.
- **Multiple Interrupt Controllers.** The I/O APIC architecture allows for multiple I/O APIC devices in the system with their own interrupt vectors.

20.5.2 Interrupt Mapping

The I/O APIC within the PCH supports 40 APIC interrupts. Each interrupt has its own unique vector assigned by software.

20.5.3 PCI/PCI Express* Message-Based Interrupts

When external devices through PCI/PCI Express* wish to generate an interrupt, they will send the message defined in the *PCI Express** *Base Specification* for generating INTA# – INTD#. These will be translated internal assertions/de-assertions of INTA# – INTD#.

20.5.4 IOxAPIC Address Remapping

To support Intel[®] Virtualization Technology (Intel[®] VT), interrupt messages are required to go through similar address remapping as any other memory request. Address remapping allows for domain isolation for interrupts, so a device assigned in one domain is not allowed to generate an interrupt to another domain.

The address remapping is based on the Bus: Device: Function field associated with the requests. The internal APIC is required to initiate the interrupt message using a unique Bus: Device: Function.



The PCH allows BIOS to program the unique Bus: Device: Function address for the internal APIC. This address field does not change the APIC functionality and the APIC is not promoted as a stand-alone PCI device. Refer Device 31: Function 0 Offset 6Ch for additional information.

20.5.5 External Interrupt Controller Support

The PCH supports external APICs off of PCI Express ports but does not support APICs on the PCI bus. The EOI special cycle is only forwarded to PCI Express* ports.

20.6 Serial Interrupt

The PCH supports a serial IRQ scheme. This allows a single signal to be used to report interrupt requests. The signal used to transmit this information is shared between the PCH and all participating peripherals. The signal line, SERIRQ, is synchronous to 24 MHz CLKOUT_LPC, and follows the sustained tri-state protocol that is used by all PCI signals. This means that if a device has driven SERIRQ low, it will first drive it high synchronous to PCI clock and release it the following PCI clock. The serial IRQ protocol defines this sustained tri-state signaling in the following fashion:

- S Sample Phase, Signal driven low
- R Recovery Phase, Signal driven high
- T Turn-around Phase, Signal released

The PCH supports a message for 21 serial interrupts. These represent the 15 ISA interrupts (IRQ0-1, 3-15), the four PCI interrupts, and the control signals SMI# and IOCHK#. The serial IRQ protocol does not support the additional APIC interrupts (20–23).

NOTE

IRQ14 and IRQ15 are special interrupts and maybe used by the GPIO controller when it is running GPIO driver mode. When the GPIO controller operates in GPIO driver mode, IRQ14 and IRQ15 shall not be utilized by the SERIRQ stream nor mapped to other interrupt sources, and instead come from the GPIO controller. If the GPIO controller is entirely in ACPI mode, these interrupts can be mapped to other devices accordingly.

20.6.1 Start Frame

The serial IRQ protocol has two modes of operation which affect the start frame. These two modes are: Continuous, where the PCH is solely responsible for generating the start frame; and Quiet, where a serial IRQ peripheral is responsible for beginning the start frame.

The mode that must first be entered when enabling the serial IRQ protocol is continuous mode. In this mode, the PCH asserts the start frame. This start frame is 4, 6, or 8 PCI clocks wide based upon the Serial IRQ Control Register, bits 1:0 at 64h in D31:F0 configuration space. This is a polling mode.

When the serial IRQ stream enters quiet mode (signaled in the Stop Frame), the SERIRQ line remains inactive and pulled up between the Stop and Start Frame until a peripheral drives the SERIRQ signal low. The PCH senses the line low and continues to drive it low for the remainder of the Start Frame. Since the first PCI clock of the start



frame was driven by the peripheral in this mode, the PCH drives the SERIRQ line low for 1 PCI clock less than in continuous mode. This mode of operation allows for a quiet, and therefore lower power, operation. Data Frames.

Once the Start frame has been initiated, all of the SERIRQ peripherals must start counting frames based on the rising edge of SERIRQ. Each of the IRQ/DATA frames has exactly 3 phases of 1 clock each:

- **Sample Phase**—During this phase, the SERIRQ device drives SERIRQ low if the corresponding interrupt signal is low. If the corresponding interrupt is high, then the SERIRQ devices tri-state the SERIRQ signal. The SERIRQ line remains high due to Pull-up resistors (there is no internal Pull-up resistor on this signal, an external Pull-up resistor is required). A low level during the IRQ0-1 and IRQ2-15 frames indicates that an active-high ISA interrupt is not being requested, but a low level during the PCI INT[A:D], SMI#, and IOCHK# frame indicates that an active-low interrupt is being requested.
- **Recovery Phase**—During this phase, the device drives the SERIRQ line high if in the Sample Phase it was driven low. If it was not driven in the sample phase, it is tri-stated in this phase.
- **Turn-around Phase**—The device tri-states the SERIRQ line.

20.6.2 Stop Frame

After all data frames, a Stop Frame is driven by the PCH. The SERIRQ signal is driven low by the PCH for 2 or 3 PCI clocks. The number of clocks is determined by the SERIRQ configuration register. The number of clocks determines the next mode.

Table 61.Stop Frame Explanation

Stop Frame Width	Next Mode
2 PCI clocks	Quiet Mode. Any SERIRQ device may initiate a Start Frame
3 PCI clocks	Continuous Mode. Only the host (the PCH) may initiate a Start Frame

20.6.3 Specific Interrupts Not Supported Using SERIRQ

There are three interrupts seen through the serial stream that are not supported by the PCH. These interrupts are generated internally, and are not sharable with other devices within the system. These interrupts are:

- IRQ0. Heartbeat interrupt generated off of the internal 8254 counter 0.
- IRQ8#. RTC interrupt can only be generated internally.
- IRQ13. Reserved internally.

The PCH ignores the state of these interrupts in the serial stream, and does not adjust their level based on the level seen in the serial stream. Data Frame Format.

The following table shows the format of the data frames. For the PCI interrupts (A–D), the output from the PCH is AND'd with the PCI input signal. This way, the interrupt can be signaled using both the PCI interrupt input signal and using the SERIRQ signal (they are shared).



Table 62.Data Frame Format

Data Frame #	Interrupt	Clocks Past Start Frame	Comment
1	IRQ0	2	Ignored. IRQ0 can only be generated using the internal 8524
2	IRQ1	5	Before port 60h latch
3	SMI#	8	Causes SMI# if low. Will set the SERIRQ_SMI_STS bit.
4	IRQ3	11	
5	IRQ4	14	
6	IRQ5	17	
7	IRQ6	20	
8	IRQ7	23	
9	IRQ8	26	Ignored. IRQ8# can only be generated internally.
10	IRQ9	29	
11	IRQ10	32	
12	IRQ11	35	
13	IRQ12	38	Before port 60h latch
14	IRQ13	41	Ignored.
15	IRQ14	44	Not attached to GPIO logic
16	IRQ15	47	Not attached to GPIO logic
17	IOCHCK#	50	Same as ISA IOCHCK# going active
18	PCI INTA#	53	Drive PIRQA#
19	PCI INTB#	56	Drive PIRQB#
20	PCI INTC#	59	Drive PIRQC#
21	PCI INTD#	62	Drive PIRQD#



21.0 Integrated Sensor Hub (ISH)

The Integrated Sensor Hub (ISH) serves as the connection point for many of the sensors on a platform. The ISH is designed with the goal of 'Always On, Always Sensing' and it provides the following functions to support this goal:

- Acquisition/sampling of sensor data.
- The ability to combine data from individual sensors to create a more complex virtual sensor that can be directly used by the firmware/OS.
- Low power operation through clock and power gating of the ISH blocks together with the ability to manage the power state of the external sensors.
- The ability to operate independently when the host platform is in a low power state (S0ix only).
- Ability to provide sensor-related data to other subsystems within the PCH, such as the ${\rm Intel}^{\scriptscriptstyle (\! B\!)}$ CSME.

The ISH consists of the following key components:

- A combined cache for instructions and data
 - ROM space intended for the bootloader
 - SRAM space for code and data
- Interfaces to sensor peripherals (I²C, UART, SPI, GPIO)
- An interface to main memory
- Out of Band signals for clock and wake-up control
- Inter Process Communications to the Host and Intel[®] CSME
- Part of the PCI tree on the host

Acronyms

Acronyms	Description
Intel [®] CSME	Intel [®] Converged Security and Management Engine
I ² C	Inter-Integrated Circuit
IPC	Inter Process Communication
SPI	Serial Peripheral Interface
ISH	Integrated Sensor Hub
PMU	Power Management Unit
SRAM	Static Random Access Memory
UART	Universal Asynchronous Receiver/Transmitter



References

Specification	Location
I ² C Specification Version 6.0	http://www.nxp.com/docs/en/user-guide/UM10204.pdf

21.1 Signal Description

Name	Туре	Description
ISH_I2C0_SDA/ GPP_D5	I/OD	ISH I ² C 0 Data
ISH_I2C0_SCL/ GPP_D6	I/OD	ISH I ² C 0 Clk
ISH_I2C1_SDA/ GPP_D7	I/OD	ISH I ² C 1 Data
ISH_I2C1_SCL/ GPP_D8	I/OD	ISH I ² C 1 Clk
ISH_I2C2_SDA / GPP_H10 / I2C5_SDA	I/OD	ISH I ² C 2 Data
ISH_I2C2_SCL / GPP_H11 / I2C5_SCL	I/OD	ISH I ² C 2 Clk
ISH_GP0/GPP_A18	I/O	ISH GPIO 0
ISH_GP1/GPP_A19	I/O	ISH GPIO 1
ISH_GP2/GPP_A20	I/O	ISH GPIO 2
ISH_GP3/GPP_A21	I/O	ISH GPIO 3
ISH_GP4/GPP_A22	I/O	ISH GPIO 4
ISH_GP5/GPP_A23	I/O	ISH GPIO 5
ISH_GP6 / GPP_A12 / BM_BUSY# / SX_EXIT_HOLDOFF#	I/O	ISH GPIO 6
ISH_GP7/ GPP_A17 / SD_VDD1_PWR_EN#	I/O	ISH GPIO 7
ISH_UARTO_TXD / GPP_D14 / SML0BCLK / I2C4B_SCL	0	ISH UART 0 Transmit Data
ISH_UARTO_RXD /GPP_D13 / SML0BDATA / I2C4B_SDA	I	ISH UART 0 Receive Data
ISH_UARTO_RTS# /GPP_D15 / GSPI2_CS1#	0	ISH UART 0 Request To Send
ISH_UARTO_CTS# /GPP_D16 / SML0BALERT#	I	ISH UART 0 Clear to Send
ISH_UART1_TXD /GPP_C13 / UART1_TXD	0	ISH UART 1 Transmit Data
ISH_UART1_RXD /GPP_C12 / UART1_RXD	I	ISH UART 1 Receive Data
ISH_UART1_RTS# /GPP_C14 / UART1_RTS#	0	ISH UART 1 Request To Send
ISH_UART1_CTS# / GPP_C15 / UART1_CTS#	H_UART1_CTS# / GPP_C15 / UART1_CTS# I ISH UART 1 Clear to Send	
ISH_SPI_CS# / GPP_D9 / GSPI2_CS0#	0	ISH SPI 2 Chip Select
	1	continued



Name	Туре	Description
ISH_SPI_CLK / GPP_D10 / GSPI2_CLK	0	ISH SPI 2 Clock
ISH_SPI_MISO / GPP_D11 / GSPI2_MISO	Ι	ISH SPI 2 MISO
ISH_SPI_MOSI / GPP_D12 / GSPI2_MOSI	0	ISH SPI 2 MOSI

21.2 Integrated Pull-Ups and Pull-Downs

Signal	Resistor Type	Value	Notes
ISH_SPI_MISO	Pull-Down	20 kohm ± 30%	

21.3 I/O Signal Planes and States

Signal Name	Power Plane	During Reset*	Immediately after Reset*	S3/S4/S5	Deep Sx
ISH_I2C0_SDA	Primary	Undriven	Undriven	Undriven	OFF
ISH_12C0_SCL	Primary	Undriven	Undriven	Undriven	OFF
ISH_I2C1_SDA	Primary	Undriven	Undriven	Undriven	OFF
ISH_I2C1_SCL	Primary	Undriven	Undriven	Undriven	OFF
ISH_I2C2_SDA	Primary	Undriven	Undriven	Undriven	OFF
ISH_I2C2_SCL	Primary	Undriven	Undriven	Undriven	OFF
ISH_GP[7:0]	Primary	Undriven	Undriven	Undriven	OFF
ISH_UART0_TXD	Primary	Undriven	Undriven	Undriven	OFF
ISH_UART0_RXD	Primary	Undriven	Undriven	Undriven	OFF
ISH_UART0_RTS#	Primary	Undriven	Undriven	Undriven	OFF
ISH_UART0_CTS#	Primary	Undriven	Undriven	Undriven	OFF
ISH_UART1_TXD	Primary	Undriven	Undriven	Undriven	OFF
ISH_UART1_RXD	Primary	Undriven	Undriven	Undriven	OFF
ISH_UART1_RTS#	Primary	Undriven	Undriven	Undriven	OFF
ISH_UART1_CTS#	Primary	Undriven	Undriven	Undriven	OFF
ISH_SPI_CS#	Primary	Undriven	Undriven	Undriven	OFF
ISH_SPI_CLK	Primary	Undriven	Undriven	Undriven	OFF
ISH_SPI_MISO	Primary	Undriven	Undriven	Undriven	OFF
ISH_SPI_MOSI	Primary	Undriven	Undriven	Undriven	OFF
Note: *Reset reference for primary well pins is RSMRST#, DSW well pins is DSW_PWROK, and RTC well pins is RTCRST#.					

21.4 Functional Description

This topic has the following sections:

- ISH Micro-Controller
- SRAM



- PCI Host Interface
- Power Domains and Management
- ISH IPC
- ISH Interrupt Handling via IOAPIC (Interrupt Controller)
- ISH I²C Controllers
- ISH UART Controller
- ISH GSPI Controller
- ISH GPIOs

21.4.1 ISH Micro-Controller

The ISH is operated by a micro-controller. This core provides localized sensor aggregation and data processing, thus off loading the processor and lowering overall platform average power. The core supports an in-built local APIC that receives messages from the IOAPIC. A local boot ROM with FW for initialization is also part of the core.

21.4.2 SRAM

The local SRAM is used for ISH FW code storage and to read/write operational data. The local SRAM block includes both the physical SRAM as well as the controller logic. The SRAM is a total of 640 kbytes organized into banks of 32 kB each and is 32-bit wide. The SRAM is shared with Intel[®] CSME as shareable memory. To protect against memory errors, the SRAM includes ECC support. The ECC mechanism is able to detect multi-bit errors and correct for single bit errors. The ISH firmware has the ability to put unused SRAM banks into lower power states to reduce power consumption.

21.4.3 PCI Host Interface

The ISH provides access to PCI configuration space via a PCI Bridge. Type 0 Configuration Cycles from the host are directed to the PCI configuration space.

MMIO Space

A memory-mapped Base Address Register (BAR0) with a set of functional memorymapped registers is accessible to the host via the Bridge. These registers are owned by the driver running on the Host OS.

The bridge also supports a second BAR (BAR1) that is an alias of the PCI Con figuration space. It is used only in ACPI mode (that is, when the PCI configuration space is hidden).

DMA Controller

The DMA controller supports up to 64-bit addressing.

PCI Interrupts

The PCI bridge supports standard PCI interrupts, delivered using IRQx to the system IOAPIC and not using an MSI to the host CPU.



PCI Power Management

PME is not supported in ISH.

21.4.4 Power Domains and Management

ISH Power Management

The various functional blocks within the ISH are all on the primary power plane within the PCH. The ISH is only intended for use during S0 and S0ix states. There is no support for operation in S3, S4, or S5 states. Thus, the system designer must ensure that the inputs to the ISH signals are not driven high while the PCH is in S3–S5 state.

The unused banks of the ISH SRAM can be power-gated by the ISH Firmware.

External Sensor Power Management

External sensors can generally be put into a low power state through commands issued over the I/O interface (I^2C). Refer to the datasheets of the individual sensors to obtain the commands to be sent to the peripheral.

21.4.5 ISH IPC

The ISH has IPC channels for communication with the Host Processor and Intel[®] CSME. The functions supported by the ISH IPC block are listed below.

Function 1:Allows for messages and interrupts to be sent from an initiator (such as the ISH) and a target (such as the Intel[®] CSME). The supported initiator -> target flows using this mechanism are shown in the table below.

Table 63.IPC Initiator -> Target Flows

Initiator	Target
ISH	Host processor
Host processor	ISH
ISH	Intel [®] CSME
Intel [®] CSME	ISH

Function 2: Provides status registers and remap registers that assist in the boot flow and debug. These are simple registers with dual access read/write support and cause no interrupts.

21.4.6 ISH Interrupt Handling via IOAPIC (Interrupt Controller)

The PCH legacy IOAPIC is the interrupt controller for the ISH. It collects inputs from various internal blocks and sends interrupt messages to the ISH controller. When there is a change on one of its inputs, the IOAPIC sends an interrupt message to the ISH controller.

The PCH IOAPIC allows each interrupt input to be active high or active low and edge or level triggered.



21.4.7 ISH I²C Controllers

The ISH supports three I^2C controllers capable of operating at speeds up to 2.4 Mbps each. The I^2C controllers are completely independent of each other: they do not share any pins, memory spaces, or interrupts.

The ISH's I²C host controllers share the same general specifications:

- Master Mode Only (all peripherals must be slave devices)
- Support for the following operating speeds:
 - Standard mode: 100 kbps
 - Fast Mode: 400 kbps
 - Fast Mode Plus: 1000 kbps
 - High Speed Mode: 2400 kbps
- Support for both 7-bit and 10-bit addressing formats on the I²C bus
- FIFO of 64 bytes with programmable watermarks/thresholds

21.4.8 ISH UART Controller

The ISH has two UART ports, each comprised of a four-wire, bi-directional point-topoint connection between the ISH and a peripheral.

The UART has the following Capabilities:

- Support for operating speeds up to 4 Mbps
- Support for auto flow control using the RTS#/CTS# signals
- 64-byte FIFO
- DMA support to allow direct transfer to the ISH local SRAM without intervention by the controller. This saves interrupts on packets that are longer than the FIFO or when there are back-to-back packets to send or receive

21.4.9 ISH GSPI Controller

The ISH supports one SPI controller comprises of four-wired interface connecting the ISH to external sensor devices.

The SPI controller includes:

- Master Mode Only
- Single Chip Select
- Half Duplex operation only
- Programmable SPI clock frequency range with maximum rate of 24 Mbits/sec
- FIFO of 64 bytes with programmable thresholds
- Support Programmable character length (2 to 16 bits)

21.4.10 ISH GPIOs

The ISH supports eight dedicated GPIOs.



ΝΟΤΕ

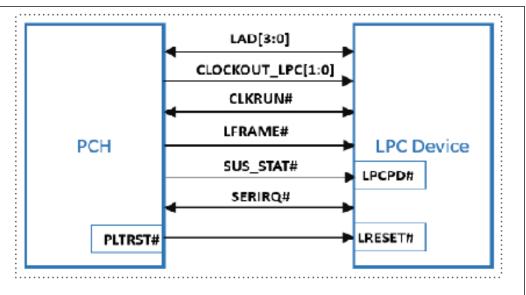
Refer Signal Description on page 148 for the ISH GPIO pins.



22.0 Low Pin Count (LPC)

The PCH implements an LPC interface as described in the *Low Pin Count Interface Specification, Revision 1.1.* The LPC interface to the PCH is shown in the figure below.

Figure 34. LPC Interface Diagram



Acronyms

Acronyms	Description	
LPC	Low Pin Count	

References

Specification	Location
Intel [®] Low Pin Count Interface Specification Revision 1.1	https://www.intel.com/content/dam/www/program/ design/us/en/documents/low-pin-count-interface- specification.pdf



22.1 Signal Description

Name	Туре	Description
GPP_A1 / LAD0 / ESPI_IO0	I/O	LPC Multiplexed Command, Address, Data.For LAD0, internal Pull-up is provided.
GPP_A2 / LAD1 / ESPI_IO1	I/O	LPC Multiplexed Command, Address, Data.For LAD1, internal Pull-up is provided.
GPP_A3 / LAD2 / ESPI_IO2	I/O	LPC Multiplexed Command, Address, Data.For LAD2, internal Pull-up is provided.
GPP_A4 / LAD3 / ESPI_IO3	I/O	LPC Multiplexed Command, Address, Data.For LAD3, internal Pull-up is provided.
GPP_A5 / LFRAME# / ESPI_CS#	0	LPC Frame: LFRAME# indicates the start of an LPC cycle, or an abort.
GPP_A9 / CLKOUT_LPCO / ESPI_CLK	0	Low Pin Count (LPC) Clock Outputs: Single-Ended 24-MHz output to various single load connectors/ devices.
GPP_A10 / CLKOUT_LPC1	0	Low Pin Count (LPC) Clock Outputs: Single-Ended 24-MHz output to various single load connectors/ devices.
GPP_A8 / CLKRUN#	I/O	LPC Clock Run for control of CLKOUT_LPC[1:0]: Connects to peripherals that need to request clock restart or prevention of clock stopping.
GPP_A6 / SERIRQ / ESPI_CS1#	I/O	This signal implements the serial interrupt protocol. <i>Note:</i> An external Pull-up to V3.3S power rail is required.
GPP_A14 / SUS_STAT# / ESPI_RESET#	0	LPC Mode - Suspend Status: This signal is asserted by the PCH to indicate that the system will be entering a low power state soon. This can be monitored by devices with memory that need to switch from normal refresh to suspend refresh mode. It can also be used by other peripherals as an indication that they should isolate their outputs that may be going to powered-off planes.

22.2 Integrated Pull-Ups and Pull-Downs

Signal	Resistor Type	Value	Notes
LAD[3:0]	Pull-up	15 - 40 kohm	

22.3 I/O Signal Planes and States

Signal Name	Power Plane	During Reset*	Immediately after Reset*	S3/S4/S5	Deep Sx
LAD[3:0]	Primary	Internal Pull-up	Internal Pull-up	Undriven	OFF
LFRAME#	Primary	Driven High	Driven High	Driven Low	OFF
CLKOUT_LPC0	Primary	Toggling	Toggling	Driven Low	OFF
CLKOUT_LPC1	Primary	Toggling	Toggling	Driven Low	OFF
CLKRUN#	Primary	Undriven	Undriven	Undriven	OFF
continued					



Signal Name	Power Plane	Power Plane During Reset*		S3/S4/S5	Deep Sx
SERIRQ	Primary	Undriven	Undriven	Undriven	OFF
SUS_STAT# Primary Driven Low			Driven Low	Driven Low	OFF
Note: *Reset reference for primary well pins is RSMRST#					

22.4 Functional Description

The PCH LPC interface supports the *Low Pin Count Interface Specification*. The bus operates at 24 MHz clock frequency.

22.4.1 LPC Cycle Types

The PCH implements the cycle types shown in the table below.

Table 64. LPC Cycle Types Supported

Cycle Type	Comment
Memory Read	1 byte only—(Refer Note below)
Memory Write 1 byte only—(Refer Note below)	
I/O Read	1 byte only—The PCH breaks up 16-bit and 32-bit processor cycles into multiple 8-bit transfers.
I/O Write	1 byte only—The PCH breaks up 16-bit and 32-bit processor cycles into multiple 8-bit transfers.
Firmware Memory Read	1 byte only
Firmware Memory Write	1 byte only
Memory cycles on the anywhere in the 4 GB necessary memory re	ngle generic memory range (LGMR) for decoding memory cycles and forwarding them as LPC LPC bus. The LGMR memory decode range is 64 KB in size. and can be defined as being memory space. This range needs to be configured by BIOS during POST to provide the sources. BIOS should advertise the LPC Generic Memory Range as Reserved to the OS in order fict. For larger transfers, the PCH performs multiple 8-bit transfers. If the cycle is not claimed

to avoid resource conflict. For larger transfers, the PCH performs multiple 8-bit transfers. If the cycle is not claimed by any peripheral, it is subsequently aborted, and the PCH returns a value of all 1s to the processor. This is done to maintain compatibility with ISA memory cycles where pull-up resistors would keep the bus high if no device responds.

22.4.2 Start Field Definition

Table 65.Start Field Bit Definitions

Bits[3:0] Encoding	Definition			
0000	Start of cycle for a generic target			
1111	Stop/Abort: End of a cycle for a target			
Note: All other encodi	Note: All other encodings are RESERVED.			

22.4.3 Cycle Type/Direction (CYCTYPE + DIR)

The PCH always drives bit0 of this field to 0. The Table below shows the valid bit encodings.



Bits[3:2]	Bit1	Definition
00	0	I/O Read
00	1	I/O Write
01	0	Memory Read
01	1	Memory Read
11	x	Reserved. If a peripheral performing a bus master cycle generates this value, the PCH aborts the cycle.
Note: All other	encodings ar	re RESERVED.

Table 66. Cycle Type Bit Definitions

22.4.4 Size

Bits[3:2] are reserved. The PCH always drives them to 00. Bits[1:0] are encoded as listed in Table below.

Table 67. Transfer Size Bit Definition

Bits[1:0]	Size
00	8-bit transfer (1 byte)
01	16-bit transfer (2 bytes)
10	Reserved
11	32-bit transfer (4 bytes)

SYNC

Valid values for the SYNC field are shown in the table below.

22.4.5 SYNC Timeout

Table 68.SYNC Bit Definition

Bits[3:0]	Indication			
0000	Ready: SYNC achieved with no error.			
0101	Short Wait: Part indicating wait-states. For bus master cycles, the PCH does not use this encoding. Instead, the PCH uses the long wait encoding.			
0110	Long Wait: Part indicating wait-states, and many wait-states will be added. This encoding driven by the PCH for bus master cycles, rather than the Short Wait (0101).			
1010	Error: Sync achieved with error. This is generally used to replace the SERR# or IOCHK# signal on the PCI/ISA bus. It indicates that the data is to be transferred, but there is a serious error in this transfer.			
	 All other combinations are RESERVED. If the LPC controller receives any SYNC returned from the device other than short (0101), long wait (0110), or 			

 If the LPC controller receives any SYNC returned from the device other than short (0101), long wait (0110), or ready (0000) when running a FWH cycle, indeterminate results may occur. A FWH device is not allowed to assert *Notes:* an Error SYNC.

There are several error cases that can occur on the LPC interface. The PCH responds as defined in Section 4.2.1.9 of the *Low Pin Count Interface Specification*, Revision 1.1 to the stimuli described therein. There may be other peripheral failure conditions; however, these are not handled by the PCH.



22.4.6 SYNC Error Indication

The PCH responds as defined in Section 4.2.1.10 of the *Low Pin Count Interface Specification Revision 1.1*.

Upon recognizing the SYNC field indicating an error, the PCH treats this as a SERR# by reporting this into the Device 31 Error Reporting Logic.

22.4.7 LFRAME# Usage

The PCH follows the usage of LFRAME# as defined in the *Low Pin Count Interface Specification*, Revision 1.1.

The PCH performs an abort for the following cases (possible failure cases):

- The PCH starts a Memory or I/O cycle, but no device drives a valid SYNC after four consecutive clocks
- The PCH starts a Memory or I/O and the peripheral drives an invalid SYNC pattern
- A peripheral drives an invalid value

22.4.8 **I/O Cycles**

For I/O cycles targeting registers specified in the PCH's decode ranges, the PCH performs I/O cycles as defined in the *Low Pin Count Interface Specification*, Revision 1.1. These are 8-bit transfers. If the processor attempts a 16-bit or 32-bit transfer, the PCH breaks the cycle up into multiple 8-bit transfers to consecutive I/O addresses.

NOTE

If the cycle is not claimed by any peripheral (and subsequently aborted), the PCH returns a value of all 1s (FFh) to the processor. This is to maintain compatibility with ISA I/O cycles where Pull-up resistors would keep the bus high if no device responds.

22.4.9 LPC Power Management

LPCPD# Protocol

Same timings as SUS_STAT#. Upon driving SUS_STAT# low, the PCH drives LFRAME# low and tri-states (or drives low) LAD[3:0].

NOTE

The Low Pin Count Interface Specification, Revision 1.1 defines the LPCPD# protocol where there is at least 30 µs from LPCPD# assertion to LRST# assertion. This specification explicitly states that this protocol only applies to entry/exit of low power states which does not include asynchronous reset events. The PCH asserts both SUS_STAT# (connects to LPCPD#) and PLTRST# (connects to LRST#) at the same time during a global reset. This is not inconsistent with the LPCPD# protocol.



22.4.10 Configuration and PCH Implications

LPC I/F Decoders

To allow the I/O cycles and memory mapped cycles to go to the LPC interface, the PCH includes several decoders. During configuration, the PCH must be programmed with the same decode ranges as the peripheral. The decoders are programmed using the D 31:F0 configuration space.

NOTE

The PCH cannot accept PCI write cycles from PCI-to-PCI bridges or devices with similar characteristics (specifically those with a "Retry Read" feature which is enabled) to an LPC device if there is an outstanding LPC read cycle towards the same PCI device or bridge. These cycles are not part of normal system operation, but may be encountered as part of platform validation testing using custom test fixtures.

Turn Around Cycle Behavior

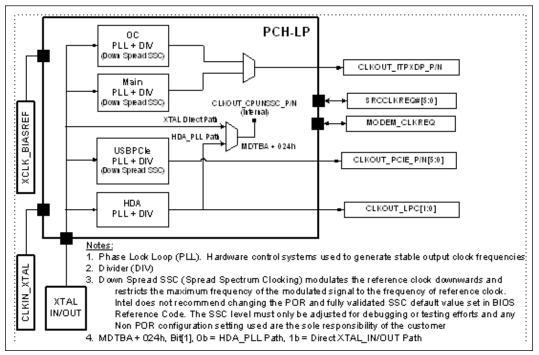
The turn around cycle is defined by the LPC specification as a 2 clock period where the PCH transfers ownership of the LPC LAD[3:0] bus to another device that would like to transfer data. During this turn around cycle it is expected that the state of the bus is to be at high-Z or logic high. During the first clock period of the turnaround cycle the PCH LPC controller will drive an active '1111' on the LAD[3:0] while its output buffers are enabled. At end of the first clock period and start of the second clock period the PCH LPC controller will internally drive LAD[3:0] to '0000' while simultaneously disabling its output buffers to allow the internal pull-up resistors to keep the LAD[3:0] at high-Z. The high-Z condition allows a secondary device to take ownership of the LPC bus after the second clock of the turnaround cycle and drive LAD[3:0] signals. Due to variances in the PCH silicon there may be a delay between the PCH LPC controller disabling its output buffers while internally driving LAD[3:0] to '0000' during the first to second clock transition of the turn-around cycle resulting in a small observable voltage droop on LAD[3:0]. This droop is not expected to cause any bus contention as no devices should be transmitting or reading information on LAD[3:0] during either of the 2 clock periods of the turn around cycle as defined by the LPC specification.



23.0 PCH and System Clocks

Platform Controller Hub (PCH) based platforms require several single-ended and differential clocks to synchronize signal operations and data propagations system wide between many interfaces and across multiple clock domains. The PCH generates and provides this complete system clocking solution through its Integrated Clock Controller (ICC).

Figure 35. Integrated Clock Controller (ICC) Diagram



23.1 PCH ICC Clocking Profiles

The PCH ICC hardware includes the following clocking profiles:

- "Standard" Profile (Figure 35 on page 160)
 - OC PLL = Disabled
 - Main PLL = Enabled with Down Spread Spectrum Clocking (SSC)
 - USBPCIe PLL = Enabled with Down Spread Spectrum Clocking (SSC)
 - HDA PLL = Enabled
- "Adaptive" Profile (Figure 35 on page 160)
 - OC PLL = Enabled with Down Spread Spectrum Clocking (SSC) and Under Clocking Capability

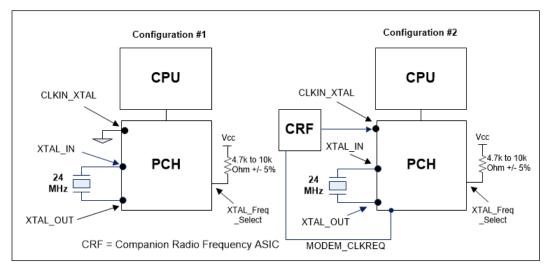


- Main PLL = Disabled
- USBPCIe PLL = Enabled with Down Spread Spectrum Clocking (SSC)
- HDA PLL = Enabled

NOTE

The Standard ICC Profile is set by default and is the recommended ICC Clocking Profile.

23.2 PCH ICC XTAL Input Configurations



23.3 Signal Descriptions

Name	Туре	SSC Capable	Description
CLKOUT_ITPXDP_P CLKOUT_ITPXDP_N	0	Yes	Differential ITP Debug Clock: 100 MHz differential output to processor XDP/ITP connector on the platform
CLKOUT_PCIE_P[5:0] CLKOUT_PCIE_N[5:0]	0	Yes	PCI Express* Clock Output: Serial Reference 100 MHz PCIe* 3.0 specification compliant differential output clocks to PCIe* devices
CLKOUT_LPC[1:0]	0	No	Low Pin Count (LPC) Clock Outputs: Single-Ended 24-MHz output to various single load connectors/devices
SRCCLKREQ#[5:0]	I/O		Clock Request: Serial Reference Clock request signals for PCIe* 100 MHz differential clocks
CLKOUT_CPUNSSC_P CLKOUT_CPUNSSC_N	0	No	Filtered Crystal Reference Clock to CPU: 24 MHz differential, filtered crystal reference clock to the processor
MODEM_CLKREQ	0		Aggregated XTAL CLKREQ: Used for Companion Radio Frequency ASIC (CRF) device initialization flow indication
XTAL_IN	Ι		Crystal Input: Input connection for 24 MHz crystal to PCH
XTAL_OUT	0		Crystal Output: Output connection for 24 MHz crystal to PCH
		•	continued



Name	Туре	SSC Capable	Description	
XCLK_BIASREF	I/O		Differential Clock Bias Reference: Used to set BIAS reference for differential clocks	
CLKIN_XTAL	I		XTAL Clock Input: Single ended integrated CNV (Connectivity) XTAL clock input	
XTAL_Freq_Select (GPP_H21)	I	XTAL Frequency Select: GPP_H21 Pin Strap for XTAL frequer selection. An external pull-up to VCC (1.8V or 3.3V) is required o strap for 24 MHz XTAL operation		
 Notes: 1. SSC = Spread Spectrum Clocking. Intel does not recommend changing the Plan of Record and fully validated SSC default value set in BIOS Reference Code. The SSC level must only be adjusted for debugging or testing efforts and any Non POR configuration setting used are the sole responsibility of the customer. 2. The SRCCLKREQ# signals can be configured to map to any of the PCH PCI Express* Root Ports while using any 				

of the CLKOUT_PCIE_P/N differential pairs.

23.4 I/O Signal Pin States

Signal Name	S3/S4/S5	S0 Entry	S0	Deep Sx
CLKOUT_ITPXDP_P CLKOUT_ITPXDP_N	OFF (Gated Low)	Bringing up the Clock	Toggling	OFF (Gated Low)
CLKOUT_PCIE_P[5:0] CLKOUT_PCIE_N[5:0]	OFF (Gated Low)	Bringing up the Clock	Toggling	OFF (Gated Low)
CLKOUT_LPC[1:0]	OFF (Gated Low)	Bringing up the Clock	Toggling	OFF (Gated Low)
SRCCLKREQ#[5:0]	Un-driven	Un-driven	Driven	OFF
MODEM_CLKREQ	Un-driven	Un-driven	Driven	OFF
CLKOUT_CPUNSSC_P CLKOUT_CPUNSSC_N	OFF (Gated Low)	Bringing up the Clock	Toggling	OFF (Gated Low)

23.5 General Features

- The PCH Integrated Clock Controller (ICC) generates and supplies all the PCH reference clocks for internal needs and it provides the complete platform system clocking solution.
- All of the ICC PCH internal reference clocks and all of the single-ended and differential clock outputs are generated from an external 24 MHz crystal through the PCH XTAL_IN/OUT pins, where the crystal accuracy is required to be less than 100 ppm.

NOTE

ppm stands for parts per million, and it indicates how much a crystal's frequency may deviate from the nominal value.

- CLKOUT_PCIE_P/CLKOUT_PCIE_N 100MHz PCIe* 3.0 compliant differential output clocks support CLKREQ# based power management
- CLKOUT_LPC[1:0] single-ended output clocks support CLKRUN# based power management, they require no external loop back clock for internal logic, and they only support a single load configurations.



• System Power Management support includes shutdown of all PCH ICC Phase Locked Loops (PLL), PCH ICC internal and external clocks, and includes the shutdown of the external crystal source.



24.0 PCI Express* (PCIe*)

- PCH-U supports up to 6 PCIe* Ports (or devices) and 16 PCIe* Lanes, with transfer rates up to 8 GT/s (Gen3)
- Intel[®] Rapid Storage Technology (Intel[®] RST) for PCIe* Storage Devices
 - Remapped PCIe* NVMe* SSD Non-Windows* Boot Operating System configurations are not supported
- Interrupt Generation
- PCI Express* Power Management
- Latency Tolerance Reporting (LTR)
- Dynamic Link Throttling
- Port 8xh Decode
- PCI Express* Separate Reference Clock with Independent Spread Spectrum Clocking (SRIS)
- Advanced Error Reporting
- Single Root I/O Virtualization (SR- IOV) Capability with Access Control Services (ACS) and Alternative Routing ID (ARI)
- SERR# Generation
- PCI Express* ExpressCard 1.0 module based hot-plug
- PCI Express* TX and RX Lane Polarity Inversion
- End-to-End PCI Express* Controller Lane Reversal
- Dynamic Link Width Negotiation as a Target
- Dynamic Speed Change
- 256B Maximum Data Payload Size
- PCIe* Subtractive Decode is not supported
 - PCI can still be supported via a PCIe*-to-PCI bridge. However, legacy PCI devices (such as PCMCIA or non-plug-and-play device) that need subtractive decode are not supported
- Common RefClk RX Architecture support
- Precision Time Measurement (PTM)

24.1 Signal Description

РСН	Name	Туре	Description
PCH-U	PCIE[16:1]_TXP PCIE[16:1]_TXN	0	PCI Express* Differential Transmit Pairs
			continued



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РСН	Name	Туре	Description
			These are PCI Express* based outbound high-speed differential signals
	PCIE[16:1]_RXP PCIE [16:1]_RXN	I	PCI Express* Differential Receive Pairs These are PCI Express* based inbound high-speed differential signals
	PCIE_RCOMPP PCIE_RCOMPN	Ι	Impedance Compensation Inputs

I/O Signal Planes and States 24.2

Table 69.	Power Plane	and States for PCI	Express* Signals
	I UIIUI I IUIIU		Express orginals

Signal Name	Туре	Power Plane	During Reset ²	Immediately After Reset ²	S3/S4/S5	Deep Sx	
PCIE_TXP PCIE_TXN	0	Primary	Internal Pull- down	Internal Pull-down	Internal Pull- down	OFF	
PCIE_RXP PCIE_RXN	I	Primary	Internal Pull- down	Internal Pull-down	Internal Pull- down	OFF	
PCIE_RCOMPP PCIE_RCOMPN	I	Primary	Undriven	Undriven	Undriven	OFF	
Notes: 1. PCIE_RXP\RXN pins transition from un-driven to Internal Pull-down during Reset. 2. Reset reference for primary well pins is RSMRST#.							

PCI Express* Port Support Feature Details 24.3

РСН	Maximum Device (Ports)	Maximum Lanes	PCIe* Gen Type	Encoding	Transfer Rate (MT/s)	Theoretica	al Maximum E (GB/s)	Bandwidth
					•	x1	x2	x4
			1	8b/10b	2500	0.25	0.50	1.00
PCH-U	6	16	2	8b/10b	5000	0.50	1.00	2.00
			3	128b/130b	8000	1.00	2.00	3.94
	<i>lotes:</i> 1. Theoretical Maximum Bandwidth (GB/s) = ((Transfer Rate * Encoding * # PCIe Lanes) /8)/1000							

• Gen3 Example: = ((8000 * 128/130* 4)/8)/1000 = 3.94 GB/s

2. When GbE is enabled on a PCIe* Root Port, the Maximum Device (Ports) value listed is reduced by a factor of 1.



PCH-LP		BCL	PCIe* Controller #1			PCIe* Controller #2				PCIe* Controller #3 Cycle Router #2				PCIe* Controller #4				
PCH	-LF	PCIe* Controller #1												C	ycle Ro	outer #	#3	
F	lex I/O Lane	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	
	PCIe* Lane	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	
	1x4					R	P5			R	9			RP	13			
	1x4 LR						RI	P5			RI	P9			RP	P13		
	2x2					R	P5	R	۶7	RI	P9	RP	11	RP	13	RP	15	
Base-U	Base-U 2x2 LR				RP7			°5	RP11		RP9		RP15		RP13			
	1x2+2x1					R	P5	RP7	RP8	RI	P9	RP11	RP12	RP	13	RP15	RP1	
	2x1+1x2					RP8	RP7	R	°5	RP12	RP11	R	99	RP16	RP15	RP	13	
	4x1					RP5	RP6	RP7	RP8	RP9	RP10	RP11	RP12	RP13	RP14	RP15	RP1	
	1x4		RI	P1			RP5				RP9				RP13			
	1x4 LR		RI	P1			R	P5		RP9				RP13				
	2x2	RI	P1	RI	P3	R	P5	R	P7	RP9 RP11			11	RP13 R		RP	15	
Premium-U	emium-U 2x2 LR RP3 RP1		R	P7	R	P5	RP	11	RI	P9	RP	15	RP	13				
	1x2+2x1	R	P1	RP3	RP4	R	P5	RP7	RP8	RI	P9	RP11	RP12	RP	13	RP15	RP1	
	2x1+1x2	RP4	RP3	RI	P1	RP8	RP7	R	P5	RP12	RP11	RI	9	RP16	RP15	RP	13	
	4x1	RP1	RP2	RP3	RP4	RP5	RP6	RP7	RP8	RP9	RP10	RP11	RP12	RP13	RP14	RP15	RP1	

Figure 36. Supported PCI Express* Link Configurations

NOTES

- 1. The PCH PCIe* Link Configuration support will vary depending on the PCH SKU
- RP# refers to a specific PCH PCI Express* Root Port #; for example RP3 = PCH PCI Express* Root Port 3
- 3. A PCIe* Lane is composed of a single pair of Transmit (TX) and Receive (RX) differential pairs, for a total of four data wires per PCIe* Lane (such as, PCIE[3]_TXP/ PCIE[3]_TXN and PCIE[3]_RXP/ PCIE[3]_RXN make up PCIe Lane 3). A connection between two PCIe* devices is known as a PCIe* Link, and is built up from a collection of one or more PCIe* Lanes which make up the width of the link (such as bundling two PCIe* Lanes together would make a x2 PCIe* Link). A PCIe* Link is addressed by the lowest number PCIe* Lane it connects to and is known as the PCIe* Root Port (such as a x2 PCIe* Link connected to PCIe* Lanes 3 and 4 would be called x2 PCIe* Root Port 3).
- 4. The PCIe* Lanes can be configured independently from one another but the maximum number of configured Root Ports (Devices) must not be exceeded.
 - PCH-U: A maximum of six PCIe* Root Ports (or devices) can be enabled
 - When a GbE Port is enabled, the maximum number of PCIe* Ports (or devices) that can be enabled reduces based off the following:
 - PCH-U: Maximum PCIe* Ports (or devices) = 6 GbE (0 or 1)
- 5. Unidentified lanes within a PCIe* Link Configuration are disabled but their physical lanes are used for the identified Root Port
- 6. Supports up to Two Remapped (Intel $^{\ensuremath{\mathbb{R}}}$ Rapid Storage Technology) PCIe* Storage Devices
 - Cells highlighted in Green identify controllers, configurations, and lanes that can be used for a x2/x4 Intel[®] Rapid Storage Technology Remapped PCIe*
 NVMe SSD or a x2/x4 Next Generation Intel[®] Optane[™] Memory Device
- The PCH PCIe* Root Ports can be configured to map to any of the SRCCLKREQ# PCIe* clock request signals and the CLKOUT_PCIE_P/N PCIe* differential clock signal pairs.
- 8. Reference and understand the PCIe* High Speed I/O Multiplexing details covered in the "Flexible I/O" Chapter.



- Lane Reversal Supported Motherboard PCIe* Configurations = 1x4, 2x1+1x2, and 2x2
 - The 2x1+1x2 configuration is enabled by setting the PCIe* Controller soft straps to 1x2+2x1 with Lane Reversal Enabled.
 - 1x4 = 1x4 with Lane Reversal Disabled, 1x4 LR = 1x4 with Lane Reversal Enabled.
 - 2x2 = 2x2 with Lane Reversal Disabled, 2x2 LR = 2x2 with Lane Reversal Enabled.
- 10. For unused SATA/PCIe* Combo Lanes, Flex I/O Lanes that can be configured as PCIe* or SATA, the lanes must be statically assigned to SATA or PCIe* via the SATA/PCIe* Combo Port Soft Straps These unused SATA/PCIe* Combo Lanes must not be assigned as polarity based.
 - Refer Flexible I/O on page 19 chapter for SATA/PCIe* Combo Lane identification.

24.3.1 Intel[®] Rapid Storage Technology (Intel[®] RST) for PCIe* Storage

Intel[®] Rapid Storage Technology for PCIe* Storage includes the PCH PCIe* Controller Remapping Hardware, also referred to as Cycle Routers, and the Intel[®] RST Driver. The Remapping Hardware is a PCH PCIe* Controller architecture feature that works with the Intel[®] RST Driver to control and remap PCIe* storage devices to the PCH AHCI SATA Controller.

The PCH has multiple PCIe* Controllers where some, not all, of these Controllers have the Remapping Hardware. These specific PCIe* Controllers along with the Intel[®] RST Driver handle the remapping for x2 or x4 PCIe* storage devices. Special care must be taken to make sure the correct PCH PCIe* Lanes are used that are associated with these specific PCIe* Controllers. The Intel[®] RST for PCIe* Storage controller, configuration, and lane support will vary depending on the PCH SKU.

24.3.2 Interrupt Generation

The root port generates interrupts on behalf of hot-plug, power management, link bandwidth management, Link Equalization Request and link error events, when enabled. These interrupts can either be pin-based, or can be Message Signal Interrupt (MSI), when enabled.

When an interrupt is generated using the legacy pin, the pin is internally routed to the SoC interrupt controllers. The pin that is driven is based upon the setting of the STRPFUSECFG.PXIP configuration registers.

The following table summarizes interrupt behavior for MSI and wire-modes. In the table "bits" refers to the hot-plug and PME interrupt bits.

Table 70.MSI Versus PCI IRQ Actions

Interrupt Register	Wire-Mode Action	MSI Action
All bits 0	Wire inactive	No action
One or more bits set to 1	Wire active	Send message
One or more bits set to 1, new bit gets set to 1	Wire active	Send message
		continued



Interrupt Register	Wire-Mode Action	MSI Action
One or more bits set to 1, software clears some (but not all) bits	Wire active	Send message
One or more bits set to 1, software clears all bits	Wire inactive	No action
Software clears one or more bits, and one or more bits are set on the same clock	Wire active	Send message

24.3.3 PCI Express* Power Management

S3/S4/S5 Support

Software initiates the transition to S3/S4/S5 by performing an I/O write to the Power Management Control register in the SoC. After the I/O write completion has been returned to the processor, the Power Management Controller will signal each root port to send a PME_Turn_Off message on the downstream link. The device attached to the link will eventually respond with a PME_TO_Ack followed by sending a PM_Enter_L23 DLLP (Data Link Layer Packet) request to enter L23. The Express ports and Power Management Controller take no action upon receiving a PME_TO_Ack. When all the Express port links are in state L23, the Power Management Controller will proceed with the entry into S3/S3/S5.

Prior to entering S3, software is required to put each device into $D3_{HOT}$. When a device is put into $D3H_{HOT}$, it will initiate entry into a L1 link state by sending a PM_Enter_L1 DLLP. Under normal operating conditions when the root ports sends the PME_Turn_Off message, the link will be in state L1. However, when the root port is instructed to send the PME_Turn_Off message, it will send it whether or not the link was in L1. Endpoints attached to the PCH can make no assumptions about the state of the link prior to receiving a PME_Turn_Off message.

Device Initiated PM_PME Message

When the system has returned to a working state from a previous low power state, a device requesting service will send a PM_PME message continuously, until acknowledged by the root port. The root port will take different actions depending upon whether this is the first PM_PME that has been received, or whether a previous message has been received but not yet serviced by the operating system.

If this is the first message received (RSTS.PS), the root port will set RSTS.PS, and log the PME Requester ID into RSTS.RID. If an interrupt is enabled using RCTL.PIE, an interrupt will be generated. This interrupt can be either a pin or an MSI if MSI is enabled using MC.MSIE.

If this is a subsequent message received (RSTS.PS is already set), the root port will set RSTS.PP. No other action will be taken.

When the first PME event is cleared by software clearing RSTS.PS, the root port will set RSTS.PS, clear RSTS.PP, and move the requester ID into RSTS.RID.

If RCTL.PIE is set, an interrupt will be generated. If RCTL.PIE is not set, a message will be sent to the power management controller so that a GPE can be set. If messages have been logged (RSTS.PS is set), and RCTL.PIE is later written from a 0b to a 1b, an interrupt will be generated. This last condition handles the case where the message was received prior to the operating system re-enabling interrupts after resuming from a low power state.



SMI/SCI Generation

Interrupts for power management events are not supported on legacy operating systems. To support power management on non-PCI Express aware operating systems, PM events can be routed to generate SCI. To generate SCI, MPC.PMCE must be set. When set, a power management event will cause SMSCS.PMCS to be set.

Additionally, BIOS workarounds for power management can be supported by setting MPC.PMME. When this bit is set, power management events will set SMSCS.PMMS, and SMI# will be generated. This bit will be set regardless of whether interrupts or SCI is enabled. The SMI# may occur concurrently with an interrupt or SCI.

Latency Tolerance Reporting (LTR)

The root port supports the extended Latency Tolerance Reporting (LTR) capability. LTR provides a means for device endpoints to dynamically report their service latency requirements for memory access to the root port. Endpoint devices should transmit a new LTR message to the root port each time its latency tolerance changes (and initially during boot). The PCH uses the information to make better power management decisions. The processor uses the worst case tolerance value communicated by the PCH to optimize C-state transitions. This results in better platform power management without impacting endpoint functionality.

NOTE

Endpoint devices that support LTR must implement the reporting and enable mechanism detailed in the PCI-SIG "Latency Tolerance Reporting Engineering Change Notice" (www.pcisig.com).

24.3.4 Dynamic Link Throttling

Root Port supports dynamic link throttling as a mechanism to help lower the overall component power, ensuring that the component never operates beyond the thermal limit of the package. Dynamic link throttling is also used as a mechanism for ensuring that the ICCmax current rating of the voltage regulator is never exceeded. The target response time for this particular usage model is < 100 μ s.

If dynamic link throttling is enabled, the link will be induced by the Root Port to enter TxL0s and RxL0s based on the throttle severity indication received. To induce the link into TxL0s, new TLP requests and opportunistic flow control update will be blocked. Eventually, in the absence of TLP and DLLP requests, the transmitter side of the link will enter TxL0s.

The periodic flow control update, as required by the PCI Express Base Specification is not blocked. However, the flow control credit values advertised to the component on the other side of the link will not be incremented, even if the periodic flow control update packet is sent. Once the other component runs out of credits, it will eventually enter TxL0s, resulting in the local receiver entering RxL0s.

Each of the Root Ports receives four throttle severity indications; T0, T1, T2, and T3. The throttling response for each of the four throttle severity levels can be independently configured in the Root Port TNPT.TSLxM register fields. This allows the duty cycle of the Throttling Window to be varied based on the severity levels, when dynamic link throttling is enabled.



A Throttling Window is defined as a period of time where the duty cycle of throttling can be specified. A Throttling Window is sub-divided into a Throttling Zone and a Non-Throttling Zone. The period of the Throttling Zone is configurable through the TNPT.TT field. Depending on the throttle severity levels, the throttling duration specified by the TNPT.TT field will be multiplied by the multipliers configurable through TNPT.TSLxM.

The period of the Throttling Window is configurable through the TNPT.TP field. The Throttling Window is always referenced from the time a new Throttle State change indication is received by the Root Port or from the time the throttling is enabled by the configuration register. The Throttling Window and Throttling Zone timers continue to behave the same as in L0 or L0s even if the link transitions to other LTSSM states, except for L1, L23_Rdy and link down. For L1 case, the timer is allowed to be stopped and hardware is allowed to re-start the Throttling Window and the corresponding Throttling Zone timers on exit from L1.

24.3.5 Port 8xh Decode

The PCIe* root ports will explicitly decode and claim I/O cycles within the 80h – 8Fh range when MPC.P8XDE is set. The claiming of these cycles are not subjected to standard PCI I/O Base/Limit and I/O Space Enable fields. This allows a POST-card to be connected to the Root Port either directly as a PCI Express* device or through a PCI Express to PCI bridge as a PCI card.

Any I/O reads or writes will be forwarded to the link as it is. The device will need to be able to return the previously written value, on I/O read to these ranges. BIOS must ensure that at any one time, no more than one Root Port is enabled to claim Port 8xh cycles.

24.3.6 Separate Reference Clock with Independent SSC (SRIS)

The current PCI-SIG "PCI Express* External Cabling Specification" (www.pcisig.com) defines the reference clock as part of the signals delivered through the cable. Inclusion of the reference clock in the cable requires an expensive shielding solution to meet EMI requirements.

The need for an inexpensive PCIe* cabling solution for PCIe* SSDs requires a cabling form factor that supports non-common clock mode with spread spectrum enabled, such that the reference clock does not need to be part of the signals delivered through the cable. This clock mode requires the components on both sides of a link to tolerate a much higher ppm tolerance of ~5600 ppm compared to the PCIe* Base Specification defined as 600 ppm.

Soft straps are needed as a method to configure the port statically to operate in this mode. This mode is only enabled if the SSD connector is present on the motherboard, where the SSD connector does not include the reference clock. No change is being made to PCIe* add-in card form factors and solutions.

ASPM LOs is not supported in this form factor. The L1 exit latency advertised to software would be increased to 10 us. The root port does not support Lower SKP Ordered Set generation and reception feature defined in SRIS ECN.

24.3.7 Advanced Error Reporting

The PCI Express* Root Ports each provide basic error handling, as well as Advanced Error Reporting (AER) as described in the latest PCI Express Base Specification.



24.3.8 Single- Root I/O Virtualization (SR- IOV)

Alternative Routing ID Interpretation (ARI) and Access Control Services (ACS) are supported as part of the complementary technologies to enable SR-IOV capability.

Alternative Routing- ID Interpretation (ARI)

Alternative Routing-ID Interpretation (ARI) is a mechanism that can be used to extend the number of functions supported by a multi-function ARI device connected to the Root Port, beyond the conventional eight functions.

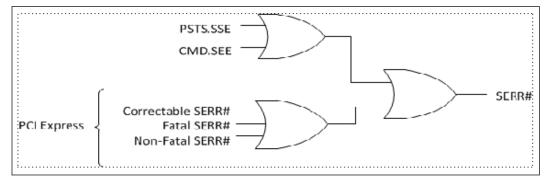
Access Control Services (ACS)

ACS is defined to control access between different Endpoints and between different Functions of a multi-function device. ACS defines a set of control points to determine whether a TLP should be routed normally, blocked, or redirected.

24.3.9 SERR# Generation

SERR# may be generated using two paths—through PCI mechanisms involving bits in the PCI header, or through PCI Express* mechanisms involving bits in the PCI Express* capability structure.

Figure 37. Generation of SERR# to Platform



24.3.10 Hot-Plug

All PCIe* Root Ports support Express Card 1.0 based hot-plug that performs the following:

- Presence Detect and Link Active Changed Support
- Interrupt Generation Support

Presence Detection

When a module is plugged in and power is supplied, the physical layer will detect the presence of the device, and the root port sets SLSTS.PDS and SLSTS.PDC. If SLCTL.PDE and SLCTL.HPE are both set, the root port will also generate an interrupt.

When a module is removed (using the physical layer detection), the root port clears SLSTS.PDS and sets SLSTS.PDC. If SLCTL.PDE and SLCTL.HPE are both set, the root port will also generate an interrupt.



SMI/SCI Generation

Interrupts for power-management events are not supported on legacy operating systems. To support power-management on non-PCI Express aware operating systems, power management events can be routed to generate SCI. To generate SCI, MPC.HPCE must be set. When set, enabled hot-plug events will cause SMSCS.HPCS to be set.

Additionally, BIOS workarounds for hot-plug can be supported by setting MPC.HPME. When this bit is set, hot-plug events can cause SMI status bits in SMSCS to be set. Supported hot-plug events and their corresponding SMSCS bit are:

- Presence Detect Changed SMSCS.HPPDM
- Link Active State Changed SMSCS.HPLAS

When any of these bits are set, SMI# will be generated. These bits are set regardless of whether interrupts or SCI is enabled for hot-plug events. The SMI# may occur concurrently with an interrupt or SCI.

24.3.11 PCI Express* Lane Polarity Inversion

The PCI Express* Base Specification requires polarity inversion to be supported independently by all receivers across a Link—each differential pair within each Lane of a PCIe* Link handles its own polarity inversion. Polarity inversion is applied, as needed, during the initial training sequence of a Lane. In other words, a Lane will still function correctly even if a positive (Tx+) signal from a transmitter is connected to the negative (Rx-) signal of the receiver. Polarity inversion eliminates the need to untangle a trace route to reverse a signal polarity difference within a differential pair and no special configuration settings are necessary in the PCH to enable it. It is important to note that polarity inversion does not imply direction inversion or direction reversal; that is, the Tx differential pair from one device must still connect to the Rx differential pair on the receiving device, per the PCIe* Base Specification. Polarity Inversion is not the same as "PCI Express* Controller Lane Reversal".

24.3.12 PCI Express* Controller Lane Reversal

For each PCIe* Controller we support end-to-end lane reversal across the four lanes mapped to a controller for the two motherboard PCIe* configurations listed below. Lane Reversal means that the most significant lane of a PCIe* Controller is swapped with the least significant lane of the PCIe* Controller while the inner lanes get swapped to preserve the data exchange sequence (order).

NOTE

Lane Reversal Supported Motherboard PCIe* Configurations = 1x4, 2x1+1x2, and 2x2

• The 2x1+1x2 configuration is enabled by setting the PCIe* Controller soft straps to 1x2+2x1 with Lane Reversal Enabled

NOTE

PCI Express* Controller Lane Reversal is not the same as PCI Express* Lane Polarity Inversion.



24.3.13 Precision Time Measurement (PTM)

Hardware protocol for precise coordination of events and timing information across multiple upstream and downstream devices using Transaction Layer Protocol (TLP) Message Requests. Minimizes timing translation errors resulting in the increased coordination of events across multiple components with very fine precision.

All of the PCH PCIe* Controllers and their assigned Root Ports support PTM where each Root Port can have PTM enabled or disabled individually from one another.



25.0 Power Management

The Power Management Controller (PMC) is the PCH unit that handles all PCH power management related activities. This unit administers power management functions of the PCH including interfacing with other logic and controllers on the platform to perform power state transitions (such as SLP_S3# and PLTRST#); configure, manage and respond to wake events; aggregate and report latency tolerance information for devices and peripherals connected to and integrated into the PCH.

NOTE

DeepS3 is not supported in this PCH. In this document DeepSx refers to DeepS4 and DeepS5 states.

Acronyms

Acronyms	Description
РМС	Power Management Controller
STD	Suspend To Disk
STR	Suspend To RAM
PMIC	Power Management Integrated Circuit
VR	Voltage Regulator

References

Specification	Location
Advanced Configuration and Power Interface (ACPI)	http://www.acpi.info/spec.htm

25.1 Signal Description

Name	Туре	Description
ACPRESENT/GPD1	I	ACPRESENT: This input pin indicates when the platform is plugged into AC power or not. In addition to the previous Intel [®] CSME to EC communication, the PCH uses this information to implement the Deep Sx policies. For example, the platform may be configured to enter Deep Sx when in S4 or S5 and only when running on battery. This is powered by Deep Sx Well.
BATLOW#/GPD0	I	Battery Low : An input from the battery to indicate that there is insufficient power to boot the system. Assertion will prevent wake from S3/S4/S5 states and exit from Deep Sx state. This signal can also be enabled to cause an SMI# when asserted. This signal is multiplexed with GPD0. For any platform not using this pin functionality, this signal must be tied high to VCCDSW_3P3. 1. An external pull-up resistor to VCCDSW_3P3 is required.
CORE_VID0/GPP_B0	0	PCH Core VID Bit 0 : May connect to discrete VRs and used to communicate the supported VCCPRIM_CORE voltage.
		continued



Name	Туре	Description
		This pin will only be driven high ('1') in native mode, to reflect a VCCPRIM_CORE supported voltage of 1.05 V.
CORE_VID1/GPP_B1	0	PCH Core VID Bit 1:May connect to discrete VRs and used to communicate the supported VCCPRIM_CORE voltage. This pin will only be driven high ('1') in native mode, to reflect a VCCPRIM_CORE supported voltage of 1.05 V.
CPU_C10_GATE# / GPP_H18	ο	External Power Gate control for VCCIO, VCCSTG and VCCPLL_OC during C10. When asserted, VCCIO and VCCSTG can be 0V, however the power good indicators for these rails must remain asserted.
EXT_PWR_GATE#/ GPP_B11	0	External Power Gate control for MPHY and SRAMs power supply.
DRAM_RESET#	OD	System Memory DRAM Reset : Active low reset signal to DRAM. <i>Note:</i> An external pull-up to the DRAM power plane is required.
DSW_PWROK	I	DSW PWROK : Power OK Indication for the VCCDSW_3P3 voltage rail. This input is tied together with RSMRST# on platforms that do not support Deep Sx. <i>Note:</i> This signal is in the RTC well.
LAN_WAKE#/GPD2	I	LAN WAKE : is an active low wake indicator from the GbE PHY. <i>Note:</i> External pull-up required.
LANPHYPC /GPD11	0	LAN PHY Power Control : LANPHYPC is used to indicate that power needs to be restored to the Platform LAN Connect Device.
PCH_PWROK	I	PCH Power OK : When asserted, PCH_PWROK is an indication to the PCH that all of its core power rails have been stable for at least 5 ms. PCH_PWROK can be driven asynchronously. When PCH_PWROK is negated, the PCH asserts PLTRST#. <i>Note:</i> PCH_PWROK must not glitch, even if RSMRST# is low.
PLTRST#/GPP_B13	0	 Platform Reset: The PCH asserts PLTRST# to reset devices on the platform (such as SIO, LAN, processor, and so forth.). The PCH asserts PLTRST# low in Sx states and when a cold, warm, or global reset occurs. The PCH de-asserts PLTRST# upon exit from Sx states and the aforementioned resets. There is no guaranteed minimum assertion time for PLTRST#. Note: PCIe* specification requires that the power rails associated with PCIe* (typically the 3.3 V, 5 V, and 12 V core well rails) have been valid for 100 ms prior to PLTRST# de-assertion. System designers must ensure the requirement is met on the platform.
PME#/GPP_A11/ GSPI1_CS1#/ SD_VDD2_PWR_EN#	I/OD	Power Management Event : Driven by devices to wake the system or issue SCI.
PWRBTN#/GPD3	I	 Power Button: The Power Button will cause SMI# or SCI to indicate a system request to go to a sleep state. If the system is already in a sleep state, this signal will cause a wake event. If PWRBTN# is pressed for more than 4 seconds (default; timing is configurable), this will cause an unconditional transition (power button override) to the S5 state. Override will occur even if the system is in the S3-S4 states. This signal has an internal Pull-up resistor and has an internal 16 ms de-bounce on the input. Note: Upon entry to S5 due to a power button override, if Deep Sx is enabled and conditions are met, the system will transition to Deep S5.
RSMRST#	I	Primary Well: This signal is used for resetting the resume power plane logic. This signal must be asserted for at least 10ms after the suspend power wells are valid. When de-asserted, this signal is an indication that the primary power wells are stable.
		continued



Name	Туре	Description
SLP_A#/GPD6	0	SLP_A# : Signal asserted when the Intel [®] CSME platform goes to M-Off or M3-PG. Depending on the platform, this pin may be used to control power to various devices that are part of the Intel [®] CSME sub-system in the platform.
SLP_LAN#	0	LAN Sub-System Sleep Control : When SLP_LAN# is de-asserted it indicates that the PHY device must be powered. When SLP_LAN# is asserted, power can be shut off to the PHY device. SLP_LAN# will always be de-asserted in S0 and anytime SLP_A# is de-asserted.
SLP_WLAN# / GPD9	0	WLAN Sub-System Sleep Control : When SLP_WLAN# is asserted, power can be shut off to the external wireless LAN device. SLP_WLAN# will always will be de-asserted in S0. SLP_WLAN# shall not be used to shut down power to integrated connectivity (CNVi).
SLP_S0# /GPP_B12	0	S0 Sleep Control : When PCH is idle and processor is in C10 state, this pin will assert to indicate VR controller can go into a light load mode. This signal can also be connected to EC for other power management related optimizations.
SLP_S3#/GPD4	0	S3 Sleep Control: SLP_S3# is for power plane control. This signal shuts off power to all non-critical systems when in S3 (Suspend To RAM), S4 (Suspend to Disk), or S5 (Soft Off) states.
SLP_S4#/GPD5	0	 S4 Sleep Control: SLP_S4# is for power plane control. This signal shuts power to all non-critical systems when in the S4 (Suspend to Disk) or S5 (Soft Off) state. Note: This pin must be used to control the DRAM power in order to use the PCH DRAM power-cycling feature.
SLP_S5#/GPD10	0	S5 Sleep Control: SLP_S5# is for power plane control. This signal is used to shut power off to all non-critical systems when in the S5 (Soft Off) states.
SLP_SUS#	0	Deep Sx Indication : When asserted (driven low), this signal indicates PCH is in Deep Sx state where primary power is shut off for enhanced power saving. When de-asserted (driven high), this signal indicates exit from Deep Sx state and primarypower can be applied to PCH. If Deep Sx is not supported, then this pin can be left unconnected. <i>Note:</i> This pin is in the DSW power well.
SUSACK#/GPP_A15	I	SUSACK# : If Deep Sx is supported, the EC/motherboard controlling logic must change SUSACK# to match SUSWARN# once the EC/motherboard controlling logic has completed the preparations discussed in the description for the SUSWARN# pin. <i>Note:</i> SUSACK# is only required to change in response to SUSWARN# if Deep Sx is supported by the platform.
SUSCLK/GPD8	0	Suspend Clock: This clock is a digitally buffer version of the RTC clock.
SUSWARN#/ SUSPWRDNACK/ GPP_A13	0	SUSWARN# : This pin asserts low when the PCH is planning to enter the Deep Sx power state and remove Primary power (using SLP_SUS#). The EC/motherboard controlling logic must observe edges on this pin, preparing for primary well power loss on a falling edge and preparing for Primary well related activity (host/Intel [®] CSME wakes and runtime events) on a rising edge. SUSACK# must be driven to match SUSWARN# once the above preparation is complete. SUSACK# should be asserted within a minimal amount of time from SUSWARN# assertion as no wake events are supported if SUSWARN# is asserted but SUSACK# is not asserted. Platforms supporting Deep Sx, but not wishing to participate in the handshake during wake and Deep Sx entry may tie SUSACK# to SUSWARN#. This pin is multiplexed with SUSPWRDNACK since it is not needed in Deep
SUSPWRDNACK/		Sx supported platforms. SUSPWRDNACK: Active high. Asserted by the PCH on behalf of the
SUSWARN#/GPP_A13	0	Intel [®] CSME when it does not require the PCH Primary well to be powered.
		continued



Name	Туре	Description				
		Platforms are not expected to use this signal when the PCH Deep Sx feature is used.				
SX_EXIT_HOLDOFF#/ GPP_A12 /ISH_GP6 / BM_BUSY#	I	Sx Exit Holdoff Delay : Delay exit from Sx state after SLP_A# is de- asserted. Refer Sx_Exit_Holdoff# on page 196 for more details.				
SYS_PWROK	I	System Power OK : This generic power good input to the PCH is driven and utilized in a platform-specific manner. While PCH_PWROK always indicates that the primary wells of the PCH are stable, SYS_PWROK is used to inform the PCH that power is stable to some other system component(s) and the system is ready to start the exit from reset.				
SYS_RESET#	Ι	System Reset: This pin forces an internal reset after being de-bounced.				
VRALERT#/GPP_B2	I	VR Alert: ICC Max. throttling indicator from the PCH voltage regulators. VRAlert# pin allows the VR to force throttling to prevent an over current shutdown.				
WAKE#	I/OD	PCI Express* Wake Event in Sx: Input Pin in Sx. Sideband wake sign on PCI Express* asserted by components requesting wake up. <i>Note:</i> This is Output pin during S0ix states hence this pin can not be used to wake up the system during S0ix states. <i>Note:</i> External pull-up required.				
CLKRUN#/GPP_A8	I/OD	LPC Clock Run : Used to control CLKOUT_LPC[1:0]. Connects to peripherals that need to request clock restart or prevention of clock stopping.				
SUS_STAT #/ ESPI_RESET#/GPP_A14	0	 LPC Mode - Suspend Status: This signal is asserted by the PCH to indicate that the system will be entering a low power state soon. This can be monitored by devices with memory that need to switch from normal refresh to suspend refresh mode. It can also be used by other peripherals as an indication that they should isolate their outputs that may be going to powered-off planes. Note: In eSPI Mode, this signal functions as ESPI Reset#. Reset signal from PCH to eSPI slave. 				
INPUT3VSEL	I	 Strapped high if PCH's VCCDSW_3P3 rail is 3.0 V +/-5%; else PCH's VCCDSW_3P3 rail is 3.3 V +/- 5%. This pin is in the VCCPRIM_3P3 well. <i>Note:</i> When strapped for 3.0V operation, it is expected that the rest of the platform's 3.3 V rails are at 3.0 V (example, the battery is a 1S configured battery) and that components can function properly at 3.0 V. 				

25.2 Integrated Pull-Ups and Pull-Downs

Signal	Resistor Type	Value				
ACPRESENT	Pull-down	15 kohm - 40 kohm				
LAN_WAKE#	Pull-down	15 kohm - 40 kohm				
PWRBTN#	Pull-up	20 kohm +/- 30%				
SUSACK#	Pull-up	20 kohm +/- 30%				
WAKE#	Pull-down	15 kohm - 40 kohm				
Note: Pull-down is configurable and can be enabled in Deep Sx state; refer to DSX_CFG register for more details.						



25.3 I/O Signal Planes and States

Signal Name	Power Plane	During Reset ¹⁸	Immediately after Reset ¹⁸	S3/S4/S5	Deep Sx
ACPRESENT ^{6,10,15}	DSW	Undriven /Driven Low ⁴	Undriven	Undriven	Undriven/Internal Pull-down ⁸
BATLOW#	DSW	Undriven	Undriven	Undriven	OFF
CORE_VID0 ^{11,17}	Primary	Driven High	Driven High	Driven High	OFF
CORE_VID111,17	Primary	Driven High	Driven High	Driven High	OFF
CPU_C10_GATE# ¹	Primary	Driven High	Driven High	Driven High	OFF
DRAM_RESET#	DSW	Undriven	Undriven	Undriven	Undriven
DSW_PWROK	RTC	Undriven	Undriven	Undriven	Undriven
EXT_PWR_GATE#	Primary	Driven High	Driven High	Driven High	OFF
INPUT3VSEL	DSW	Undriven	Undriven	Undriven	Undriven
LANPHYPC ^{10,16}	DSW	Driven Low	Driven Low	Driven Low	Driven Low
LAN_WAKE# ¹⁵	DSW	Undriven	Undriven	Undriven	Undriven/Internal Pull-down ⁸
PCH_PWROK	RTC	Undriven	Undriven	Undriven	Undriven
PLTRST# ¹⁶	Primary	Driven Low	Driven High	Driven Low	OFF
PME# ¹⁵	Primary	Internal Pull-up	Internal Pull-up	Internal Pull-up	OFF
PWRBTN# ¹⁵	DSW	Internal Pull-up	Internal Pull-up	Internal Pull-up	Internal Pull-up
RSMRST#	RTC	Undriven	Undriven	Undriven	Undriven
SUSACK# ¹⁵	Primary	Internal Pull-up	Internal Pull-up	Internal Pull-up	OFF
SUSCLK ^{10,16}	DSW	Driven Low	Toggling	Toggling	Toggling ¹⁰
SUSWARN#/ SUSPWRDNACK ^{6,10, 16}	Primary	Driven Low	Driven Low	Driven Low ⁵	OFF
SLP_A# ^{6,16}	DSW	Driven Low	Driven High	Driven High/ Driven Low ¹²	Driven High/ Driven Low ¹²
SLP_S0#1	Primary	Driven High	Driven High	Driven High	OFF
SLP_S3# ^{6,16}	DSW	Driven Low	Driven High	Driven Low	Driven Low
SLP_S4# ^{6,16}	DSW	Driven Low	Driven High	Driven High/ Driven Low ²	Driven High/ Driven Low ⁹
SLP_S5# ^{6,16}	DSW	Driven Low	Driven High	Driven High/ Driven Low ³	Driven High/ Driven Low ⁹
SLP_LAN# ⁶	DSW	Driven Low	Driven Low	Driven High/ Driven Low ⁷	Driven High/ Driven Low ⁷
SLP_WLAN# ^{6,16}	DSW	Driven Low	Driven Low	Driven High/ Driven Low ⁷	Driven High/ Driven Low ⁷
SLP_SUS# ⁶	DSW	Driven Low	Driven High	Driven High	Driven Low
SX_EXIT_HOLDOFF# ¹⁵	Primary	Undriven	Undriven	Undriven	OFF



Signal Name	Power Plane	During Reset ¹⁸	Immediately after Reset ¹⁸	S3/S4/S5	Deep Sx
SYS_PWROK ¹³	Primary	Undriven	Undriven	Undriven	OFF
SYS_RESET# ¹³	Primary	Undriven	Undriven	Undriven	OFF
VRALERT# ¹⁵	Primary	Undriven	Undriven	Undriven	OFF
WAKE# ¹³	DSW	Undriven	Undriven	Undriven	Undriven/Internal Pull-down

Notes: 1. Driven High during S0 and driven Low during S0 CS.

- 2. SLP_S4# is driven high in S3, driven low in S4/S5.
- 3. SLP_S5# is driven high in S3/S4, driven low in S5.
- 4. In non-Deep Sx mode, pin is driven low.
- 5. Based on wake events and Intel[®] CSME state. SUSPWRDNACK is always '0' while in M0 or M3, but can be driven to '0' or '1' while in Moff state. SUSPWRDNACK is the default mode of operation. If Deep Sx is supported, then subsequent boots will default to SUSWARN#.
- 6. The pin requires glitch-free output sequence. The pad should only be pulled low momentarily when the corresponding buffer power supply is not stable.
- 7. Based on wake event and Intel[®] CSME state.
- 8. Pull-down is configurable and can be enabled in Deep Sx state; refer to DSX_CFG register for more details.
- 9. When platform enters Deep Sx, the SLP_S4# and SLP_S5# pin will retain the value it held prior to Deep Sx entry.
- 10.Internal weak pull-down resistor is enabled during power sequencing, but configurable (pull-down/ pull-up/ none) after boot.
- 11.The CORE_VID pins defaults to `1' and will be driven to `1' to reflect that VCCPRIM_CORE voltage will be support 1.05V. N/A
- 12.Pin state is a function of whether the platform is configured to have Intel[®] CSME on or off in Sx.
- 13. Output High-Z, not glitch free.
- 14.Output High-Z, glitch free with \sim 1 kohm Pull-down during respective power sequencing.
- 15. Output High-Z, not glitch free.
- 16.Output High-Z, glitch free with ~20 kohm Pull-down during respective power sequencing.
- 17.Output High-Z, glitch free with \sim 20 kohm Pull-up during respective power sequencing.
- 18. Reset reference for primary well pins is RSMRST#, DSW well pins is DSW_PWROK, and RTC well pins is RTCRST#.

25.4 Functional Description

This section covers the information about the following:

- Features
- PCH S0 Low Power
- PCH and System Power States
- System Power Planes
- SMI#/SCI Generation
- C-States
- Dynamic 24 MHz Clock Control
- Sleep States
- Event Input Signals and Their Usage
- ALT Access Mode
- System Power Supplies, Planes, and Signals
- Legacy Power Management Theory of Operation
- Reset Behavior



25.4.1 Features

- Support for Advanced Configuration and Power Interface (ACPI) providing power and thermal management
 - ACPI 24-Bit Timer SCI and SMI# Generation
- PCI PME# signal for Wake Up from Low-Power states
- System Sleep State Control
 - ACPI S3 state Suspend to RAM (STR)
 - ACPI S4 state Suspend-to-Disk (STD)
 - ACPI G2/S5 state Soft Off (SOFF)
 - Power Failure Detection and Recovery
 - Deep Sx
- Intel[®] Converged Security and Management Engine Power Management Support
 - Wake events from the Intel[®] Converged Security and Management Engine (enabled from all S-States including Catastrophic S5 conditions)
- SLP_S0# signal for external platform VR power gating or EC power management handling during lower power condition

NOTE

Power Management timers accuracy is ${\sim}4.2\%$ which will affect energy reporting counters, power button override duration etc.

25.4.2 PCH S0 Low Power

The PCH has many independent functions and I/O interfaces making power management a highly distributive task. The first level of power management is to control the independent resources and the best place to do that is in the controllers. The second level of power management is to control the shared resources, which requires communication amongst the users of the shared resources.

The PCH power states are a combination of first level and second level power management functions. The "deeper" the power state, meaning the lower power required, generally means that more resources are disabled.

PCH S0 Low Power State Definition

A high level description of the global PCH low power states are described in below table. This table does not discuss the conditions to enter into these states, only the summary of the PCH power actions that are taken. These states are also not rigid definitions of actual HW states meaning that there are not specific flows to enter into LPx states. Most of the power management on the PCH is done autonomously by the I/O interface's controller and is not globally controlled.



Power State	Description	CPU Package State	Power Action			
LP1	Fully running S0 with aggressive opportunistic power management actions	C0	 OPI L1 and PLL shutdown Individual PLL shutdown¹ Internal power gating of PCH controllers² Internal HSIO per lane power gating³ 			
LP2	Pervasively Idle S0 and Root PLLs are off	C6 or deeper	All actions from LP1 + • Main PLL and OC PLL shutdown			
LP3	Idle Floor	C10	All actions from LP2 + • XTAL shutdown • SLP_S0# • VCCPRIM_CORE Low Voltage Mode			
 Notes: 1. Individual PLL shutdown – Each I/O interface when becoming sufficiently idle (typically requiring a minimum link power state) can have its respective I/O PLL be shutdown dynamically. This includes PCIe* Gen3, SATA, USB 2.0 and MIPI. 2. Internal Power Gating of PCH controllers – Each host controller (that is, xHCI, AHCI), PCIe* root port or embedded subsystem (ISH, Intel[®] CSME, Audio) when becoming sufficiently idle can autonomously power gate its core digital logic and local memory arrays. xHCI power gating is on a per port basis. 						

Table 71.PCH Low Power State

24 MHz Crystal Shutdown

When the CPU and system are in a power management state that can tolerate gating the 24 MHz crystal clock, this circuit can be powered down. This occurs when the processor enters C10 state, the PCH is in LP3 and all other consumers of the 24 MHz XTAL de-assert their clock request.

External Power Gating for MPHY/SRAM

External power gating for the MPHY and SRAM supply for additional power savings during connected standby states can be implemented by using EXT_PWR_GATE# to control a FET gating off the supply to PCH. The ramp time of the FET can be controlled via MODPHY_PM_CFG3.

CPU_C10_GATE#

When asserted, CPU_C10_GATE# is the indication to the system that the processor is entering C10 and can handle the voltages on the VCCIO, VCCSTG and VCCPLL_OC rails being lowered to 0V. When de-asserted, the VCCIO and VCCSTG rails must ramp back up to their operational voltage levels. The power good indicators for these rails must still be asserted high when these rails are lowered to 0V during CPU_C10_GATE# assertion and while these rails ramp back up to their operational levels after CPU_C10_GATE# de-assertion.

NOTE

VCCIO, VCCSTG and VCCPLL_OC are processor power rails.



SLP_S0#

SLP_SO# is the indication to the system to enter the deterministic idle state (S0i3). This is a PCH hardware controlled output pin. This signal is defined as active low which means a OV indicates the deterministic idle state. Additional power saving steps such as VPCLVM may happen during this state.

VCCPRIM_CORE Low Voltage Mode (VPCLVM)

When SLP_SO# asserts and the PCH enters the deterministic idle state, the power supplied to the VCCPRIM_CORE rail can transition to a lower 0.75V with tolerance of +60mV/-40mV to further reduce the PCH idle power. PMIC or discrete VR solutions that support this low voltage mode would use the SLP_SO# input assertion as indication of entry into VPCLVM and de-assertion as an indication to exit VPCLVM.

NOTE

1. The VCCPRIM_CORE voltage level during VPMLVM is lower than the active 1.05 V voltage level.

25.4.3 PCH and System Power States

Below table shows the power states defined for PCH-based platforms. The state names generally match the corresponding ACPI states.

Table 72.General Power States for Systems Using the PCH

State / Substates	Legacy Name/Description
G0/S0/C0	Full On : Processor operating. Individual devices may be shut down or be placed into lower power states to save power.
G0/S0/Cx	Cx State : Cx states are processor power states within the S0 system state that provide for various levels of power savings. The processor manages c-state itself. The actual c-state is not passed to the PCH. Only c-state related messages are sent to the PCH and PCH will base its behavior on the actual data passed.
G1/S3	Suspend-To-RAM (STR): The system context is maintained in system DRAM, but power is shut off to non-critical circuits. Memory is retained and refreshes continue. All external clocks stop except RTC.
G1/S4	Suspend-To-Disk (STD): The context of the system is maintained on the disk. All power is then shut off to the system except for the logic required to resume.
G2/S5	Soft Off (SOFF): System context is not maintained. All power is shut off except for the logic required to restart. A full boot is required when waking.
S0ix	S0 idle states are often referred as S0ix states. CPU PKG C-states and platform latency tolerance will decide when to take the aggressive power management actions.
Deep Sx	Deep Sx: An optional low power state where system context may or may not be maintained depending upon entry condition. All power is shut off except for minimal logic that allows exiting Deep Sx. If Deep Sx state was entered from S4 state, then the resume path will place system back into S4. If Deep Sx state was entered from S5 state, then the resume path will place system back into S5.
G3	Mechanical OFF (M-Off): System context not maintained. All power is shut off except for the RTC. No "Wake" events are possible. This state occurs if the user removes the main system batteries in a mobile system, turns off a mechanical switch, or if the system power supply is at a level that is insufficient to power the "waking" logic. When system power returns, transition will depend on the state just prior to the entry to G3 and the AFTERG3_EN bit in the General Power Management Configuration (GEN_PMCON) register. Refer Table 78 on page 191 for more details.



The following table shows the transitions rules among the various states.

NOTE

Transitions among the various states may appear to temporarily transition through intermediate states. For example, in going from S0 to S4, it may appear to pass through the G1/S3 state. These intermediate transitions and states are not listed in the below table.

Table 73. State Transition Rules for the PCH

Present State	Transition Trigger	Next State
G0/S0/C0	 OPI Msg SLP_EN bit set Power Button Override^{3,5} Mechanical Off/Power Failure 	 G0/S0/Cx G1/Sx or G2/S5 state G2/S5 G3
G0/S0/Cx	 OPI Msg Power Button Override^{3,5} Mechanical Off/Power Failure 	 G0/S0/C0 S5 G3
G1/S3	 Any Enabled Wake Event Power Button Override^{3,5} Mechanical Off/Power Failure 	 G0/S0/C0² G2/S5 G3
G1/S4	 Any Enabled Wake Event Power Button Override^{3,5} Conditions met as described in Entry into Deep Sx and Exit from Deep Sx in Deep Sx on page 191 Mechanical Off/Power Failure 	 G0/S0/C0² G2/S5 Deep S4 G3
G2/S5	 Any Enabled Wake Event Conditions met as described in Entry into Deep Sx and Exit from Deep Sx in Deep Sx on page 191 Mechanical Off/Power Failure 	 G0/S0/C0² Deep S5 G3
G2/Deep Sx	 Any Enabled Wake Event ACPRESENT Assertion Mechanical Off/Power Failure Power Button Override 	 G0/S0/C0² G1/S4 or G2/S5 (Refer Exit from Deep Sx in Deep Sx on page 191) G3 G2/S5
G3	Power Returns	 S0/C0 (reboot) or G2/S5⁴ (stay off until power button pressed or other wake event)^{1,2}
 Transition inactive in 3. Includes 	n mobile configurations. all other applicable types of events t	power failure. e S0 state are deferred until BATLOW# is hat force the host into and stay in G2/S5.

If the system was in G1/S4 before G3 entry, then the system will go to S0/C0 or G1/S4.

- 5. Upon entry to S5 due to a power button override, if Deep S5 is enabled and conditions are
 - met per Deep Sx on page 191, the system will transition to Deep S5.

25.4.4 System Power Planes

The system has several independent power planes, as described in below table.



NOTE

When a particular power plane is shut off, it should go to a 0 V level.

Table 74.System Power Plane

Plane	Controlled By	Description
Processor	SLP_S3# signal	The SLP_S3# signal can be used to cut the power to the processor completely.
Main (Applicable to Platform, PCH does not have a Main well)	SLP_S3# signal	 When SLP_S3# goes active, power can be shut off to any circuit not required to wake the system from the S3 state. Since the S3 state requires that the memory context be preserved, power must be retained to the main memory. The processor, LPC I/F, and PCI Express will typically be power-gated when the Main power plane is shut, although there may be small subsections powered. <i>Note:</i> The PCH power is not controlled by the SLP_S3# signal, but instead by the SLP_SUS# signal.
Memory	SLP_S4# signal SLP_S5# signal	When SLP_S4# goes active, power can be shut off to any circuit not required to wake the system from the S4. Since the memory context does not need to be preserved in the S4 state, the power to the memory can also be shut down. When SLP_S5# goes active, power can be shut off to any circuit not required to wake the system from the S5 state. Since the memory context does not need to be preserved in the S5 state, the power to the memory can also be shut.
Intel [®] CSME	SLP_A#	SLP_A# signal is asserted when the Intel [®] CSME platform goes to M- Off or M3-PG. Depending on the platform, this pin may be used to control power to various devices that are part of the Intel [®] CSME sub- system in the platform.
LAN	SLP_LAN#	This signal is asserted in Sx/M-Off or Sx/M3-PG when both host and Intel [®] CSME WoL are not supported. This signal can be use to control power to the Intel GbE PHY.
Primary/ Suspend Well	SLP_SUS#	This signal is asserted when the Primary/Suspend rails can be externally shut off for enhanced power saving.
MPHY and SRAM	EXT_PWR_GATE#	This signal is asserted in connected standby state where the MPHY and SRAM power supply can be gated.
DEVICE[n]	Implementation Specific	Individual subsystems may have their own power plane. For example, GPIO signals may be used to control the power to disk drives, audio amplifiers, or the display screen.

25.4.5 SMI#/SCI Generation

Upon any enabled SMI event taking place while the End of SMI (EOS) bit is set, the PCH will clear the EOS bit and assert SMI to the processor, which will cause it to enter SMM space. SMI assertion is performed using a Virtual Legacy Wire (VLW) message. Prior system generations (those based upon legacy processors) used an actual SMI# pin.

Once the SMI VLW has been delivered, the PCH takes no action on behalf of active SMI events until Host software sets the End of SMI (EOS) bit. At that point, if any SMI events are still active, the PCH will send another SMI VLW message.



The SCI is a level-mode interrupt that is typically handled by an ACPI-aware operating system. In non-APIC systems (which is the default), the SCI IRQ is routed to one of the 8259 interrupts (IRQ 9, 10, or 11). The 8259 interrupt controller must be programmed to level mode for that interrupt.

In systems using the APIC, the SCI can be routed to interrupts 9, 10, 11, 20, 21, 22, or 23. The interrupt polarity changes depending on whether it is on an interrupt shareable with a PIRQ or not. The interrupt remains asserted until all SCI sources are removed.

The following table shows which events can cause an SMI and SCI.

NOTE

Some events can be programmed to cause either an SMI or SCI. The usage of the event for SCI (instead of SMI) is typically associated with an ACPI-based system. Each SMI or SCI source has a corresponding enable and status bit.

Cause	SCI	SMI	Additional Enables (Note 1)	Where Reported
PME#	Yes	Yes	PME_EN=1	PME_STS
PME_B0 (Internal, Bus 0, PME-Capable Agents)	Yes	Yes	PME_B0_EN=1	PME_B0_STS
PCI Express* PME Messages	Yes	Yes	PCI_EXP_EN=1 (Not enabled for SMI)	PCI_EXP_STS
PCI Express Hot-Plug Message	Yes	Yes	HOT_PLUG_EN=1 (Not enabled for SMI)	HOT_PLUG_STS
Power Button Press	Yes	Yes	PWRBTN_EN=1	PWRBTN_STS
Power Button Override (Note 6)	Yes	No	None	PRBTNOR_STS
RTC Alarm	Yes	Yes	RTC_EN=1	RTC_STS
ACPI Timer overflow (2.34 seconds)	Yes	Yes	TMROF_EN=1	TMROF_STS
GPIO (Note 8)	Yes	Yes		
LAN_WAKE#	Yes	Yes	SCI_EN=0, LAN_WAKE_EN=1	LAN_WAKE_STS
TCO SCI message from processor	Yes	No	None	CPUSCI_STS
TCO SCI Logic	Yes	No	TCOSCI_EN=1	TCOSCI_STS
TCO SMI Logic	No	Yes	TCO_EN=1	TCO_STS
TCO SMI – Year 2000 Rollover	No	Yes	None	NEWCENTURY_STS
TCO SMI – TCO TIMEROUT	No	Yes	None	TIMEOUT
TCO SMI – OS writes to TCO_DAT_IN register	No	Yes	None	OS_TCO_SMI
TCO SMI – NMI occurred (and NMIs mapped to SMI)	No	Yes	NMI2SMI_EN=1	TCO_STS, NMI2SMI_STS
TCO SMI – INTRUDER# signal goes active	No	Yes	INTRD_SEL=10	INTRD_DET
TCO SMI – Changes of the WPD (Write Protect Disable) bit from 0 to 1	No	Yes	LE (Lock Enable)=1	BIOSWR_STS
		1	1	continued

Table 75.Causes of SMI and SCI



Cause	SCI	SMI	Additional Enables (Note 1)	Where Reported
TCO SMI – Write attempted to BIOS	No	Yes	WPD=0	BIOSWR_STS
BIOS_RLS written to 1 (Note 7)	Yes	No	GBL_EN=1	GBL_STS
GBL_RLS written to	No	Yes	BIOS_EN=1	BIOS_STS
Write to B2h register	No	Yes	$APMC_EN = 1$	APM_STS
Periodic timer expires	No	Yes	PERIODIC_EN=1	PERIODIC_STS
64 ms timer expires	No	Yes	SWSMI_TMR_EN=1	SWSMI_TMR_STS
Enhanced USB Legacy Support Event	No	Yes	LEGACY_USB2_EN = 1	LEGACY_USB2_STS
Serial IRQ SMI reported	No	Yes	None	SERIRQ_SMI_STS
Device monitors match address in its range	No	Yes	Refer DEVTRAP_STS register description	DEVTRAP_STS
SMBus Host Controller	No	Yes	SMB_SMI_EN, Host Controller Enabled	SMBus host status reg.
SMBus Slave SMI message	No	Yes	None	SMBUS_SMI_STS
SMBus SMBALERT# signal active	No	Yes	None	SMBUS_SMI_STS
SMBus Host Notify message received	No	Yes	HOST_NOTIFY_INTREN	SMBUS_SMI_STS, HOST_NOTIFY_STS
BATLOW# assertion	Yes	Yes	BATLOW_EN=1	BATLOW_STS
Access microcontroller 62h/66h	No	Yes	MCSMI_EN	MCSMI_STS
SLP_EN bit written to 1	No	Yes	SMI_ON_SLP_EN=1	SMI_ON_SLP_EN_STS
SPI Command Completed	No	Yes	None	SPI_SMI_STS
eSPI SCI/SMI Request	Yes	Yes	eSPI_SCI_EN For SMI, refer eSPI section	eSPI_SCI_STS eSPI_SMI_STS
Software Generated GPE	Yes	Yes	SWGPE_EN=1	SWGPE_STS
Intel [®] CSME	Yes	Yes	ME_SCI_EN=1 ME_SCI_EN=0; ME_SMI_EN=1;	ME_SCI_STS ME_SMI_STS
GPIO Lockdown Enable bit changes from `1' to `0'	No	Yes	GPIO_UNLOCK_SMI_EN=1	GPIO_UNLOCK_SMI_STS
USB 3.2(xHCI) SMI Event	No	Yes	XHCI_SMI_EN=1	XHCI_SMI_STS
Wake Alarm Device Timer	Yes	Yes	WADT_EN	WADT_STS
ISH	Yes	No	ISH_EN	ISH_STS
RTC update-in-progress	No	Yes	Refer I/O Trap Register section	RTC_UIP_SMI_STS
			•	continued



Cause	SCI	SMI	Additional Enables (Note 1)	Where Reported
SIO SMI events	No	Yes	SIP_SMI_EN	SIO_SMI_STS
SCC	No	Yes	SCC_SMI_EN	SCC_SMI_STS

Notes: 1. SCI_EN must be 1 to enable SCI, except for BIOS_RLS. SCI_EN must be 0 to enable SMI.

2. SCI can be routed to cause interrupt 9:11 or 20:23 (20:23 only available in APIC mode).

3. GBL_SMI_EN must be 1 to enable SMI.

- 4. EOS must be written to 1 to re-enable SMI for the next 1.
- 5. The PCH must have SMI fully enabled when the PCH is also enabled to trap cycles. If SMI is not enabled in conjunction with the trap enabling, then hardware behavior is undefined.
- 6. When a power button override first occurs, the system will transition immediately to S5. The SCI will only occur after the next wake to S0 if the residual status bit (PRBTNOR_STS) is not cleared prior to setting SCI_EN.
- 7. GBL_STS being set will cause an SCI, even if the SCI_EN bit is not set. Software must take great care not to set the BIOS_RLS bit (which causes GBL_STS to be set) if the SCI handler is not in place.
- 8. Refer #unique_212 for specific GPIOs enabled for SCIs and/or SMIs.

PCI Express* SCI

PCI Express ports and the processor have the ability to cause PME using messages. When a PME message is received, the PCH will set the PCI_EXP_STS bit. If the PCI_EXP_EN bit is also set, the PCH can cause an SCI using the GPE0_STS register.

PCI Express* Hot-Plug

PCI Express* has a hot-plug mechanism and is capable of generating a SCI using the GPE0 register. It is also capable of generating an SMI. However, it is not capable of generating a wake event.

25.4.6 C-States

PCH-based systems implement C-states by having the processor control the states. The chipset exchanges messages with the processor as part of the C-state flow, but the chipset does not directly control any of the processor impacts of C-states, such as voltage levels or processor clocking.

25.4.7 Dynamic 24 MHz Clock Control

The 24 MHz clock can be dynamically controlled independent of any other low-power state.

The Dynamic 24 MHz Clock control is handled using the following signal:

CLKRUN#: Used by LPC peripherals or other legacy devices to request the system 24 MHz clock to run.

Conditions for Checking the 24 MHz Clock

When there is a lack of activity, the PCH has the capability to stop the 24 MHz clocks to conserve power. "Clock activity" is defined as any activity that would require the 24 MHz clock to be running.

Any of the following conditions will indicate that it is **not okay** to stop the 24 MHz clock:

- Cycles on LPC
- SERIRQ activity



Conditions for Maintaining the 24 MHz Clock

LPC or any other devices that wish to maintain the 24 MHz clock running will observe the CLKRUN# signal de-asserted, and then must re-assert if (drive it low) within 92 clocks.

- When the PCH has tri-stated the CLKRUN# signal after de-asserting it, the PCH then checks to see if the signal has been re-asserted (externally).
- After observing the CLKRUN# signal asserted for 1 clock, the PCH again starts asserting the signal.

Conditions for Stopping the 24 MHz Clock

- When there is a lack of activity (as defined above) for 29 to 30 clock cycles, the PCH de-asserts (drive high) CLKRUN# for 1 clock cycle and then tri-states the signal.
- If no device drives CLKRUN# low within 6 clock cycles after it has been deasserted, the PCH will stop the 24 MHz clocks.

Conditions for Re-starting the 24 MHz Clock

- A peripheral asserts CLKRUN# to indicate that it needs the 24 MHz clock restarted.
- Observing the CLKRUN# signal asserted externally for 1 (free running) clock, the PCH again starts driving CLKRUN# asserted.

If an internal source requests the clock to be re-started, the PCH re-asserts CLKRUN#, then the PCH will start the 24 MHz clocks.

25.4.8 Sleep States

Sleep State Overview

The PCH directly supports different sleep states (S3–S5), which are entered by methods such as setting the SLP_EN bit or due to a Power Button press. The entry to the Sleep states is based on several assumptions:

• The G3 state cannot be entered using any software mechanism. The G3 state indicates a complete loss of power.

Initiating Sleep State

Sleep states (S3–S5) are initiated by:

- Masking interrupts, turning off all bus master enable bits, setting the desired type in the SLP_TYP field, and then setting the SLP_EN bit. The hardware then attempts to gracefully put the system into the corresponding Sleep state.
- Pressing the PWRBTN# Signal for more than 4 seconds to cause a Power Button Override event. In this case the transition to the S5 state is less graceful, since there are no dependencies on OPI messages from the processor or on clocks other than the RTC clock.
- Assertion of the THERMTRIP# signal will cause a transition to the S5 state. This can occur when system is in S0 state.
- Shutdown by integrated manageability functions (ASF/Intel[®] AMT).
- Internal watchdog timer Timeout events.



Table 76. Sleep Types

Sleep Type	Comment
S3	The PCH asserts SLP_S3#. The SLP_S3# signal controls the power to non-critical circuits. Power is only retained to devices needed to wake from this sleeping state, as well as to the memory.
S4	The PCH asserts SLP_S3# and SLP_S4#. The SLP_S4# signal shuts off the power to the memory subsystem. Only devices needed to wake from this state should be powered.
S5	The PCH asserts SLP_S3#, SLP_S4# and SLP_S5#.

Exiting Sleep States

Sleep states (S3–S5) are exited based on wake events. The wake events forces the system to a full on state (S0), although some non-critical subsystems might still be shut off and have to be brought back manually. For example, the hard disk may be shut off during a sleep state and have to be enabled using a GPIO pin before it can be used.

Upon exit from the PCH-controlled Sleep states, the WAK_STS bit is set. The possible causes of wake events (and their restrictions) are shown in below table.

NOTE

If the BATLOW# signal is asserted, the PCH does not attempt to wake from an S3–S5 state, nor will it exit from Deep Sx state, even if the power button is pressed. This prevents the system from waking when the battery power is insufficient to wake the system. Wake events that occur while BATLOW# is asserted are latched by the PCH, and the system wakes after BATLOW# is de-asserted.

Cause	How Enabled	Wake from Sx	Wake from Deep Sx	Wake from Sx After Power Loss (Note 2)	Wake from "Reset" Types (Note 3)
RTC Alarm	Set RTC_EN bit in PM1_EN_STS register.	Yes	Yes	Yes	No
Power Button	Always enabled as Wake event.	Yes	Yes	Yes	Yes
Any GPIOs except DSW GPIOs can be enabled for wake ⁵		Yes	No	No	No
LAN_WAKE#	Enabled natively (unless pin is configured to be in GPIO mode)	Yes	Yes	Yes	Yes
Intel [®] High Definition Audio	Event sets PME_B0_STS bit; PM_B0_EN must be enabled. Can not wake from S5 state if it was entered due to power failure or power button override.	Yes	No	Yes	No
Primary PME#	PME_B0_EN bit in GPE0_EN[127:96] register.	Yes	No	Yes	No
Secondary PME#	Set PME_EN bit in GPE0_EN[127:96] register.	Yes	No	Yes	No
PCI Express* WAKE# pin	PCIEXP_WAKE_DIS bit.	Yes	Yes	Yes	No
SMBALERT#	(Note 4)	Yes	No	Yes	Yes
					continued

Table 77.Causes of Wake Events



Cause	How Enabled	Wake from Sx	Wake from Deep Sx	Wake from Sx After Power Loss (Note 2)	Wake from "Reset" Types (Note 3)
SMBus Slave Wake Message (01h)	Wake/SMI# command always enabled as a Wake event.				
	Note: SMBus Slave Message can wake the system from S3–S5, as well as from S5 due to Power Button Override.	Yes	No	Yes	Yes
SMBus Host Notify message received	HOST_NOTIFY_WKEN bit SMBus Slave Command register. Reported in the SMB_WAK_STS bit in the GPE0_STS register.	Yes	No	Yes	Yes
Intel [®] CSME Non- Maskable Wake	Always enabled as a wake event.	Yes	No	Yes	Yes
Integrated WoL Enable Override	WoL Enable Override bit (in Configuration Space).	Yes	Yes	Yes	Yes
Wake Alarm Device	WADT_EN in GPE0_EN[127:96]	Yes	Yes	No	No

Notes: 1. If BATLOW# signal is low, PCH will not attempt to wake from S3-S5 (nor will it exit Deep Sx), even if valid wake event occurs. This prevents the system from waking when battery power is insufficient to wake the system. However, once BATLOW# goes back high, the system will boot.

2. This column represents what the PCH would honor as wake events but there may be enabling dependencies on the device side which are not enabled after a power loss.

3. Reset Types include: Power Button override, Intel[®] CSME -initiated power button override, Intel[®] CSME -initiated host partition reset with power down, Intel[®] CSME Watchdog Timer, SMBus unconditional power down, processor thermal trip, PCH catastrophic temperature event.

- 4. SMBALERT# signal is multiplexed with a GPIO pin that defaults to GPIO mode. Hence, SMBALERT# related wakes are possible only when this GPIO is configured in native mode, which means that BIOS must program this GPIO to operate in native mode before this wake is possible. Because GPIO configuration is in the resume well, wakes remain possible until one of the following occurs: BIOS changes the pin to GPIO mode, a G3 occurs or Deep Sx entry occurs.
- 5. There are only 72 bits in the GPE registers to be assigned to GPIOs, though any of the GPIOs can trigger a wake, only those status of GPIO mapped to 1-tier scheme are directly accessible through the GPE status registers. For those GPIO mapped under 2-tier scheme, their status would be reflected under single master status, "GPIO_TIER2_SCI_STS" or GPE0_STS and further comparison needed to know which 2-tier GPI(s) has triggered the GPIO Tier 2 SCI.
- 6. A change in AC_PRESENT causes an exit from Deep Sx to Sx, but the system will not wake all the way to S0.

PCI Express* WAKE# Signal and PME Event Message

PCI Express* ports can wake the platform from any sleep state (S3, S4, S5 or Deep Sx) using the WAKE# pin. WAKE# is treated as a wake event, but does not cause any bits to go active in the GPE_STS register.

PCI Express* ports and the processor have the ability to cause PME using messages. These are logically OR'd to set the single PCI_EXP_STS bit. When a PME message is received, the PCH will set the PCI_EXP_STS bit. If the PCI_EXP_EN bit is also set, the PCH can cause an SCI via GPE0_STS register.

Sx-G3-Sx, Handling Power Failures

Depending on when the power failure occurs and how the system is designed, different transitions could occur due to a power failure.

The AFTERG3_EN bit provides the ability to program whether or not the system should boot once power returns after a power loss event. If the policy is to not boot, the system remains in an S5 state (unless previously in S4). There are only three possible events that will wake the system after a power failure.



- 1. **PWRBTN#**: PWRBTN# is always enabled as a wake event. When PCH DPWROK is low (G3 state), the PWRBTN STS bit is reset. When the PCH exits G3 after power returns (PCH DPWROK goes high), the PWRBTN# signal will transition high due internal Pull-up, unless there is an on-board Pull-up/Pull-down) and the PWRBTN STS bit is 0.
- 2. **RTC Alarm**: The RTC EN bit is in the RTC well and is preserved after a power loss. Like PWRBTN STS the RTC STS bit is cleared when PCH DPWROK goes low.
- 3. Any enabled wake event that was preserved through the power failure.

DSW PWROK going low would place the PCH into a G3 state.

Although PME_EN is in the RTC well, this signal cannot wake the system after a power loss. PME_EN is cleared by RTCRST#, and PME_STS is cleared by RSMRST#.

Table 78. **Transitions Due to Power Failure**

1 0 1 0	S5 S0 S4
1	
1	S4
0	
0	S0
1	S5
0	S0
1	Deep S4 ¹
0	S0
1	Deep S5 ¹
0	S0
	1 0 1

Deep Sx

To minimize power consumption while in S4/S5, the PCH supports a lower power, lower featured version of these power states known as Deep Sx. In the Deep Sx state, the Suspend wells are powered off, while the Deep Sx Well (DSW) remains powered. A limited set of wake events are supported by the logic located in the DSW.

The Deep Sx capability and the SUSPWRDNACK pin functionality are mutually exclusive.

Entry Into Deep Sx

A combination of conditions is required for entry into Deep Sx.

All of the following must be met:

- 1. Intel[®] CSME in M-Off or M3-PG AND
- 2. Either a. or b. as defined below
 - a. (S4AC_GATE_SUS AND S4) OR (S5AC_GATE_SUS AND S5)), OR
 - b. ((AC PRESENT = 0) AND ((S3DC GATE SUS AND S3) OR (S4DC GATE SUS AND S4) OR (S5DC GATE SUS AND S5)))



NOTES

- 1. If REQ_CNV_NOWAKE_DSX is set to `1,' connectivity wake must be disabled in addition to the above DeepSx entry conditions to allow DeepSx entry.
- 2. If REQ_BATLOW_DSX is set to `1,' BATLOW# must be asserted in addition to the above DeepSx entry conditions to allow DeepSx entry.

Table 79.Supported Deep Sx Policy Configurations

Configuration	S4DC_GATE_S US	S4AC_GATE_S US	S5DC_GATE_S US	S5AC_GATE_S US			
1. Enabled in S5 when on Battery (ACPRESENT = 0)	0	0	1	0			
2. Enabled in S5 (ACPRESENT not considered)	0	0	1	1			
3. Enabled in S4 and S5 when on Battery (ACPRESENT = 0)	1	0	1	0			
4. Enabled in S4 and S5 (ACPRESENT not considered)	1	1	1	1			
5. Enabled in S4 and S5 when on Battery (ACPRESENT = 0)	1	0	1	0			
6. Enabled in S4 and S5 (ACPRESENT not considered)	1	1	1	1			
7. Deep S4/ S5 disabled	0	0	0	0			
Note: All other configurations are RESERVED.							

The PCH also performs a SUSWARN#/SUSACK# handshake to ensure the platform is ready to enter Deep Sx. The PCH asserts SUSWARN# as notification that it is about to enter Deep Sx. Before the PCH proceeds and asserts SLP_SUS#, the PCH waits for SUSACK# to assert.

• Exit from Deep Sx

While in Deep Sx, the PCH monitors and responds to a limited set of wake events (RTC Alarm, Power Button and WAKE#). Upon sensing an enabled Deep Sx wake event, the PCH brings up the Suspend well by de-asserting SLP_SUS#.

Table 80.Deep Sx Wake Events

Event	Enable
RTC Alarm	RTC_EN bit in PM1_EN_STS Register
Power Button	Always enabled
PCIe* WAKE# pin	PCIEXP_WAKE_DIS
Wake Alarm Device	WADT_EN in GPE0_EN
LAN_WAKE#	Enabled natively (unless the pin is configured to be in the GPIO mode)

ACPRESENT has some behaviors that are different from the other Deep Sx wake events. If the Intel[®] CSME has enabled ACPRESENT as a wake event then it behaves just like any other Intel[®] CSME Deep Sx wake event. However, even if ACPRESENT wakes are not enabled, if the Host policies indicate that Deep Sx is only supported when on battery, then ACPRESENT going high will cause the PCH



to exit Deep Sx. In this case, the Suspend wells gets powered up and the platform remains in Sx/M-Off or Sx/M3-PG. If ACPRESENT subsequently drops (before any Host or Intel[®] CSME wake events are detected), the PCH will re-enter Deep Sx.

25.4.9 Event Input Signals and Their Usage

The PCH has various input signals that trigger specific events. This section describes those signals and how they should be used.

PWRBTN# (Power Button)

The PCH PWRBTN# signal operates as a "Fixed Power Button" as described in the *Advanced Configuration and Power Interface Specification*. PWRBTN# signal has a 16 ms de-bounce on the input. The state transition descriptions are included in the below table.

After any PWRBTN# assertion (falling edge), the 16ms de-bounce applies before the state transition starts if PB_DB_MODE='0'. If PB_DB_MODE='1', the state transition starts right after any PWRBTN# assertion (before passing through the de-bounce logic) and subsequent falling PWRBTN# edges are ignored until after 16ms.

During the time that any SLP_* signal is stretched for an enabled minimum assertion width, the host wake-up is held off. As a result, it is possible that the user will press and continue to hold the Power Button waiting for the system to wake. Unfortunately, a 4 second press of the Power Button is defined as an unconditional power down, resulting in the opposite behavior that the user was intending. Therefore, the Power Button Override Timer will be extended to 9-10 seconds while the SLP_* stretching timers are in progress. Once the stretching timers have expired, the Power Button will awake the system. If the user continues to press Power Button for the remainder of the 9-10 seconds it will result in the override condition to S5. Extension of the Power Button Override timer is only enforced following graceful sleep entry and during host partition resets with power cycle or power down. The timer is not extended immediately following power restoration after a global reset, G3 or Deep Sx.

The PCH also supports modifying the length of time the Power Button must remain asserted before the unconditional power down occurs (4-14 seconds). The length of the Power Button override duration has no impact on the "extension" of the power button override timer while SLP_* stretching is in progress. The extended power button override period while stretching is in progress remains 9-10 seconds in all cases.

Present State	Event	Transition/Action	Comment
S0/Cx	PWRBTN# goes low	SMI or SCI generated (depending on SCI_EN, PWRBTN_EN and GLB_SMI_EN)	Software typically initiates a Sleep state Note: Processing of transitions starts within 100 us of the PWRBTN# input pin to PCH going low. ¹
S3 - S5	PWRBTN# goes low	Wake Event. Transitions to S0 state	Standard wakeup
			continued

Table 81. Transitions Due to Power Button



Present State	Event	Transition/Action	Comment
			Note: Could be impacted by SLP_* min assertion. The minimum time the PWRBTN# pin should be asserted is 150 us. The PCH will start processing this change once the minimum time requirement is satisfied. ¹
Deep Sx	PWRBTN# goes low	Wake Event. Transitions to S0 state	Standard wakeup Note: Could be impacted by SLP_* min assertion. The minimum time the PWRBTN# pin should be asserted is 150 us. The PCH will start processing this change once the minimum time requirement is satisfied but subsequently the PWRBTN# pin needs to de-assert for at least 500 us after RSMRST# de-assertion otherwise the system waits indefinitely in S5 state. ¹
G3	PWRBTN# pressed	None	 No effect since no power Not latched nor detected <i>Notes:</i> 1. During G3 exit, PWRBTN# pin must be kept de-asserted for a minimum time of 500 us after the RSMRST# has de- asserted.² 2. Beyond this point, the minimum time the PWRBTN# pin has to be asserted to be registered by PCH as a valid wake event is 150 us.¹
S0 - S4	PWRBTN# held low for at least 4 3 consecutive seconds	Unconditional transition to S5 state and if Deep Sx is enabled and conditions are met per Deep Sx on page 191, the system will then transition to Deep Sx.	No dependence on processor or any other subsystem Note: Due to internal PCH latency, it could take up to an additional ~1.3s after PWRBTN# has been held low for 4s before the system would begin transitioning to S5.
2.	processing of power but This minimum time is ir	ton assertions. ndependent of the PM_CFG.F	dds 16 ms to the start/minimum time for PB_DB_MODE value. configurable via PM_CFG2.PBOP. 4

Power Button Override Function

If PWRBTN# is observed active for at least four consecutive seconds (always sampled after the output from debounce logic), the PCH should unconditionally transition to the G2/S5 state or Deep Sx, regardless of present state (S0 – S4), even if the PCH_PWROK is not active. In this case, the transition to the G2/S5 state or Deep Sx does not depend on any particular response from the processor, nor any similar dependency from any other subsystem.

The minimum period is configurable by BIOS and defaults to the legacy value of 4 seconds.



The PWRBTN# status is readable to check if the button is currently being pressed or has been released. If PM_CFG.PB_DB_MODE='0', the status is taken after the debounce. If PM_CFG.PB_DB_MODE='1', the status is taken before the de-bounce. In either case, the status is readable using the PWRBTN_LVL bit.

NOTE

The 4-second PWRBTN# assertion should only be used if a system lock-up has occurred.

Sleep Button

The Advanced Configuration and Power Interface Specification defines an optional Sleep button. It differs from the power button in that it only is a request to go from S0 to S3–S4 (not S5). Also, in an S5 state, the Power Button can wake the system, but the Sleep Button cannot.

Although the PCH does not include a specific signal designated as a Sleep Button, one of the GPIO signals can be used to create a "Control Method" Sleep Button. Refer the *Advanced Configuration and Power Interface Specification* for implementation details.

PME# (PCI Power Management Event)

The PME# signal comes from a PCI Express* device to request that the system be restarted. The PME# signal can generate an SMI#, SCI, or optionally a wake event. The event occurs when the PME# signal goes from high to low. No event is caused when it goes from low to high.

There is also an internal PME_B0_STS bit that will be set by the PCH when any internal device with PCI Power Management capabilities on bus 0 asserts the equivalent of the PME# signal. This is separate from the external PME# signal and can cause the same effect.

SYS_RESET# Signal

When the SYS_RESET# pin is detected as active (on signal's falling edge if de-bounce logic is disabled, or after 16 ms if 16ms de-bounce logic is enabled), the PCH attempts to perform a "graceful" reset by entering a host partition reset entry sequence.

Once the reset is asserted, it remains asserted for 5 to 6 ms regardless of whether the SYS_RESET# input remains asserted or not. It cannot occur again until SYS_RESET# has been detected inactive after the de-bounce logic, and the system is back to a full S0 state with PLTRST# inactive.

NOTES

- The normal behavior for a SYS_RESET# assertion is host partition reset without power cycle. However, if bit 3 of the CF9h I/O register is set to '1' then SYS_RESET# will result in a full power-cycle reset.
- 2. It is not recommended to use the PCH_PWROK pin for a reset button as it triggers a global power cycle reset.
- 3. SYS_RESET# is in the primary power well but it only affects the system when PCH_PWROK is high.



THERMTRIP# Signal

If THERMTRIP# goes active, the processor is indicating an overheat condition, and the PCH immediately transitions to an S5 state, driving SLP_S3#, SLP_S4#, SLP_S5# low, and setting the GEN_PMCON_2.PTS bit. The transition will generally look like a power button override.

When a THERMTRIP# event occurs, the PCH will power down immediately without following the normal S0 -> S5 path. The PCH will immediately drive SLP_S3#, SLP_S4#, and SLP_S5# low within 1 us after sampling THERMTRIP# active.

The reason the above is important is as follow: if the processor is running extremely hot and is heating up, it is possible (although very unlikely) that components around it, such as the PCH, are no longer executing cycles properly. Therefore, if THERMTRIP# goes active, and the PCH is relying on various handshakes to perform the power down, the handshakes may not be working, and the system will not power down. Hence the need for PCH to power down immediately without following the normal S0 -> S5 path.

The PCH provides filtering for short low glitches on the THERMTRIP# signal in order to prevent erroneous system shut downs from noise. Glitches shorter than 25 nsec are ignored.

PCH must only honor the THERMTRIP# pin while it is being driven to a valid state by the processor. The THERMTRIP# Valid Point ='0', implies PCH will start monitoring THERMTRIP# at PLTRST# de-assertion (default). The THERMTRIP# Valid Point ='1', implies PCH will start monitoring THERMTRIP# at CPUPWRGD assertion. Regardless of the setting, the PCH must stop monitoring THERMTRIP# at CPUPWRGD de-assertion.

NOTE

A thermal trip event will clear the PWRBTN_STS bit.

Sx_Exit_Holdoff#

When S3/S4/S5 is entered and SLP_A# is asserted, Sx_Exit_Holdoff# can be asserted by a platform component to delay resume to S0. SLP_A# de-assertion is an indication of the intent to resume to S0, but this will be delayed so long as Sx_Exit_Holdoff# is asserted. Sx_Exit_Holdoff is ignored outside of an S3/S4/S5 entry sequence with SLP_A# asserted. With the de-assertion of RSMRST# (either from G3->S0 or DeepSx->S0), this pin is a GPIO input and must be programmed by BIOS to operate as Sx_Exit_Holdoff. When SLP_A# is asserted (or it is de-asserted but Sx_Exit_Holdoff# is asserted), the PCH will not access SPI Flash. How a platform uses this signal is platform specific.

Requirements to support Sx_Exit_Holdoff#

If the PCH is in G3/DeepSx or in the process of exiting G3/DeepSx (RSMRST# is asserted), the EC must not allow RSMRST# to de-assert until the EC completed its flash accesses.

After the PCH has booted up to S0 at least once since the last G3 or DeepSx exit, the EC can begin monitoring SLP_A# and using the SX_EXIT_HOLDOFF# pin to stop the PCH from accessing flash. When SLP_A# asserts, if the EC intends to access flash, it will assert SX_EXIT_HOLDOFF#. To cover the case where the PCH is going through a



global reset, and not a graceful Sx+CMoff/Sx+CM3PG entry, the EC must monitor the SPI flash CS0# pin for 5ms after SLP_A# assertion before making the determination that it is safe to access flash.

- If no flash activity is seen within this 5ms window, the EC can begin accessing flash. Once its flash accesses are complete, the EC de-asserts (drives to `1') SX_EXIT_HOLDOFF# to allow the PCH to access flash.
- If flash activity is seen within this 5ms window, the PCH has gone through a global reset. And so the EC must wait until the PCH reaches S0 again before reattempting the holdoff flow.

25.4.10 ALT Access Mode

Before entering a low power state, several registers from powered down parts may need to be saved. In the majority of cases, this is not an issue, as registers have read and write paths. However, several of the ISA compatible registers are either read only or write only. To get data out of write-only registers, and to restore data into readonly registers, the PCH implements an ALT access mode.

If the ALT access mode is entered and exited after reading the registers of the PCH timer (8254), the timer starts counting faster (13.5 ms). The following steps listed below can cause problems:

- 1. BIOS enters ALT access mode for reading the PCH timer related registers.
- 2. BIOS exits ALT access mode.
- 3. BIOS continues through the execution of other needed steps and passes control to the operating system.

After getting control in step #3, if the operating system does not reprogram the system timer again, the timer ticks may be happening faster than expected.

Operating systems reprogram the system timer and therefore do not encounter this problem.

For other operating systems, the BIOS should restore the timer back to 54.6 ms before passing control to the operating system. If the BIOS is entering ALT access mode before entering the suspend state it is not necessary to restore the timer contents after the exit from ALT access mode.

Write Only Registers with Read Paths in ALT Access Mode

The registers described in below table have read paths in ALT access mode. The access number field in the table indicates which register will be returned per access to that port.

			Restore Data
I/O Addr	# of Rds	Access	Data
		1	PIC ICW2 of Master controller
20h	12	2	PIC ICW3 of Master controller
2011	12	3	PIC ICW4 of Master controller
		4	PIC OCW1 of Master controller ¹
			continued

Table 82. Write Only Registers with Read Paths in ALT Access Mode



			Restore Data
I/O Addr	# of Rds	Access	Data
		5	PIC OCW2 of Master controller
		6	PIC OCW3 of Master controller
		7	PIC ICW2 of Slave controller
		8	PIC ICW3 of Slave controller
		9	PIC ICW4 of Slave controller
		10	PIC OCW1 of Slave controller ¹
		11	PIC OCW2 of Slave controller
		12	PIC OCW3 of Slave controller
		1	Timer Counter 0 status, bits [5:0]
		2	Timer Counter 0 base count low byte
40h	7	3	Timer Counter 0 base count high byte
		6	Timer Counter 2 base count low byte
		7	Timer Counter 2 base count high byte
42h	1		Timer Counter 2 status, bits [5:0]
70h	1		Bit 7 = Read value is '0'. Bits [6:0] = RTC Address
Notes	OCW1 register 5, 3, 1, and 0		re entering ALT access mode.

PIC Reserved Bits

Many bits within the PIC are reserved, and must have certain values written in order for the PIC to operate properly. Therefore, there is no need to return these values in ALT access mode. When reading PIC registers from 20h and A0h, the reserved bits shall return the values listed in table below.

Table 83. PIC Reserved Bits Return Values

PIC Reserved Bits	Value Returned
ICW2(2:0)	000
ICW4(7:5)	000
ICW4(3:2)	00
ICW4(0)	0
OCW2(4:3)	00
OCW3(7)	0
OCW3(5)	Reflects bit 6
OCW3(4:3)	01



25.4.11 System Power Supplies, Planes, and Signals

Power Plane Control

The SLP_S3# output signal can be used to cut power to the system core supply, since it only goes active for the Suspend-to-RAM state (typically mapped to ACPI S3). Power must be maintained to the PCH primary well, and to any other circuits that need to generate Wake signals from the Suspend-to-RAM state. During S3 (Suspend-to-RAM) all signals attached to powered down planes will be tri-stated or driven low, unless they are pulled using a Pull-up resistor.

Cutting power to the system core supply may be done using the power supply or by external FETs on the motherboard.

The SLP_S4# output signal is used to remove power to additional subsystems that are powered during SLP_S3#, as well as power to the system memory, since the context of the system is saved on the disk. Cutting power to the memory may be done using the power supply, or by external FETs on the motherboard.

SLP_S5# output signal can be used to cut power to the system core supply.

SLP_A# output signal can be used to cut power to the Intel[®] Converged Security and Management Engine and SPI flash on a platform that supports the M3 state (for example, certain power policies in Intel[®] AMT).

SLP_LAN# output signal can be used to cut power to the external Intel GbE PHY device.

SLP_S4# and Suspend-to-RAM Sequencing

The system memory suspend voltage regulator is controlled by the Glue logic. The SLP_S4# signal should be used to remove power to system memory rather than the SLP_S5# signal. The SLP_S4# logic in the PCH provides a mechanism to fully cycle the power to the DRAM and/or detect if the power is not cycled for a minimum time.

NOTE

To use the minimum DRAM power-down feature that is enabled by the SLP_S4# Assertion Stretch Enable bit (D31:F0:A4h Bit 3), the DRAM power must be controlled by the SLP_S4# signal.

PCH_PWROK Signal

When asserted, PCH_PWROK is an indication to the PCH that its core well power rails are powered and stable. PCH_PWROK can be driven asynchronously. When PCH_PWROK is low, the PCH asynchronously asserts PLTRST#. PCH_PWROK must not glitch, even if RSMRST# is low.

It is required that the power associated with PCIe* have been valid for 99 ms prior to PCH_PWROK assertion in order to comply with the 100 ms PCIe* 2.0 specification on PLTRST# de-assertion.



NOTE

SYS_RESET# is recommended for implementing the system reset button. This saves external logic that is needed if the PCH_PWROK input is used. Additionally, it allows for better handling of the SMBus and processor resets and avoids improperly reporting power failures.

BATLOW# (Battery Low)

The BATLOW# input can inhibit waking from S3, S4, S5 and Deep Sx states if there is not sufficient power. It also causes an SMI if the system is already in an S0 state.

SLP_LAN# Pin Behavior

The PCH controls the voltage rails into the external LAN PHY using the SLP_LAN# pin.

- The LAN PHY is always powered when the Host and Intel[®] CSME systems are running.
 - SLP_LAN#='1' whenever SLP_S3#='1' or SLP_A#='1'.
- If the LAN PHY is required by Intel[®] CSME in Sx/M-Off or Deep Sx, Intel[®] CSME must configure SLP_LAN#='1' irrespective of the power source and the destination power state. Intel[®] CSME must be powered at least once after G3 to configure this.
- If the LAN PHY is required after a G3 transition, the host BIOS must set AG3_PP_EN.
- If the LAN PHY is required in Sx/M-Off, the host BIOS must set SX_PP_EN.
- If the LAN PHY is required in Deep Sx, the host BIOS must keep DSX_PP_DIS cleared.
- If the LAN PHY is not required if the source of power is battery, the host BIOS must set DC_PP_DIS.

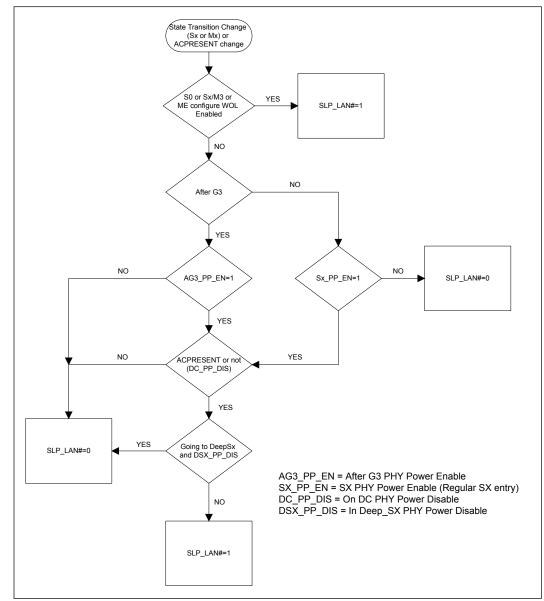
NOTE

Intel[®] CSME configuration of SLP_LAN# in Sx/M-Off and Deep Sx is dependent on Intel[®] CSME power policy configuration.

The flow chart below shows how a decision is made to drive SLP_LAN# every time its policy needs to be evaluated.







SLP_WLAN# Pin Behavior

The PCH controls the voltage rails into the external wireless LAN PHY using the SLP_WLAN# pin.

- The wireless LAN PHY is always powered when the Host is running.
 - SLP_WLAN#='1' whenever SLP_S3#='1'.
- If Wake on Wireless LAN (WoWLAN) is required from S3/S4/S5 states, the host BIOS must set HOST_WLAN_PP_EN.
- If WoWLAN is required from Deep Sx, the host BIOS must set DSX_WLAN_PP_EN.
- If Intel[®] CSME has access to the Wireless LAN device:



- The Wireless LAN device must always be powered as long as Intel[®] CSME is powered. SLP_WLAN#='1' whenever SLP_A#='1'.
- If Wake on Wireless LAN (WoWLAN) is required from M-Off state, Intel[®] CSME will configure SLP_WLAN#='1' in Sx/M-Off.

Intel[®] CSME configuration of SLP_WLAN# in Sx/M-Off is dependent on Intel[®] CSME power policy configuration.

When the Wireless LAN device is an integrated connectivity device (CNVi) the power to the CNVi external RF chip (CRF) must be always on. In this case the SLP_WLAN# shall not control the CRF 3.3V power rail.

EXT_PWR_GATE# Pin Behavior

EXT_PWR_GATE# can be used to control a FET gating off the MPHY/SRAM power supply to PCH. This provides additional power savings during connected standby states. The ramp time of the FET can be controlled via MODPHY_PM_CFG3.

It is expected that the MPHY/SRAM supply will ramp along with the other primary wells, and must be valid for at least 10ms before RSMRST# deassertion during a G3/DSx -> Sx transition. System designers will need to account for this behavior to make sure the rail turns on as expected.

SUSPWRDNACK/SUSWARN#/GPP_A13 Steady State Pin Behavior

Below table summarizes SUSPWRDNACK/SUSWARN#/GPP_A13 pin behavior.

Table 84. SUSPWRDNACK/SUSWARN#/GPP_A13 Pin Behavior

Pin	Deep Sx (Supported /Not- Supported)	GPP_A13 Input/Output (Determine by GP_IO_SEL bit)	Pin Value in S0	Pin Value in Sx/M-Off	Pin Value in Sx/M3	Pin Value in Deep Sx
SUSPWRDNACK	Not Supported	Native	0	Depends on Intel [®] CSME power package and power source (Note 1)	0	Off
SUSWARN#	Supported	Native	1	1 (Note 2)	1	Off
	Do not Care	IN	High-Z	High-Z	High-Z	Off
GPP_A13	Do not Care	OUT	Depends on GPP_A13 output data value	Depends on GPP_A13 output data value	Depends on GPP_A13 output data value	Off
2. If ente		n based on Intel [®] (in will assert and b				lrops



Table 85. SUSPWRDNACK During Reset

SPDA Value
0
0
PCH initially drive '0' and then drive per Intel [®] CSME power policy configuration.
-

RTCRST# and SRTCRST#

RTCRST# is used to reset PCH registers in the RTC Well to their default value. If a jumper is used on this pin, it should only be pulled low when system is in the G3 state and then replaced to the default jumper position. Upon booting, BIOS should recognize that RTCRST# was asserted and clear internal PCH registers accordingly. It is imperative that this signal not be pulled low in the S0 to S5 states.

SRTCRST# is used to reset portions of the Intel[®] Converged Security and Management Engine and should not be connected to a jumper or button on the platform. The only time this signal gets asserted (driven low in combination with RTCRST#) should be when the coin cell battery is removed or not installed and the platform is in the G3 state. Pulling this signal low independently (without RTCRST# also being driven low) may cause the platform to enter an indeterminate state. Similar to RTCRST#, it is imperative that SRTCRST# not be pulled low in the S0 to S5 states.

25.4.12 Legacy Power Management Theory of Operation

Instead of relying on ACPI software, legacy power management uses BIOS and various hardware mechanisms. The scheme relies on the concept of detecting when individual subsystems are idle, detecting when the whole system is idle, and detecting when accesses are attempted to idle subsystems.

However, the operating system is assumed to be at least APM enabled. Without APM calls, there is no quick way to know when the system is idle between keystrokes. The PCH does not support burst modes.

Mobile APM Power Management

In mobile systems, there are additional requirements associated with device power management. To handle this, the PCH has specific SMI traps available. The following algorithm is used:

- 1. The periodic SMI timer checks if a device is idle for the require time. If so, it puts the device into a low-power state and sets the associated SMI trap.
- 2. When software (not the SMI handler) attempts to access the device, a trap occurs (the cycle does not really go to the device and an SMI is generated).
- 3. The SMI handler turns on the device and turns off the trap.
- 4. The SMI handler exits with an I/O restart. This allows the original software to continue.



25.4.13 Reset Behavior

When a reset is triggered, the PCH will send a warning message to the processor to allow the processor to attempt to complete any outstanding memory cycles and put memory into a safe state before the platform is reset. When the processor is ready, it will send an acknowledge message to the PCH. Once the message is received the PCH asserts PLTRST#.

The PCH does not require an acknowledge message from the processor to trigger PLTRST#. A global reset will occur after four seconds if an acknowledge from the processor is not received.

When the PCH causes a reset by asserting PLTRST#, its output signals will go to their reset states.

A reset in which the host platform is reset and PLTRST# is asserted is called a Host Reset or Host Partition Reset. Depending on the trigger a host reset may also result in power cycling, refer below table for details. If a host reset is triggered and the PCH times out before receiving an acknowledge message from the processor a Global Reset with power-cycle will occur.

A reset in which the host and Intel[®] CSME partitions of the platform are reset is called a Global Reset. During a Global Reset, all PCH functionality is reset except RTC Power Well backed information and Suspend well status, configuration, and functional logic for controlling and reporting the reset. Intel[®] CSME and Host power back up after the power-cycle period.

Straight to S5 is another reset type where all power wells that are controlled by the SLP_S3#, SLP_S4#, and SLP_A# pins, as well as SLP_S5# and SLP_LAN# (if pins are not configured as GPIOs), are turned off. All PCH functionality is reset except RTC Power Well backed information and Suspend well status, configuration, and functional logic for controlling and reporting the reset. The host stays there until a valid wake event occurs.

The following table shows the various reset triggers.

Table 86. Causes of Host and Global Resets

Trigger	Host Reset Without Power Cycle ¹	Host Reset With Power Cycle ²	Global Reset With Power Cycle ³	Straight to S5 ⁶ (Host Stays There)
Write of 0Eh to CF9h (RST_CNT Register) when CF9h when Global Reset Bit=0b	No	Yes	No (Note 4)	
Write of 06h to CF9h (RST_CNT Register) when CF9h when Global Reset Bit=0b	Yes	No	No (Note 4)	
Write of 06h or 0Eh to CF9h (RST_CNT Register) when CF9h when Global Reset Bit=1b	No	No	Yes	
SYS_RESET# Asserted and CF9h (RST_CNT Register) Bit 3 = 0	Yes	No	No (Note 4)	
SYS_RESET# Asserted and CF9h (RST_CNT Register) Bit 3 = 1	No	Yes	No (Note 4)	
SMBus Slave Message received for Reset with Power-Cycle	No	Yes	No (Note 4)	
				continued

Power Management—Datasheet



Trigger	Host Reset Without Power Cycle ¹	Host Reset With Power Cycle ²	Global Reset With Power Cycle ³	Straight to S5 ⁶ (Host Stays There)
SMBus Slave Message received for Reset without Power-Cycle	Yes	No	No (Note 4)	
SMBus Slave Message received for unconditional Power Down	No	No	No	Yes
TCO Watchdog Timer reaches zero two times	Yes	No	No (Note 4)	
Power Failure: PCH_PWROK signal goes inactive in S0 or DSW_PWROK drops	No	No	Yes	
SYS_PWROK Failure: SYS_PWROK signal goes inactive in S0	No	No	Yes	
Processor Thermal Trip (THERMTRIP#) causes transition to S5 and reset asserts	No	No	No	Yes
PCH internal thermal sensors signals a catastrophic temperature condition	No	No	No	Yes
Power Button 4 second override causes transition to S5 and reset asserts	N	No	No	Yes
Special shutdown cycle from processor causes CF9h-like PLTRST# and CF9h Global Reset Bit = 1	No	No	Yes	
Special shutdown cycle from processor causes CF9h-like PLTRST# and CF9h Global Reset Bit = 0 and CF9h (RST_CNT Register) Bit 3 = 1	No	Yes	No (Note 4)	
Special shutdown cycle from processor causes CF9h-like PLTRST# and CF9h Global Reset Bit = 0 and CF9h (RST_CNT Register) Bit 3 = 0	Yes	No	No (Note 4)	
Intel [®] Converged Security and Management Engine Triggered Host Reset without Power-Cycle	Yes	No	No (Note 4)	
Intel [®] Converged Security and Management Engine Triggered Host Reset with Power-Cycle	No	Yes	No (Note 4)	
Intel [®] Converged Security and Management Engine Triggered Power Button Override	No	No	No	Yes
Intel [®] Converged Security and Management Engine Watchdog Timer Timeout	No	No	No (Note 8)	Yes
Intel [®] Converged Security and Management Engine Triggered Global Reset	No	No	Yes	
Intel [®] Converged Security and Management Engine Triggered Host Reset with power down (host stays there)	No	Yes (Note 5)	No (Note 4)	
PLTRST# Entry Timeout (Note 7)	No	No	Yes	
CPUPWRGD Stuck Low	No	No	Yes	



Trigger	Host Reset Without Power Cycle ¹	Host Reset With Power Cycle ²	Global Reset With Power Cycle ³	Straight to S5 ⁶ (Host Stays There)
Power Management Watchdog Timer	No	No	No (Note 8)	Yes
Intel [®] Converged Security and Management Engine Hardware Uncorrectable Error	No	No	No (Note 8)	Yes

Notes: 1. The PCH drops this type of reset request if received while the system is in S3/S4/S5.

 PCH does not drop this type of reset request if received while system is in a software-entered S3/S4/S5 state. However, the PCH will perform the reset without executing the RESET_WARN protocol in these states.

3. The PCH does not send warning message to processor, reset occurs without delay.

- 4. Trigger will result in Global Reset with Power-Cycle if the acknowledge message is not received by the PCH.
- 5. The PCH waits for enabled wake event to complete reset.
- 6. Upon entry to S5, if Deep Sx is enabled and conditions are met as per Deep Sx on page 191, the system will transition to Deep Sx.

7. PLTRST# Entry Timeout is automatically initiated if the hardware detects that the PLTRST# sequence has not been completed within 4 seconds of being started.

8. Trigger will result in Global Reset with Power-Cycle if AGR_LS_EN=1 and Global Reset occurred while the current or destination state was S0.



26.0 Real Time Clock (RTC)

The PCH contains a Motorola* MC146818B-compatible real-time clock with 256 bytes of battery-backed RAM. The real-time clock performs two key functions—keeping track of the time of day and storing system data, even when the system is powered down. The RTC operates on a 32.768 kHz crystal and a 3V battery or system battery if configured by design as the source.

The RTC also supports two lockable memory ranges. By setting bits in the configuration space, two 8-byte ranges can be locked to read and write accesses. This prevents unauthorized reading of passwords or other system security information.

The RTC also supports a date alarm that allows for scheduling a wake up event up to 30 days in advance, rather than just 24 hours in advance.

Acronyms

Acronyms	Description	
ESR	Equivalent Series Resistance. Resistive element in a circuit such as a clock crystal	
GPI	General Purpose Input	
РРМ	Parts Per Million. Crystal accuracy or frequency variation indicator	
RAM	Random Access Memory	

26.1 Signal Description

Name	Туре	Description		
RTCX1	I	Crystal Input 1: This signal is connected to the 32.768 kHz crystal. If no external crystal is used, then RTCX1 can be driven with the desired clock rate. Maximum voltage allowed on this pin is 1.2V.		
RTCX2	0	Crystal Input 2: This signal is connected to the 32.768 kHz crystal. If no external crystal is used, then RTCX2 must be left floating.		
RTCRST#	I	 RTC Reset: When asserted, this signal resets register bits in the RTC well. 1. Unless CMOS is being cleared (only to be done in the G3 power state) with a jumper, the RTCRST# input must always be high when all other RTC power planes are on. 2. In the case where the RTC battery is dead or missing on the platform, the RTCRST# pin must rise before the DSW_PWROK pin. 		
SRTCRST#	I	 Secondary RTC Reset: This signal resets the manageability register bits in the RTC well when the RTC battery is removed. Notes: 1. The SRTCRST# input must always be high when all other RTC power planes are on. 2. In the case where the RTC battery is dead or missing on the platform, the SRTCRST# pin must rise before the DSW_PWROK pin. 3. SRTCRST# and RTCRST# should not be shorted together. 		



26.2 I/O Signal Planes and States

Signal Name	Power Plane	During Reset ¹	Immediately after Reset ¹	S3/S4/S5	Deep Sx	
RTCRST#	RTC	Undriven	Undriven	Undriven	Undriven	
SRTCRST# RTC Undriven Undriven Undriven Undriven						
Note: 1. Reset reference for RTC well pins is RTCRST#.						

26.3 Functional Description

The Real Time Clock (RTC) module provides a battery backed-up date and time keeping device with two banks of static RAM with 128 bytes each, although the first bank has 114 bytes for general purpose usage.

Three interrupt features are available: time of day alarm with once a second to once a month range, periodic rates of 122 – 500 ms, and end of update cycle notification. Seconds, minutes, hours, days, day of week, month, and year are counted. Daylight savings compensation is no longer supported.

The hour is represented in twelve or twenty-four hour format, and data can be represented in BCD or binary format. The design is functionally compatible with the Motorola MS146818B. The time keeping comes from a 32.768 kHz oscillating source, which is divided to achieve an update every second. The lower 14 bytes on the lower RAM block has very specific functions. The first ten are for time and date information. The next four (0Ah to 0Dh) are registers, which configure and report RTC functions.

The time and calendar data should match the data mode (BCD or binary) and hour mode (12 or 24 hour) as selected in register B. It is up to the programmer to make sure that data stored in these locations is within the reasonable values ranges and represents a possible date and time. The exception to these ranges is to store a value of CO–FFh in the Alarm bytes to indicate a do not care situation. All Alarm conditions must match to trigger an Alarm Flag, which could trigger an Alarm Interrupt if enabled.

The SET bit must be 1 while programming these locations to avoid clashes with an update cycle. Access to time and date information is done through the RAM locations. If a RAM read from the ten time and date bytes is attempted during an update cycle, the value read do not necessarily represent the true contents of those locations. Any RAM writes under the same conditions are ignored.

NOTES

- 1. The leap year determination for adding a 29th day to February does not take into account the end-of-the-century exceptions. The logic simply assumes that all years divisible by 4 are leap years. According to the Royal Observatory Greenwich, years that are divisible by 100 are typically not leap years. In every fourth century (years divisible by 400, like 2000), the 100-year-exception is over-ridden and a leap-year occurs.
- The year 2100 will be the first time in which the current RTC implementation would incorrectly calculate the leap-year. The PCH does not implement month/year alarms.



26.3.1 Update Cycles

An update cycle occurs once a second, if the SET bit of register B is not asserted and the divide chain is properly configured. During this procedure, the stored time and date are incremented, overflow is checked, a matching alarm condition is checked, and the time and date are rewritten to the RAM locations.

The update cycle will start at least 488 μ s after the UIP bit of register A is asserted, and the entire cycle does not take more than 1984 μ s to complete. The time and date RAM locations (0–9) are disconnected from the external bus during this time.

To avoid update and data corruption conditions, external RAM access to these locations can safely occur at two times. When a updated-ended interrupt is detected, almost 999 ms is available to read and write the valid time and date data. If the UIP bit of Register A is detected to be low, there is at least 488 µs before the update cycle begins.

WARNING

The overflow conditions for leap years adjustments are based on more than one date or time item. To ensure proper operation when adjusting the time, the new time and data values should be set at least two seconds before leap year occurs.

26.3.2 Interrupts

The real-time clock interrupt is internally routed within the PCH both to the I/O APIC and the 8259. It is mapped to interrupt vector 8. This interrupt does not leave the PCH, nor is it shared with any other interrupt. IRQ8# from the SERIRQ stream is ignored. However, the High Performance Event Timers can also be mapped to IRQ8#; in this case, the RTC interrupt is blocked.

26.3.3 Lockable RAM Ranges

The RTC battery-backed RAM supports two 8-byte ranges that can be locked using the configuration space. If the locking bits are set, the corresponding range in the RAM will not be readable or writable. A write cycle to those locations will have no effect. A read cycle to those locations will not return the location's actual value (resultant value is undefined).

Once a range is locked, the range can be unlocked only by a hard reset, which will invoke the BIOS and allow it to relock the RAM range.

26.3.4 Century Rollover

The PCH detects a rollover when the Year byte transitions form 99 to 00. Upon detecting the rollover, the PCH sets the NEWCENTURY_STS bit.

If the system is in an S0 state, this causes an SMI#. The SMI# handler can update registers in the RTC RAM that are associated with century value.

If the system is in a sleep state (S3–S5) when the century rollover occurs, the PCH also sets the NEWCENTURY_STS bit, but no SMI# is generated. When the system resumes from the sleep state, BIOS should check the NEWCENTURY_STS bit and update the century value in the RTC RAM.



26.3.5 Clearing Battery-Backed RTC RAM

Clearing CMOS RAM in a PCH-based platform can be done by using a jumper on RTCRST# or GPI. Implementations should not attempt to clear CMOS by using a jumper to pull VccRTC low.

Using RTCRST# to Clear CMOS

A jumper on RTCRST# can be used to clear CMOS values, as well as reset to default, the state of those configuration bits that reside in the RTC power well.

When the RTCRST# is strapped to ground, the RTC_PWR_STS bit will be set and those configuration bits in the RTC power well will be set to their default state. BIOS can monitor the state of this bit and manually clear the RTC CMOS array once the system is booted. The normal position would cause RTCRST# to be pulled up through a weak Pull-up resistor. This RTCRST# jumper technique allows the jumper to be moved and then replaced—all while the system is powered off. Then, once booted, the RTC_PWR_STS can be detected in the set state.

Using a GPI to Clear CMOS

A jumper on a GPI can also be used to clear CMOS values. BIOS would detect the setting of this GPI on system boot-up, and manually clear the CMOS array.

NOTE

The GPI strap technique to clear CMOS requires multiple steps to implement. The system is booted with the jumper in new position, then powered back down. The jumper is replaced back to the normal position, then the system is rebooted again.

WARNING

Do not implement a jumper on VccRTC to clear CMOS.

26.3.6 External RTC Circuitry

The PCH implements an internal oscillator circuit that is sensitive to step voltage changes in VCCRTC.

Table 87.RTC Crystal Requirements

Parameter	Specification
Frequency	32.768 kHz
Typical Tolerance	20 ppm or better
ESR	< 50 kohm

Table 88.External Crystal Oscillator Requirements

Parameter	Specification	
Frequency	32.768 kHz	
Typical Tolerance	20 ppm or better	
Voltage Swing	0 to 1.0Vp-p (±5%)	



27.0 Serial ATA (SATA)

The PCH SATA controller support two modes of operation, AHCI mode using memory space and RAID mode. The PCH SATA controller no longer supports IDE legacy mode using I/O space. Therefore, AHCI software is required. The PCH SATA controller supports the Serial ATA Specification, Revision 3.2.

Acronyms

Acronyms	Description
AHCI	Advanced Host Controller Interface
DMA	Direct Memory Access
DEVSLP	Device Sleep
IDE	Integrated Drive Electronics
RAID	Redundant Array of Independent Disks
SATA	Serial Advanced Technology Attachment

References

Specification	Document Number/Location		
Serial ATA Specification, Revision 3.2	https://www.sata-io.org		
Serial ATA II: Extensions to Serial ATA 1.0, Revision 1.0	https://www.sata-io.org		
Serial ATA II Cables and Connectors Volume 2 Gold	https://www.sata-io.org		
Advanced Host Controller Interface Specification	http://www.intel.com/ content/www/us/en/io/serial-ata/ ahci.html		

27.1 Signals Description

Name	Туре	Description		
SATA_DEVSLP0 / GPP_E4	OD	Serial ATA Port [0] Device Sleep: This is an open-drain pin on the PCH side. PCH w tri-state this pin to signal to the SATA device that it may enter a lower power state (pir will go high due to Pull-up that's internal to the SATA device, per DEVSLP specification) PCH will drive pin low to signal an exit from DEVSLP state. Design Constraint: No external Pull-up or Pull-down termination required when used as DEVSLP. <i>Note:</i> This pin can be mapped to SATA Port 0.		
SATA_DEVSLP1 / GPP_E5	OD	Serial ATA Port [1] Device Sleep: This is an open-drain pin on the PCH side. PCH will tri-state this pin to signal to the SATA device that it may enter a lower power state (pin will go high due to Pull-up that's internal to the SATA device, per DEVSLP specification). PCH will drive pin low to signal an exit from DEVSLP state. Design Constraint: No external Pull-up or Pull-down termination required when used as DEVSLP. <i>Note:</i> This pin can be mapped to SATA Port 1.		
	1	continued		



Name	Туре	Description
SATA_DEVSLP2 / GPP_E6	OD	Serial ATA Port [2] Device Sleep: This is an open-drain pin on the PCH side. PCH will tri-state this pin to signal to the SATA device that it may enter a lower power state (pin will go high due to Pull-up that's internal to the SATA device, per DEVSLP specification). PCH will drive pin low to signal an exit from DEVSLP state. Design Constraint: No external Pull-up or Pull-down termination required when used as
		DEVSLP. Note: This pin can be mapped to SATA Port 2.
SATAO_TXP/ PCIE11_TXP SATAO_TXN/ PCIE11_TXN	о	Serial ATA Differential Transmit Pair 0: These outbound SATA Port 0 high-speed differential signals support 1.5 Gb/s, 3 Gb/s and 6 Gb/s. The signals are multiplexed with PCIe* Port 11 signals.
SATAO_RXP/ PCIE11_RXP	I	Serial ATA Differential Receive Pair 0: These inbound SATA Port 0 high-speed differential signals support 1.5 Gb/s, 3 Gb/s and 6 Gb/s.
SATAO_RXN/ PCIE11_RXN		The signals are multiplexed with PCIe* Port 11 signals.
SATA1A_TXP/ PCIE12_TXP SATA1A_TXN/ PCIE12_TXN	0	Serial ATA Differential Transmit Pair 1 [First Instance] : These outbound SATA Port 1 high-speed differential signals support 1.5 Gb/s, 3 Gb/s and 6 Gb/s. The signals are multiplexed with PCIe* Port 12.
SATA1A_RXP/ PCIE12_RXP SATA1A_RXN/ PCIE12_RXN	I	Serial ATA Differential Receive Pair 1 [First Instance]: These inbound SATA Port 1 high-speed differential signals support 1.5 Gb/s, 3 Gb/s and 6 Gb/s. The signals are multiplexed with PCIe* Port 12.
SATA1B_TXP/ PCIE15_TXP	0	Serial ATA Differential Transmit Pair 1 [Second Instance]: These outbound SATA Port 1 high-speed differential signals support 1.5 Gb/s, 3 Gb/s and 6 Gb/s.
SATA1B_TXN/ PCIE15_TXN		The signals are multiplexed with PCIe* Port 15 signals.
SATA1B_RXP/ PCIE15_RXP SATA1B_RXN/ PCIE15_RXN	I	Serial ATA Differential Receive Pair 1 [Second Instance] : These inbound SATA Port 1 high-speed differential signals support 1.5 Gb/s, 3 Gb/s and 6 Gb/s. The signals are multiplexed with PCIe* Port 15 signals.
SATA2_TXP/ PCIE16_TXP SATA2_TXN/ PCIE16_TXN	0	Serial ATA Differential Transmit Pair 2 (PCH-U Only): These outbound SATA Port 2 high-speed differential signals support 1.5 Gb/s, 3 Gb/s and 6 Gb/s. The signals are multiplexed with PCIe* Port 16 signals.
SATA2_RXP/ PCIE16_RXP SATA2_RXN/ PCIE16_RXN /	I	Serial ATA Differential Receive Pair 2 (PCH-U Only): These inbound SATA Port 2 high-speed differential signals support 1.5 Gb/s, 3 Gb/s and 6 Gb/s. The signals are multiplexed with PCIe* Port 16 signals.
SATAGP0 /GPP_E0 / SATAXPCIE0	I	Serial ATA Port [0] General Purpose Inputs: When configured as SATAGP0, this is an input pin that is used as an interlock switch status indicator for SATA Port 0. Drive the pin to '0' to indicate that the switch is closed and to '1' to indicate that the switch is open. Note: The default use of this pin is GPP_E0. Pin defaults to Native mode as
		SATAXPCIE0 depends on soft-strap.
SATAGP1 /GPP_E1 / SATAXPCIE1	I	 Serial ATA Port [1] General Purpose Inputs: When configured as SATAGP1, this is an input pin that is used as an interlock switch status indicator for SATA Port 1. Drive the pin to '0' to indicate that the switch is closed and to '1' to indicate that the switch is open. Note: This default use of this pin is GPP_E1. Pin defaults to Native mode as SATAXPCIE1 depends on soft-strap.
SATAGP2 /GPP_E2 / SATAXPCIE2	I	Serial ATA Port [2] General Purpose Inputs: When configured as SATAGP2, this is an input pin that is used as an interlock switch status indicator for SATA Port 2. Drive the pin to '0' to indicate that the switch is closed and to '1' to indicate that the switch is open.
	1	continued



Name	Туре	Description	
		<i>Note:</i> The default use of this pin is GPP_E2. Pin defaults to Native mode as SATAXPCIE2 depends on soft-strap.	
SATALED#/GPP_E8/ SPI1_CS1#	OD O	Serial ATA LED : This signal is an open-drain output pin driven during SATA command activity. It is to be connected to external circuitry that can provide the current to drive a platform LED. When active, the LED is on. When tri-stated, the LED is off. <i>Note:</i> An external Pull-up resistor to VCC3_3 is required.	

27.2 Integrated Pull-Ups and Pull-Downs

Signal	Resistor type	Notes
SATAXPCIE[2:0]	Internal pull-up	Internal Pull-Up Resistors are 20K±30%

27.3 I/O Signal Planes and States

Signal Name	Power Plane	During Reset ³	Immediately after Reset ³	S3/S4/S5	Deep Sx
SATA0_TXP/N, SATA0_RXP/N	Primary	Internal Pull- down	Internal Pull-down	Internal Pull- down	OFF
SATA1A_TXP/N, SATA1A_RXP/N	Primary	Internal Pull- down	Internal Pull-down	Internal Pull- down	OFF
SATA1B_TXP/N, SATA1B_RXP/N	Primary	Internal Pull- down	Internal Pull-down	Internal Pull- down	OFF
SATA2_TXP/N, SATA2_RXP/N	Primary	Internal Pull- down	Internal Pull-down	Internal Pull- down	OFF
SATALED#/GPP_E81	Primary	Undriven	Undriven	Undriven	OFF
DEVSLP[2:0]/ GPP_E[6:4] ¹	Primary	Undriven	Undriven	Driven Low	OFF
SATAGP[2:0]/ GPP_E[2:0] ²	Primary	Undriven	Undriven	Undriven	OFF
SATAXPCIE[2:0] ²	Primary	Internal Pull-up	Internal Pull-up	Undriven	OFF

Notes: 1. Pin defaults to GPIO mode. The pin state during and immediately after reset follows default GPIO mode pin state. The pin state for S0 to Deep Sx reflects assumption that GPIO Use Select register was programmed to native mode functionality. If GPIO Use Select register is programmed to GPIO mode, refer to Multiplexed GPIO (Defaults to GPIO Mode) section for the respective pin states in S0 to Deep Sx.

2. Pin defaults to Native mode as SATAXPCIEx depends on soft-strap.

3. Reset reference for primary well pins is RSMRST#.

27.4 Functional Description

The PCH SATA host controller (D23:F0) supports AHCI or RAID mode.

The PCH SATA controller does not support legacy IDE mode or combination mode.

The PCH SATA controller interacts with an attached mass storage device through a register interface that is compatible with an SATA AHCI/RAID host adapter. The host software follows existing standards and conventions when accessing the register interface and follows standard command protocol conventions.



27.4.1 SATA 6 Gb/s Support

The PCH SATA controller is SATA 6 Gb/s capable and supports 6 Gb/s transfers with all capable SATA devices. The PCH SATA controller also supports SATA 3 Gb/s and 1.5 Gb/s transfer capabilities.

27.4.2 SATA Feature Support

The PCH SATA controller is capable of supporting all AHCI 1.3 and AHCI 1.3.1, refer to the Intel web site on Advanced Host Controller Interface Specification for current specification status: http://www.intel.com/content/www/us/en/io/serial-ata/ahci.html.

For capability details, refer to PCH SATA controller register (D23:F0:Offset 00h CAP, and AHCI BAR PxCMD Offset 18h).

The PCH SATA controller does **<u>not</u>** support:

- Port Multiplier
- FIS Based Switching
- Command Based Switching
- IDE mode or combination mode
- Cold Presence Detect
- Function Level Reset (FLR)

27.4.3 Hot-Plug Operation

The PCH SATA controller supports Hot-Plug Surprise removal and Insertion Notification. An internal SATA port with a Mechanical Presence Switch can support PARTIAL and SLUMBER with Hot-Plug Enabled. Software can take advantage of power savings in the low power states while enabling Hot-Plug operation. Refer to Chapter 7 of the AHCI specification for details.

27.4.4 Intel[®] Rapid Storage Technology (Intel[®] RST)

The PCH SATA controller provides support for Intel[®] Rapid Storage Technology, providing both AHCI and integrated RAID functionality. The RAID capability provides high-performance/data-redundancy RAID 0/1 functionality on up to two ports for PCH-Y and RAID 0/1/5 functionality on up to three ports for PCH-U of the PCH SATA controller. Matrix RAID support is provided to allow multiple RAID levels to be combined on a single set of hard drives, such as RAID 0 and RAID 1 on two disks. Other RAID features include hot spare support, SMART alerting, and RAID 0 auto replace. Software components include an Option ROM and UEFI Driver for pre-boot configuration and boot functionality, a Windows* compatible driver, and a user interface for configuration and management of the RAID capability of PCH SATA controller.

Intel[®] Rapid Storage Technology (Intel[®] RST) Configuration

Intel[®] RST offers several diverse options for RAID (redundant array of independent disks) to meet the needs of the end user. AHCI support provides higher performance and alleviates disk bottlenecks by taking advantage of the independent DMA engines that each SATA port offers in the PCH SATA controller.



- RAID Level 0 performance scaling up to 6 drives, enabling higher throughput for data intensive applications such as video editing.
- Data redundancy is offered through RAID Level 1, which performs mirroring.
- RAID Level 5 provides highly efficient storage while maintaining fault-tolerance on 3 or more drives. By striping parity, and rotating it across all disks, fault tolerance of any single drive is achieved while only consuming 1 drive worth of capacity. That is, a 3-drive RAID 5 has the capacity of 2 drives, or a 4-drive RAID 5 has the capacity of 3 drives. RAID 5 has high read transaction rates, with a medium write rate. RAID 5 is well suited for applications that require high amounts of storage while maintaining fault tolerance.

By using the PCH's built-in Intel[®] Rapid Storage Technology, there is no loss of additional PCIe*/system resources or add-in card slot/motherboard space footprint used compared to when a discrete RAID controller is implemented. Intel[®] Rapid Storage Technology functionality requires the following items:

- 1. PCH SKU enabled for Intel[®] Rapid Storage Technology.
- 2. Intel[®] Rapid Storage Technology RAID Option ROM or UEFI Driver must be on the platform.
- 3. Intel[®] Rapid Storage Technology drivers, most recent revision.
- 4. At least two SATA hard disk drives (minimum depends on RAID configuration).

Intel[®] Rapid Storage Technology is not available in the following configurations:

1. The SATA controller is programmed in RAID mode, but the AIE bit (D23:F0:Offset 9Ch bit 7) is set to 1.

Intel[®] Rapid Storage Technology (Intel[®] RST) RAID Option ROM

The Intel[®] Rapid Storage Technology RAID Option ROM is a standard PnP Option ROM that is easily integrated into any System BIOS. When in place, it provides the following three primary functions:

- Provides a text mode user interface that allows the user to manage the RAID configuration on the system in a pre-operating system environment. Its feature set is kept simple to keep size to a minimum, but allows the user to create and delete RAID volumes and select recovery options when problems occur.
- Provides boot support when using a RAID volume as a boot disk. It does this by providing Int13 services when a RAID volume needs to be accessed by MS-DOS applications (such as NTLDR) and by exporting the RAID volumes to the System BIOS for selection in the boot order.
- At each boot up, provides the user with a status of the RAID volumes and the option to enter the user interface by pressing CTRL-I.

27.4.5 **Power Management Operation**

Power management of the PCH SATA controller and ports will cover operations of the host controller and the SATA link.

Power State Mappings

The D0 PCI Power Management (PM) state for device is supported by the PCH SATA controller.



SATA devices may also have multiple power states. SATA adopted 3 main power states from parallel ATA. The three device states are supported through ACPI. They are:

- **D0** Device is working and instantly available.
- **D1** Device enters when it receives a STANDBY IMMEDIATE command. Exit latency from this state is in seconds.
- D3 From the SATA device's perspective, no different than a D1 state, in that it is entered using the STANDBY IMMEDIATE command. However, an ACPI method is also called which will reset the device and then cut its power.

Each of these device states are subsets of the host controller's D0 state.

Finally, the SATA specification defines three PHY layer power states, which have no equivalent mappings to parallel ATA. They are:

- **PHY READY** PHY logic and PLL are both on and in active state.
- **Partial** PHY logic is powered up, and in a reduced power state. The link PM exit latency to active state maximum is 10 ns.
- **Slumber** PHY logic is powered up, and in a reduced power state. The link PM exit latency to active state maximum is 10 ms.
- Devslp PHY logic is powered down. The link PM exit latency from this state to active state maximum is 20 ms, unless otherwise specified by DETO in Identify Device Data Log page 08h.

Since these states have much lower exit latency than the ACPI D1 and D3 states, the SATA controller specification defines these states as sub-states of the device D0 state.

Power State Transitions

• Partial and Slumber State Entry/Exit

The partial and slumber states save interface power when the interface is idle. It would be most analogous to CLKRUN# (in power savings, not in mechanism), where the interface can have power saved while no commands are pending. The SATA controller defines PHY layer power management (as performed using primitives) as a driver operation from the host side, and a device proprietary mechanism on the device side. The SATA controller accepts device transition types, but does not issue any transitions as a host. All received requests from a SATA device will be ACKed.

When an operation is performed to the SATA controller such that it needs to use the SATA cable, the controller must check whether the link is in the Partial or Slumber states, and if so, must issue a COMWAKE to bring the link back online. Similarly, the SATA device must perform the same COMWAKE action.

NOTE

SATA devices shall not attempt to wake the link using COMWAKE/COMINIT when no commands are outstanding and the interface is in Slumber.

Devslp State Entry/Exit

Device Sleep (DEVSLP) is a host-controlled SATA interface power state. To support a hardware autonomous approach that is software agnostic Intel is recommending that BIOS configure the AHCI controller and the device to enable Device Sleep. This allows the AHCI controller and associated device to automatically enter and exit Device Sleep without the involvement of OS software.



To enter Device Sleep the link must first be in Slumber. By enabling HIPM (with Slumber) or DIPM on a Slumber capable device, the device/host link may enter the DevSleep Interface Power state.

The device must be DevSleep capable. Device Sleep is only entered when the link is in slumber, therefore when exiting the Device Sleep state, the device must resume with the COMWAKE out-of-band signal (and not the COMINIT out-of-band signal). Assuming Device Sleep was asserted when the link was in slumber, the device is expected to exit DEVSLP to the DR_Slumber state. Devices that do not support this feature will not be able to take advantage of the hardware automated entry to Device Sleep that is part of the AHCI 1.3.1 specification and supported by Intel platforms.

• Device D1 and D3 States

These states are entered after some period of time when software has determined that no commands will be sent to this device for some time. The mechanism for putting a device in these states does not involve any work on the host controller, other then sending commands over the interface to the device. The command most likely to be used in ATA/ATAPI is the "STANDBY IMMEDIATE" command.

• Host Controller D3_{HOT} State

After the interface and device have been put into a low power state, the SATA host controller may be put into a low power state. This is performed using the PCI power management registers in configuration space. There are two very important aspects to Note when using PCI power management.

- 1. When the power state is D3, only accesses to configuration space are allowed. Any attempt to access the memory or I/O spaces will result in master abort.
- 2. When the power state is D3, no interrupts may be generated, even if they are enabled. If an interrupt status bit is pending when the controller transitions to D0, an interrupt may be generated.

When the controller is put into D3, it is assumed that software has properly shut down the device and disabled the ports. Therefore, there is no need to sustain any values on the port wires. The interface will be treated as if no device is present on the cable, and power will be minimized.

When returning from a D3 state, an internal reset will not be performed.

Low Power Platform Consideration

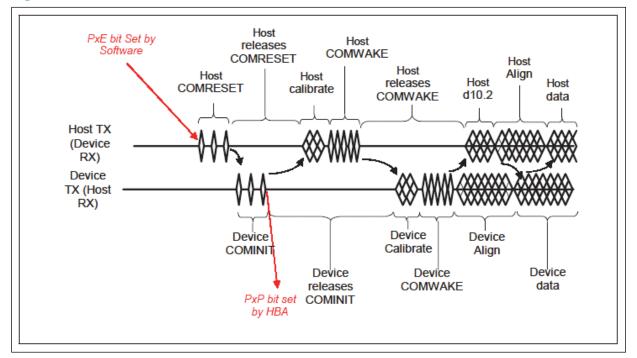
When low power feature is enabled, the Intel SATA controller may power off PLLs or OOB detection circuitry while in the Slumber link power state. As a result, a device initiated wake may not be recognized by the host. For example, when the low power feature is enabled it can prevent a Zero Power ODD (ZPODD) device from successfully communicating with the host on media insertion.

The SATA MPHY Dynamic Power Gating (PHYDPGEPx) can be enabled/disabled for each SATA ports. Refer to SATA SIR Index 50h for the PHYDPGEPx register details.

27.4.6 SATA Device Presence

The flow used to indicate SATA device presence is shown in below figure. The 'PxE' bit refers to PCS.P[2:0]E bits, depending on the port being checked and the 'PxP' bits refer to the PCS.P[2:0]P bits, depending on the port being checked. If the PCS/PxP bit is set a device is present, if the bit is cleared a device is not present. If a port is disabled, software can check to see if a new device is connected by periodically re-

enabling the port and observing if a device is present, if a device is not present it can disable the port and check again later. If a port remains enabled, software can periodically poll PCS.PxP to see if a new device is connected.





27.4.7 SATA LED

The SATALED# output is driven whenever the BSY bit is set in any SATA port. The SATALED# is an active-low open-drain output. When SATALED# is low, the LED should be active. When SATALED# is high, the LED should be inactive.

27.4.8 Advanced Host Controller Interface (AHCI) Operation

The PCH SATA controller provides hardware support for Advanced Host Controller Interface (AHCI), a standardized programming interface for SATA host controllers developed through a joint industry effort. Platforms supporting AHCI may take advantage of performance features such as port independent DMA Engines—each device is treated as a master—and hardware-assisted native command queuing.

AHCI defines transactions between the SATA controller and software and enables advanced performance and usability with SATA. Platforms supporting AHCI may take advantage of performance features such as no master/slave designation for SATA devices—each device is treated as a master—and hardware assisted native command queuing. AHCI also provides usability enhancements such as hot-plug and advanced power management. AHCI requires appropriate software support (such as, an AHCI driver) and for some features, hardware support in the SATA device or additional platform hardware. Visit the Intel web site for current information on the AHCI specification.



The PCH SATA controller supports all of the mandatory features of the *Serial ATA Advanced Host Controller Interface Specification*, Revision 1.3.1 and many optional features, such as hardware assisted native command queuing, aggressive power management, LED indicator support, and hot-plug through the use of interlock switch support (additional platform hardware and software may be required depending upon the implementation).

NOTE

For reliable device removal notification while in AHCI operation without the use of interlock switches (surprise removal), interface power management should be disabled for the associated port. Refer Section 7.3.1 of the AHCI Specification for more information.



28.0 System Management Interface and SMLink

The PCH provides two SMLink interfaces, SMLink0 and SMLink1. The interfaces are intended for system management and are controlled by the Intel[®] CSME. Refer System Management on page 31 for more detail.

Acronyms

Acronyms	Description	
BMC	Baseboard Management Controller	
EC	Embedded Controller	

28.1 Signal Description

Name	Туре	Description	
INTRUDER#	I	Intruder Detect : This signal can be set to disable the system if box detected open.	
SMLODATA/GPP_C4	I/OD	System Management Link 0 Data: SMBus link to external PHY. External pull-up resistor is required.	
SMLOBDATA/ GPP_D13 / ISH_UARTO_RXD / I2C4B_SDA	I/OD	Second Instant of System Management Link 0 Data: used for Comms Hub. External pull-up resistor is required.	
SMLOCLK /GPP_C3	I/OD	System Management Link 0 Clock External pull-up resistor is required.	
SML0BCLK/ GPP_D14 / ISH_UART0_TXD / I2C4B_SCL	I/OD	Second Instant of System Management Link 0 Clock: used for Comms Hub. External pull-up resistor is required.	
SMLOALERT# / GPP_C5	I/OD	System Management 0 Alert : Alert for the SMBus controller to optional Embedded Controller or BMC. External pull-up resistor is required.	
SMLOBALERT# / GPP_D16 / ISH_UART0_CTS#	I/OD	Second instance of System Management 0 Alert: used for Comms Hub External pull-up resistor is required.	
SML1CLK / GPP_C6	I/OD	System Management Link 1 Clock : SMBus link to optional Embedded Controller or BMC. External pull-up resistor is required.	
SML1DATA/ GPP_C7	I/OD	System Management Link 1 Data: SMBus link to optional Embedded Controller or BMC. External pull-up resistor is required.	
SML1ALERT#/ PCHHOT# /GPP_B23	I/OD	System Management 1 Alert: Alert for the SMBus controller to optional Embedded Controller or BMC. A soft-strap determines the native function SML1ALERT# or PCHHOT# usage. External pull-up resistor is required.	
PCHHOT# / GPP_B23 / SML1ALERT#	OD	PCHHOT# : This signal is used to indicate a PCH temperature out of bounds condition to an external EC. External pull-up resistor is required.	

28.2 Integrated Pull-Ups and Pull-Downs

Signal	Resistor Type	Value	Notes
SML[1:0]ALERT#	Pull-down	20 kohm ± 30%	
PCHHOT#	Pull-down	20 kohm ± 30%	

28.3 I/O Signal Planes and States

Signal Name	Power Plane	During Reset	Immediately after Reset	S3/S4/S5	Deep Sx
INTRUDER#	RTC	Undriven	Undriven	Undriven	Undriven
SML[1:0]DATA	Primary	Undriven	Undriven	Undriven	OFF
SML[1:0]CLK	Primary	Undriven	Undriven	Undriven	OFF
SML[1:0]ALERT#	Primary	Pull-down (Internal)	Driven Low	Driven Low	OFF
PCHHOT#	HOT# Primary Pull-down (Internal)		Driven Low	Pull-down (Internal)	OFF
Note: Reset reference for primary well pins is RSMRST# and RTC well pins is RTCRST#.					

28.4 Functional Description

The SMLink interfaces are controlled by the Intel[®] CSME.

SMLink0 is mainly used for integrated LAN. When an Intel LAN PHY is connected to SMLink0, a soft strap must be set to indicate that the PHY is connected to SMLink0. The interface will be running at a frequency of up to 1 MHz depending on different factors such as board routing or bus loading when the Fast Mode is enabled using a soft strap.

SMLink1 can be used with an Embedded Controller (EC) or Baseboard Management Controller (BMC).

Both SMLink0 and SMLink1 support up to 1 MHz.



29.0 Host System Management Bus (SMBus) Controller

The PCH provides a System Management Bus (SMBus) 2.0 host controller as well as an SMBus Slave Interface. The PCH is also capable of operating in a mode in which it can communicate with I^2C compatible devices.

The host SMBus controller supports up to 100 kHz clock speed.

Acronyms

Acronyms	Description
ARP	Address Resolution Protocol
CRC	Cyclic Redundancy Check
PEC	Package Error Checking
SMBus	System Management Bus

References

Specification	Location
System Management Bus (SMBus) Specification, Version 2.0	http://www.smbus.org/specs/

29.1 Signal Description

Name	Туре	Description	
SMBCLK/ GPP_C0	I/OD	SMBus Clock: External Pull-up resistor is required.	
SMBDATA/ GPP_C1	I/OD	SMBus Data: External Pull-up resistor is required.	
SMBALERT#/ GPP_C2	I/OD	SMBus Alert : This signal is used to wake the system or generate SMI#. External Pull-up resistor is required.	

29.2 Integrated Pull-Ups and Pull-Downs

Signal	Resistor Type	Value	Notes
SMBALERT#	Pull-down	20 kohm ± 30%	The integrated pull down is disabled after PCH_PWROK assertion



29.3 I/O Signal Planes and States

Signal Name	Power Plane	During Reset ¹	Immediately after Reset ¹	S3/S4/S5	Deep Sx
SMBDATA	Primary	Undriven	Undriven	Undriven	OFF
SMBCLK	Primary	Undriven	Undriven	Undriven	OFF
SMBALERT# Primary		Pull-down (Internal)	Driven Low	Driven Low	OFF
Note: 1. Reset reference for primary well pins is RSMRST#, DSW well pins is DSW_PWROK, and RTC well pins is RTCRST#.					

29.4 Functional Description

The PCH provides a System Management Bus (SMBus) 2.0 host controller as well as an SMBus Slave Interface.

- Host Controller: Provides a mechanism for the processor to initiate communications with SMBus peripherals (slaves). The PCH is also capable of operating in a mode in which it can communicate with I²C compatible devices.
- **Slave Interface:** Allows an external master to read from or write to the PCH. Write cycles can be used to cause certain events or pass messages, and the read cycles can be used to determine the state of various status bits. The PCH's internal host controller cannot access the PCH's internal Slave Interface.

29.4.1 Host Controller

The host SMBus controller supports up to 100 kHz clock speed and is clocked by the RTC clock.

The PCH can perform SMBus messages with either Packet Error Checking (PEC) enabled or disabled. The actual PEC calculation and checking is performed in SW. The SMBus host controller logic can automatically append the CRC byte if configured to do so.

The SMBus Address Resolution Protocol (ARP) is supported by using the existing host controller commands through software, except for the Host Notify command (which is actually a received message).

The PCH SMBus host controller checks for parity errors as a target. If an error is detected, the detected parity error bit in the PCI Status Register is set.

Host Controller Operation Overview

The SMBus host controller is used to send commands to other SMBus slave devices. Software sets up the host controller with an address, command, and, for writes, data and optional PEC; and then tells the controller to start. When the controller has finished transmitting data on writes, or receiving data on reads, it generates an SMI# or interrupt, if enabled.

The host controller supports 8 command protocols of the SMBus interface (Refer System Management Bus (SMBus) Specification, Version 2.0): Quick Command, Send Byte, Receive Byte, Write Byte/Word, Read Byte/Word, Process Call, Block Read/Write, and Block Write–Block Read Process Call.



The SMBus host controller requires that the various data and command fields be setup for the type of command to be sent. When software sets the START bit, the SMBus Host controller performs the requested transaction, and interrupts the processor (or generates an SMI#) when the transaction is completed. Once a START command has been issued, the values of the "active registers" (Host Control, Host Command, Transmit Slave Address, Data 0, Data 1) should not be changed or read until the interrupt status message (INTR) has been set (indicating the completion of the command). Any register values needed for computation purposes should be saved prior to issuing of a new command, as the SMBus host controller updates all registers while completing the new command.

Slave functionality, including the Host Notify protocol, is available on the SMBus pins.

Using the SMB host controller to send commands to the PCH SMB slave port is not supported.

Command Protocols

In all of the following commands, the Host Status Register (offset 00h) is used to determine the progress of the command. While the command is in operation, the HOST_BUSY bit is set. If the command completes successfully, the INTR bit will be set in the Host Status Register. If the device does not respond with an acknowledge, and the transaction times out, the DEV_ERR bit is set.

If software sets the KILL bit in the Host Control Register while the command is running, the transaction will stop and the FAILED bit will be set after the PCH forces a time-out. In addition, if KILL bit is set during the CRC cycle, both the CRCE and DEV_ERR bits will also be set.

Quick Command

When programmed for a Quick Command, the Transmit Slave Address Register is sent. The PEC byte is never appended to the Quick Protocol. Software should force the PEC_EN bit to 0 when performing the Quick Command. Software must force the I2C_EN bit to 0 when running this command. Refer section 5.5.1 of the *System Management Bus (SMBus) Specification*, Version 2.0 for the format of the protocol.

Send Byte/Receive Byte

For the Send Byte command, the Transmit Slave Address and Device Command Registers are sent. For the Receive Byte command, the Transmit Slave Address Register is sent. The data received is stored in the DATA0 register. Software must force the I2C_EN bit to 0 when running this command.

The Receive Byte is similar to a Send Byte, the only difference is the direction of data transfer. Refer sections 5.5.2 and 5.5.3 of the *System Management Bus (SMBus) Specification*, Version 2.0 for the format of the protocol.

Write Byte/Word

The first byte of a Write Byte/Word access is the command code. The next 1 or 2 bytes are the data to be written. When programmed for a Write Byte/Word command, the Transmit Slave Address, Device Command, and Data0 Registers are sent. In addition, the Data1 Register is sent on a Write Word command. Software must force the I2C_EN bit to 0 when running this command. Refer section 5.5.4 of the *System Management Bus (SMBus) Specification*, Version 2.0 for the format of the protocol.

Read Byte/Word



Reading data is slightly more complicated than writing data. First the PCH must write a command to the slave device. Then it must follow that command with a repeated start condition to denote a read from that device's address. The slave then returns 1 or 2 bytes of data. Software must force the I2C_EN bit to 0 when running this command.

When programmed for the read byte/word command, the Transmit Slave Address and Device Command Registers are sent. Data is received into the DATA0 on the read byte, and the DAT0 and DATA1 registers on the read word. Refer section 5.5.5 of the *System Management Bus (SMBus) Specification,* Version 2.0 for the format of the protocol.

Process Call

The process call is so named because a command sends data and waits for the slave to return a value dependent on that data. The protocol is simply a Write Word followed by a Read Word, but without a second command or stop condition.

When programmed for the Process Call command, the PCH transmits the Transmit Slave Address, Host Command, DATA0 and DATA1 registers. Data received from the device is stored in the DATA0 and DATA1 registers.

The Process Call command with I2C_EN set and the PEC_EN bit set produces undefined results. Software must force either I2C_EN or PEC_EN to 0 when running this command. Refer section 5.5.6 of the *System Management Bus (SMBus) Specification,* Version 2.0 for the format of the protocol.

NOTE

For process call command, the value written into bit 0 of the Transmit Slave Address Register needs to be 0.

NOTE

If the I2C_EN bit is set, the protocol sequence changes slightly, the Command Code (Bits 18:11 in the bit sequence) are not sent. As a result, the slave will not acknowledge (Bit 19 in the sequence).

Block Read/Write

The PCH contains a 32-byte buffer for read and write data which can be enabled by setting bit 1 of the Auxiliary Control register at offset 0Dh in I/O space, as opposed to a single byte of buffering. This 32-byte buffer is filled with write data before transmission, and filled with read data on reception. In the PCH, the interrupt is generated only after a transmission or reception of 32 bytes, or when the entire byte count has been transmitted/received.

The byte count field is transmitted but ignored by the PCH as software will end the transfer after all bytes it cares about have been sent or received.

For a Block Write, software must either force the I2C_EN bit or both the PEC_EN and AAC bits to 0 when running this command.



The block write begins with a slave address and a write condition. After the command code the PCH issues a byte count describing how many more bytes will follow in the message. If a slave had 20 bytes to send, the first byte would be the number 20 (14h), followed by 20 bytes of data. The byte count may not be 0. A Block Read or Write is allowed to transfer a maximum of 32 data bytes.

When programmed for a block write command, the Transmit Slave Address, Device Command, and Data0 (count) registers are sent. Data is then sent from the Block Data Byte register; the total data sent being the value stored in the Data0 Register.

On block read commands, the first byte received is stored in the Data0 register, and the remaining bytes are stored in the Block Data Byte register. Refer section 5.5.7 of the *System Management Bus (SMBus) Specification,* Version 2.0 for the format of the protocol.

NOTE

For Block Write, if the I2C_EN bit is set, the format of the command changes slightly. The PCH will still send the number of bytes (on writes) or receive the number of bytes (on reads) indicated in the DATA0 register. However, it will not send the contents of the DATA0 register as part of the message.When operating in I²C mode (I2C_EN bit is set), the PCH will never use the 32-byte buffer for any block commands.

I²C Read

This command allows the PCH to perform block reads to certain I^2C devices, such as serial E^2 PROMs. The SMBus Block Read supports the 7-bit addressing mode only.

However, this does not allow access to devices using the I^2C "Combined Format" that has data bytes after the address. Typically these data bytes correspond to an offset (address) within the serial memory chips.

NOTE

This command is supported independent of the setting of the I^2C_EN bit. The I^2C Read command with the PEC_EN bit set produces undefined results. Software must force both the PEC_EN and AAC bit to 0 when running this command.

For I²C Read command, the value written into bit 0 of the Transmit Slave Address Register (SMB I/O register, offset 04h) needs to be 0.

The format that is used for the command is shown in table below.

Table 89.I²C Block Read

Bit	Description
1	Start
8:2	Slave Address – 7 bits
9	Write
10	Acknowledge from slave
18:11	Send DATA1 register
19	Acknowledge from slave
	continued



Bit	Description
20	Repeated Start
27:21	Slave Address – 7 bits
28	Read
29	Acknowledge from slave
37:30	Data byte 1 from slave – 8 bits
38	Acknowledge
46:39	Data byte 2 from slave – 8 bits
47	Acknowledge
-	Data bytes from slave/Acknowledge
-	Data byte N from slave – 8 bits
-	NOT Acknowledge
-	Stop

The PCH will continue reading data from the peripheral until the NAK is received.

Block Write-Block Read Process Call

The block write-block read process call is a two-part message. The call begins with a slave address and a write condition. After the command code the host issues a write byte count (M) that describes how many more bytes will be written in the first part of the message. If a master has 6 bytes to send, the byte count field will have the value 6 (0000 0110b), followed by the 6 bytes of data. The write byte count (M) cannot be 0.

The second part of the message is a block of read data beginning with a repeated start condition followed by the slave address and a Read bit. The next byte is the read byte count (N), which may differ from the write byte count (M). The read byte count (N) cannot be 0.

The combined data payload must not exceed 32 bytes. The byte length restrictions of this process call are summarized as follows:

- $M \ge 1$ byte
- $N \ge 1$ byte
- $M + N \le 32$ bytes

The read byte count does not include the PEC byte. The PEC is computed on the total message beginning with the first slave address and using the normal PEC computational rules. It is highly recommended that a PEC byte be used with the Block Write-Block Read Process Call. Software must do a read to the command register (offset 2h) to reset the 32 byte buffer pointer prior to reading the block data register.

NOTE

There is no STOP condition before the repeated START condition, and that a NACK signifies the end of the read transfer.



NOTE

E32B bit in the Auxiliary Control register must be set when using this protocol.

Refer section 5.5.8 of the *System Management Bus (SMBus) Specification,* Version 2.0 for the format of the protocol.

Bus Arbitration

Several masters may attempt to get on the bus at the same time by driving the SMBDATA line low to signal a start condition. The PCH continuously monitors the SMBDATA line. When the PCH is attempting to drive the bus to a 1 by letting go of the SMBDATA line, and it samples SMBDATA low, then some other master is driving the bus and the PCH will stop transferring data.

If the PCH sees that it has lost arbitration, the condition is called a collision. The PCH will set the BUS_ERR bit in the Host Status Register, and if enabled, generate an interrupt or SMI#. The processor is responsible for restarting the transaction.

Clock Stretching

Some devices may not be able to handle their clock toggling at the rate that the PCH as an SMBus master would like. They have the capability of stretching the low time of the clock. When the PCH attempts to release the clock (allowing the clock to go high), the clock will remain low for an extended period of time.

The PCH monitors the SMBus clock line after it releases the bus to determine whether to enable the counter for the high time of the clock. While the bus is still low, the high time counter must not be enabled. Similarly, the low period of the clock can be stretched by an SMBus master if it is not ready to send or receive data.

Bus Timeout (PCH as SMBus Master)

If there is an error in the transaction, such that an SMBus device does not signal an acknowledge or holds the clock lower than the allowed Timeout time, the transaction will time out. The PCH will discard the cycle and set the DEV_ERR bit. The timeout minimum is 25 ms (800 RTC clocks). The Timeout counter inside the PCH will start after the first bit of data is transferred by the PCH and it is waiting for a response.

The 25-ms Timeout counter will not count under the following conditions:

- 1. BYTE_DONE_STATUS bit (SMBus I/O Offset 00h, Bit 7) is set.
- The SECOND_TO_STS bit (TCO I/O Offset 06h, Bit 1) is not set (this indicates that the system has not locked up).

Interrupts/SMI#

The PCH SMBus controller uses PIRQB# as its interrupt pin. However, the system can alternatively be set up to generate SMI# instead of an interrupt, by setting the SMBUS_SMI_EN bit.

The following tables specify how the various enable bits in the SMBus function control the generation of the interrupt, Host and Slave SMI, and Wake internal signals. The rows in the tables are additive, which means that if more than one row is true for a particular scenario then the Results for all of the activated rows will occur.



Table 90.Enable for SMBALERT#

Event	INTREN (Host Control I/O Register, Offset 02h, Bit 0)	SMB_SMI_EN (Host Configuration Register, D31:F4:Offset 40h, Bit 1)	SMBALERT_DIS (Slave Command I/O Register, Offset 11h, Bit 2)	Result
SMBALERT# asserted	х	х	х	Wake generated
low (always reported in Host Status Register, Bit 5)	х	1	0	Slave SMI# generated (SMBUS_SMI_STS)
	1	0	0	Interrupt generated

Table 91. Enables for SMBus Slave Write and SMBus Host Events

Event	INTREN (Host Control I/O Register, Offset 02h, Bit 0)	SMB_SMI_EN (Host Configuration Register, D31:F4:Offset 40h, Bit 1)	Event
Slave Write to Wake/SMI# Command	Х	х	Wake generated when asleep. Slave SMI# generated when awake (SMBUS_SMI_STS).
Slave Write to SMLINK_SLAVE_SMI Command	Х	х	Slave SMI# generated when in the S0 state (SMBUS_SMI_STS)
Any combination of Host	0	Х	None
Status Register [4:1] asserted	1	0	Interrupt generated
	1	1	Host SMI# generated

Table 92. Enables for the Host Notify Command

HOST_NOTIFY_INTREN (Slave Control I/O Register, Offset 11h, Bit 0)	SMB_SMI_EN (Host Config Register, D31:F4:Off40h, Bit 1)	HOST_NOTIFY_WKEN (Slave Control I/O Register, Offset 11h, Bit 1)	Result
0	Х	0	None
Х	х	1	Wake generated
1	0	Х	Interrupt generated
1	1	Х	Slave SMI# generated (SMBUS_SMI_STS)

SMBus CRC Generation and Checking

If the AAC bit is set in the Auxiliary Control register, the PCH automatically calculates and drives CRC at the end of the transmitted packet for write cycles, and will check the CRC for read cycles. It will not transmit the contents of the PEC register for CRC. The PEC bit must not be set in the Host Control register if this bit is set, or unspecified behavior will result.

If the read cycle results in a CRC error, the DEV_ERR bit and the CRCE bit in the Auxiliary Status register at Offset 0Ch will be set.



29.4.2 SMBus Slave Interface

The PCH SMBus Slave interface is accessed using the SMBus. The SMBus slave logic will not generate or handle receiving the PEC byte and will only act as a Legacy Alerting Protocol device. The slave interface allows the PCH to decode cycles, and allows an external microcontroller to perform specific actions.

Key features and capabilities include:

- Supports decode of three types of messages: Byte Write, Byte Read, and Host Notify.
- Receive Slave Address register: This is the address that the PCH decodes. A default value is provided so that the slave interface can be used without the processor having to program this register.
- Receive Slave Data register in the SMBus I/O space that includes the data written by the external microcontroller.
- Registers that the external microcontroller can read to get the state of the PCH.
 - Status bits to indicate that the SMBus slave logic caused an interrupt or SMI# Bit 0 of the Slave Status Register for the Host Notify command
 - Bit 16 of the SMI Status Register for all others

NOTES

The external microcontroller should not attempt to access the PCH SMBus slave logic until either:

- 800 milliseconds after both: RTCRST# is high and RSMRST# is high, OR
- The PLTRST# de-asserts

If a master leaves the clock and data bits of the SMBus interface at 1 for 50 μ s or more in the middle of a cycle, the PCH slave logic's behavior is undefined. This is interpreted as an unexpected idle and should be avoided when performing management activities to the slave logic.

Format of Slave Write Cycle

The external master performs Byte Write commands to the PCH SMBus Slave I/F. The "Command" field (bits 11:18) indicate which register is being accessed. The Data field (bits 20:27) indicate the value that should be written to that register.

The following table has the values associated with the registers.

Table 93.Slave Write Registers

Register	Function	
0	Command Register. Refer below table for valid values written to this register.	
1-3	Reserved	
4	Data Message Byte 0	
	continued	



Register	Function
5	Data Message Byte 1
6–FFh	Reserved
<i>Note:</i> The external microcontroller is responsible to make sure that it does not update the contents of the data byte registers until they have been read by the system processor. The PCH overwrites the	

the data byte registers until they have been read by the system processor. The PCH overwrites the old value with any new value received. A race condition is possible where the new value is being written to the register just at the time it is being read. The PCH will not attempt to cover this race condition (that is, unpredictable results in this case).

Table 94.Command Types

Command Type	Description
0	Reserved
1	WAKE/SMI#. This command wakes the system if it is not already awake. If system is already awake, an SMI# is generated.
2	Unconditional Powerdown. This command sets the PWRBTNOR_STS bit, and has the same effect as the Powerbutton Override occurring.
3	HARD RESET WITHOUT CYCLING: This command causes a soft reset of the system (does not include cycling of the power supply). This is equivalent to a write to the CF9h register with Bits 2:1 set to 1, but Bit 3 set to 0.
4	HARD RESET SYSTEM. This command causes a hard reset of the system (including cycling of the power supply). This is equivalent to a write to the CF9h register with Bits 3:1 set to 1.
5	Disable the TCO Messages. This command will disable the PCH from sending Heartbeat and Event messages. Once this command has been executed, Heartbeat and Event message reporting can only be re-enabled by assertion and then de-assertion of the RSMRST# signal.
6	WD RELOAD: Reload watchdog timer.
7	Reserved
8	SMLINK_SLV_SMI. When the PCH detects this command type while in the S0 state, it sets the SMLINK_SLV_SMI_STS bit. This command should only be used if the system is in an S0 state. If the message is received during S3–S5 states, the PCH acknowledges it, but the SMLINK_SLV_SMI_STS bit does not get set.
	• It is possible that the system transitions out of the S0 state at the same time that the SMLINK_SLV_SMI command is received. In this case, the SMLINK_SLV_SMI_STS bit may get set but not serviced before the system goes to sleep. Once the system returns to S0, the SMI associated with this bit would then be generated. Software must be able to handle this scenario.
9–FFh	Reserved.

Format of Read Command

The external master performs Byte Read commands to the PCH SMBus Slave interface. The "Command" field (bits 18:11) indicate which register is being accessed. The Data field (bits 30:37) contain the value that should be read from that register.

Table 95. Slave Read Cycle Format

Bit	Description	Driven By	Comment
1	Start	External Microcontroller	
2-8	Slave Address - 7 bits	External Microcontroller	Must match value in Receive Slave Address register
			continued



Bit	Description	Driven By	Comment
9	Write	External Microcontroller	Always 0
10	ACK	РСН	
11-18	Command code – 8 bits	External Microcontroller	Indicates which register is being accessed. Refer below table for a list of implemented registers.
19	ACK	РСН	
20	Repeated Start	External Microcontroller	
21-27	Slave Address - 7 bits	External Microcontroller	Must match value in Receive Slave Address register
28	Read	External Microcontroller	Always 1
29	ACK	РСН	
30-37	Data Byte	РСН	Value depends on register being accessed. Refer below table for a list of implemented registers.
38	NOT ACK	External Microcontroller	
39	Stop	External Microcontroller	

Table 96. Data Values for Slave Read Registers

Register	Bits	Description
0	7:0	Reserved
1	2:0	System Power State 000 = S0 011 = S3 100 = S4 101 = S5 Others = Reserved
	7:3	Reserved
2	7:0	Reserved
3	5:0	Watchdog Timer current value Note: The Watchdog Timer has 10 bits, but this field is only 6 bits. If the current value is greater than 3Fh, the PCH will always report 3Fh in this field.
	7:6	Reserved
	0	Intruder Detect . 1 = The Intruder Detect (INTRD_DET) bit is set. This indicates that the system cover has probably been opened.
	2:1	Reserved
4	3	1 = SECOND_TO_STS bit set. This bit will be set after the second Timeout (SECOND_TO_STS bit) of the Watchdog Timer occurs.
	6:4	Reserved. Will always be 0, but software should ignore.
	7	SMBALERT# Status. Reflects the value of the SMBALERT# pin (when the pin is configured to SMBALERT#). Valid only if SMBALERT_DISABLE = 0. Value always returns 1 if SMBALERT_DISABLE = 1.
5	0	FWH bad bit. This bit will be 1 to indicate that the FWH read returned FFh, which indicates that it is probably blank.
	1	Battery Low Status. 1 if the BATLOW# pin a low.
		continued



Register	Bits	Description
	2	SYS_PWROK Failure Status: This bit will be 1 if the SYSPWR_FLR bit in the GEN_PMCON_2 register is set.
	3	Reserved
	4	Reserved
	5	POWER_OK_BAD : Indicates the failure core power well ramp during boot/resume. This bit will be active if the SLP_S3# pin is de-asserted and PCH_PWROK pin is not asserted.
	6	Thermal Trip : This bit will shadow the state of processor Thermal Trip status bit (CTS). Events on signal will not create a event message
	7	Reserved: Default value is "X" Note: Software should not expect a consistent value when this bit is read through SMBus/ SMLink
6	7:0	Contents of the Message 1 register.
7	7:0	Contents of the Message 2 register.
8	7:0	Contents of the WDSTATUS register.
9	7:0	Seconds of the RTC
А	7:0	Minutes of the RTC
В	7:0	Hours of the RTC
С	7:0	"Day of Week" of the RTC
D	7:0	"Day of Month" of the RTC
E	7:0	Month of the RTC
F	7:0	Year of the RTC
10h-FFh	7:0	Reserved

• Behavioral Notes

According to SMBus protocol, Read and Write messages always begin with a Start bit—Address—Write bit sequence. When the PCH detects that the address matches the value in the Receive Slave Address register, it will assume that the protocol is always followed and ignore the Write bit (Bit 9) and signal an Acknowledge during bit 10. In other words, if a Start—Address—Read occurs (which is invalid for SMBus Read or Write protocol), and the address matches the PCH's Slave Address, the PCH will still grab the cycle.

Also according to SMBus protocol, a Read cycle contains a Repeated Start— Address—Read sequence beginning at Bit 20. Once again, if the Address matches the PCH's Receive Slave Address, it will assume that the protocol is followed, ignore bit 28, and proceed with the Slave Read cycle.

Slave Read of RTC Time Bytes

The PCH SMBus slave interface allows external SMBus master to read the internal RTC's time byte registers.

The RTC time bytes are internally latched by the PCH's hardware whenever RTC time is not changing and SMBus is idle. This ensures that the time byte delivered to the slave read is always valid and it does not change when the read is still in progress on the bus. The RTC time will change whenever hardware update is in progress, or there is a software write to the RTC time bytes.



The PCH SMBus slave interface only supports Byte Read operation. The external SMBus master will read the RTC time bytes one after another. It is software's responsibility to check and manage the possible time rollover when subsequent time bytes are read.

For example, assuming the RTC time is 11 hours: 59 minutes: 59 seconds. When the external SMBus master reads the hour as 11, then proceeds to read the minute, it is possible that the rollover happens between the reads and the minute is read as 0. This results in 11 hours: 0 minute instead of the correct time of 12 hours: 0 minutes. Unless it is certain that rollover will not occur, software is required to detect the possible time rollover by reading multiple times such that the read time bytes can be adjusted accordingly if needed.

Format of Host Notify Command

The PCH tracks and responds to the standard Host Notify command as specified in the *System Management Bus (SMBus) Specification,* Version 2.0. The host address for this command is fixed to 0001000b. If the PCH already has data for a previously-received host notify command which has not been serviced yet by the host software (as indicated by the HOST_NOTIFY_STS bit), then it will NACK following the host address byte of the protocol. This allows the host to communicate non-acceptance to the master and retain the host notify address and data values for the previous cycle until host software completely services the interrupt.

NOTE

Host software must always clear the HOST_NOTIFY_STS bit after completing any necessary reads of the address and data registers.

The table below shows the Host Notify format.

Bit	Description	Driven By	Comment
1	Start	External Master	
2-8	SMB Host Address – 7 bits	External Master	Always 0001_000
9	Write	External Master	Always 0
10	ACK (or NACK)	РСН	PCH NACKs if HOST_NOTIFY_STS is 1
11-17	Device Address – 7 bits	External Master	Indicates the address of the master; loaded into the Notify Device Address Register
18	Unused – Always 0	External Master	7-bit-only address; this bit is inserted to complete the byte
19	ACK	РСН	
20-27	Data Byte Low – 8 bits	External Master	Loaded into the Notify Data Low Byte Register
28	ACK	РСН	
29-36	Data Byte High – 8 bits	External Master	Loaded into the Notify Data High Byte Register
37	ACK	РСН	
38	Stop	External Master	

Table 97. Host Notify Format



Format of Read Command

The external master performs Byte Read commands to the PCH SMBus Slave interface. The "Command" field (bits 18:11) indicate which register is being accessed. The Data field (bits 30:37) contain the value that should be read from that register.

Table 98.Slave Read Cycle Format

Bit	Description	Driven By	Comment
1	Start	External Microcontroller	
2-8	Slave Address - 7 bits	External Microcontroller	Must match value in Receive Slave Address register
9	Write	External Microcontroller	Always 0
10	АСК	РСН	
11-18	Command code – 8 bits	External Microcontroller	Indicates which register is being accessed. Refer below table for a list of implemented registers.
19	АСК	РСН	
20	Repeated Start	External Microcontroller	
21-27	Slave Address - 7 bits	External Microcontroller	Must match value in Receive Slave Address register
28	Read	External Microcontroller	Always 1
29	АСК	РСН	
30-37	Data Byte	РСН	Value depends on register being accessed. Refer below table for a list of implemented registers.
38	NOT ACK	External Microcontroller	
39	Stop	External Microcontroller	

Table 99. Data Values for Slave Read Registers

Register	Bits	Description
0	7:0	Reserved for capabilities indication. Should always return 00h. Future chips may return another value to indicate different capabilities.
1	2:0	System Power State 000 = S0 011 = S3 100 = S4 101 = S5 Others = Reserved
	7:3	Reserved
2	7:0	Reserved
3	5:0	Watchdog Timer current value Note: The Watchdog Timer has 10 bits, but this field is only 6 bits. If the current value is greater than 3Fh, the PCH will always report 3Fh in this field.
	7:6	Reserved
		continued



Register	Bits	Description				
-	0	Intruder Detect. 1 = The Intruder Detect (INTRD_DET) bit is set. This indicates that the system cover has probably been opened.				
	1	Temperature Event. 1 = Temperature Event occurred. This bit will be set if the PCH's THRM# input signal is active. Else this bit will read "0."				
	2	DOA Processor Status . This bit will be 1 to indicate that the processor is dead				
4	3	1 = SECOND_TO_STS bit set. This bit will be set after the second Timeout (SECOND_TO_STS bit) of the Watchdog Timer occurs.				
	6:4	Reserved. Will always be 0, but software should ignore.				
	7	SMBALERT# Status. Reflects the value of the GPIO11/SMBALERT# pin (when the pin is configured as SMBALERT#). Valid only if SMBALERT_DISABLE = 0. Value always return 1 if SMBALERT_DISABLE = 1. (high = 1, low = 0).				
	0	FWH bad bit. This bit will be 1 to indicate that the FWH read returned FFh, which indicates that it is probably blank.				
	1	Battery Low Status. 1 if the BATLOW# pin is a 0.				
	2	SYS_PWROK Failure Status: This bit will be 1 if the SYSPWR_FLR bit in the GEN_PMCON_2 register is set.				
	4:3	Reserved				
5	5	POWER_OK_BAD. Indicates the failure core power well ramp during boot/resume. This bit will be active if the SLP_S3# pin is de-asserted and PCH_PWROK pin is not asserted.				
	6	Thermal Trip. This bit will shadow the state of processor Thermal Trip status bit (CTS). Events on signal will not create a event message				
		Reserved: Default value is "X"				
	7	Note: Software should not expect a consistent value when this bit is read through SMBus/SMLink				
6	7:0	Contents of the Message 1 register.				
7	7:0	Contents of the Message 2 register.				
8	7:0	Contents of the WDSTATUS register.				
9	7:0	Seconds of the RTC				
А	7:0	Minutes of the RTC				
В	7:0	Hours of the RTC				
С	7:0	"Day of Week" of the RTC				
D	7:0	"Day of Month" of the RTC				
E	7:0	Month of the RTC				
F	7:0	Year of the RTC				
10h-FFh	7:0	Reserved				



Event	INTREN (Host Control I/O Register, Offset 02h, Bit 0)	SMB_SMI_EN (Host Configuration Register, D31:F3:Offset 40h, Bit 1)	Event
Slave Write to Wake/SMI# Command	Х	х	Wake generated when asleep. Slave SMI# generated when awake (SMBUS_SMI_STS)
Slave Write to SMLINK_SLAVE_SMI Command	х	х	Slave SMI# generated when in the S0 state (SMBUS_SMI_STS)
Any combination of Host	0	Х	None
Status Register [4:1] asserted	1	0	Interrupt generated
	1	1	Host SMI# generated

Table 100. Enables for SMBus Slave Write and SMBus Host Events

29.5 SMBus Power Gating

SMBus shares the Power Gating Domain with LPC and Primary-to-Sideband Bridge (P2SB).

A single FET controls the single Power Gating Domain; but LPC, SMBus and P2SB each has its own dedicated Power Gating Control Block.

The FET is only turned off when all these interfaces are ready to PG entry or already in the PG state.



30.0 Serial Peripheral Interface (SPI)

The PCH provides two Serial Peripheral Interface (SPI) interfaces. The SPI0 interface consists of 3 chip select signals, allowing up to two flash memory devices (SPI0_CS0# and SPI0_CS1#) and one TPM device (SPI0_CS2#) to be connected to the PCH. The SPI1 interface implements one Chip Select signal (SPI1_CS#) and is intended for integrated touch implementations. The SPI0 supports either 1.8 V or 3.3 V. But SPI1 interface supports 1.8 V only.

Acronyms

Acronyms	Description
CLK	Clock
CS	Chip Select
FCBA	Flash Component Base Address
FIBA	Flash Initialization Base Address
FLA	Flash Linear Address
FMBA	Flash Master Base Address
FPSBA	Flash PCH Strap Base Address
FRBA	Flash Region Base Address
MDTBA	MIP Descriptor Table Base Address
FRBA	Flash Region Base Address
MISO	Mater In Slave Out
MOSI	Mater Out Slave In
SFDP	Serial Flash Discovery Parameter
ТРМ	Trusted Platform Module

30.1 Signal Description

Name	Туре	Description		
SPI0_CLK	0	SPI0 Clock : SPI clock signal for the common flash/TPM interface. Supports 20 MHz, 33 MHz and 50 MHz.		
SPI0_CS0#	0	SPI0 Chip Select 0: Used to select the primary SPI0 Flash device.This signal cannot be used for any other type of device than SPI Flash.		
SPI0_CS1#	0	SPIO Chip Select 1: Used to select an optional secondary SPIO Flash device.This signal cannot be used for any other type of device than SPI Flash.		
SPI0_CS2#	0	 SPIO Chip Select 2: Used to select the TPM device if it is connected to the SPIO interface. It cannot be used for any other type of device. TPM can be configured through Soft Straps to operate over LPC or SPIO, but no more than 1 TPM is allowed in the system. 		
	continued			



Name	Туре	Description	
SPI0_MOSI	I/O	SPIO Master OUT Slave IN : Defaults as a data output pin for PCH in Dual Output Fast Read mode. Can be configured with a Soft Strap as a bidirectional signal (SPI0_IO0) to support the Dual I/O Fast Read, Quad I/O Fast Read and Quad Output Fast Read modes.	
SPI0_MISO	I/O	SPIO Master IN Slave OUT : Defaults as a data input pin for PCH in Dual Output Fast Read mode. Can be configured with a Soft Strap as a bidirectional signal (SPI0_IO1) to support the Dual I/O Fast Read, Quad I/O Fast Read and Quad Output Fast Read modes.	
SPI0_I0[3:2]	I/O	SPI0 Data I/O : A bidirectional signal used to support Dual I/O Fast Read, Quad I/O Fast Read and Quad Output Fast Read modes. This signal is not used in Dual Output Fast Read mode.	
GPP_D1 / SPI1_CLK / BK1 / SBK1	0	SPI1 Clock: SPI1 Clock output from PCH	
GPP_D2 / SPI1_MISO / BK2 / SBK2	I/O	SPI1 Master IN Slave OUT : SPI1 serial input data from the SPI1 Touch Screen device to PCH. This Pin will also function as Output during Dual and Quad I/O operation	
GPP_D3 / SPI1_MOSI / BK3 / SBK3	I/O	SPI1 Master OUT Slave IN : SPI1 serial output data from PCH to the SPI1 Touch Screen device. This Pin will also function as Input during Dual and Quad I/O operation	
GPP_D21 / SPI1_IO2	I/O	SPI1 Data I/O : SPI1 I/O to comprehend the support for the Quad I/O operation	
GPP_D22 / SPI1_IO3	I/O	SPI1 Data I/O : SPI1 I/O to comprehend the support for the Quad I/O operation	
GPP_D0 / SPI1_CS# / BK0 / SBK0	0	SPI1 Chip Select: SPI1 chip select	

30.2 Integrated Pull-Ups and Pull-Downs

Signal	Resistor Type	Value	Notes
SPI0_CLK	Pull-down	20 kohm ± 30%	
SPI0_MOSI	Pull-up	20 kohm ± 30%	Note
SPI0_MISO	Pull-up	20 kohm ± 30%	Note
SPI0_CS[2:0]#	Pull-down	20 kohm ± 30%	
SPI0_IO[2:3]	Pull-up	20 kohm ± 30%	Note

NOTE

The internal pull-up is disabled when RSMRST# is asserted (during reset) and only enabled after RSMRST# de-assertion.



30.3 I/O Signal Planes and States

Signal Name	Power Plane	During Reset (Refer Note 1)	Immediately after Reset	S3/S4/S5	Deep Sx
SPI0_CLK	Primary	Internal Pull- down	Driven Low	Driven Low	OFF
SPI0_MOSI	Primary	Hi-Z (Refer Note 2)	Internal PU, then Driven Low	Driven Low	OFF
SPI0_MISO	Primary	Hi-Z	Internal Pull-up	Internal Pull-up	OFF
SPI0_CS0#	Primary	Internal Pull- down	Driven High	Driven High	OFF
SPI0_CS1#	Primary	Internal Pull- down	Driven High	Driven High	OFF
SPI0_CS2#	Primary	Internal Pull- down	Driven High	Driven High	OFF
SPI0_I0[3:2]	Primary	Hi-Z (Refer Note 2)	Internal Pull-up	Internal Pull-up	OFF

Notes: 1. During reset refers to when RSMRST# is asserted.

2. SPI0_MOSI, SPI0_IO[3:2] also function as strap pins. The actual pin state during Reset is

dependent on the platform Pull-up/Pull-down resistor.

30.4 Functional Description

This section covers the following information:

- SPI0 for Flash
- SPI0 support for TPM
- SPI1 for Touch Integration
- SPI1 support for Touch Device

30.4.1 SPI0 for Flash

The Serial Peripheral Interface (SPI0) supports two SPI flash devices via 2 chip select (SPI0_CS0# and SPI0_CS1#). The maximum size of flash supported is determined by the SFDP-discovered addressing capability of each device. Each component can be up to 16 MB (32 MB total addressable) using 3-byte addressing. Each component can be up to 64 MB (128 MB total addressable) using 4-byte addressing. Another chip select (SPI0_CS2#) is also available and only used for TPM on SPI support. PCH drives the SPI0 interface clock at either 20 MHz, 33 MHz, or 50 MHz and will function with SPI flash devices that support at least one of these frequencies. The SPI interface supports either 3.3 V or 1.8 V.

A SPI0 flash device supporting SFDP (Serial Flash Discovery Parameter) is required for all PCH design. A SPI0 flash device on SPI0_CS0# with a valid descriptor must be attached directly to the PCH.

The PCH supports fast read which consist of:

- 1. Dual Output Fast Read (Single Input Dual Output)
- 2. Dual I/O Fast Read (Dual Input Dual Output)



- 3. Quad Output Fast Read (Single Input Quad Output)
- 4. Quad I/O Fast Read (Quad Input Quad Output)

The PCH SPI0 has a third chip select SPI0_CS2# for TPM support over SPI. The TPM on SPI0 will use SPI0_CLK, SPI0_MISO, SPI0_MOSI and SPI0_CS2# SPI signals.

NOTE

If Boot BIOS Strap ='1' then LPC is selected as the location for BIOS. BIOS may still be placed on LPC, but all platforms with PCH require a SPI0 flash connected to SPI bus with a valid descriptor connected to Chip Select 0 in order to boot.

SPI0 Supported Features

• Descriptor Mode

Descriptor Mode is required for all SKUs of the PCH. Non-Descriptor Mode is not supported.

• SPI0 Flash Regions

In Descriptor Mode the Flash is divided into six separate regions.

Table 101.SPI0 Flash Regions

Region	Content
0	Flash Descriptor
1	BIOS
2	Intel [®] Converged Security and Manageability Engine
3	Gigabit Ethernet
4	Platform Data
5	EC

Only four masters can access the regions: Host processor running BIOS code, Integrated Gigabit Ethernet and Host processor running Gigabit Ethernet Software, Intel[®] Converged Security and Manageability Engine and the EC.

The Flash Descriptor and $Intel^{(R)}$ CSME region are the only required regions. The Flash Descriptor has to be in region 0 and region 0 must be located in the first sector of Device 0 (Offset 0). All other regions can be organized in any order.

Regions can extend across multiple components, but must be contiguous.

Flash Region Sizes

SPI0 flash space requirements differ by platform and configuration. The Flash Descriptor requires one 4-KB or larger block. GbE requires two 4-KB or larger blocks. The amount of flash space consumed is dependent on the erase granularity of the flash part and the platform requirements for the Intel[®] CSME and BIOS regions. The Intel[®] CSME region contains firmware to support Intel[®] Active Management Technology and other Intel[®] CSME capabilities.



Region	Size with 4-KB Blocks	Size with 8-KB Blocks	Size with 64-KB Blocks
Descriptor	4 KB	8 KB	64 KB
GbE	8 KB	16 KB	128 KB
BIOS	Varies by Platform	Varies by Platform	Varies by Platform
Intel [®] CSME	Varies by Platform	Varies by Platform	Varies by Platform
EC	Varies by Platform	Varies by Platform	Varies by Platform

Table 102. Region Size Versus Erase Granularity of Flash Components

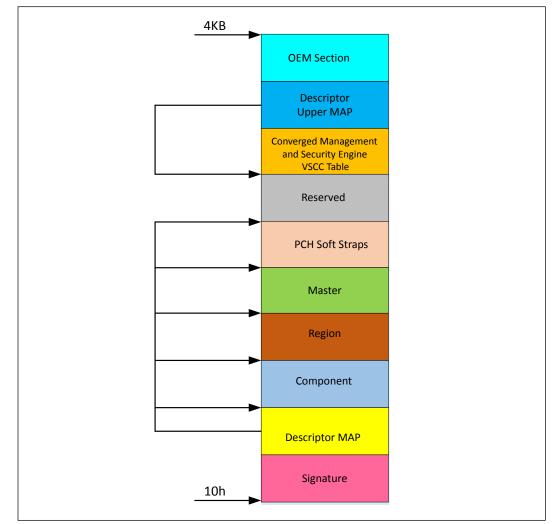
Flash Descriptor

The bottom sector of the flash component 0 contains the Flash Descriptor. The maximum size of the Flash Descriptor is 4 KB. If the block/sector size of the SPI0 flash device is greater than 4 KB, the flash descriptor will only use the first 4 KB of the first block. The flash descriptor requires its own block at the bottom of memory (00h). The information stored in the Flash Descriptor can only be written during the manufacturing process as its read/write permissions must be set to read only when the computer leaves the manufacturing floor.

The Flash Descriptor region sections are shown in figure below.







- The Flash signature selects Descriptor Mode as well as verifies if the flash is programmed and functioning. The data at the bottom of the flash (offset 10h) must be 0FF0 A55Ah in order to be in Descriptor mode.
- The Descriptor map has pointers to the other five descriptor sections as well as the size of each.
- The component section has information about the SPI0 flash in the system including: the number of components, density of each, invalid instructions (such as chip erase), and frequencies for read, fast read and write/erase instructions.
- The Region section points to the three other regions as well as the size of each region.
- The master region contains the security settings for the flash, granting read/write permissions for each region and identifying each master by a requestor ID.
- The Reserved region between the top of the processor strap section and the bottom of the OEM Section is reserved for future chipset usages.



- The Descriptor Upper MAP determines the length and base address of the Intel[®]CSME VSCC Table.
- The Intel[®]CSME VSCC Table holds the JEDEC ID and the VSCC information of the entire SPI0 Flash supported by the NVM image.
- OEM Section is 256 bytes reserved at the top of the Flash Descriptor for use by OEM.

• Descriptor Master Region

The master region defines read and write access setting for each region of the SPI0 device. The master region recognizes four masters: BIOS, Gigabit Ethernet, Intel[®]CSME, and EC. Each master is only allowed to do direct reads of its primary regions.

Table 103. Region Access Control Table

Master Access	Descriptor Region	BIOS Region	Intel [®] CSME	GbE Controller	EC
Intel [®] CSME Read access	Yes	No	Yes	Yes	No
Intel [®] CSME Write access	No	No	Yes	No	No
Gigabit Ethernet read access	Yes	No	No	Yes	No
Gigabit Ethernet write access	No	No	No	Yes	No
BIOS read access	Yes	Yes	No	Yes	Note
BIOS write access	No	Yes	No	Yes	Note
EC read access	Yes	Yes	No	No	Yes
EC write access	No	No	No	No	Yes
Note: Optional BIOS access to the EC region.					

• Flash Descriptor CPU Complex Soft Strap Section

Region Name	Starting Address
Signature	10h
Component FCBA	30h
Regions FRBA	40h
Masters FMBA	80h
PCH Straps FPSBA	100h
MDTBA	C00h
PMC Straps	C14h
CPU Straps	C2Ch
Intel [®] CSME Straps	C3Ch
Register Init FIBA	340h

Flash Access

There are two types of accesses: Direct Access and Program Register Accesses.



• Direct Access

- Masters are allowed to do direct read only of their primary region
 - Gigabit Ethernet region can only be directly accessed by the Gigabit Ethernet controller. Gigabit Ethernet software must use Program Registers to access the Gigabit Ethernet region.
- Master's Host or Intel[®] CSME virtual read address is converted into the SPI0 Flash Linear Address (FLA) using the Flash Descriptor Region Base/Limit registers

Direct Access Security

- Requester ID of the device must match that of the primary Requester ID in the Master Section
- Calculated Flash Linear Address must fall between primary region base/limit
- Direct Write not allowed
- Direct Read Cache contents are reset to 0's on a read from a different master

Program Register Access

- Program Register Accesses are not allowed to cross a 4-KB boundary and cannot issue a command that might extend across two components
- Software programs the FLA corresponding to the region desired
 - Software must read the devices Primary Region Base/Limit address to create a FLA.

Register Access Security

- Only primary region masters can access the registers

30.4.2 SPI0 Support for TPM

The Serial Peripheral Interface (SPI0) supports a discrete TPM on the platform via its dedicated SPI0_CS2# signal.

SPI0 controller supports accesses to SPI0 TPM at approximately 17 MHz, 33 MHz and 48 MHz depending on the PCH soft strap. 20 MHz is the reset default, a valid PCH soft strap setting overrides the requirement for the 20 MHz. SPI0 TPM device must support a clock of 20 MHz, and thus should handle 15-20 MHz. It may but is not required to support a frequency greater than 20 MHz.

TPM requires the support for the interrupt routing. However, the TPM's interrupt pin is routed to the PCH's PIRQ pin. Thus, TPM interrupt is completely independent from the SPI0 controller.

30.4.3 SPI1 Support for Touch Device

The Serial Peripheral Interface (SPI1) supports SPI1 touch device via chip select (SPI1_CS#) with Quad IO. The PCH drives the SPI1 interface clock at 30 MHz and will function with a SPI Touch device that supports this frequency.



31.0 Intel[®] Serial I/O Generic SPI (GSPI) Controllers

The PCH implements three generic SPI interfaces to support devices that uses serial protocol for transferring data.

Each interface consists of a clock (CLK), two chip selects (CS) and two data lines (MOSI and MISO).

Acronyms

Acronyms	Description
GSPI	Generic Serial Peripheral Interface
LTR	Latency Tolerance Reporting

31.1 Signal Description

Name	Туре	Description
GSPI0_CS0#/GPP_B15	0	Generic SPI 0 Chip Select
GSPI0_CS1# /GPP_A7 / PIRQA#	0	Generic SPI 0 Chip Select
GSPI0_CLK/GPP_B16	0	Generic SPI 0 Clock
GSPIO_MISO/GPP_B17	I	Generic SPI 0 MISO
GSPI0_MOSI/GPP_B18	0	Generic SPI 0 MOSI Note: This signal is also utilized as a strap. Refer the pin strap section for more info.
GSPI1_CS0#/GPP_B19	0	Generic SPI 1 Chip Select 0
GSPI1_CS1# /GPP_A11 / PME# / SD_VDD2_PWR_EN#	0	Generic SPI 1 Chip Select 1
GSPI1_CLK/GPP_B20	0	Generic SPI 1 Clock
GSPI1_MISO/GPP_B21	Ι	Generic SPI 1 MISO
GSPI1_MOSI/GPP_B22	0	Generic SPI 1 MOSI Note: This signal is also utilized as a strap. Refer the pin strap section for more info.
GSPI2_CS0#/GPP_D9 / ISH_SPI_CS#	0	Generic SPI 2 Chip Select 0
GSPI2_CS1#/GPP_D15/ ISH_UART0_RTS#	0	Generic SPI 2 Chip Select 1
GSPI2_CLK/GPP_D10 / ISH_SPI_CLK	0	Generic SPI 2 Clock
GSPI2_MISO/GPP_D11 / ISH_SPI_MISO	Ι	Generic SPI 2 MISO
GSP12_MOSI/GPP_D12 / ISH_SPI_MOSI	0	Generic SPI 2 MOSI



31.2 Integrated Pull-Ups and Pull-Downs

Signal	Signal Resistor Type		Notes	
GSPI0_MOSI	Pull Down	20 kohm ± 30%	Internal Pull Down is not enabled by default.	
GSPI1_MOSI	Pull Down	20 kohm ± 30%	Internal Pull Down is not enabled by default.	
SSPI2_MOSI Pull Down		20 kohm ± 30%	Internal Pull Down is not enabled by default.	
GSPI0_MISO	Pull Down	20 kohm ± 30%		
GSPI1_MISO	Pull Down	20 kohm ± 30%		
GSPI2_MISO	Pull Down	20 kohm ± 30%		

31.3 I/O Signal Planes and States

Signal Name	Power Plane	During Reset ¹	Immediately after Reset ¹	S3/S4/S5	Deep Sx
GSPI2_CS0#, GSPI2_CS1#, GSPI1_CS0#, GSPI1_CS1#, GSPI0_CS0#, GSPI0_CS1#	Primary	Undriven Undriven Undriven		Undriven	OFF
GSPI2_CLK, GSPI1_CLK, GSPI0_CLK	Primary	Undriven	Undriven	Undriven	OFF
GSPI2_MISO, GSPI1_MISO, GSPI0_MISO	Primary	Undriven Undriven		Undriven	OFF
GSPI2_MOSI, GSPI1_MOSI, GSPI0_MOSI	Primary	Internal Pull down	Driven Low	n Low Internal Pull O down O	

31.4 Functional Description

This section covers the following information:

- Features
- Controller Overview
- DMA Controller
- Reset
- Power Management
- Interrupts
- Error Handling



31.4.1 Features

The GSPI interfaces support the following features:

- Full duplex synchronous serial interface
- Support Motorola's SPI protocol
- Operates in master mode only
- Supports bit rates up to 20 Mbits/s
- Supports data size from 4 to 32 bits in length and FIFO depths of 64 entries
- Supports DMA with 128-byte FIFO per channel (up to 64-byte burst)

NOTE

Slave mode is not supported.

31.4.2 Controller Overview

The generic SPI controllers can only be set to operate as a master.

The processor or DMA accesses data through the GSPI port's transmit and receive FIFOs.

A processor access takes the form of programmed I/O, transferring one FIFO entry per access. Processor accesses must always be 32 bits wide. Processor writes to the FIFOs are 32 bits wide, but the PCH will ignore all bits beyond the programmed FIFO data size. Processor reads to the FIFOs are also 32 bits wide, but the receive data written into the Receive FIFO is stored with '0' in the most significant bits (MSB) down to the programmed data size.

The FIFOs can also be accessed by DMA, which must be in multiples of 1, 2, or 4 bytes, depending upon the value, and must also transfer one FIFO entry per access.

For writes, the PCH takes the data from the transmit FIFO, serializes it, and sends it over the serial wire to the external peripheral. Receive data from the external peripheral on the serial wire is converted to parallel words and stored in the receive FIFO.

A programmable FIFO trigger threshold, when exceeded, generates an interrupt or DMA service request that, if enabled, signals the processor or DMA respectively to empty the Receive FIFO or to refill the Transmit FIFO.

The GSPI controller, as a master, provides the clock signal and controls the chip select line. Commands codes as well as data values are serially transferred on the data signals. The PCH asserts a chip select line to select the corresponding peripheral device with which it wants to communicate. The clock line is brought to the device whether it is selected or not. The clock serves as synchronization of the data communication.

31.4.3 DMA Controller

The GSPI controllers have an integrated DMA controller.



DMA Transfer and Setup Modes

The DMA can operate in the following modes:

- 1. Memory to peripheral transfers. This mode requires that the peripheral control the flow of the data to itself.
- 2. Peripheral to memory transfer. This mode requires that the peripheral control the flow of the data from itself.

The DMA supports the following modes for programming:

- 1. Direct programming. Direct register writes to DMA registers to configure and initiate the transfer.
- Descriptor based linked list. The descriptors will be stored in memory. The DMA will be informed with the location information of the descriptor. DMA initiates reads and programs its own register. The descriptors can form a linked list for multiple blocks to be programmed.
- 3. Scatter Gather mode.

Channel Control

- The source transfer width and destination transfer width are programmable. The width can be programmed to 1, 2, or 4 bytes.
- Burst size is configurable per channel for source and destination. The number is a power of 2 and can vary between 1,2,4,...,128. This number times the transaction width gives the number of bytes that will be transferred per burst.
- Individual Channel enables. If the channel is not being used, then it should be clock gated.
- Programmable Block size and Packing/Unpacking. Block size of the transfer is programmable in bytes. The block size is not limited by the source or destination transfer widths.
- Address incrementing modes. The DMA has a configurable mechanism for computing the source and destination addresses for the next transfer within the current block. The DMA supports incrementing addresses and constant addresses.
- Flexibility to configure any hardware handshake sideband interface to any of the DMA channels.
- Early termination of a transfer on a particular channel.

31.4.4 Reset

Each host controller has an independent rest associated with it. Control of these resets is accessed through the Reset Register.

Each host controller and DMA will be in reset state once powered ON and require SW (BIOS or driver) to write into the corresponding reset register to bring the controller from reset state into operational mode.



31.4.5 Power Management

Device Power Down Support

In order to power down peripherals connected to the PCH GSPI bus, the idle configured state of the I/O signals must be retained to avoid transitions on the bus that can affect the connected powered peripheral. Connected devices are allowed to remain in the D0 active or D2 low power states when the bus is powered off (power gated). The PCH HW will prevent any transitions on the serial bus signals during a power gate event.

Latency Tolerance Reporting (LTR)

Latency Tolerance Reporting is used to allow the system to optimize internal power states based on dynamic data, comprehending the current platform activity and service latency requirements. However, the GSPI bus architecture does not provide the architectural means to define dynamic latency tolerance messaging. Therefore, the interface supports this by reporting its service latency requirements to the platform power management controller via LTR registers.

The controller's latency tolerance reporting can be managed by one of the two following schemes. The platform integrator must choose the correct scheme for managing latency tolerance reporting based on the platform, OS and usage.

- Platform/HW Default Control: This scheme is used for usage models in which the controller's state correctly informs the platform of the current latency requirements. In this scheme, the latency requirement is a function of the controller state. The latency for transmitting data to/from its connected device at a given rate while the controller is active is representative of the active latency requirements. On the other hand if the device is not transmitting or receiving data and idle, there is no expectation for end to end latency.
- 2. Driver Control. This scheme is used for usage models in which the controller state does not inform the platform correctly of the current latency requirements. If the FIFOs of the connected device are much smaller than the controller FIFOs, or the connected device's end-to-end traffic assumptions are much smaller than the latency to restore the platform from low power state, driver control should be used.

31.4.6 Interrupts

GSPI interface has an interrupt line which is used to notify the driver that service is required.

When an interrupt occurs, the device driver needs to read both the host controller and DMA interrupt status and transmit completion interrupt registers to identify the interrupt source. Clearing the interrupt is done with the corresponding interrupt register in the host controller or DMA.

All interrupts are active high and their behavior is level interrupt.

31.4.7 Error Handling

Errors that might occur on the external GSPI signals are comprehended by the host controller and reported to the interface host controller driver through the MMIO registers.



32.0 Testability

32.1 JTAG

This section contains information regarding the testability signals that provides access to JTAG, run control, system control, and observation resources. JTAG (TAP) ports are compatible with the IEEE Standard Test Access Port and Boundary Scan Architecture 1149.1 and 1149.6 Specification, as detailed per device in each BSDL file. JTAG Pin definitions are from IEEE Standard Test Access Port and Boundary-Scan. Architecture (IEEE Std. 1149.1-2001).

Acronyms

Acronyms	Description		
ООВ	Out of Band		
IEEE	Institute of Electrical and Electronics Engineers		
I/O	Input/Output		
I/OD	Input/Output Open Drain		
JTAG	Joint Test Action Group		
DCI	Direct Connect Interface		
BSDL	Boundary Scan Description Language		
DbC	Debug Class Devices		

References

Specification	Location
IEEE Standard Test Access Port and Boundary Scan Architecture	http://standards.ieee.org/findstds/standard/ 1149.1-2013.html

32.1.1 Signal Description

Table 104. Testability Signals

Name	Туре	Description			
PCH_JTAG_TCK	I/O	Test Clock Input (TCK): The test clock input provides the clock for the JTAG test logic.			
PCH_JTAG_TMS	I/OD	Test Mode Select (TMS): The signal is decoded by the Test Access Port (TAP) controller to control test operations.			
PCH_JTAG_TDI	I/OD	Test Data Input (TDI): Serial test instructions and data are received by the test logic at TDI.			
		continued			



Name	Туре	Description		
PCH_JTAG_TDO	I/OD	Test Data Output (TDO): TDO is the serial output for test instructions and data from the test logic defined in this standard.		
PCH_JTAGX	I/O	This pin is used to support merged debug port topologies.		
ITP_PMODE	I/O	ITP Power Mode Indicator. This signal is used to transmit processor and PCH power/reset information to the Debugger.		

32.1.2 I/O Signal Planes and States

Table 105. Power Planes and States for Testability Signals

Signal Name	Power Plane	Resisters	During Reset ²	Immediately after Reset ²	S3/S4/S5	Deep Sx
PCH_JTAG_TCK	Primary	Strong Internal Pull-Down	L	L	L	OFF
PCH_JTAG_TMS	Primary	Internal Pull-Up	Н	н	Н	OFF
PCH_JTAG_TDI	Primary	Internal Pull-Up	Н	н	н	OFF
PCH_JTAG_TDO	Primary	External Pull-Up	Z	Z	Z	OFF
PCH_JTAGX1	Primary	Internal Strong Pull-Up (as TDO i/p), Internal Strong Pull-Down (as TCK o/p)	Н	H/L	H/L	OFF

Notes: 1. This signal is used in common JTAG topology to take in last device's TDO to DCI. The only planned supported topology is the Shared Topology. Thus, this pin will operate as TCK mode.

2. Reset reference for primary well pins is RSMRST#

32.2 Intel[®] Trace Hub (Intel[®] TH)

Intel[®] Trace Hub is a debug architecture that unifies hardware and software system visibility. Intel[®] Trace Hub is not merely intended for hardware debug or software debug, but full system debug. This includes debugging hardware and software as they interact and produce complex system behavior. Intel[®] Trace Hub defines features and also leverages some existing debug technologies to provide a complete framework for hardware and software co-debug, software development and tuning, as well as overall system performance optimization.

Intel[®] Trace Hub is a set of silicon features with supported software API. The primary purpose is to collect trace data from different sources in the system and combine them into a single output stream with time-correlated to each other. Intel[®] Trace Hub uses common hardware interface for collecting time-correlated system traces through standard destinations. Intel[®] Trace Hub adopts industry standard (MIPI* STPv2) debug methodology for system debug and software development.

There are multiple destinations to receive the trace data from Intel[®] Trace Hub:

- Direct Connect Interface (DCI)
 - OOB Hosting DCI
 - USB 3.1 hosting DCI.DBC
- System Memory

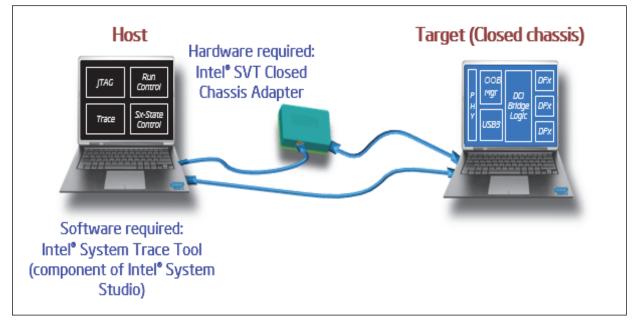


There are multiple trace sources in the platform:

- BIOS
- Intel[®] CSME
- AET (Architecture Event Trace)
- Power Management Event Trace
- Windows* ETW (for driver or application)

32.2.1 Platform Setup





32.3 Direct Connect Interface (DCI)

Direct Connect Interface (DCI) is a debug transport technology to enable closed chassis debug through any of USB 3.2 or USB 2.0 ports out from Intel silicon. Some bridging logic is embedded in the silicon to "bridge" the gap between standard I/O ports and the debug interfaces including JTAG, probe mode, hooks, trace infrastructure, and etc. To control the operation of this embedded logic, a DCI packet based protocol is invented which controls and data can be sent or received. This protocol can operate over a few different physical transport paths to the target which known as "hosting interfaces".

NOTE

DCI and USB based debugger (kernel level debugger) are mutually exclusive.

There are two types of DCI hosting interfaces in the platform:

- OOB Hosting DCI
- USB 3.2 or USB 2.0 Hosting DCI.DBC



Supported capabilities in DCI are:

- Closed Chassis Debug at S0 and Sx State
- JTAG Access and Run Control (Probe Mode)
- System Tracing with Intel[®] Trace Hub

Debug host software that support DCI are:

• Intel[®] System Studio

32.3.1 Out Of Band (OOB) Hosting DCI

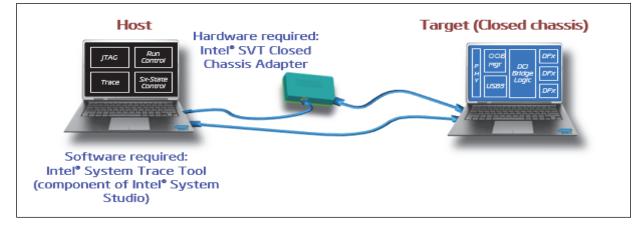
OOB was developed to provide an alternate path to convey controls and data to or from the embedded logic by connecting physically to the target through any USB 3.2 port. OOB provides an alternate side band path around the USB 3.2 Host controller, so that the embedded logic can be accessed, even when the USB controller is not alive (such as in low power states), or is malfunctioning. This path does not rely on USB protocol, link layer, or physical layer, because the xHCI functions are generally not available in such conditions. Instead, this path relies on a special adapter that developed by Intel called Intel[®] SVT Closed Chassis Adapter (CCA). It is a simple data transformation device. This adapter generates a OOB signaling protocol operating at up to 100 MHz and serializes data flowing through it. This adapter works together with debug host software and the embedded logic, contain a back-pressure scheme that makes both sides tolerant of overflow and starvation conditions, which is the moral equivalent of the USB link layer. This path also uses native DCI packet protocol instead of USB protocol. DCI.OOB - slower speed, CCA box needed. But survives S0ix and Sx states. Provides early boot access. Cannot tolerate re-driver circuits in its path.

32.3.2 USB 3.2 Gen 1x1 (5 Gb/s) and USB 2.0 Hosting DCI.DBC

It relies on Debug Class Devices (DbC) which is comprised of a set of logic that is bolted to the side of the xHCI host controller and enable the target to act the role of a USB device for debug purpose. This path uses the USB packet protocol layer, USB layer flow control and USB physical layer at 5 GHz (for USB 3.2 Gen 1x1 (5 Gb/s)) and 480MHz (for USB 2.0). DCI.DBC - fast speed. USB 3.2 Gen 2x1 (10 Gb/s) only works in S0. USB 2.0 survives S0ix and Sx states and provides early boot access.

32.3.3 Platform Setup







33.0 Intel[®] Serial I/O Universal Asynchronous Receiver/Transmitter (UART) Controllers

The PCH implements three independent UART interfaces, UART0, UART1 and UART2. Each UART interface is a 4-wire interface supporting up to 6.25 Mbit/s.

The interfaces can be used in the low-speed, full-speed, and high-speed modes. The UART communicates with serial data ports that conform to the RS-232 interface protocol.

UART2 only implements the UART Host controller and does not incorporate a DMA controller which is implemented for UART0 and UART1. Therefore, UART2 is restricted to operate in PIO mode only.

NOTE

Bluetooth* devices are not supported on the PCH UART interfaces.

Acronyms

Acronyms	Description
DMA	Direct Memory Access
UART	Universal Asynchronous Receiver/Transmitter

33.1 Signal Description

Name	Туре	Description
UARTO_RXD/ GPP_C8	I	UART 0 Receive Data
UARTO_TXD/ GPP_C9	0	UART 0 Transmit Data
UARTO_RTS#/ GPP_C10	0	UART 0 Request to Send
UARTO_CTS#/ GPP_C11	Ι	UART 0 Clear to Send
UART1_RXD/ISH_UART1_RXD/ GPP_C12	Ι	UART 1 Receive Data
UART1_TXD/ISH_UART1_TXD/ GPP_C13	0	UART 1 Transmit Data
UART1_RTS#/ ISH_UART1_RTS#/ GPP_C14	0	UART 1 Request to Send
UART1_CTS#/ ISH_UART1_CTS#/ GPP_C15	Ι	UART 1 Clear to Send
UART2_RXD/ GPP_C20	I	UART 2 Receive Data
UART2_TXD/ GPP_C21	0	UART 2 Transmit Data
UART2_RTS#/ GPP_C22	0	UART 2 Request to Send
UART2_CTS#/ GPP_C23	Ι	UART 2 Clear to Send



33.2 I/O Signal Planes and States

Signal Name	Power Plane	During Reset ¹	Immediately after Reset ¹	S3/S4/S5	Deep Sx
UART[2:0]_RXD	Primary	Undriven	Undriven	Undriven	OFF
UART[2:0]_TXD	Primary	Undriven	Undriven	Undriven	OFF
UART[2:0]_RTS#	Primary	Undriven	Undriven	Undriven	OFF
UART[2:0]_CTS#	Primary	Undriven	Undriven	Undriven	OFF
Note: 1 Deset reference for primary well pipe is DSMDST#					

Note: 1. Reset reference for primary well pins is RSMRST#.

33.3 Functional Description

This section describes the following:

- Features
- UART Serial (RS-232) Protocols Overview
- 16550 8-bit Addressing Debug Driver Compatibility
- DMA Controller
- Reset
- Power Management
- Interrupts
- Error Handling

33.3.1 Features

The UART interfaces support the following features:

- Up to 6.25 Mbits/s Auto Flow Control mode as specified in the 16750 standard
- Transmitter Holding Register Empty (THRE) interrupt mode
- 64-byte TX and 64-byte RX host controller FIFOs
- DMA support with 64-byte DMA FIFO per channel (up to 32-byte burst)
- Functionality based on the 16550 industry standards
- Programmable character properties, such as number of data bits per character (5-8), optional parity bit (with odd or even select) and number of stop bits (1, 1.5, or 2)
- Line break generation and detection
- DMA signaling with two programmable modes
- Prioritized interrupt identification
- Programmable FIFO enable/disable
- Programmable serial data baud rate
- Modem and status lines are independently controlled
- Programmable BAUD RATE supported (baud rate = (serial clock frequency)/ (16xdivisor))



NOTES

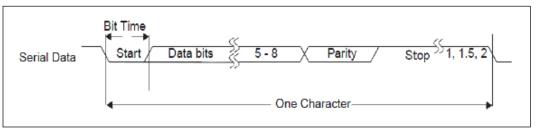
- 1. SIR mode is not supported.
- 2. External read enable signal for RAM wake up when using external RAMs is not supported.

33.3.2 UART Serial (RS-232) Protocols Overview

Because the serial communication between the UART host controller and the selected device is asynchronous, Start and Stop bits are used on the serial data to synchronize the two devices. The structure of serial data accompanied by Start and Stop bits is referred to as a character.

An additional parity bit may be added to the serial character. This bit appears after the last data bit and before the stop bit(s) in the character structure to provide the UART Host Controller with the ability to perform simple error checking on the received data.

Figure 43. UART Serial Protocol



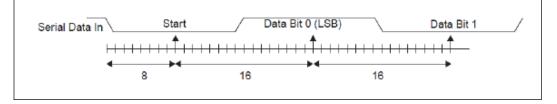
The UART Host Controller Line Control Register (LCR) is used to control the serial character characteristics. The individual bits of the data word are sent after the Start bit, starting with the least significant bit (LSB). These are followed by the optional parity bit, followed by the Stop bit(s), which can be 1, 1.5, or 2.

The Stop bit duration implemented by UART host controller may appear longer due to idle time inserted between characters for some configurations and baud clock divisor values in the transmit direction.

All bit in the transmission (with exception to the half stop bit when 1.5 stop bits are used) are transmitted for exactly the same time duration (which is referred to as Bit Period or Bit Time). One Bit Time equals to 16 baud clocks.

To ensure stability on the line, the receiver samples the serial input data at approximately the midpoint of the Bit Time once the start bit has been detected.

Figure 44. UART Receiver Serial Data Sample Points





33.3.3 16550 8-bit Addressing - Debug Driver Compatibility

The PCH UART host controller is not compatible with legacy UART 16550 debug-port drivers. The UART host controller operates in 32-bit addressing mode only. UART 16550 legacy drivers only operate with 8-bit (byte) addressing. In order to provide compatibility with standard in-box legacy UART drivers a 16550 Legacy Driver mode has been implemented in the UART controller that will convert 8-bit addressed accesses from the 16550 legacy driver to the 32-bit addressing that the UART host controller supports.

NOTE

The UART 16550 8-bit Legacy mode only operates with PIO transactions. DMA transactions are not supported in this mode.

33.3.4 DMA Controller

The UART controllers 0 and 1 (UART0 and UART1) have an integrated DMA controller. Each channel contains a 64-byte FIFO. Max. burst size supported is 32 bytes.

UART controller 2 (UART2) only implements the host controllers and does not incorporate a DMA. Therefore, UART2 is restricted to operate in PIO mode only.

DMA Transfer and Setup Modes

The DMA can operate in the following modes:

- 1. Memory to peripheral transfers. This mode requires that the peripheral control the flow of the data to itself.
- 2. Peripheral to memory transfer. This mode requires that the peripheral control the flow of the data from itself.

The DMA supports the following modes for programming:

- 1. Direct programming. Direct register writes to DMA registers to configure and initiate the transfer.
- 2. Descriptor based linked list. The descriptors will be stored in memory (such as DDR or SRAM). The DMA will be informed with the location information of the descriptor. DMA initiates reads and programs its own register. The descriptors can form a linked list for multiple blocks to be programmed.
- 3. Scatter Gather mode.

Channel Control

- The source transfer width and destination transfer width are programmable. It can vary to 1 byte, 2 bytes, and 4 bytes.
- Burst size is configurable per channel for source and destination. The number is a power of 2 and can vary between 1,2,4,...,128. this number times the transaction width gives the number of bytes that will be transferred per burst.
- Individual Channel enables. If the channel is not being used, then it should be clock gated.
- Programmable Block size and Packing/Unpacking. Block size of the transfer is programmable in bytes. the block size is not be limited by the source or destination transfer widths.



- Address incrementing modes: The DMA has a configurable mechanism for computing the source and destination addresses for the next transfer within the current block. The DMA supports incrementing addresses and constant addresses.
- Flexibility to configure any hardware handshake sideband interface to any of the DMA channels.
- Early termination of a transfer on a particular channel.

33.3.5 Reset

Each host controller has an independent rest associated with it. Control of these resets is accessed through the Reset Register.

Each host controller and DMA will be in reset state once powered off and require SW (BIOS or driver) to write into specific reset register to bring the controller from reset state into operational mode.

33.3.6 Power Management

Device Power Down Support

In order to power down peripherals connected to PCH UART bus, the idle, configured state of the I/O signals must be retained to avoid transitions on the bus that can affect the connected powered peripheral. Connected devices are allowed to remain in the D0 active or D2 low power states when the bus is powered off (power gated). The PCH HW will prevent any transitions on the serial bus signals during a power gate event.

Latency Tolerance Reporting (LTR)

Latency Tolerance Reporting is used to allow the system to optimize internal power states based on dynamic data, comprehending the current platform activity and service latency requirements. The UART bus architecture, however, does not provide the architectural means to define dynamic latency tolerance messaging. Therefore, the interface supports this by reporting its service latency requirements to the platform power management controller via LTR registers.

The controller's latency tolerance reporting can be managed by one of the two following schemes. The platform integrator must choose the correct scheme for managing latency tolerance reporting based on the platform, OS and usage.

- Platform/HW Default Control. This scheme is used for usage models in which the controller's state correctly informs the platform of the current latency requirements. In this scheme, the latency requirement is a function of the controller state. The latency for transmitting data to/from its connected device at a given rate while the controller is active is representative of the active latency requirements. On the other hand if the device is not transmitting or receiving data and idle, there is no expectation for end to end latency.
- 2. Driver Control. This scheme is used for usage models in which the controller state does not inform the platform correctly of the current latency requirements. If the FIFOs of the connected device are much smaller than the controller FIFOs, or the connected device's end to end traffic assumptions are much smaller than the latency to restore the platform from low power state, driver control should be used.



33.3.7 Interrupts

UART interface has an interrupt line which is used to notify the driver that service is required.

When an interrupt occurs, the device driver needs to read both the host controller and DMA status and TX completion interrupt registers to identify the interrupt source. Clearing the interrupt is done with the corresponding interrupt register in the host controller or DMA.

All interrupts are active high and their behavior is level interrupt.

33.3.8 Error Handling

Errors that might occur on the external UART signals are comprehended by the host controller and reported to the interface host controller driver through the MMIO registers.



34.0 Universal Serial Bus (USB)

The PCH implements an USB 3.2 xHCI controller which provides support for up to USB 2.0 signal pairs and 6 USB 3.2 signal pairs. The xHCI controller supports wake up from sleep states S1-S4. The xHCI controller supports up to 64 devices for a maximum number of 2048 Asynchronous endpoints (Control / Bulk) or maximum number of 128 Periodic endpoints (Interrupt / isochronous).

NOTE

Each walk-up USB 3.2 capable port must have USB 3.2 signaling and USB 2.0 signaling.

Acronyms

Acronyms	Description
xHCI	eXtensible Host Controller Interface

References

Specification	Location
USB 3.2 Specification	www.usb.org
USB 3.1 Specification	www.usb.org
USB 3.0 Specification	www.usb.org
USB 2.0 Specification	www.usb.org

34.1 Signal Description

Name	Туре	Description
USB31_1_RXN/ USB31_1_RXP	I	USB 3.2 Differential Receive Pair 1 : These are USB 3.2-based high- speed differential signals for Port #1 and the xHCI Controller. This signal should be mapped to a USB connector and with one of the OC (overcurrent) signals.
USB31_1_TXN/ USB31_1_TXP	0	USB 3.2 Differential Transmit Pair 1 : These are USB 3.2-based high- speed differential signals for Port #1 and the xHCI Controller. This signal should be mapped to a USB connector and with one of the OC (overcurrent) signals
USB31_2_RXN/ USB31_2_RXP	I	USB 3.2 Differential Receive Pair 2 : These are USB 3.2-based high- speed differential signals for Port #2 and the xHCI Controller. This signal should be mapped to a USB connector and with one of the OC (overcurrent) signals
USB31_2_TXN/ USB31_2_TXP	0	USB 3.2 Differential Transmit Pair 2 : These are USB 3.2-based high- speed differential signals for Port #2 and the xHCI Controller. This signal should be mapped to a USB connector and with one of the OC (overcurrent) signals
	1	continued



Name	Туре	Description	
USB31_3_RXN/ USB31_3_RXP	I	USB 3.2 Differential Receive Pair 3 : These are USB 3.2-based high- speed differential signals for Port #3 and the xHCI Controller. This signal should be mapped to a USB connector and with one of the OC (overcurrent) signals.	
USB31_3_TXN/ USB31_3_TXP	0	USB 3.2 Differential Transmit Pair 3 : These are USB 3.2-based high- speed differential signals for Port #3 and the xHCI Controller. This signal should be mapped to a USB connector and with one of the OC (overcurrent) signals.	
USB31_4_RXN/ USB31_4_RXP	I	USB 3.2 Differential Receive Pair 4 : These are USB 3.2-based high- speed differential signals for Port #4 and the xHCI Controller. This signal should be mapped to a USB connector and with one of the OC (overcurrent) signals	
USB31_4_TXN/ USB31_4_TXP	0	USB 3.2 Differential Transmit Pair 4 : These are USB 3.2-based high- speed differential signals for Port #4 and the xHCI Controller. This signal should be mapped to a USB connector and with one of the OC (overcurrent) signals.	
USB31_5_RXN/ PCIE5_RXN, USB31_5_RXP / PCIE5_RXP	I	USB 3.2 Differential Receive Pair 5 : These are USB 3.2-based high- speed differential signals for Port #5 and the xHCI Controller. This signal should be mapped to a USB connector and with one of the OC (overcurrent) signals.	
USB31_5_TXN/ PCIE5_TXN, USB31_5_TXP / PCIE5_TXP	0	USB 3.2 Differential Transmit Pair 5 : These are USB 3.2-based high- speed differential signals for Port #5 and the xHCI Controller. This signal should be mapped to a USB connector and with one of the OC (overcurrent) signals.	
USB31_6_RXN/ PCIE6_RXN, USB31_6_RXP / PCIE6_RXP	I	USB 3.2 Differential Receive Pair 6 : These are USB 3.2-based high- speed differential signals for Port #6 and the xHCI Controller. This signal should be mapped to a USB connector and with one of the OC (overcurrent) signals.	
USB31_6_TXN/ PCIE6_TXN, USB31_6_TXP / PCIE6_TXP	0	USB 3.2 Differential Transmit Pair 6 : These are USB 3.2-based high- speed differential signals for Port #6 and the xHCI Controller. This signal should be mapped to a USB connector and with one of the OC (overcurre signals.	
USB2P_1/ USB2N_1	I/O	USB 2.0 Port 1 Transmit/Receive Differential Pair 1: This USB 2.0 signal pair are routed to xHCI Controller and should be mapped to a USB connector with one of the overcurrent OC (overcurrent) signals.	
USB2P_2/ USB2N_2	I/O	USB 2.0 Port 1 Transmit/Receive Differential Pair 2: This USB 2.0 signal pair are routed to xHCI Controller and should be mapped to a USB connector with one of the overcurrent OCOC (overcurrent) signals.	
USB2P_3/ USB2N_3	I/O	USB 2.0 Port 1 Transmit/Receive Differential Pair 3: This USB 2.0 signal pair are routed to xHCI Controller and should be mapped to a USB connector with one of the overcurrent OC (overcurrent) signals.	
USB2P_4/ USB2N_4	I/O	USB 2.0 Port 1 Transmit/Receive Differential Pair 4: This USB 2.0 signal pair are routed to xHCI Controller and should be mapped to a USB connector with one of the overcurrent OC (overcurrent) signals.	
USB2P_5/ USB2N_5	I/O	USB 2.0 Port 1 Transmit/Receive Differential Pair 5: This USB 2.0 signal pair are routed to xHCI Controller and should be mapped to a USB connector with one of the overcurrent OC (overcurrent) signals.	
USB2P_6/ USB2N_6	I/O	USB 2.0 Port 1 Transmit/Receive Differential Pair 6: This USB 2.0 signal pair are routed to xHCI Controller and should be mapped to a USB connector with one of the overcurrent OC.OC (overcurrent) signals.	
USB2P_7/ USB2N_7	I/O	USB 2.0 Port 1 Transmit/Receive Differential Pair 7: This USB 2.0 signal pair are routed to xHCI Controller and should be mapped to a USB connector with one of the overcurrent OC (overcurrent) signals.	
		continued	



Name	Туре	Description	
USB2P_8/ USB2N_8	I/O	USB 2.0 Port 1 Transmit/Receive Differential Pair 8: This USB 2.0 signal pair are routed to xHCI Controller and should be mapped to a USB connector with one of the overcurrent OC (overcurrent) signals.	
USB2P_9/ USB2N_9	I/O	USB 2.0 Port 1 Transmit/Receive Differential Pair 9: This USB 2.0 signal pair are routed to xHCI Controller and should be mapped to a USB connector with one of the overcurrent OC (overcurrent) signals.	
USB2P_10/ USB2N_10	I/O	USB 2.0 Port 1 Transmit/Receive Differential Pair 10: This USB 2.0 signal pair are routed to xHCI Controller and should be mapped to a USB connector with one of the overcurrent OC (overcurrent) signals.	
USB2_OC0# / GPP_E9	Ι	Overcurrent Indicators : These signals set corresponding bits in the USB controller to indicate that an overcurrent condition has occurred.	
USB2_OC1# / GPP_E10	I	Overcurrent Indicators : These signals set corresponding bits in the USB controller to indicate that an overcurrent condition has occurred.	
USB2_OC2# / GPP_E11	I	Overcurrent Indicators : These signals set corresponding bits in the USB controller to indicate that an overcurrent condition has occurred.	
USB2_OC3# / GPP_E12	I	Overcurrent Indicators : These signals set corresponding bits in the USB controller to indicate that an overcurrent condition has occurred.	
USB2_VBUSSENSE	I	VBUS Sense for USB Device mode. Note: This HW signal is not used on the PCH for USB device mode functionality. This signal should be connected to ground.	
USB2_ID	I	ID detect for USB Device mode. <i>Note:</i> This HW signal is not used on the PCH for dual role mode selection. The switching of USB port role is done by EC through the eSPI Out of Band (OOB) message or LPC SCI/SMI to notify BIOS to set the SPR registers in the PCH. This signal should be connected to ground.	
USB2_COMP	Ι	USB Resistor Bias, analog connection points for an external resistor to ground.	

NOTE

It is not recommended to route the USB 3.2 signals to the USB connector for USB ports that is USB 2.0 capable only.

34.2 Integrated Pull-Ups and Pull-Downs

Signal	Resistor Type	Value	Notes	
USB2N_[10:1]	Internal Pull-down	14.25–24.8 kohm	1	
USB2P_[10:1]	Internal Pull-down	14.25-24.8 kohm	1	
USB2_ID Internal Weak Pull-up 14.25-24.8 kohm If this signal is not in use, then the pin shall be connected directly to ground.				
Note: 1. Series resistors (45 ohm ±10%).				



I/O Signal Planes and States 34.3

Signal Name	Power Plane	During Reset ²	Immediately After Reset ²	S3/S4/S5	Deep Sx
USB31_[6:1]_RXN USB31_[6:1]_RXP	Primary	Internal Pull-down	Internal Pull-down	Internal Pull-down	OFF
USB31_[6:1]_TXN USB31_[6:1]_TXP	Primary	Internal Pull-down	Internal Pull-down	Internal Pull-down	OFF
USB2N_[10:1]	DSW	Internal Pull-down	Internal Pull-down	Internal Pull-down	Internal Pull- down
USB2P_[10:1]	DSW	Internal Pull-down	Internal Pull-down	Internal Pull-down	Internal Pull- down
USB2_OC0#	Primary	Undriven	Undriven	Undriven	OFF
USB2_OC1#	Primary	Undriven	Undriven	Undriven	OFF
USB2_OC2#	Primary	Undriven	Undriven	Undriven	OFF
USB2_OC3#	Primary	Undriven	Undriven	Undriven	OFF
USB2_VBUSSENSE	Primary	Undriven	Undriven	Undriven	OFF
USB2_ID ¹	Primary	Internal Pull-up	Undriven/Internal Pull-up	Undriven/Internal Pull-up	OFF
USB2_COMP	Primary	Undriven	Undriven	Undriven	OFF

2. Reset reference for primary well pins is RSMRST#, DSW well pins is DSW_PWROK, and RTC well pins is RTCRST#.

34.4 **Functional Description**

This section covers the following information:

- eXtensible Host Controller Interface (xHCI) Controller (D20:F0) •
- USB Dual Role Support eXtensible Device Controller Interface (xHCI) Controller (D20:F1)
- Supported USB 2.0 Ports

34.4.1 eXtensible Host Controller Interface (xHCI) Controller (D20:F0)

The PCH contains an eXtensible Host Controller Interface (xHCI) which supports up to 10 USB 2.0 ports and up to 6 USB 3.2 ports with board routing, ACPI table and BIOS considerations are required. This controller allows data transfers of up to 10 Gb/s for USB 3.2 Gen 2x1 ports and 5 Gb/s for USB 3.2 Gen 1x1 ports. The controller supports SuperSpeed USB 10 Gbps, SuperSpeed USB 5 Gbps, High-Speed (HS), Full-Speed (FS) and Low-Speed (LS) traffic on the bus. The xHCI supports USB Debug port on all USB 3.2 capable ports. The xHCI also supports USB Attached SCIS Protocol (UASP). The PCH also support dual role capability.



34.4.2 USB Dual Role Support - eXtensible Device Controller Interface (xHCI) Controller (D20:F1)

The PCH also supports Dual Role Capability. The xHCI can now be paired with a standalone eXtensible Device Controller Interface (xDCI) to provide dual role functionality. The USB subsystem incorporates a USB 3.2 Gen 1x1 (5 Gb/s) xDCI controller. The Device controller support SuperSpeed USB 5 Gbps, High-Speed (HS). This controller is instantiated as a separate PCI function. The PCH USB implementation is compliant to the Device specification and supports host/device through USB Type-C* connector.

The xDCI shares all USB ports with the host controller, with ownership of the port being decided based the USB Power Delivery specification. Since all the ports support device mode, xDCI enabling must be extended by System BIOS and EC. While the port is mapped to the device controller, the host controller Rx detection must always indicate a disconnected port.

34.4.3 Supported USB 2.0 Ports

Due to the USB 2.0 port requirement for integrated Bluetooth^{*} functionality with the integrated Intel[®] Wireless-AC (CNVi) solution, PCH-LP USB 2.0 port 10 will be available for the following:

- Premium-U and Mainstreams Base-U
 - USB 2.0 port 10 will be enabled on U platforms.

The total USB 2.0 port availability for a given SKU will also take into account the USB 2.0 port requirement for integrated Bluetooth^{*} functionality. The following table describes the number of port supported and the associated port number enabled per SKU.

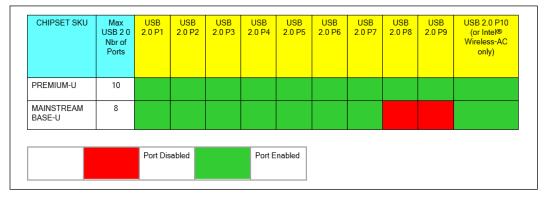


Figure 45. PCH-LP SKU



35.0 Connectivity Integrated (CNVi)

Connectivity Integrated (CNVi) is a general term referring to a family of connectivity solutions which are based on the Connectivity Controller family. The common component of all these solutions is the Connectivity Controller IP, which is a hard macro embedded in various Intel SoC chips.

The Integrated Connectivity (CNVi) solution consists of the following entities:

- The containing chip (PCH which contains the Connectivity Controller IP)
- Buttress (as applicable to each platform)
- Companion RF chip that is in a pre-certified module (that is, M.2) or soldered as chip on board.

Acronyms

Acronyms	Description
CNVi	Connectivity Integrated
IP	Literally, Intellectual Property. IP refers to architecture, design, validation, and software components collectively delivered to enable one or more specific features
MFUART	Multifunction Universal Asynchronous Receiver/Transmitter
RGI	Radio Generic interface
UART	Universal Asynchronous Receiver/Transmitter

References

Specification	Document Number / Location
M.2 Specification	https://pcisig.com/specifications/pciexpress/M.2_Specification/
$\ensuremath{MIPI}^{\ensuremath{\mathbb{S}}}$ Alliance specification for D-PHY v1.1	http://www.mipi.org/specifications/

35.1 Signal Description

Name	Туре	Description
GPIO fixed function		
GPP_H0 / I2S2_SCLK / CNV_BT_I2S_SCLK	I/O	For CNVi: Unused For standard Connectivity with UART host support: Optional Bluetooth* $\rm I^2S$ bus clock.
GPP_H1 / I2S2_SFRM / CNV_BT_I2S_BCLK / CNV_RF_RESET#	0	For CNVi: RF companion (CRF) reset signal, active low, must be low and glitch free at power up. For standard Connectivity with UART host support: Optional Bluetooth* I ² S bus sync.
GPP_H2 / I2S2_TXD / CNV_BT_I2S_SDI / MODEM_CLKREQ	0	For CNVi: Clock request signal. Used to request the RF companion clock (38.4 Mhz Ref clock) for Pulsar and the PCH.
		continued



Name	Туре	Description
		For standard Connectivity with UART host Bluetooth* support: Optional Bluetooth* $\rm I^2S$ bus data output (input to Bluetooth* module).
GPP_D8 / 12S2_SCLK	I	For CNVi: Unused. For standard Connectivity with UART host support: Optional Bluetooth* $\rm I^2S$ bus clock (input to Bluetooth* module).
GPP_H3 / I2S2_RXD / CNV_BT_I2S_SDO	I	For CNVi: Unused. For standard Connectivity with UART host support: Optional Bluetooth* $\rm I^2S$ bus data output (input to Bluetooth* module).
GPP_F0 / CNV_PA_BLANKING	I	For CNVi and standard Connectivity: Optional WLAN/Bluetooth*-WWAN coexistence signal COEX3. Co-existance signal for external GNSS solution
GPP_F8 / CNV_MFUART2_RXD	I	For CNVi and standard Connectivity: Optional WLAN/Bluetooth*-WWAN coexistence signal COEX2.
GPP_F9 / CNV_MFUART2_TXD	0	For CNVi and standard Connectivity: Optional WLAN/Bluetooth*-WWAN coexistence signal COEX1.
GPP_F4 / CNV_BRI_DT	0	For CNVi: BRI bus TX. For standard Connectivity with UART host support: Bluetooth* UART RTS#
GPP_F5 / CNV_BRI_RSP	I	For CNVi: BRI bus RX. For standard Connectivity with UART host support: Bluetooth* UART RXD
GPP_F6 / CNV_RGI_DT	0	For CNVi: RGI bus TX. For standard Connectivity with UART host support: Bluetooth* UART TXD
GPP_F7 / CNV_RGI_RSP	I	For CNVi: RGI bus RX. For standard Connectivity with UART host support: Bluetooth* UART CTS#
GPIO selectable function		
GPP_B2	0	UART_BT_WAKE output. Optional to connect to Bluetooth* Wake on Bluetooth* Module. This is the recommended GPIO but other GPIOs can be selected for this function.
GPP_B4	0	BT_KILL output. Optional to connect to a Bluetooth* KILL pin on the Bluetooth* module. This is the recommended GPIO but other GPIOs can be selected for this function.
GPP_B8	0	For CNVi: Unused Wi-Fi* PCIe* clock request output for standard CNV. Optional to connect to a WLAN PCIe* clock request pin on the Wi-Fi* module. This is the recommended GPIO but other GPIOs can be selected for this function
GPP_C2	0	WLAN_KILL output. Optional to connect to a WLAN KILL pin on the Wi-Fi* module. This is the recommended GPIO but other GPIOs can be selected for this function.
GPP_C5	0	For CNVi: Unused Wi-Fi* PCIe* host wake output for standard Connectivity. Optional to connect to a WLAN PCIe* host wake pin on the Wi-Fi* module. This is the recommended GPIO but other GPIOs can be selected for this function.
Fixed Special Purpose I/O		
CNV_WT_CLKP	0	CNVio bus TX CLK+
CNV_WT_CLKN	0	CNVio bus TX CLK-
CNV_WT_D0P	0	CNVio bus Lane 0 TX+
CNV_WT_D0N	0	CNVio bus Lane 0 TX-



Name	Туре	Description
CNV_WT_D1P	0	CNVio bus Lane 1 TX+
CNV_WT_D1N	0	CNVio bus Lane 1 TX-
CNV_WR_CLKP	I	CNVio bus RX CLK+
CNV_WR_CLKN	I	CNVio bus RX CLK-
CNV_WR_D0P	I	CNVio bus Lane 0 RX+
CNV_WR_D0N	I	CNVio bus Lane 0 RX-
CNV_WR_D1P	I	CNVio bus Lane 1 RX+
CNV_WR_D1N	I	CNVio bus Lane 1 RX-
CLKIN_XTAL	I	Single-ended clock signal input for CNVi (38.4MHz). Should be connected to the reference clock output of the RF companion (CRF)
Selectable Special Purpose I/O		
USB2_P10_DP		Bluetooth* USB host bus (positive) for standard Connectivity. Optional to connect to a Bluetooth* USB+ pin on the Bluetooth* module. Port 10 is the recommended port but other USB2 ports can be selected for this function.
USB2_P10_DN		Bluetooth* USB host bus (negative) for standard Connectivity. Optional to connect to a Bluetooth* USB+ pin on the Bluetooth* module. Port 10 is the recommended port but other USB2 ports can be selected for this function.
PCIE14_LAN0E_TX_DP	0	Wi-Fi* PCIe* host bus TX (positive) for standard Connectivity. Optional to connect to a Wi-Fi* PCIe* PERp0 pin on the Wi-Fi* module. This is the recommended port but other PCIe* ports can be selected for this function.
PCIE14_LAN0E_TX_DN	0	Wi-Fi* PCIe* host bus TX (negative) for standard Connectivity. Optional to connect to a Wi-Fi* PCIe* PERn0 pin on the Wi-Fi* module. This is the recommended port but other PCIe* ports can be selected for this function.
PCIE14_LAN0E_RX_DP	I	Wi-Fi* PCIe* host bus RX (positive) for standard Connectivity. Optional to connect to a Wi-Fi* PCIe* PETp0 pin on the Wi-Fi* module. This is the recommended port but other PCIe* ports can be selected for this function.
PCIE14_LAN0E_RX_DN	I	Wi-Fi* PCIe* host bus RX (negative) for standard Connectivity. Optional to connect to a Wi-Fi* PCIe* PETn0 pin on the Wi-Fi* module. This is the recommended port but other PCIe* ports can be selected for this function.
CLK_SRC3_DP	0	Wi-Fi* PCIe* host bus clock (positive) for standard Connectivity. Optional to connect to a Wi-Fi* PCIe* REFCLKp pin on the Wi-Fi* module. This is the recommended clock signal but other PCIe* clocks can be selected for this function.
CLK_SRC3_DN	0	Wi-Fi* PCIe* host bus clock (negative) for standard Connectivity. Optional to connect to a Wi-Fi* PCIe* REFCLKp pin on the Wi-Fi* module. This is the recommended clock signal but other PCIe* clocks can be selected for this function.
CL_RST#	0	Wi-Fi* Controller Link host bus reset for standard Connectivity with Controller Link support (Intel [®] vPro [™]). Optional to connect to a Wi-Fi* Controller Link reset pin on the Intel [®] vPro [™] Wi-Fi* module.
CL_DATA	I/O	Wi-Fi* Controller Link host bus data for standard Connectivity with Controller Link support (Intel [®] vPro [™]). Optional to connect to a Wi-Fi* Controller Link data pin on the Intel [®] vPro [™] Wi-Fi* module.
		continued



Name	Туре	Description
CL_CLK	0	Wi-Fi* Controller Link host bus clock for standard Connectivity with Controller Link support (Intel [®] vPro ^{T}). Optional to connect to a Wi-Fi* Controller Link clock pin on the Intel [®] vPro ^{T} Wi-Fi* module.
W_DISABLE1#	I	Used for Wi-Fi* RF-Kill control. This pin can be connected to a platform switch or to SoC GPIOs (recommendation- if possible do not use GPIOs that have Platform impact as "bootstraps" during platform init).
W_DISABLE2#	I	Used for Bluetooth* RF-Kill control. This pin can be connected to a platform switch or to SoC GPIOs (recommendation- if possible do not use GPIOs that have Platform impact as "bootstraps" during platform init).

35.2 Integrated Pull-ups and Pull-downs

The OEM should consider the pull-ups and pull-downs on the CRF card, as described in the below table

I/F	Signals	PU/PD in CNVi (CRF)	PU/PD in CNVi (SoC)	Comments
BRI/RGI (Bluetooth* UART)	RGI_DT /BRI_DT	PU (~120-150 Kohm), RGI_DT shall be applied with 1 Kohm pull down during power- on Init	-	Shared with BT UART .Expected power wasted while active with 100K <32uW at each pin. RGI_DT is used by the platform to strap the presence of the CRF, as such it is a strong pull-down by the CRF (1K) as long as RF_RESET_B = 0. BRI_RSP is used by the CNVi to strap the
	RGI_RSP/BRI_RSP	none	PU = 20 Kohm . This can be set by the BIOS after boot-up; needs to be enabled ONLY if CNVi is not used in the platform	CRF type; i.e, when to apply PLL speed: when BRI_RSP = 0 - PLL at 1280 Mohm (Jefferson Peak), when BRI_RSP =1 - PLL at 1320 (Harrison Peak and other future parts)
W_DISABLE#	Wi-Fi/BT RF Kill	PU (~110-130Ko hm)	-	
Slow CLK	SUSCLK (32kHz)	PD (~100Kohm)	-	If available on platform
Init signals	RF_RESET_B	PD (~100Kohm)	-	Shared with PCM_SYNC
	CLKREQ0	PD (~200Kohm)	-	Shared with PCM_OUT

35.3 Platform PU/PD requirements

The OEM should apply pull-ups and pull-downs on the platform side according to the below table



I/F	Signals	PU/PD in Platform	Comments
BRI/RGI (Bluetooth* UART)	RGI_DT	PU (20 Kohm)	This pull is required so that the SOC will be able to reliably detect that the CRF is present at power-up. However, it is possible to increase the resistor to 50K or even to 100K instead of 20K.
Init signals	CNV_ RF_RESET#	PU (75 Kohm)	It is highly encouraged to increase this resistor (or allow to switch it off when CNVi is active; not sure this is possible at the platform level). This resistor consumes power (43uW) all the time.
38.4 Ref clock	RefCLK	PD (10 Kohm) (for Jefferson Peak)	If used (a platform-level decision); not supported and not connected by Harrison Peak.
A4WP indication	A4WP_PRESENT	PD (75 Kohm)	Native function A4WP is not supported. The pin can instead be used as GPIO (when BIOS programs the pin to GPIO functionality). It is recommended to have an external pull down (75 Kohm) on the pin regardless of the pin being used or not to minimize power consumption. If the pin is used as GPIO, there should NOT be any on-board device driving the pin high until BIOS programs it to GPIO functionality

The OEM must avoid using a specific PU/PD when not needed or when required to not be used. Unless this rule is followed, a back-bias condition will result, where the IO is getting voltage before the device side is ready for it.

35.4 I/O Signal Planes and States

Signal Name	Power plane	During Reset	Immediately After Reset	S3/S4/S5	Deep Sx
CNV_BT_I2S_SCLK	Primary	Undriven	Undriven	Undriven	OFF
CNV_BT_I2S_BCLK	Primary	Undriven	Undriven	Undriven	OFF
CNV_BT_I2S_SDI	Primary	Undriven	Undriven	Undriven	OFF
CNV_BT_I2S_SDO	Primary	Undriven	Undriven	Undriven	OFF
CNV_RF_RESET#	Primary	Driven	Driven	Driven	OFF
MODEM_CLKREQ	Primary	Driven	Driven	Driven	OFF
CNV_PA_BLANKING	Primary	Undriven	Undriven	Undriven	OFF
CNV_MFUART2_RXD	Primary	Undriven	Undriven	Undriven	OFF
CNV_MFUART2_TXD	Primary	Undriven	Undriven	Undriven	OFF
CNV_BRI_DT	Primary	Driven	Driven	Driven	OFF
CNV_BRI_RSP	Primary	Powered (input, PU)	Powered (input, PU)	Powered (input, PU)	OFF
CNV_RGI_DT	Primary	Driven	Driven	Driven	OFF
CNV_RGI_RSP	Primary	Powered (input, PU)	Powered (input, PU)	Powered (input, PU)	OFF
	·				continued



Signal Name	Power plane	During Reset	Immediately After Reset	S3/S4/S5	Deep Sx
CNV_WT_CLKP	Primary	Undriven	Undriven	Driven	OFF
CNV_WT_CLKN	Primary	Undriven	Undriven	Driven	OFF
CNV_WT_D0P	Primary	Undriven	Undriven	Driven	OFF
CNV_WT_D0N	Primary	Undriven	Undriven	Driven	OFF
CNV_WT_D1P	Primary	Undriven	Undriven	Driven	OFF
CNV_WT_D1N	Primary	Undriven	Undriven	Driven	OFF
CNV_WR_CLKP	Primary	Undriven	Undriven	Powered (input)	OFF
CNV_WR_CLKN	Primary	Undriven	Undriven	Powered (input)	OFF
CNV_WR_D0P	Primary	Undriven	Undriven	Powered (input)	OFF
CNV_WR_D0N	Primary	Undriven	Undriven	Powered (input)	OFF
CNV_WR_D1P	Primary	Undriven	Undriven	Powered (input)	OFF
CNV_WR_D1N	Primary	Undriven	Undriven	Powered (input)	OFF
CNV_WT_RCOMP	Primary	Undriven	Undriven	Driven	OFF
CLKIN_XTAL_LCP	Primary	Depends on MODEM_CLKR EQ	Depends on MODEM_CLKREQ	Depends on MODEM_CLKR EQ	OFF
Note: Reset reference for primary well pins is RSMRST#.					

35.5 Functional Description

The main blocks of the integrated Connectivity solution are partitioned according to the following:

- Connectivity Controller IP contains:
 - Interfaces to the PCH
 - Debug and testing interfaces
 - Power management and clock Interfaces
 - Interface to the Companion RF module (CRF)
 - Interface to physical I/O pins controlled by the PCH
 - Interfaces to the LTE modem via PCH GPIO
- **Companion RF (CRF)**: This is the integrated connectivity M.2 module. The CRF Top contains:
 - Debug and testing interfaces
 - Power and clock Interfaces
 - Interface to the Connectivity Controller chip



 Physical I/O pins: The SCU units are responsible for generating and controlling the power and clock resources of Connectivity Controller and CRF. There are unique SCUs in Connectivity Controller and CRF and their operation is coordinated due to power and clock dependencies. This coordination is achieved by signaling over a control bus (AUX) connecting Connectivity Controller and CRF.

Both Connectivity Controller and CRF have a dedicated AUX bus and arbiter. These two AUX buses are connected by a special interface that connects over the RGI bus. Each of the Connectivity Controller and CRF cores is dedicated to handle a specific connectivity function (Wi-Fi, Bluetooth[®]).

Connectivity Controller core includes only the digital part of the connectivity function , while the CRF cores handle some digital and most of analog and RF functionality. Each core in the Connectivity Controller has an interface to the host and an interface to its counterpart in CRF. CRF cores include an analog part which is connected to board level RF circuitry and to an antenna.



36.0 embedded Multimedia Card (eMMC*)

The eMMC* is a universal data storage and communication media. It is designed to cover a wide area of applications such as smart phones, tablets, computers, cameras, and so on. PCH supports only 1.8V operating devices and PCH supports eMMC* version 5.1.

Key Features Supported

- HW Command Queuing support complaint to eMMC* v5.1 specification
- Supports enhanced Strobe for HS400 mode @1.8V
- Both ADMA2/DMA and Non-DMA mode of operation
- Transfers the data in 1 bit, 4 bit and 8 bit mode
- Supports 64 bit address

36.1 Signals Description

Name	Туре	Description
EMMC_CMD/GPP_F11	I/O	eMMC* Command/Response
EMMC_DATA0/GPP_F12	I/O	eMMC* Data
EMMC_DATA1/GPP_F13	I/O	eMMC* Data
EMMC_DATA2/GPP_F14	I/O	eMMC* Data
EMMC_DATA3/GPP_F15	I/O	eMMC* Data
EMMC_DATA4/GPP_F16	I/O	eMMC* Data
EMMC_DATA5/GPP_F17	I/O	eMMC* Data
EMMC_DATA6/GPP_F18	I/O	eMMC* Data
EMMC_DATA7/GPP_F19	I/O	eMMC* Data
EMMC_RCLK/GPP_F20	I	eMMC* Receive Clock
EMMC_CLK/GPP_F21	0	eMMC* Clock
EMMC_RCOMP	I/O	eMMC* compensation (200 Ohm +/- 1% pull down to ground)
EMMC_RESET#/GPP_F22	0	Reset (Recommend device reset to be connected to platform reset and not to this pin)



36.2 I/O Signal Planes and States

Signal Name	Power Well	During Reset ¹	Immediately after Reset ¹	S0/S3/S4/S5	Deep Sx
EMMC_DATA[7:0]	Primary	Undriven	Undriven	Undriven	OFF
EMMC_RCLK	Primary	Undriven	Undriven	Undriven	OFF
EMMC_CLK	Primary	Undriven	Undriven	Undriven	OFF
EMMC_CMD	Primary	Undriven	Undriven	Undriven	OFF
EMMC_RCOMP	Primary	Undriven	Undriven	Undriven	OFF
EMMC_RESET#	Primary	Undriven	Undriven	Undriven	OFF
Note: 1. Reset reference for primary well pins is RSMRST#.					

NOTE

Internal weak pull resistor is default off but configurable (pu/pd/none) after boot. The pin may be "L" or "H" after reset depending on the configuration.

36.3 Functional Description

The Controller handles eMMC* Protocol at transmission, packing data, adding cyclic redundancy check (CRC), start/end bit, and checking for transaction format correctness. Main supported features are listed below.

The eMMC* main use case is to connect an on board external storage device.

36.3.1 eMMC5.1 Command Queuing

Command Queuing (CQ) definition for eMMC* includes new commands for issuing tasks to the device, for ordering the execution of previously issued tasks and for additional task management function. The host controller with CQ can queue up to 32 commands to the device and the device selects and indicates one of the queued commands to host for service.

The host controller implements additional logic for handling a door-bell based DMA for the 32 descriptor / task list and manages the entire CQ flow which includes:

- Fetch and send the tasks/commands to device using existing logic
- Maintains context of each queued command
- Periodically read the device queue status and indicates completion of task to SW
- Implements interrupt coalescing to reduce burden on software ISR

36.3.2 eMMC5.1 Enhanced Strobe

Enhanced Strobe Mode for HS400 improves upon the HS400 mode interface speed increase that was first defined in eMMC* version 5.0, by facilitating faster synchronization between the host and the device.

Refer JEDEC eMMC5.1 specification for additional information.



36.3.3 eMMC* Working Modes

The following table shows the working modes of $eMMC^*$.

Table 106.eMMC* Working Modes

eMMC* Mode	Data Rate	Clock Frequency	Maximum Data Throughput	Actual Throughput
Compatibility	Single	0 – 26 MHz	26 MB/s	24 MB/s
High Speed SDR	Single	0 – 52 MHz	52 MB/s	48 MB/s
High Speed DDR	Dual	0 – 52 MHz	104MB/s	96 MB/s
HS200	Single	0 - 200 MHz	200 MB/s	192 MB/s
HS400	Dual	0 - 200 MHz	400 MB/s	384 MB/s



37.0 Secure Digital eXtended Capacity (SDXC)

The SDXC controller is to connect to an external detachable storage devices. It supports SDXC specification version 3.01.

Acronyms

Acronyms	Description
SDXC	Secure Digital eXtended Capacity

References

Specification	Location
SDXC Specifications	http://www.sdcard.org

37.1 Signal Description

Name	Туре	Description	Voltage
SD_CMD /GPP_G0	I/O	SD Command/Response	3.3V or 1.8V
SD_DATA0/GPP_G1	I/O	SD Data	3.3V or 1.8V
SD_DATA1/GPP_G2	I/O	SD Data	3.3V or 1.8V
SD_DATA2/GPP_G3	I/O	SD Data	3.3V or 1.8V
SD_DATA3/GPP_G4	I/O	SD Data	3.3V or 1.8V
SD_CD#/GPP_G5	I	SDXC Detect	3.3V or 1.8V
SD_CLK/GPP_G6	0	SD clock	3.3V or 1.8V
SD_WP/GPP_G7	I	SDXC write protect	3.3V or 1.8V
SD_VDD1_PWR_EN# / ISH_GP7 /GPP_A17	0	SDXC power enable for 3.3V Note: Signal assertion logic can be changed by BIOS. (Active High is default assertion logic)	1.8V
SD_3P3_RCOMP	I/O	Impedance compensation for 3.3V operation of SD card and GPIO buffers. External reference resistor (200 Ohm +/- 1% pull down to ground) is required, regardless of SD card interface is used or not.	NA
SD_1P8_RCOMP	I/O	Impedance compensation for 1.8V operation of SD card and GPIO buffers. External reference resistor (200 Ohm +/- 1% pull down to ground) is required, regardless of SD card interface is used or not. The RCOMP resistor can be shared with SD_3P3_RCOMP.	NA



I/O Signal Planes and States 37.2

Signal Name	Power Plane	During Reset ¹	Immediately after Reset ¹	S3/S4/S5	Deep Sx
SD_CMD	Primary	Undriven	Undriven	Undriven	OFF
SD_DATA[3:0]	Primary	Undriven	Undriven	Undriven	OFF
SD_CD#	Primary	Undriven	Undriven	Undriven	OFF
SD_CLK	Primary	Undriven	Undriven	Undriven	OFF
SD_WP	Primary	Undriven	Undriven	Undriven	OFF
SD_VDD1_PWR_EN#	Primary	Undriven	Driven	Undriven	OFF
SD_3P3_RCOMP	Primary	Undriven	Undriven	Undriven	OFF
SD_1P8_RCOMP	Primary	Undriven	Undriven	Undriven	OFF
Note: 1. Reset reference for primary well pins is RSMRST#.					

37.3 **Functional Description**

The SDXC controller handles SD Protocol at transmission, packing data, adding cyclic redundancy check (CRC), start/end bit, and checking for transaction format correctness. The SDXC main use case is to connect to an external detachable storage device. It supports SDXC card specification version 3.01. Both 1.8V and 3.3V signaling is supported. Additional information can be obtained from the SDXC 3.01 specification.

The following chart maps the working modes of SDXC.

Table 107. SD Working Modes

SDXC Mode	Data Rate	Clock Frequency	Maximum Data Throughput	Actual Throughput
Default Speed/SDR12	Single	0 – 25 MHz	12.5 MB/s	12 MB/s
High Speed/SDR25	Single	0 – 50 MHz	25 MB/s	24 MB/s
SDR50	Single	0 – 100 MHz	50 MB/s	48 MB/s
DDR50	Dual	0 – 50 MHz	50 MB/s	48 MB/s
SDR104	Single	0 – 208 MHz	104 MB/s	96 MB/s



38.0 Private Configuration Space Target Port ID

The PCH incorporates a wide variety of devices and functions. The registers within these devices are mainly accessed through the primary interface, such as PCI configuration space and IO/MMIO space. Some devices also have registers that are distributed within the PCH Private Configuration Space at individual endpoints which are only accessible through the PCH Sideband Interface. Refer to Volume 2 for registers that reside in the PCH Private Configuration Space (PCR registers).

These PCH Private Configuration Space Registers can be addressed via SBREG_BAR, Target Port ID, and register offset.

Acronyms

Acronyms	Description
OTG	On the go

The following table lists the PCH Target Port IDs for PCR register access.

Table 108. Private Configuration Space Register Target Port IDs

PCH Device/Function Type	Target Port ID
General Purpose I/O (GPIO) Community 4	6Ah
General Purpose I/O (GPIO) Community 2	6Ch
General Purpose I/O (GPIO) Community 1	6Dh
General Purpose I/O (GPIO) Community 0	6Eh
DCI	71h
PSF1	BAh
PSF2	BBh
PSF3	BCh
ISH Controller	BEh
Real Time Clock (RTC)	C3h
Processor Interface, 8254 Timer, HPET, APIC	C4h
SMBus	C6h
LPC	C7h
USB 2.0	CAh
UART, I ² C, GSPI	CBh
FIA Configuration	CFh
SATA	D9h
Integrated Clock Controller (ICC)	DCh
	continued

PCH Device/Function Type	Target Port ID
PCIe* Controller #1 (SPA)	80h
PCIe* Controller #2 (SPB)	81h
PCIe* Controller #3 (SPC)	82h
PCIe* Controller #4 (SPD)	83h
USB Dual Role / OTG	E5h
eSPI / SPI	72h
OPI Configuration	88h
Intel [®] Trace Hub	B6h
CNVi	73h